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Linear Charger Touch Flash MCU

**BS45F2141**

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[www.holtek.com](http://www.holtek.com)

## Features

### CPU Features

- Operating Voltage
  - ♦  $f_{\text{SYS}}=8\text{MHz}$ : 1.8V~5.5V
  - ♦  $f_{\text{SYS}}=12\text{MHz}$ : 2.7V~5.5V
  - ♦  $f_{\text{SYS}}=16\text{MHz}$ : 3.3V~5.5V
- Up to 0.25 $\mu\text{s}$  instruction cycle with 16MHz system clock at  $V_{\text{DD}}=5\text{V}$
- Power down and wake-up functions to reduce power consumption
- Oscillator types
  - ♦ Internal High Speed 8/12/16MHz RC – HIRC
  - ♦ Internal Low Speed 32kHz RC – LIRC
- Multi-mode operation: FAST, SLOW, IDLE and SLEEP
- Fully integrated internal oscillators require no external components
- All instructions executed in 1~3 instruction cycles
- Table read instructions
- 115 powerful instructions
- 6-level subroutine nesting
- Bit manipulation instruction

### Peripheral Features

- Flash Program Memory: 4K $\times$ 16
- Data Memory: 512 $\times$ 8
- True EEPROM Memory: 512 $\times$ 8
- 3 touch key functions – fully integrated without requiring external components
- Watchdog Timer function
- In Application Programming function – IAP
- 10 bidirectional I/O lines
- Programmable I/O port source current for LED driver
- Single external interrupt line shared with I/O pin
- Multiple Timer Modules for time measurement, input capture, compare match output or PWM output or single pulse output function
- Dual Time-Base functions for generation of fixed time interrupt signals
- 3 external channel 12-bit resolution A/D converter with internal reference voltage  $V_{\text{VR}}$
- I<sup>2</sup>C interface
- Fully-duplex/Half-duplex Universal Asynchronous Receiver and Transmitter Interface – UART
- Integrated 16-bit Cyclic Redundancy Check function – CRC
- Low voltage reset function – LVR
- Low voltage detect function – LVD

- Input voltage detect function
  - ♦ Input maximum rating 20V
  - ♦ Over voltage protection
  - ♦ Under voltage lockout
- Linear charger
  - ♦ Charging current up to 1A programmed through  $R_{SET}$  when  $V_{IN}=5V$
  - ♦ Charger status indication
  - ♦  $\pm 10\%$  charging current regulation in constant current mode
  - ♦  $\pm 1\%$  output voltage regulation in constant voltage mode @  $0^{\circ}C$  to  $85^{\circ}C$
  - ♦ Constant temperature regulation
  - ♦ Battery reverse current blocking when VIN input is invalid
- $2.0V \pm 1\%$  reference voltage output
- Package type: 16-pin NSOP

## General Description

The BS45F2141 is a Flash Memory A/D type 8-bit high performance RISC architecture microcontroller, designed especially for 3.7V lithium touch personal care products (electric toothbrushes, shavers, etc.) and 3.7V lithium portable touch electronic products.

For memory features, the Flash Memory offers users the convenience of Flash Memory multi-programming features. Other memory includes an area of RAM Data Memory as well as an area of true EEPROM memory for storage of non-volatile data such as serial numbers, calibration data etc. By using the In Application Programming technology, user have a convenient means to directly store their measured data in the Flash Program Memory as well as having the ability to easily update their application programs.

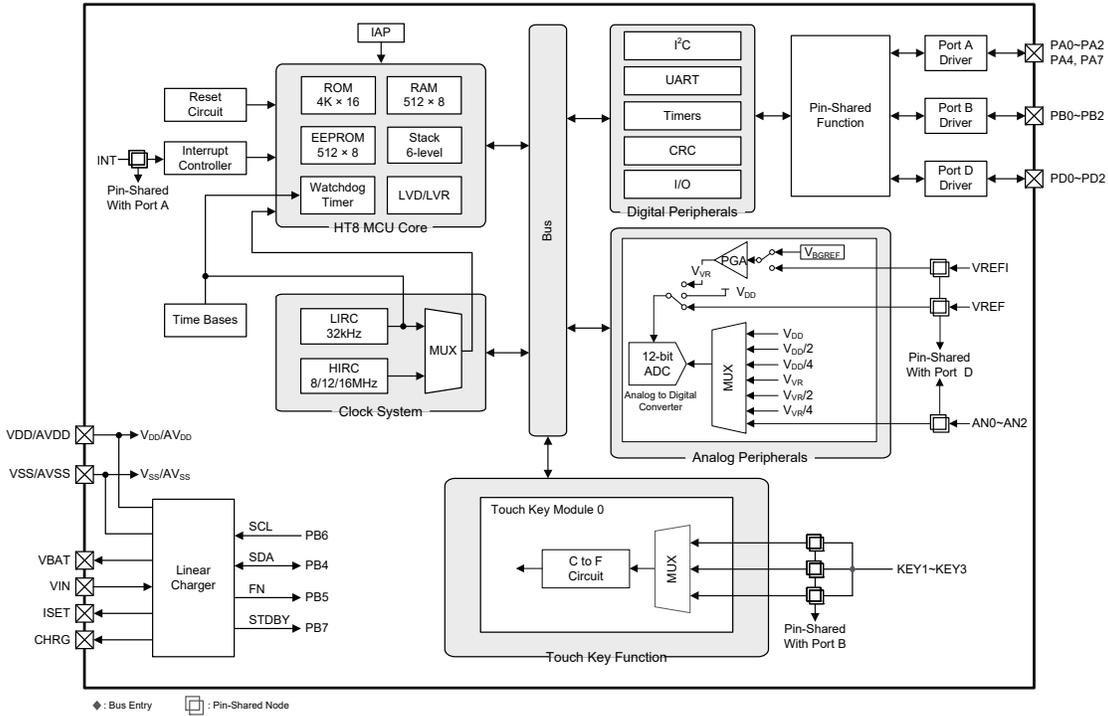
Analog feature includes a multi-channel 12-bit A/D converter. Easy communication with the outside world is provided using the internal I<sup>2</sup>C and UART interfaces. Protective features such as an internal Watchdog Timer, Low Voltage Detector and Low Voltage Reset coupled with excellent noise immunity and ESD protection ensure that reliable operation is maintained in hostile electrical environments.

A full choice of internal high and low speed oscillators are provided including fully integrated system oscillators which require no external components for its implementation. The ability to operate and switch dynamically between a range of operating modes using different clock sources gives users the ability to optimise microcontroller operation and minimise power consumption. The inclusion of flexible I/O programming features, Time-Base function, Timer Modules and many other features further enhance device functionality and flexibility.

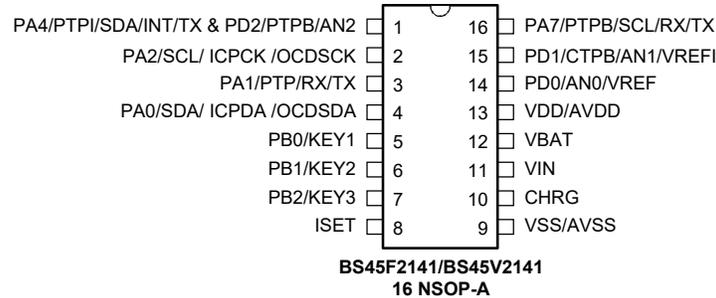
The device includes the functions of input over/under voltage protection, linear charger, charger status indication, reference voltage output, etc. It supports a maximum input rating of 20V to overcome unexpected high voltage from the USB input. The linear charger provides an up to 1A charging current for the Li-ion battery. The reference voltage function is used by the MCU for measuring battery voltage and current. The device uses a two-line communication interface to select different function, such as to control the linear charger and reference voltage function, or to read the charging status and control the STDBY signal and CHRГ pin by using the FN signal.

The device will find excellent use in a huge range of 3.7V lithium touch personal care products (electric toothbrushes, shavers, etc.) and 3.7V lithium portable touch electronic products to name but a few.

## Block Diagram



## Pin Assignment



- Note: 1. On Pin 1 there are two sets of pin functions, the PA4/PTPI/SDA/INT/TX or PD2/PTPB/AN2, however cannot be used simultaneously. If the PA4/PTPI/SDA/INT/TX function set is used, the PD2 should be configured as an input with pull-high function disabled. If the PD2/PTPB/AN2 function set is used, the PA4 should be configured as an input with pull-high function disabled.
2. If the pin-shared pin functions have multiple outputs, the desired pin-shared function is determined by the corresponding software control bits.
3. The OCSDA and OCDSCK pins are supplied for the OCDS dedicated pins and only available for the BS45V2141 device which is the OCDS EV chip of the for the BS45F2141 device.
4. There are some unbonded pins which should be properly configured to avoid unwanted current consumption resulting from floating input conditions. Refer to the “Standby Current Considerations” and “Input/Output Ports” sections.

## Pin Description

The function of each pin is listed in the following table, however the details behind how each pin is configured is contained in other sections of the datasheet. Note that the PA4 and PD2 share the same pin location, refer to the Pin Assignment.

Pin Name	Function	OPT	I/T	O/T	Description
PA0/SDA/ICPDA/ OCSDA	PA0	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	SDA	PAS0 IFS	ST	NMOS	I <sup>2</sup> C data line
	ICPDA	—	ST	CMOS	ICP data/address pin
	OCSDA	—	ST	CMOS	OCDS data/address pin, for EV chip only
PA1/PTP/RX/TX	PA1	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTP	PAS0	—	CMOS	PTM output
	RX/TX	PAS0 IFS	ST	CMOS	UART serial data input in full-duplex communication or UART serial data input/output in single wire mode communication
PA2/SCL/ICPCK/ OCDSCK	PA2	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	SCL	PAS0	ST	NMOS	I <sup>2</sup> C clock line
	ICPCK	—	ST	—	ICP clock pin
	OCDSCK	—	ST	—	OCDS clock pin, for EV chip only
PA4/PTPI/SDA/ INT/TX	PA4	PAPU PAWU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTPI	PAS1 IFS	ST	—	PTM capture input
	SDA	PAS1 IFS	ST	NMOS	I <sup>2</sup> C data line
	INT	INTC0 INTEG PAS1	ST	—	External interrupt input
	TX	PAS1	—	CMOS	UART serial data output
PA7/PTPB/SCL/ RX/TX	PA7	PAPU PAWU PAS1	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTPB	PAS1	—	CMOS	PTM inverted output
	SCL	PAS1 IFS	ST	NMOS	I <sup>2</sup> C clock line
	RX/TX	PAS1 IFS	ST	CMOS	UART serial data input in full-duplex communication or UART serial data input/output in single wire mode communication
PB0/KEY1~ PB2/KEY3	PB0~PB2	PBPU PBS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	KEY1~KEY3	PBS0	AN	—	Touch key input
PD0/AN0/VREF	PD0	PDP PDS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	AN0	PDS0	AN	—	A/D Converter external input channel
	VREF	PDS0	AN	—	A/D Converter external reference voltage input

Pin Name	Function	OPT	I/T	O/T	Description
PD1/CTPB/AN1/VREF1	PD1	PDP PDS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	CTPB	PDS0	—	CMOS	CTM inverted output
	AN1	PDS0	AN	—	A/D Converter external input channel
	VREF1	PDS0	AN	—	A/D Converter PGA input
PD2/PTPB/AN2	PD2	PDP PDS0	ST	CMOS	General purpose I/O. Register enabled pull-up
	PTPB	PDS0	—	CMOS	PTM inverted output
	AN2	PDS0	AN	—	A/D Converter external input channel
ISET	ISET	—	—	AN	Charging current setting
CHRG	CHRG	—	—	OD	Open-drain output, refer to the “Linear Charger” section
VIN	VIN	—	PWR	—	Input power
VBAT	VBAT	—	—	AN	Battery power
VDD/AVDD	VDD	—	PWR	—	Digital positive power supply
	AVDD	—	PWR	—	Analog positive power supply
VSS/AVSS	VSS	—	PWR	—	Digital negative power supply, ground
	AVSS	—	PWR	—	Analog negative power supply, ground

Legend: I/T: Input type;

O/T: Output type;

OPT: Optional by register selection;

PWR: Power;

ST: Schmitt Trigger input;

CMOS: CMOS output;

NMOS: NMOS output;

OD: Open drain;

AN: Analog signal.

### Internally Connected Signals

Several signals are not connected to external package pins. These signals are interconnection lines between the MCU and the Linear Charger and are listed in the following table. Users should properly configure the relevant pin-shared control bits and I/O control bits to implement correct interconnection.

MCU Signal Name	Linear Charger Signal Name	Function	Description
PB6	SCL	PB6	General purpose I/O Internally connected to the Linear Charger SCL
		SCL	Two-line communication clock line Internally connected to the MCU PB6
PB4	SDA	PB4	General purpose I/O Internally connected to the Linear Charger SDA
		SDA	Two-line communication data line Internally connected to the MCU PB4
PB5	FN	PB5	General purpose I/O Internally connected to the Linear Charger FN
		FN	Different status and functions based on two-line communication setting, refer to the “Interface” section Internally connected to the MCU PB5
PB7	STDBY	PB7	General purpose I/O Internally connected to the Linear Charger STDBY
		STDBY	Open-drain output, refer to the “Linear Charger” and “Interface” sections Internally connected to the MCU PB7

## Absolute Maximum Ratings

Supply Voltage .....	$V_{SS}-0.3V$ to $V_{SS}+6.0V$
Input Voltage .....	$V_{SS}-0.3V$ to $V_{DD}+0.3V$
VIN, CHRG.....	-0.3V to 20V
VBAT, ISET .....	-0.3V to 7.0V
Maximum Junction Temperature.....	160°C
Lead Temperature (Soldering 10sec) .....	260°C
Storage Temperature.....	-60°C to 150°C
Operating Temperature.....	-40°C to 85°C
IOH Total .....	-80mA
IOL Total .....	80mA
Total Power Dissipation .....	500mW

Note: These are stress ratings only. Stresses exceeding the range specified under “Absolute Maximum Ratings” may cause substantial damage to the device. Functional operation of the device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

## Recommended Operating Ranges

VIN, CHRG.....	4.5V to 7.0V
VBAT .....	2.5V to 4.2V
IBAT (max.) @ VIN=5V .....	1A
Ta.....	-40°C to 85°C

Note: Absolute Maximum Ratings indicate limitations beyond which damage to the device may occur. Recommended Operating Ranges indicate conditions for which the device is intended to be functional, but do not guarantee specified performance limits.

## D.C. Electrical Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency, pin load conditions, temperature and program instruction type, can all exert an influence on the measured values.

### Operating Voltage Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V <sub>DD</sub>	Operating Voltage – HIRC	f <sub>sys</sub> =8MHz	1.8	—	5.5	V
		f <sub>sys</sub> =12MHz	2.7	—	5.5	
		f <sub>sys</sub> =16MHz	3.3	—	5.5	
	Operating Voltage – LIRC	f <sub>sys</sub> =32kHz	1.8	—	5.5	V

**Operating Current Characteristics**

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
I <sub>DD</sub>	SLOW Mode – LIRC	1.8V	f <sub>sys</sub> =32kHz	—	8	16	μA
		3V		—	10	20	
		5V		—	30	50	
	FAST Mode – HIRC	1.8V	f <sub>sys</sub> =8MHz	—	0.6	1.0	mA
		3V		—	0.8	1.2	
		5V		—	1.6	2.4	
		2.7V	f <sub>sys</sub> =12MHz	—	1.0	1.4	mA
		3V		—	1.2	1.8	
		5V		—	2.4	3.6	
		3.3V	f <sub>sys</sub> =16MHz	—	1.5	3.0	mA
5V	—	2.5		5.0			

Note: When using the characteristic table data, the following notes should be taken into consideration:

1. Any digital input is setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Operating Current values are measured using a continuous NOP instruction program loop.

**Standby Current Characteristics**

Ta=25°C, unless otherwise specified.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Max. @85°C	Unit
		V <sub>DD</sub>	Conditions					
I <sub>STB</sub>	SLEEP Mode	1.8V	WDT on	—	1.2	2.4	2.9	μA
		3V		—	1.5	3.0	3.6	
		5V		—	3	5	6	
	IDLE0 Mode – LIRC	1.8V	f <sub>sub</sub> on	—	2.4	4.0	4.8	μA
		3V		—	3	5	6	
		5V		—	5	10	12	
	IDLE1 Mode – HIRC	1.8V	f <sub>sub</sub> on, f <sub>sys</sub> =8MHz	—	288	400	480	μA
		3V		—	360	500	600	
		5V		—	600	800	960	
		2.7V	f <sub>sub</sub> on, f <sub>sys</sub> =12MHz	—	432	600	720	μA
		3V		—	540	750	900	
		5V		—	800	1200	1440	
		3.3V	f <sub>sub</sub> on, f <sub>sys</sub> =16MHz	—	0.80	1.20	1.44	mA
5V	—	1.4		2.0	2.4			

Note: When using the characteristic table data, the following notes should be taken into consideration:

1. Any digital input is setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Standby Current values are taken after a HALT instruction executed thus stopping all instruction execution.

## A.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency and temperature etc., can all exert an influence on the measured values.

### High Speed Internal Oscillator – HIRC – Frequency Accuracy

During the program writing operation the writer will trim the HIRC oscillator at a user selected HIRC frequency and user selected voltage of either 3V or 5V.

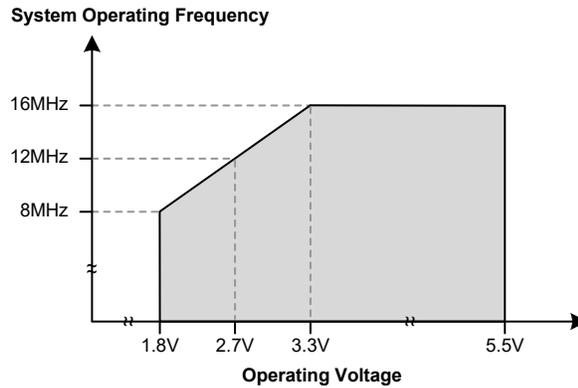
Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit	
		V <sub>DD</sub>	Temp.					
f <sub>HIRC</sub>	8MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	8	+1%	MHz	
			-40°C~85°C	-2%	8	+2%		
		2.2V~5.5V	25°C	-3.5%	8	+3.5%		
			-40°C~85°C	-5%	8	+5%		
		1.8V~5.5V	25°C	-5%	8	+5%		
			-40°C~85°C	-10%	8	+10%		
		2.7V~5.5V	25°C	-2.5%	8	+2.5%		
			-40°C~85°C	-3%	8	+3%		
	12MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	12	+1%		MHz
			-40°C~85°C	-2%	12	+2%		
		2.7V~5.5V	25°C	-2.5%	12	+2.5%		
			-40°C~85°C	-3%	12	+3%		
16MHz Writer Trimmed HIRC Frequency	5V	25°C	-1%	16	+1%	MHz		
		-40°C~85°C	-2%	16	+2%			
	3.3V~5.5V	25°C	-2.5%	16	+2.5%			
		-40°C~85°C	-3%	16	+3%			

- Note: 1. The 3V/5V values for V<sub>DD</sub> are provided as these are the two selectable fixed voltages at which the HIRC frequency is trimmed by the writer.
2. The row below the 3V/5V trim voltage row is provided to show the values for the full V<sub>DD</sub> range operating voltage. It is recommended that the trim voltage is fixed at 3V for application voltage ranges from 1.8V to 3.6V and fixed at 5V for application voltage ranges from 3.3V to 5.5V.
3. The minimum and maximum tolerance values provided in the table are only for the frequency at which the writer trims the HIRC oscillator. After trimming at this chosen specific frequency any change in HIRC oscillator frequency using the oscillator register control bits by the application program will give a frequency tolerance to within ±20%.

### Low Speed Internal Oscillator Characteristics – LIRC – Frequency Accuracy

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Temp.				
f <sub>LIRC</sub>	LIRC Frequency	2.2V~5.5V	25°C	-10%	32	+10%	kHz
			-40°C~85°C	-50%	32	+60%	
		1.8V~5.5V	25°C	-50%	32	+10%	
t <sub>START</sub>	LIRC Start Up Time	—	—	—	—	500	µs

### Operating Frequency Characteristic Curves



### System Start Up Time Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
t <sub>SST</sub>	System Start-up Time Wake-up from Condition where f <sub>sys</sub> is Off	—	f <sub>sys</sub> =f <sub>H</sub> ~f <sub>H</sub> /64, f <sub>H</sub> =f <sub>HIRC</sub>	—	16	—	t <sub>HIRC</sub>
		—	f <sub>sys</sub> =f <sub>SUB</sub> =f <sub>LIRC</sub>	—	2	—	t <sub>LIRC</sub>
	System Start-up Time Wake-up from Condition where f <sub>sys</sub> is On	—	f <sub>sys</sub> =f <sub>H</sub> ~f <sub>H</sub> /64, f <sub>H</sub> =f <sub>HIRC</sub>	—	2	—	t <sub>H</sub>
		—	f <sub>sys</sub> =f <sub>SUB</sub> =f <sub>LIRC</sub>	—	2	—	t <sub>SUB</sub>
t <sub>RSTD</sub>	System Speed Switch Time FAST to SLOW Mode or SLOW to FAST Mode	—	f <sub>HIRC</sub> switches from off → on	—	16	—	t <sub>HIRC</sub>
	System Reset Delay Time Reset Source from Power-on Reset or LVR Hardware Reset	—	RR <sub>POR</sub> =5V/ms	10	16	24	ms
		—	—	10	16	24	ms
—	System Reset Delay Time LVRC/WDT Software Reset	—	—	10	16	24	ms

- Note: 1. For the System Start-up time values, whether f<sub>sys</sub> is on or off depends upon the mode type and the chosen f<sub>sys</sub> system oscillator. Details are provided in the System Operating Modes section.
2. The time units, shown by the symbols t<sub>HIRC</sub>, t<sub>sys</sub> etc. are the inverse of the corresponding frequency values as provided in the frequency tables. For example t<sub>HIRC</sub>=1/f<sub>HIRC</sub>, t<sub>sys</sub>=1/f<sub>sys</sub> etc.
3. If the LIRC is used as the system clock and if it is off when in the SLEEP Mode, then an additional LIRC start up time, t<sub>START</sub>, as provided in the LIRC frequency table, must be added to the t<sub>SST</sub> time in the table above.
4. The System Speed Switch Time is effectively the time taken for the newly activated oscillator to start up.

## Input/Output Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
V <sub>IL</sub>	Input Low Voltage for I/O Ports	5V	—	0	—	1.5	V
		—		0	—	0.2V <sub>DD</sub>	
V <sub>IH</sub>	Input High Voltage for I/O Ports	5V	—	3.5	—	5	V
		—		0.8V <sub>DD</sub>	—	V <sub>DD</sub>	
I <sub>OL</sub>	Sink Current for I/O Ports	3V	V <sub>OL</sub> =0.1V <sub>DD</sub>	16	32	—	mA
		5V		32	65	—	
I <sub>OH</sub>	Source Current for I/O Ports	3V	V <sub>OH</sub> =0.9V <sub>DD</sub> , SLEDCn[m+1:m]=00B (n=0, 1; m=0, 2, 4 or 6)	-0.7	-1.5	—	mA
		5V		-1.5	-2.9	—	
		3V	V <sub>OH</sub> =0.9V <sub>DD</sub> , SLEDCn[m+1:m]=01B (n=0, 1; m=0, 2, 4 or 6)	-1.3	-2.5	—	
		5V		-2.5	-5.1	—	
		3V	V <sub>OH</sub> =0.9V <sub>DD</sub> , SLEDCn[m+1:m]=10B (n=0, 1; m=0, 2, 4 or 6)	-1.8	-3.6	—	
		5V		-3.6	-7.3	—	
		3V	V <sub>OH</sub> =0.9V <sub>DD</sub> , SLEDCn[m+1:m]=11B (n=0, 1; m=0, 2, 4 or 6)	-4	-8	—	
5V	-8	-16		—			
R <sub>PH</sub>	Pull-high Resistance for I/O Ports (Note)	3V	LVPU=0 PxPU=FFH (Px: PA, PB, PD)	20	60	100	kΩ
		5V		10	30	50	
		3V	LVPU=1 PxPU=FFH (Px: PA, PB, PD)	6.67	15.00	23.00	
		5V		3.5	7.5	12.0	
I <sub>LEAK</sub>	Input Leakage Current	5V	V <sub>IN</sub> =V <sub>DD</sub> or V <sub>IN</sub> =V <sub>SS</sub>	—	—	±1	μA
t <sub>TPI</sub>	TM Capture Input Pin Minimum Pulse Width	—	—	0.3	—	—	μs
t <sub>INT</sub>	External Interrupt Minimum Pulse Width	—	—	10	—	—	μs
f <sub>TMCLK</sub>	TM Maximum Timer Clock Source Frequency	5V	—	—	—	1	f <sub>sys</sub>
t <sub>CPW</sub>	TM Minimum Capture Pulse Width	—	—	t <sub>CPW</sub>	—	—	t <sub>TMCLK</sub>

Note: 1. The R<sub>PH</sub> internal pull high resistance value is calculated by connecting to ground and enabling the input pin with a pull-high resistor and then measuring the pin current at the specified supply voltage level. Dividing the voltage by this measured current provides the R<sub>PH</sub> value.

2.  $t_{TMCLK} = 1/f_{TMCLK}$ .

3. If PTCAPTS=0, then  $t_{CPW} = \max(2 \times t_{TMCLK}, t_{TPI})$ ; If PTCAPTS=1, then  $t_{CPW} = \max(2 \times t_{TMCLK}, t_{TCK})$

Ex1: If PTCAPTS=0, f<sub>TMCLK</sub>=16MHz, t<sub>TPI</sub>=0.3μs, then t<sub>CPW</sub>=max(0.125μs, 0.3μs)=0.3μs

Ex2: If PTCAPTS=1, f<sub>TMCLK</sub>=16MHz, t<sub>TCK</sub>=0.3μs, then t<sub>CPW</sub>=max(0.125μs, 0.3μs)=0.3μs

Ex3: If PTCAPTS=0, f<sub>TMCLK</sub>=8MHz, t<sub>TPI</sub>=0.3μs, then t<sub>CPW</sub>=max(0.25μs, 0.3μs)=0.3μs

Ex4: If PTCAPTS=0, f<sub>TMCLK</sub>=4MHz, t<sub>TPI</sub>=0.3μs, then t<sub>CPW</sub>=max(0.5μs, 0.3μs)=0.5μs

## Memory Characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
V <sub>RW</sub>	V <sub>DD</sub> for Read/Write	—	—	1.8	—	5.5	V
<b>Flash Program Memory</b>							
t <sub>FWR</sub>	ROM Program Time	—	—	1.364	1.500	1.667	ms
	IAP Write Time	—	FWERTS bit=0	—	2.2	3.2	ms
		—	FWERTS bit=1	—	3.0	4.2	ms
t <sub>FER</sub>	ROM Erase Time	—	—	2.273	2.500	2.778	ms
	IAP Erase Time	—	FWERTS bit=0	—	3.2	4.5	ms
		—	FWERTS bit=1	—	3.7	5.2	ms
E <sub>P</sub>	Cell Endurance	—	—	100K	—	—	E/W
t <sub>RETD</sub>	ROM Data Retention Time	—	Ta=25°C	—	40	—	Year
t <sub>ACTV</sub>	ROM Activation Time – Wake-up from Power Down Mode <sup>(1)</sup>	—	—	32	—	64	μs
<b>Data EEPROM Memory</b>							
t <sub>EEER</sub>	EEPROM Read Time	—	—	—	—	4	t <sub>sys</sub>
t <sub>EEWR</sub>	Write Time (byte mode)	—	EWERTS bit=0	—	5.4	8.6	ms
		—	EWERTS bit=1	—	6.7	10.6	ms
	Write Time (page mode)	—	EWERTS bit=0	—	2.2	3.6	ms
		—	EWERTS bit=1	—	3.0	4.8	ms
t <sub>EEER</sub>	Erase Time	—	EWERTS bit=0	—	3.2	5.2	ms
		—	EWERTS bit=1	—	3.7	6.0	ms
E <sub>P</sub>	Cell Endurance	—	—	100K	—	—	E/W <sup>(2)</sup>
t <sub>RETD</sub>	ROM Data Retention Time	—	Ta=25°C	—	40	—	Year
<b>RAM Data Memory</b>							
V <sub>DR</sub>	RAM Data Retention Voltage	—	—	1.0	—	—	V

Note: 1. The ROM activation time t<sub>ACTV</sub> should be added when calculating the total system start-up time of a wake-up from the power down mode.

2. “E/W” means Erase/Write times.

## LVD/LVR Electrical Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
V <sub>LVR</sub>	Low Voltage Reset Voltage	—	LVR enable, voltage select 1.7V	-5%	1.7	+5%	V
			LVR enable, voltage select 1.9V		1.9		
			LVR enable, voltage select 2.55V	-3%	2.55	+3%	
			LVR enable, voltage select 3.15V		3.15		
			LVR enable, voltage select 3.8V		3.8		
V <sub>LVD</sub>	Low Voltage Detection Voltage	—	LVD enable, voltage select 1.8V	-5%	1.8	+5%	V
			LVD enable, voltage select 2.0V		2.0		
			LVD enable, voltage select 2.4V		2.4		
			LVD enable, voltage select 2.7V		2.7		
			LVD enable, voltage select 3.0V		3.0		
			LVD enable, voltage select 3.3V		3.3		
			LVD enable, voltage select 3.6V		3.6		
			LVD enable, voltage select 4.0V		4.0		
I <sub>LVR/LVD</sub>	Operating Current	3V	LVD enable, LVR enable, V <sub>LVR</sub> =1.9V, V <sub>LVD</sub> =2V	—	—	10	μA
		5V		—	10	15	
t <sub>LVDS</sub>	LVDO Stable Time	—	For LVR enable, VBGEN=0 LVD off → on	—	—	18	μs
t <sub>LVR</sub>	Minimum Low Voltage Width to Reset	—	TLVR[1:0]=00B	120	240	480	μs
			TLVR[1:0]=01B	0.5	1.0	2.0	
			TLVR[1:0]=10B	1	2	4	
			TLVR[1:0]=11B	2	4	8	
t <sub>LVD</sub>	Minimum Low Voltage Width to Interrupt	—	—	60	120	240	μs
I <sub>LVR</sub>	Additional Current for LVR Enable	5V	LVD disable	—	—	14	μA

## A/D Converter Electrical Characteristics

Ta=-40°C~85°C, unless otherwise specified.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
V <sub>DD</sub>	Operating Voltage	—	—	1.8	—	5.5	V
V <sub>ADI</sub>	Input Voltage	—	—	0	—	V <sub>REF</sub>	V
V <sub>REF</sub>	Reference Voltage	—	—	1.8	—	V <sub>DD</sub>	V
N <sub>R</sub>	Resolution	—	—	—	—	12	Bit
DNL	Differential Non-linearity	1.8V	SAINS[3:0]=0000B, SAVRS[1:0]=01B, V <sub>REF</sub> =V <sub>DD</sub> , t <sub>ADCK</sub> =2.0μs	-3	—	3	LSB
		2V	SAINS[3:0]=0000B, SAVRS[1:0]=01B, V <sub>REF</sub> =V <sub>DD</sub> , t <sub>ADCK</sub> =0.5μs				
		3V					
		5V					
		1.8V	SAINS[3:0]=0000B, SAVRS[1:0]=01B, V <sub>REF</sub> =V <sub>DD</sub> , t <sub>ADCK</sub> =10μs				
		3V					
5V							

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit						
		V <sub>DD</sub>	Conditions										
INL	Integral Non-linearity	1.8V	SAINS[3:0]=0000B, SAVRS[1:0]=01B, V <sub>REF</sub> =V <sub>DD</sub> , t <sub>ADCK</sub> =2.0μs	-4	—	4	LSB						
		2V	SAINS[3:0]=0000B, SAVRS[1:0]=01B, V <sub>REF</sub> =V <sub>DD</sub> , t <sub>ADCK</sub> =0.5μs										
		3V											
		5V											
		I <sub>ADC</sub>	Additional Current Consumption for A/D Converter Enable					1.8V	No load, t <sub>ADCK</sub> =2.0μs	—	280	400	μA
								3V	No load, t <sub>ADCK</sub> =0.5μs	—	450	600	μA
5V	No load, t <sub>ADCK</sub> =0.5μs			—	850	1000	μA						
t <sub>ADCK</sub>	Clock Period	—	1.8V≤V <sub>DD</sub> <2.0V	2.0	—	10	μs						
			2.0V≤V <sub>DD</sub> ≤5.5V	0.5	—	10	μs						
t <sub>ON2ST</sub>	A/D Converter On-to-Start Time	—	—	4	—	—	μs						
t <sub>ADC</sub>	Conversion Time (Including A/D Converter Sample and Hold Time)	—	—	—	16	—	t <sub>ADCK</sub>						
I <sub>PGA</sub>	Additional Current for PGA Enable	2.2V	No load, PGAIS=1, PGAGS[1:0]=01	—	250	500	μA						
		3V		—	300	600							
		5V		—	400	700							
V <sub>OR</sub>	PGA Maximum Output Voltage Range	2.2V	—	V <sub>SS</sub> +0.1	—	V <sub>DD</sub> -0.1	V						
		3V											
		5V											
V <sub>VR</sub>	Fix Voltage Output of PGA	2.2V~5.5V	Ta=-40°C~85°C V <sub>RI</sub> =V <sub>BGREF</sub> (PGAIS=1)	-1%	2	+1%	V						
		3.2V~5.5V		-1%	3	+1%							
		4.2V~5.5V		-1%	4	+1%							
V <sub>IR</sub>	PGA Input Voltage Range	3V	Gain=1, PGAIS=0 Relative gain Gain error < ±5%	V <sub>SS</sub> +0.1	—	V <sub>DD</sub> -1.4	V						
		5V		V <sub>SS</sub> +0.1	—	V <sub>DD</sub> -1.4	V						

## Internal Reference Voltage Characteristics

Ta=-40°C~85°C, unless otherwise specified.

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
I <sub>BGREF</sub>	Operating Current	5.5V	—	—	25	35	μA
PSRR	Power Supply Rejection Ratio	—	Ta=25°C, V <sub>RIPPLE</sub> =1V <sub>P-P</sub> , f <sub>RIPPLE</sub> =100Hz	75	—	—	dB
En	Output Noise	—	Ta=25°C, no load current, f=0.1Hz~10Hz	—	300	—	μV <sub>RMS</sub>
I <sub>SD</sub>	Shutdown Current	—	VBGREN=0	—	—	0.1	μA
t <sub>START</sub>	Startup Time	1.8V ~5.5V	Ta=25°C	—	—	400	μs

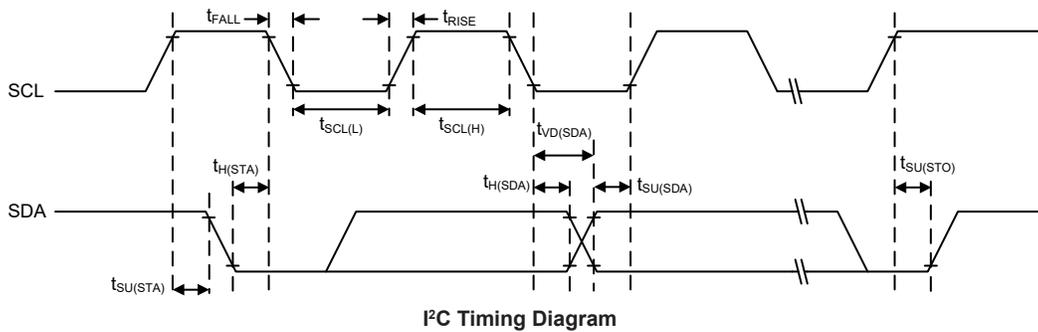
Note: 1. All the above parameters are measured under conditions of no load condition unless otherwise described.  
 2. A 0.1μF ceramic capacitor should be connected between VDD and GND.

## I<sup>2</sup>C Electrical Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V <sub>DD</sub>	Conditions				
f <sub>I2C</sub>	I <sup>2</sup> C Standard Mode (100kHz) f <sub>sys</sub> Frequency <small>(Note)</small>	—	No clock debounce	2	—	—	MHz
			2 system clock debounce	4	—	—	
			4 system clock debounce	4	—	—	
	I <sup>2</sup> C Fast Mode (400kHz) f <sub>sys</sub> Frequency <small>(Note)</small>	—	No clock debounce	4	—	—	MHz
			2 system clock debounce	8	—	—	
			4 system clock debounce	8	—	—	
f <sub>SCL</sub>	SCL Clock Frequency	3V/5V	Standard mode	—	—	100	kHz
			Fast mode	—	—	400	
t <sub>SCL(H)</sub>	SCL Clock High Time	3V/5V	Standard mode	3.5	—	—	μs
			Fast mode	0.9	—	—	
t <sub>SCL(L)</sub>	SCL Clock Low Time	3V/5V	Standard mode	3.5	—	—	μs
			Fast mode	0.9	—	—	
t <sub>FALL</sub>	SCL and SDA Fall Time	3V/5V	Standard mode	—	—	1.3	μs
			Fast mode	—	—	0.34	
t <sub>RISE</sub>	SCL and SDA Rise Time	3V/5V	Standard mode	—	—	1.3	μs
			Fast mode	—	—	0.34	
t <sub>SU(SDA)</sub>	SDA Data Setup Time	3V/5V	Standard mode	0.25	—	—	μs
			Fast mode	0.1	—	—	
t <sub>H(SDA)</sub>	SDA Data Hold Time	3V/5V	—	0.1	—	—	μs
t <sub>VD(SDA)</sub>	SDA Data Valid Time	3V/5V	—	—	—	0.6	μs
t <sub>SU(STA)</sub>	Start Condition Setup Time	3V/5V	Standard mode	3.5	—	—	μs
			Fast mode	0.6	—	—	
t <sub>H(STA)</sub>	Start Condition Hold Time	3V/5V	Standard mode	4.0	—	—	μs
			Fast mode	0.6	—	—	
t <sub>SU(STO)</sub>	Stop Condition Setup Time	3V/5V	Standard mode	3.5	—	—	μs
			Fast mode	0.6	—	—	

Note: Using the debounce function can make the transmission more stable and reduce the probability of communication failure due to interference.



## High Voltage Linear Charger Electrical Characteristics

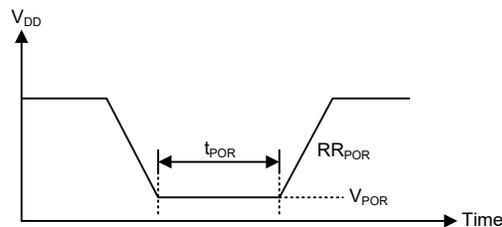
$V_{IN}=5V$ ,  $V_{BAT}=3.6V$ ,  $R_{SET}=20k\Omega$ ,  $T_a=25^\circ C$ , unless otherwise specified

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Supply and Input</b>						
$V_{IN}$	Input Voltage	—	4.5	5.0	7.0	V
$I_{IN1}$	Operation Current (Charging)	$R_{SET}=20k\Omega$ , measure $I_{VIN}-I_{VBAT}$	—	—	2	mA
$I_{IN2}$	Operation Current (Charging Done)	$V_{BAT}=4.2V$ , measure $I_{VIN}$	—	—	450	$\mu A$
$I_{BAT\_LK1}$	VBAT Leakage Current (Charger Shutdown)	D[6:0]="0000000"	—	-1	-2	$\mu A$
$I_{BAT\_LK2}$	VBAT Leakage Current (Invalid Input)	$V_{IN}=0V$	—	-1	-2	$\mu A$
$I_{BAT\_VREF}$	VREF Operation Current	$V_{IN}=0V$ , D[6:0]="0110000"	—	-150	-200	$\mu A$
<b>Over Voltage and Under Voltage Detect</b>						
$V_{IN\_UVLO1}$	Input Under Voltage Lockout 1	$V_{IN}$ rising	3.8	4.0	4.2	V
$V_{IN\_UVLO2}$	Input Under Voltage Lockout 2	$V_{IN}$ rising	—	$V_{BAT}+0.1V$	—	V
$V_{IN\_UVLO\_HYS}$	$V_{IN\_UVLO1}$ Hysteresis Voltage	$V_{IN}$ falling	20	100	—	mV
$V_{IN\_OVP}$	Input Over Voltage Threshold	$V_{IN}$ rising	7.0	7.3	7.6	V
$V_{IN\_OVP\_HYS}$	$V_{IN\_OVP}$ Hysteresis Voltage	$V_{IN}$ falling	20	100	—	mV
$t_{IN\_OVP}$	Over Voltage Response Time	$V_{IN}$ rising at $10V/1\mu s$	—	350	—	ns
<b>Linear Charger</b>						
$V_{BAT\_CV1}$	Battery Charging Target Voltage	$V_{IN}=4.5V$ , $R_{SET}=20k\Omega$ , $I_{BAT\_LOAD}=20mA$ , $T_a=0^\circ C\sim 85^\circ C$	-1%	4.2	+1%	V
$V_{BAT\_CV2}$	Battery Charging Target Voltage	$V_{IN}=5.5V$ , $R_{SET}=2k\Omega$ , $I_{BAT\_LOAD}=200mA$ , $T_a=0^\circ C\sim 85^\circ C$	—	—	—	V
$V_{BAT\_RECHG}$	Battery Recharge Threshold	$V_{BAT}$ falling	—	$V_{BAT\_CV}-0.2$	—	V
$V_{BAT\_LOW}$	Low Battery Voltage	$V_{BAT}$ rising	2.9	3.0	3.1	V
$V_{BAT\_LOW\_HYS}$	$V_{BAT\_LOW}$ Hysteresis Voltage	$V_{BAT}$ falling	—	100	—	mV
$V_{IF\_EN}$	Interface Enable Voltage	$V_{BAT}$ rising	2.2	—	—	V
$V_{IF\_DIS}$	Interface Disable Voltage	$V_{BAT}$ falling	—	—	0.8	V
$I_{BAT\_CC}$	Programmable Constant Charging Current	$R_{SET}=2k\Omega$	900	1000	1100	mA
		$R_{SET}=4k\Omega$	-10%	500	+10%	mA
		$R_{SET}=20k\Omega$	-10%	100	+10%	mA
$I_{BAT\_TC}$	Trickle Charging Current	$V_{BAT}=2.7V$	-50%	$0.1\times I_{BAT\_CC}$	+50%	mA
$I_{BAT\_TERM}$	Charge Termination Current	—	-15%	$0.1\times I_{BAT\_CC}$	+15%	mA
$T_{CT}$	Linear Charger Constant Temperature	—	—	125	—	$^\circ C$
<b>Others</b>						
$V_{REF}$	Reference Voltage	$V_{BAT}=2.5V\sim 4.2V$ , $I_{LOAD}=1mA$	-1%	2.0	+1%	V
$f_{SCL}$	SCL Frequency	—	—	50	—	kHz
$V_{IF}$	Interface Operation Voltage	—	2.2	—	5.5	V
$I_{OL}$	Sink Current for CHRG Pin	$V_{OL}=1.5V$	2.5	—	—	mA
$R_{PL}$	Pull-low Resistance for SDA and SCL Signals	—	—	100	—	k $\Omega$
$R_{DS(ON)}$	MOS On Resistance between $V_{IN}$ and $V_{BAT}$	$R_{SET}=1k\Omega$ , $V_{IN}=4.5V$	—	—	800	m $\Omega$
$t_{INOK2}$	$V_{IN}$ Status (INOK2) Holding Time on FN Signal	$V_{IN}=0V\sim 8V$ , $V_{BAT}=2.5V\sim 4.2V$ , D[6:0]="1010000"	65	—	180	$\mu s$
$t_{LCS}$	Linear Charger Status Setting Time on FN Signal	$V_{IN}=0V\sim 8V$ , $V_{BAT}=2.5V\sim 4.2V$ , D[6:0]="1010000"	—	—	30	$\mu s$
$t_{VREF}$	VREF Setting Time on FN Signal	$V_{IN}=0V$ , D[6:0]="0110000"	—	—	15	$\mu s$

## Power-on Reset Characteristics

$T_a = -40^{\circ}\text{C} \sim 85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		$V_{DD}$	Conditions				
$V_{POR}$	$V_{DD}$ Start Voltage to Ensure Power-on Reset	—	—	—	—	100	mV
$RR_{POR}$	$V_{DD}$ Rising Rate to Ensure Power-on Reset	—	—	0.035	—	—	V/ms
$t_{POR}$	Minimum Time for $V_{DD}$ Stays at $V_{POR}$ to Ensure Power-on Reset	—	—	1	—	—	ms



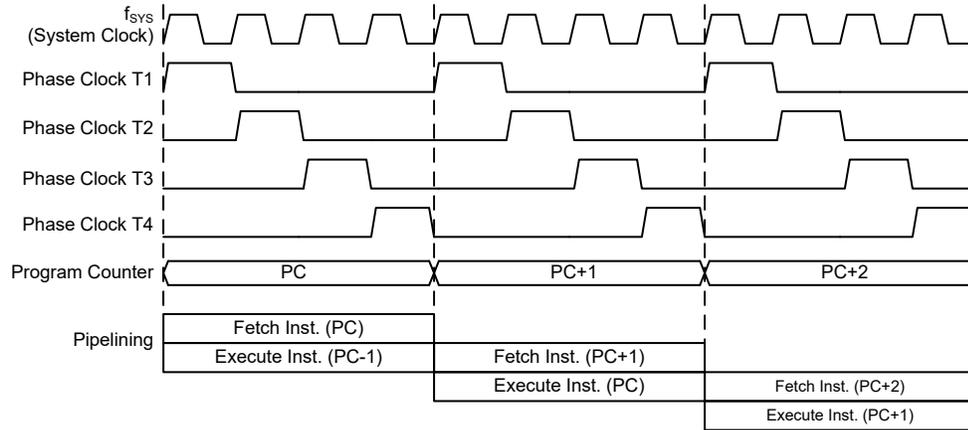
## System Architecture

A key factor in the high-performance features of the Holtek range of microcontrollers is attributed to their internal system architecture. The device takes advantage of the usual features found within RISC microcontrollers providing increased speed of operation and enhanced performance. The pipelining scheme is implemented in such a way that instruction fetching and instruction execution are overlapped, hence instructions are effectively executed in one or two cycles for most of the standard or extended instructions respectively. The exceptions to this are branch or call instructions which need one more cycle. An 8-bit wide ALU is used in practically all instruction set operations, which carries out arithmetic operations, logic operations, rotation, increment, decrement, branch decisions, etc. The internal data path is simplified by moving data through the Accumulator and the ALU. Certain internal registers are implemented in the Data Memory and can be directly or indirectly addressed. The simple addressing methods of these registers along with additional architectural features ensure that a minimum of external components is required to provide a functional I/O and A/D control system with maximum reliability and flexibility. This makes the device suitable for affordable, high-volume production for controller applications.

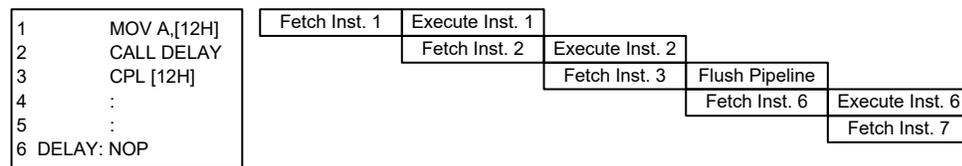
### Clocking and Pipelining

The main system clock, derived from either an HIRC or LIRC oscillator is subdivided into four internally generated non-overlapping clocks, T1~T4. The Program Counter is increased at the beginning of the T1 clock during which time a new instruction is fetched. The remaining T2~T4 clocks carry out the decoding and execution functions. In this way, one T1~T4 clock cycle forms one instruction cycle. Although the fetching and execution of instructions takes place in consecutive instruction cycles, the pipelining structure of the microcontroller ensures that instructions are effectively executed in one instruction cycle. The exception to this are instructions where the contents of the Program Counter are changed, such as subroutine calls or jumps, in which case the instruction will take one more instruction cycle to execute.

For instructions involving branches, such as jump or call instructions, two machine cycles are required to complete instruction execution. An extra cycle is required as the program takes one cycle to first obtain the actual jump or call address and then another cycle to actually execute the branch. The requirement for this extra cycle should be taken into account by programmers in timing sensitive applications.



**System Clocking and Pipelining**



**Instruction Fetching**

### Program Counter

During program execution, the Program Counter is used to keep track of the address of the next instruction to be executed. It is automatically incremented by one each time an instruction is executed except for instructions, such as “JMP” or “CALL” that demand a jump to a non-consecutive Program Memory address. Only the lower 8 bits, known as the Program Counter Low Register, are directly addressable by the application program.

When executing instructions requiring jumps to non-consecutive addresses such as a jump instruction, a subroutine call, interrupt or reset, etc., the microcontroller manages program control by loading the required address into the Program Counter. For conditional skip instructions, once the condition has been met, the next instruction, which has already been fetched during the present instruction execution, is discarded and a dummy cycle takes its place while the correct instruction is obtained.

Program Counter	
High Byte	Low Byte (PCL)
PC11~PC8	PCL7~PCL0

**Program Counter**

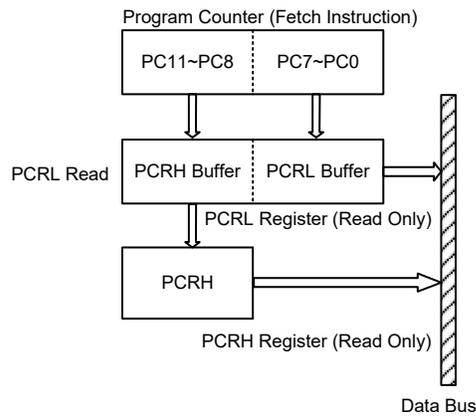
The lower byte of the Program Counter, known as the Program Counter Low register or PCL, is available for program control and is a readable and writable register. By transferring data directly into this register, a short program jump can be executed directly; however, as only this low byte is available for manipulation, the jumps are limited to the present page of memory that is 256 locations. When such program jumps are executed it should also be noted that a dummy cycle will be inserted. Manipulating the PCL register may cause program branching, so an extra cycle is needed to pre-fetch.

### Program Counter Register

The program counter register is a read only register for reading the program counter value which indicates the current program execution address. Read the low byte register first then the high byte register. Reading the low byte register, PCRL, will read the low byte data of the current program execution address, and place the high byte data of the program counter into the 8-bit PCRH buffer. Then reading the PCRH register will read the corresponding data from the 8-bit PCRH buffer.

The following example shows how to read the current program execution address. When the current program execution address is 123H, the steps to execute the instructions are as follows:

- (1) MOV A, PCRL → the ACC value is 23H, and the PCRH value is 01H;  
     MOV A, PCRH → the ACC value is 01H.
- (2) LMOV A, PCRL → the ACC value is 23H, and the PCRH value is 01H;  
     LMOV A, PCRH → the ACC value is 01H.



#### • PCRL Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0      **D7~D0**: Low byte register bit 7 ~ bit 0

#### • PCRH Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	D11	D10	D9	D8
R/W	—	—	—	—	R	R	R	R
POR	—	—	—	—	0	0	0	0

Bit 7~4      Unimplemented, read as “0”

Bit 3~0      **D11~D8**: High byte register bit 11 ~ bit 8

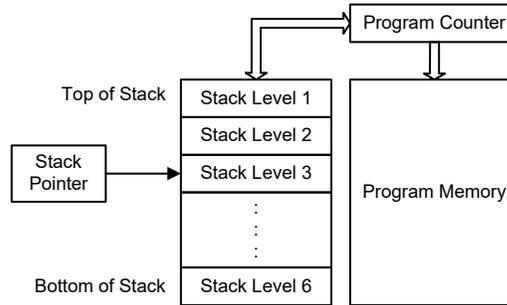
### Stack

This is a special part of the memory which is used to save the contents of the Program Counter only. The stack is organized into 6 levels and neither part of the data nor part of the program space, and is neither readable nor writeable. The activated level is indexed by the Stack Pointer, STKPTR, which is a read only register. At a subroutine call or interrupt acknowledge signal, the contents of the Program Counter are pushed onto the stack and the Stack Pointer is increased by one. At the end of a subroutine or an interrupt routine, signaled by a return instruction, RET or RETI, the Program

Counter is restored to its previous value from the stack and the Stack Pointer is decreased by one. After a device reset or when the stack is full, the Stack Pointer will point to the top of the stack with a value of 00H.

If the stack is full and an enabled interrupt takes place, the interrupt request flag will be recorded but the acknowledge signal will be inhibited. When the Stack Pointer is decremented, by RET or RETI, the interrupt will be serviced. This feature prevents stack overflow allowing the programmer to use the structure more easily. However, when the stack is full, a CALL subroutine instruction can still be executed which will result in a stack overflow. Precautions should be taken to avoid such cases which might cause unpredictable program branching.

If the stack is overflow, the first Program Counter save in the stack will be lost.



• **STKPTR Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	D2	D1	D0
R/W	—	—	—	—	—	R	R	R
POR	—	—	—	—	—	0	0	0

Bit 7~3 Unimplemented, read as “0”

Bit 2~0 **D2~D0**: Stack pointer register

The following example shows how the Stack Pointer changes when program branching conditions occur.

(1) When the CALL subroutine instruction is executed 6 times continuously and the RET instruction is not executed during the period, the corresponding changes of the STKPTR are as follows:

00H→01H→02H→03H→04H→05H→00H

(2) Then the RET instruction is executed 6 times continuously after (1), the corresponding changes of the STKPTR are as follows:

00H→05H→04H→03H→02H→01H→00H

**Arithmetic and Logic Unit – ALU**

The arithmetic-logic unit or ALU is a critical area of the microcontroller that carries out arithmetic and logic operations of the instruction set. Connected to the main microcontroller data bus, the ALU receives related instruction codes and performs the required arithmetic or logical operations after which the result will be placed in the specified register. As these ALU calculation or operations may result in carry, borrow or other status changes, the status register will be correspondingly updated to reflect these changes. The ALU supports the following functions:

• Arithmetic operations:

ADD, ADDM, ADC, ADCM, SUB, SUBM, SBC, SBCM, DAA

LADD, LADDM, LADC, LADCM, LSUB, LSUBM, LSBC, LSBCM, LDAA

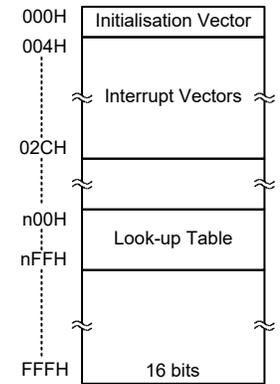
- Logic operations:  
 AND, OR, XOR, ANDM, ORM, XORM, CPL, CPLA  
 LAND, LANDM, LOR, LORM, LXOR, LXORM, LCPL, LCPLA
- Rotation:  
 RRA, RR, RRCA, RRC, RLA, RL, RLCA, RLC  
 LRR, LRRCA, LRR, LRRCA, LRRCA, LRRCA, LRRCA, LRRCA
- Increment and Decrement:  
 INCA, INC, DECA, DEC, LINCA, LINC, LDECA, LDEC
- Branch decision:  
 JMP, SZ, SZA, SNZ, SIZ, SDZ, SIZA, SDZA, CALL, RET, RETI  
 LSZ, LSZA, LSNZ, LSIZ, LSIZA, LSDZ, LSDZA

## Flash Program Memory

The Program Memory is the location where the user code or program is stored. For this device the Program Memory is Flash type, which means it can be programmed and re-programmed a large number of times, allowing the user the convenience of code modification on the same device. By using the appropriate programming tools, the Flash device offer users the flexibility to conveniently debug and develop their applications while also offering a means of field programming and updating.

### Structure

The Program Memory has a capacity of 4K×16 bits. The Program Memory is addressed by the Program Counter and also contains data, table information and interrupt entries. Table data, which can be setup in any location within the Program Memory, is addressed by a separate table pointer register.



**Program Memory Structure**

### Special Vectors

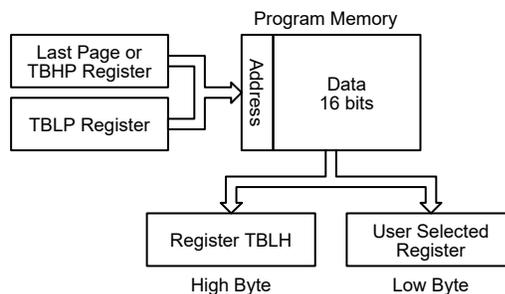
Within the Program Memory, certain locations are reserved for the reset and interrupts. The location 000H is reserved for use by the device reset for program initialisation. After a device reset is initiated, the program will jump to this location and begin execution.

## Look-up Table

Any location within the Program Memory can be defined as a look-up table where programmers can store fixed data. To use the look-up table, the table pointer must first be setup by placing the address of the look up data to be retrieved in the table pointer register, TBLP and TBHP. These registers define the total address of the look-up table.

After setting up the table pointer, the table data can be retrieved from the Program Memory using the corresponding table read instruction such as “TABRD [m]” or “TABRDL [m]” respectively when the memory [m] is located in Sector 0. If the memory [m] is located in other sectors, the data can be retrieved from the program memory using the corresponding extended table read instruction such as “LTABRD [m]” or “LTABRDL [m]” respectively. When the instruction is executed, the lower order table byte from the Program Memory will be transferred to the user defined Data Memory register [m] as specified in the instruction. The higher order table data byte from the Program Memory will be transferred to the TBLH special register.

The accompanying diagram illustrates the addressing data flow of the look-up table.



## Table Program Example

The following example shows how the table pointer and table data is defined and retrieved from the microcontroller. This example uses raw table data located in the Program Memory which is stored there using the ORG statement. The value at this ORG statement is “0F00H” which refers to the start address of the last page within the 4K Program Memory of the microcontroller. The table pointer low byte register is setup here to have an initial value of “06H”. This will ensure that the first data read from the data table will be at the Program Memory address “0F06H” or 6 locations after the start of the last page. Note that the value for the table pointer is referenced to the specific address pointed by TBLP and TBHP if the “TABRD [m]” or “LTABRD [m]” instruction is being used. The high byte of the table data which in this case is equal to zero will be transferred to the TBLH register automatically when the “TABRD [m]” or “LTABRD [m]” instruction is executed.

Because the TBLH register is a read/write register and can be restored, care should be taken to ensure its protection if both the main routine and Interrupt Service Routine use table read instructions. If using the table read instructions, the Interrupt Service Routines may change the value of the TBLH and subsequently cause errors if used again by the main routine. As a rule it is recommended that simultaneous use of the table read instructions should be avoided. However, in situations where simultaneous use cannot be avoided, the interrupts should be disabled prior to the execution of any main routine table-read instructions. Note that all table related instructions require two instruction cycles to complete their operation.

**Table Read Program Example**

```

tempreg1 db ?      ; temporary register #1
tempreg2 db ?      ; temporary register #2
:
:
mov a,06h          ; initialise low table pointer - note that this address
                  ; is referenced
mov tblp,a         ; to the last page or the page that tbhp pointed
mov a,0Fh          ; initialise high table pointer
mov tbhp,a
:
:
tabrd tempreg1     ; transfers value in table referenced by table pointer data at program
                  ; memory address "0F06H" transferred to tempreg1 and TBLH
dec tblp           ; reduce value of table pointer by one
tabrd tempreg2     ; transfers value in table referenced by table pointer
                  ; data at program memory address "0F05H" transferred to
                  ; tempreg2 and TBLH in this example the data "1AH" is
                  ; transferred to tempreg1 and data "0FH" to register tempreg2
:
:
org 0F00h          ; sets initial address of program memory
dc 00Ah, 00Bh, 00Ch, 00Dh, 00Eh, 00Fh, 01Ah, 01Bh
:
:

```

**In Circuit Programming – ICP**

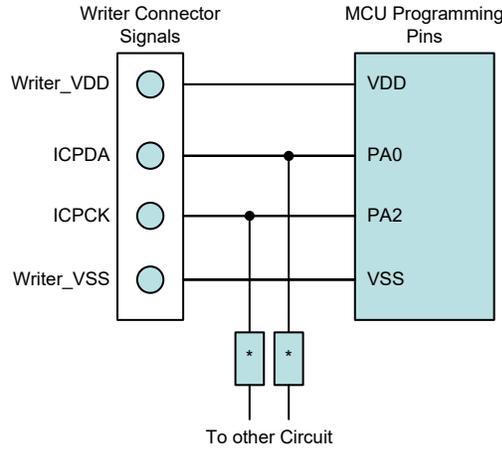
The provision of Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device.

As an additional convenience, Holtek has provided a means of programming the microcontroller in-circuit using a 4-pin interface. This provides manufacturers with the possibility of manufacturing their circuit boards complete with a programmed or un-programmed microcontroller, and then programming or upgrading the program at a later stage. This enables product manufacturers to easily keep their manufactured products supplied with the latest program releases without removal and re-insertion of the device.

Holtek Writer Pins	MCU Programming Pins	Pin Description
ICPDA	PA0	Programming Serial Data/Address
ICPCK	PA2	Programming Clock
VDD	VDD	Power Supply
VSS	VSS	Ground

The Program Memory can be programmed serially in-circuit using this 4-wire interface. Data is downloaded and uploaded serially on a single pin with an additional line for the clock. Two additional lines are required for the power supply. The technical details regarding the in-circuit programming of the device are beyond the scope of this document and will be supplied in supplementary literature.

During the programming process, the user must take care of the ICPDA and ICPCK pins for data and clock programming purposes to ensure that no other outputs are connected to these two pins.



Note: \* may be resistor or capacitor. The resistance of \* must be greater than 1kΩ or the capacitance of \* must be less than 1nF.

### On-Chip Debug Support – OCDS

An EV chip exists for the purposes of device emulation. The EV chip device also provides an “On-Chip Debug” function to debug the real MCU device during the development process. The EV chip and the real MCU device are almost functionally compatible except for “On-Chip Debug” function. Users can use the EV chip device to emulate the real chip device behavior by connecting the OCSDA and OCDSCK pins to the Holtek HT-IDE development tools. The OCSDA pin is the OCDS Data/Address input/output pin while the OCDSCK pin is the OCDS clock input pin. When users use the EV chip device for debugging, other pin functions which are shared with the OCSDA and OCDSCK pins in the device will have no effect in the EV chip. However, the two OCDS pins which are pin-shared with the ICP programming pins are still used as the Flash Memory programming pins for ICP. For a more detailed OCDS description, refer to the corresponding document named “Holtek e-Link for 8-bit MCU OCDS User’s Guide”.

Holtek e-Link Pins	EV Chip OCDS Pins	Pin Description
OCSDA	OCSDA	On-Chip Debug Support Data/Address input/output
OCDSCK	OCDSCK	On-Chip Debug Support Clock input
VDD	VDD	Power Supply
VSS	VSS	Ground

### In Application Programming – IAP

Flash type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device. The provision of IAP function offers users the convenience of Flash Memory multi-programming features. The convenience of the IAP function is that it can execute the updated program procedure using its internal firmware, without requiring an external Program Writer or PC. In addition, the IAP interface can also be any type of communication protocol, such as UART, using I/O pins. Regarding the internal firmware, the user can select versions provided by Holtek or create their own. The following section illustrates the procedures regarding how to implement the IAP firmware.

#### Flash Memory Read/Write Size

The Flash memory Erase and Write operations are carried out in a page format while the Read operation is carried out in a word format. The page size and write buffer size are both assigned with a capacity of 32 words. Note that the Erase operation should be executed before the Write operation is executed.

When the Flash Memory Erase/Write Function is successfully enabled, the CFWEN bit will be set high. When the CFWEN bit is set high, the data can be written into the write buffer. The FWT bit is used to initiate the write process and then indicate the write operation status. This bit is set high by application programs to initiate a write process and will be cleared by hardware if the write process is finished.

The Read operation can be carried out by executing a specific read procedure. The FRDEN bit is used to enable the read function and the FRD bit is used to initiate the read process by application programs and then indicate the read operation status. When the read process is finished, this bit will be cleared by hardware.

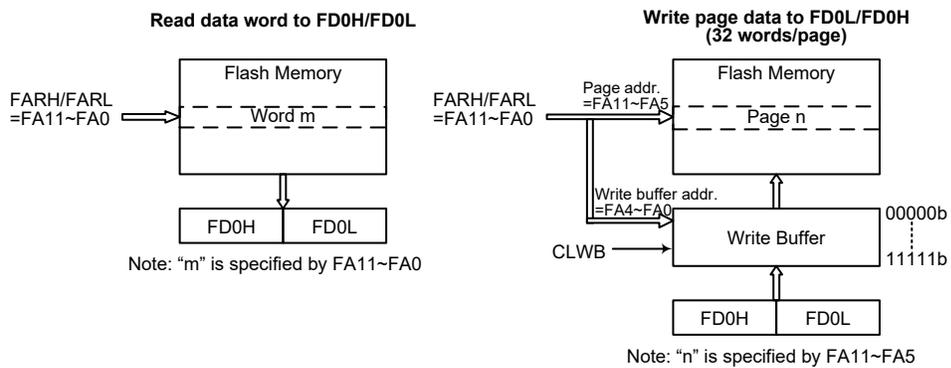
Operations	Format
Erase	32 words/page
Write	32 words/time
Read	1 word/time

Note: Page size=Write buffer size=32 words.

**IAP Read/Erase/Write Format**

Page	FARH	FARL [7:5]	FARL [4:0]
0	0000 0000	000	Tag Address
1	0000 0000	001	
2	0000 0000	010	
3	0000 0000	011	
4	0000 0000	100	
5	0000 0000	101	
6	0000 0000	110	
7	0000 0000	111	
8	0000 0001	000	
9	0000 0001	001	
:	:	:	
:	:	:	
126	0000 1111	110	
127	0000 1111	111	

**Page Number and Address Selection**



**Flash Memory IAP Read/Write Structure**

**Write Buffer**

The write buffer is used to store the written data temporarily when executing the write operation. The Write Buffer can be filled with written data after the Flash Memory Erase/Write Function has been successfully enabled by executing the Flash Memory Erase/Write Function Enable procedure. The write buffer can be cleared by configuring the CLWB bit in the FC2 register. The CLWB bit can be set high to enable the Clear Write Buffer procedure. When the procedure is finished this bit will be cleared to low by the hardware. It is recommended that the write buffer should be cleared by setting the CLWB bit high before the write buffer is used for the first time or when the data in the write buffer is updated.

The write buffer size is 32 words corresponding to a page. The write buffer address is mapped to a specific Flash memory page specified by the memory address bits, FA11~FA5. The data written into the FD0L and FD0H registers will be loaded into the write buffer. When data is written into the high byte data register, FD0H, it will result in the data stored in the high and low byte data registers both being written into the write buffer. It will also cause the flash memory address to be incremented by one, after which the new address will be loaded into the FARH and FARL address registers. When the flash memory address reaches the page boundary, 1111b of a page with 32 words, the address will now not be incremented but will stop at the last address of the page. At this point a new page address should be specified for any other erase/write operations.

After a write process is finished, the write buffer will automatically be cleared by the hardware. Note that the write buffer should be cleared manually by the application program when the data written into the flash memory is incorrect in the data verification step. The data should again be written into the write buffer after the write buffer has been cleared when the data is found to be incorrect during the data verification step.

**IAP Flash Program Memory Registers**

There are two address registers, four 16-bit data registers and three control registers, which are all located in Sector 1. Read and Write operations to the Flash memory are carried out using 16-bit data operations using the address and data registers and the control register. Several registers control the overall operation of the internal Flash Program Memory. The address registers are named FARL and FARH, the data registers are named FDnL and FDnH and the control registers are named FC0, FC1 and FC2. As these registers are all located in Sector 1, can be addressed directly only using the corresponding extended instructions or can be read from or written to indirectly using the MP1H/MP1L or MP2H/MP2L Memory Pointer pairs and Indirect Addressing Register, IAR1 or IAR2.

Register Name	Bit							
	7	6	5	4	3	2	1	0
FC0	CFWEN	FMOD2	FMOD1	FMOD0	FWPEN	FWT	FRDEN	FRD
FC1	D7	D6	D5	D4	D3	D2	D1	D0
FC2	—	—	—	—	—	—	FWERTS	CLWB
FARL	FA7	FA6	FA5	FA4	FA3	FA2	FA1	FA0
FARH	—	—	—	—	FA11	FA10	FA9	FA8
FD0L	D7	D6	D5	D4	D3	D2	D1	D0
FD0H	D15	D14	D13	D12	D11	D10	D9	D8
FD1L	D7	D6	D5	D4	D3	D2	D1	D0
FD1H	D15	D14	D13	D12	D11	D10	D9	D8
FD2L	D7	D6	D5	D4	D3	D2	D1	D0
FD2H	D15	D14	D13	D12	D11	D10	D9	D8
FD3L	D7	D6	D5	D4	D3	D2	D1	D0
FD3H	D15	D14	D13	D12	D11	D10	D9	D8

IAP Register List

• **FARL Register**

Bit	7	6	5	4	3	2	1	0
Name	FA7	FA6	FA5	FA4	FA3	FA2	FA1	FA0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0      **FA7~FA0**: Flash memory address bit 7 ~ bit 0

• **FARH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	FA11	FA10	FA9	FA8
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4      Unimplemented, read as “0”

Bit 3~0      **FA11~FA8**: Flash memory address bit 11 ~ bit 8

• **FD0L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0      **D7~D0**: The first Flash memory data word bit 7 ~ bit 0

Note that data written into the low byte data register FD0L will only be stored in the FD0L register and not loaded into the lower 8-bit write buffer.

• **FD0H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0      **D15~D8**: The first Flash memory data word bit 15 ~ bit 8

Note that when 8-bit data is written into the high byte data register FD0H, the whole 16 bits of data stored in the FD0H and FD0L registers will simultaneously be loaded into the 16-bit write buffer after which the contents of the Flash memory address register pair, FARH and FARL, will be incremented by one.

• **FD1L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0      **D7~D0**: The second Flash memory data word bit 7 ~ bit 0

• **FD1H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0      **D15~D8**: The second Flash memory data word bit 15 ~ bit 8

• **FD2L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: The third Flash memory data word bit 7 ~ bit 0

• **FD2H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D15~D8**: The third Flash memory data word bit 15 ~ bit 8

• **FD3L Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: The fourth Flash memory data word bit 7 ~ bit 0

• **FD3H Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D15~D8**: The fourth Flash memory data word bit 15 ~ bit 8

• **FC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	CFWEN	FMOD2	FMOD1	FMOD0	FWPEN	FWT	FRDEN	FRD
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **CFWEN**: Flash Memory Erase/Write enable control

0: Flash memory erase/write function is disabled

1: Flash memory erase/write function has been successfully enabled

When this bit is cleared to 0 by application program, the Flash memory write function is disabled. Note that writing a “1” into this bit results in no action. This bit is used to indicate the Flash memory write function status. When this bit is set to 1 by the hardware, it means that the Flash memory write function is enabled successfully. Otherwise, the Flash memory write function is disabled if the bit is zero.

Bit 6~4 **FMOD2~FMOD0**: Flash memory mode selection

000: Write Mode

001: Page Erase Mode

010: Reserved

011: Read Mode

100: Reserved

101: Reserved

110: Flash memory Erase/Write function Enable Mode

111: Reserved

These bits are used to select the Flash Memory operation modes. Note that the “Flash memory Erase/Write function Enable Mode” should first be successfully enabled before the Erase or Write Flash memory operation is executed.

- Bit 3**     **FWPEN:** Flash memory Erase/Write function enable procedure Trigger  
               0: Erase/Write function enable procedure is not triggered or procedure timer times out  
               1: Erase/Write function enable procedure is triggered and procedure timer starts to count
- This bit is used to activate the Flash memory Erase/Write function enable procedure and an internal timer. It is set by the application programs and then cleared by hardware when the internal timer times out. The correct patterns must be written into the FD1L/FD1H, FD2L/FD2H and FD3L/FD3H register pairs respectively as soon as possible after the FWPEN bit is set high.
- Bit 2**     **FWT:** Flash memory write initiate control  
               0: Do not initiate Flash memory write or indicating that a Flash memory write process has completed  
               1: Initiate Flash memory write process
- This bit is set by software and cleared to 0 by the hardware when the Flash memory write process has completed.
- Bit 1**     **FRDEN:** Flash memory read enable control  
               0: Flash memory read disable  
               1: Flash memory read enable
- This is the Flash memory Read Enable Bit which must be set high before any Flash memory read operations are carried out. Clearing this bit to zero will inhibit Flash memory read operations.
- Bit 0**     **FRD:** Flash memory read initiate control  
               0: Do not initiate Flash memory read or indicating that a Flash memory read process has completed  
               1: Initiate Flash memory read process
- This bit is set by software and cleared to 0 by the hardware when the Flash memory read process has completed.

- Note: 1. The FWT, FRDEN and FRD bits cannot be set to “1” at the same time with a single instruction.  
 2. Ensure that the  $f_{SUB}$  clock is stable before executing the erase/write operation.  
 3. Note that the CPU will be stopped when a read, write or erase operation is successfully activated.  
 4. Ensure that the read/erase/write operation is totally complete before executing other operations.

• **FC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7~0**     **D7~D0:** Chip reset pattern  
 When a specific value of “55H” is written into this register, a reset signal will be generated to reset the whole chip.

• **FC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	FWERTS	CLWB
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”

Bit 1 **FWERTS**: Erase time and Write time select  
 0: Erase time is 3.2ms ( $t_{FER}$ )/Write time is 2.2ms ( $t_{FWR}$ )  
 1: Erase time is 3.7ms ( $t_{FER}$ )/Write time is 3.0ms ( $t_{FWR}$ )

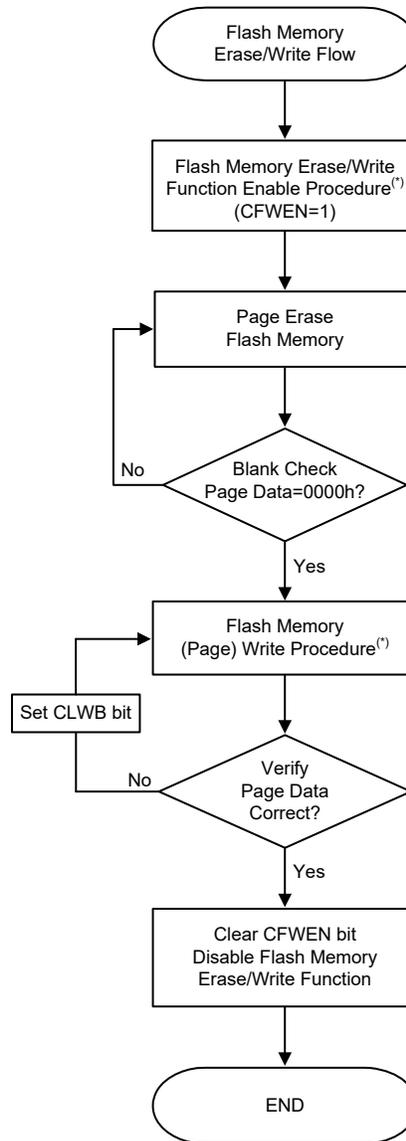
Bit 0 **CLWB**: Flash memory write buffer clear control  
 0: Do not initiate a Write Buffer Clear process or indicating that a Write Buffer Clear process has completed  
 1: Initiate Write Buffer Clear process  
 This bit is set by software and cleared to 0 by hardware when the Write Buffer Clear process has completed.

**Flash Memory Erase/Write Flow**

It is important to understand the Flash memory Erase/Write flow before the Flash memory contents are updated. Users can refer to the corresponding operation procedures when developing their IAP program to ensure that the flash memory contents are correctly updated.

**Flash Memory Erase/Write Flow Description**

1. Activate the “Flash Memory Erase/Write function enable procedure” first. When the Flash Memory Erase/Write function is successfully enabled, the CFWEN bit in the FC0 register will automatically be set high by hardware. After this, Erase or Write operations can be executed on the Flash memory. Refer to the “Flash Memory Erase/Write Function Enable Procedure” for details.
2. Configure the flash memory address to select the desired erase page, tag address and then erase this page. For a page erase operation, set the FARL and FARH registers to specify the start address of the erase page, then write dummy data into the FD0H register to tag address. The current address will be internally incremented by one after each dummy data is written into the FD0H register. When the address reaches the page boundary, 11111b, the address will not be further incremented but stop at the last address of the page. Note that the write operation to the FD0H register is used to tag address, it must be implemented to determine which addresses to be erased.
3. Execute a Blank Check operation to ensure whether the page erase operation is successful or not. The “TABRD” instruction should be executed to read the flash memory contents and to check if the contents is 0000h or not. If the flash memory page erase operation fails, users should go back to Step 2 and execute the page erase operation again.
4. Write data into the specific page. Refer to the “Flash Memory Write Procedure” for details.
5. Execute the “TABRD” instruction to read the flash memory contents and check if the written data is correct or not. If the data read from the flash memory is different from the written data, it means that the page write operation has failed. The CLWB bit should be set high to clear the write buffer and then write the data into the specific page again if the write operation has failed.
6. Clear the CFWEN bit to disable the Flash Memory Erase/Write function enable mode if the current page Erase and Write operations are complete if no more pages need to be erased or written.



**Flash Memory Erase/Write Flow**

Note: The Flash Memory Erase/Write Function Enable procedure and Flash Memory Write procedure will be described in the following sections.

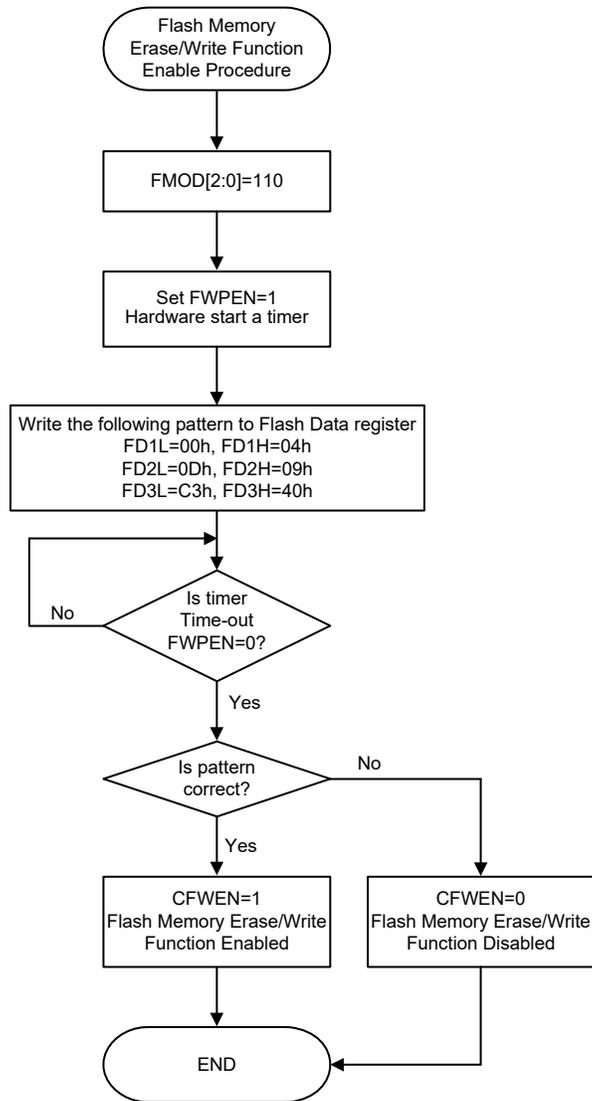
### **Flash Memory Erase/Write Function Enable Procedure**

The Flash Memory Erase/Write Function Enable Mode is specially designed to prevent the flash memory contents from being wrongly modified. In order to allow users to change the Flash memory data using the IAP control registers, users must first enable the Flash memory Erase/Write function.

#### **Flash Memory Erase/Write Function Enable Procedure Description**

1. Write data “110” to the FMOD [2:0] bits in the FC0 register to select the Flash Memory Erase/Write Function Enable Mode.
2. Set the FWPEN bit in the FC0 register to “1” to activate the Flash Memory Erase/Write Function. This will also activate an internal timer.
3. Write the correct data pattern into the Flash data registers, FD1L~FD3L and FD1H~FD3H, as soon as possible after the FWPEN bit is set high. The enable Flash memory erase/write function data pattern is 00H, 0DH, C3H, 04H, 09H and 40H corresponding to the FD1L~FD3L and FD1H~FD3H registers respectively.
4. Once the timer has timed out, the FWPEN bit will automatically be cleared to 0 by hardware regardless of the input data pattern.
5. If the written data pattern is incorrect, the Flash memory erase/write function will not be enabled successfully and the above steps should be repeated. If the written data pattern is correct, the Flash memory erase/write function will be enabled successfully.
6. Once the Flash memory write function is enabled, the Flash memory contents can be updated by executing the page erase and write operations using the IAP control registers.

To disable the Flash memory write function, the CFWEN bit in the FC0 register can be cleared. There is no need to execute the above procedure.



Flash Memory Erase/Write Function Enable Procedure

### **Flash Memory Write Procedure**

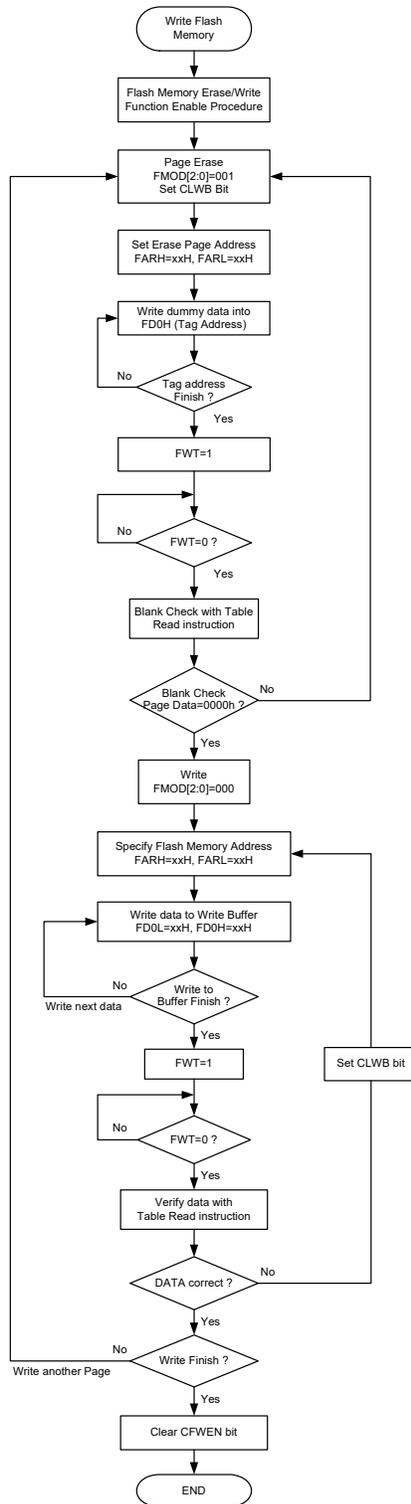
After the Flash memory erase/write function has been successfully enabled as the CFWEN bit is set high, the data to be written into the flash memory can be loaded into the write buffer. The selected flash memory page data should be erased by properly configuring the IAP control registers before the data write procedure is executed.

The write buffer size is 32 words, known as a page, whose address is mapped to a specific flash memory page specified by the memory address bits, FA11~FA5. It is important to ensure that the page where the write buffer data is located is the same one which the memory address bits, FA11~FA5, specify.

### **Flash Memory Consecutive Write Description**

The maximum amount of write data is 32 words for each write operation. The write buffer address will be automatically incremented by one when consecutive write operations are executed. The start address of a specific page should first be written into the FARL and FARH registers. Then the data word should first be written into the FD0L register and then the FD0H register. At the same time the write buffer address will be incremented by one and then the next data word can be written into the FD0L and FD0H registers for the next address without modifying the address register pair, FARH and FARL. When the write buffer address reaches the page boundary the address will not be further incremented but will stop at the last address of the page.

1. Activate the “Flash Memory Erase/Write function enable procedure”. Check the CFWEN bit value and then execute the erase/write operations if the CFWEN bit is set high. Refer to the “Flash Memory Erase/Write function enable procedure” for more details.
2. Set the FMOD field to “001” to select the erase operation and set the CLWB bit high to clear the write buffer. Set the FWT bit high to erase the desired page which is specified by the FARH and FARL registers and has been tagged address. Wait until the FWT bit goes low.
3. Execute a Blank Check operation using the table read instruction to ensure that the erase operation has successfully completed.  
Go to step 2 if the erase operation is not successful.  
Go to step 4 if the erase operation is successful.
4. Set the FMOD field to “000” to select the write operation.
5. Setup the desired start address in the FARH and FARL registers. Write the desired data words consecutively into the FD0L and FD0H registers within a page as specified by their consecutive addresses. The maximum written data number is 32 words.
6. Set the FWT bit high to write the data words from the write buffer to the flash memory. Wait until the FWT bit goes low.
7. Verify the data using the table read instruction to ensure that the write operation has successfully completed.  
If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 5.  
Go to step 8 if the write operation is successful.
8. Clear the CFWEN bit low to disable the Flash memory erase/write function.



**Flash Memory Consecutive Write Procedure**

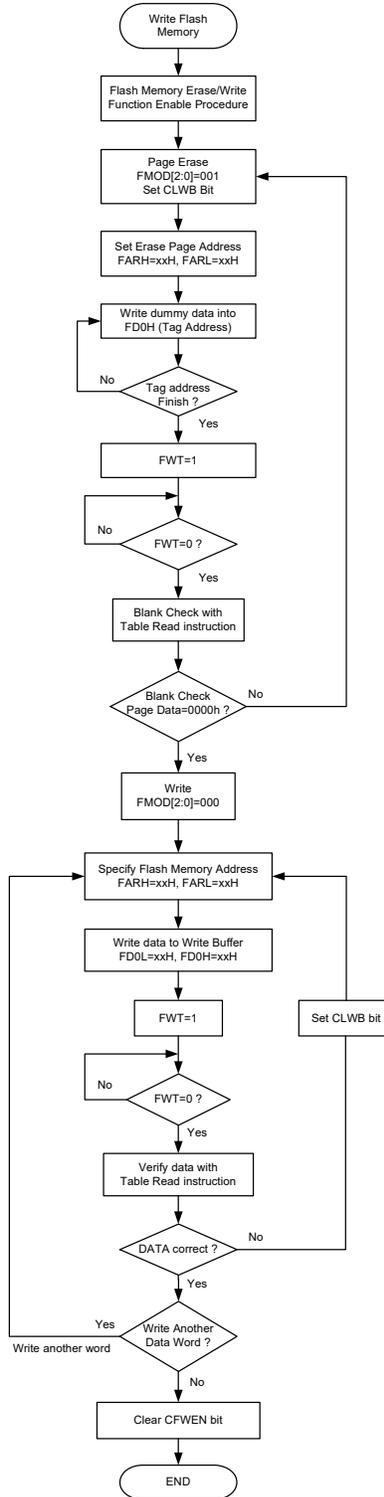
- Note: 1. When the erase or write operation is successfully activated, all CPU operations will temporarily cease.  
 2. It will take certain time for the FWT bit state changing from high to low in the erase or write operation, which can be selected by the FWERTS bit in the FC2 register.

### **Flash Memory Non-Consecutive Write Description**

The main difference between Flash Memory Consecutive and Non-Consecutive Write operations is whether the data words to be written are located in consecutive addresses or not. If the data to be written is not located in consecutive addresses the desired address should be re-assigned after a data word is successfully written into the Flash Memory.

A two data word non-consecutive write operation is taken as an example here and described as follows:

1. Activate the “Flash Memory Erase/Write function enable procedure”. Check the CFWEN bit value and then execute the erase/write operation if the CFWEN bit is set high. Refer to the “Flash Memory Erase/Write function enable procedure” for more details.
2. Set the FMOD field to “001” to select the erase operation and set the CLWB bit high to clear the write buffer. Set the FWT bit high to erase the desired page which is specified by the FARH and FARL registers and has been tagged address. Wait until the FWT bit goes low.
3. Execute a Blank Check operation using the table read instruction to ensure that the erase operation has successfully completed.  
Go to step 2 if the erase operation is not successful.  
Go to step 4 if the erase operation is successful.
4. Set the FMOD field to “000” to select the write operation.
5. Setup the desired address ADDR1 in the FARH and FRARL registers. Write the desired data word DATA1 first into the FD0L register and then into the FD0H register.
6. Set the FWT bit high to transfer the data word from the write buffer to the flash memory. Wait until the FWT bit goes low.
7. Verify the data using the table read instruction to ensure that the write operation has successfully completed.  
If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 5.  
Go to step 8 if the write operation is successful.
8. Setup the desired address ADDR2 in the FARH and FRARL registers. Write the desired data word DATA2 first into the FD0L register and then into the FD0H register.
9. Set the FWT bit high to transfer the data word from the write buffer to the flash memory. Wait until the FWT bit goes low.
10. Verify the data using the table read instruction to ensure that the write operation has successfully completed.  
If the write operation has not successfully completed, set the CLWB bit high to clear the write buffer and then go to step 8.  
Go to step 11 if the write operation is successful.
11. Clear the CFWEN bit low to disable the Flash memory erase/write function.



**Flash Memory Non-Consecutive Write Procedure**

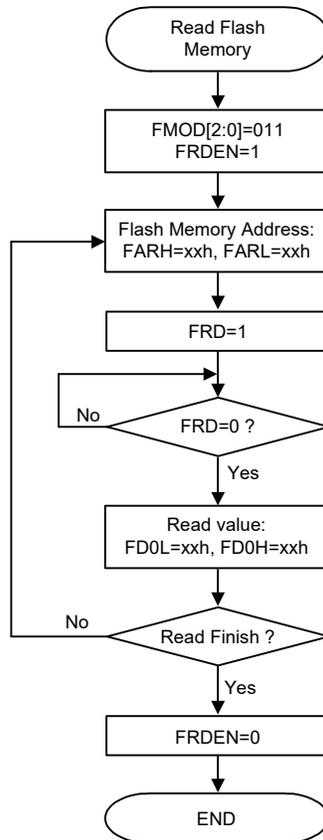
- Note: 1. When the erase or write operation is successfully activated, all CPU operations will temporarily cease.  
 2. It will take certain time for the FWT bit state changing from high to low in the erase or write operation, which can be selected by the FWERTS bit in the FC2 register.

#### **Important Points to Note for Flash Memory Write Operations**

1. The “Flash Memory Erase/Write Function Enable Procedure” must be successfully activated before the Flash Memory erase/write operation is executed.
2. The Flash Memory erase operation is executed to erase a whole page.
3. The whole write buffer data will be written into the flash memory in a page format. The corresponding address cannot exceed the page boundary.
4. After the data is written into the flash memory the flash memory contents must be read out using the table read instruction, TABRD, and checked if it is correct or not. If the data written into the flash memory is incorrect, the write buffer should be cleared by setting the CLWB bit high and then writing the data again into the write buffer. Then activate a write operation on the same flash memory page without erasing it. The data check, buffer clear and data re-write steps should be repeatedly executed until the data written into the flash memory is correct.
5. The system frequency should be setup to the maximum application frequency when data write and data check operations are executed using the IAP function.

#### **Flash Memory Read Procedure**

To activate the Flash Memory Read procedure, the FMOD field should be set to “011” to select the flash memory read mode and the FRDEN bit should be set high to enable the read function. The desired flash memory address should be written into the FARH and FARL registers and then the FRD bit should be set high. After this the flash memory read operation will be activated. The data stored in the specified address can be read from the data registers, FDOH and FDOL, when the FRD bit goes low. There is no need to first activate the Flash Memory Erase/Write Function Enable Procedure before the flash memory read operation is executed.



**Flash Memory Read Procedure**

- Note: 1. When the read operation is successfully activated, all CPU operations will temporarily cease.  
 2. It will take a typical time of three instruction cycles for the FRD bit state changing from high to low.

## Data Memory

The Data Memory is a volatile area of 8-bit wide RAM internal memory and is the location where temporary information is stored.

Categorized into two types, the first of these is an area of RAM where special function registers are located. These registers have fixed locations and are necessary for correct operation of the device. Many of these registers can be read from and written to directly under program control, however, some remain protected from user manipulation. The second area of Data Memory is reserved for general purpose use. All locations within this area are read and write accessible under program control.

### Structure

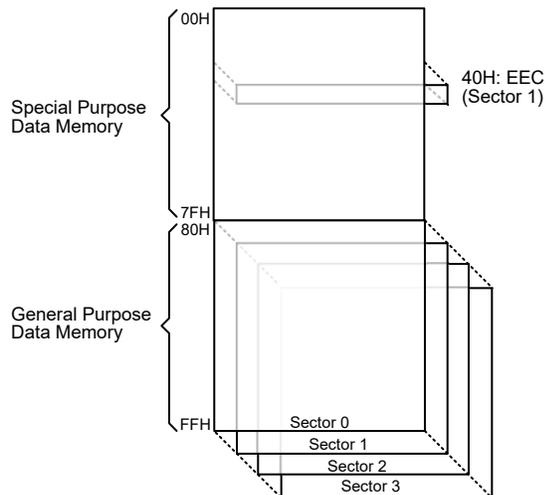
The Data Memory is subdivided into several sectors, all of which are implemented in 8-bit wide Memory.

Each of the Data Memory sectors is categorized into two types, the Special Purpose Data Memory and the General Purpose Data Memory. The address range of the Special Purpose Data Memory for the device is from 00H to 7FH while the General Purpose Data Memory address range is from 80H to FFH.

Switching between the different Data Memory sectors is achieved by setting the Memory Pointers to the correct value if using the indirect addressing method. The start address of the Data Memory for the device is the address 00H.

Special Purpose Data Memory	General Purpose Data Memory	
Available Sectors	Capacity	Sector: Address
0, 1	512×8	0: 80H~FFH 1: 80H~FFH 2: 80H~FFH 3: 80H~FFH

**Data Memory Summary**



**Data Memory Structure**

### **Data Memory Addressing**

For the device that supports the extended instructions, there is no Bank Pointer for Data Memory addressing. For Data Memory the desired Sector is pointed by the MP1H or MP2H register and the certain Data Memory address in the selected sector is specified by the MP1L or MP2L register when using indirect addressing access.

Direct Addressing can be used in all sectors using the extended instructions which can address all available data memory space. For the accessed data memory which is located in any data memory sectors except sector 0, the extended instructions can be used to access the data memory instead of using the indirect addressing access. The main difference between standard instructions and extended instructions is that the data memory address “m” in the extended instructions has 10 valid bits for this device, the high byte indicates a sector and the low byte indicates a specific address.

### **General Purpose Data Memory**

All microcontroller programs require an area of read/write memory where temporary data can be stored and retrieved for use later. It is this area of RAM memory that is known as General Purpose Data Memory. This area of Data Memory is fully accessible by the user programming for both reading and writing operations. By using the bit operation instructions individual bits can be set or reset under program control giving the user a large range of flexibility for bit manipulation in the Data Memory.

### **Special Purpose Data Memory**

This area of Data Memory is where registers, necessary for the correct operation of the microcontroller, are stored. Most of the registers are both readable and writeable but some are protected and are readable only, the details of which are located under the relevant Special Function Register section. Note that for locations that are unused, any read instruction to these addresses will return the value “00H”.

	Sector 0	Sector 1		Sector 0	Sector 1
00H	IAR0	CRCCR	40H	PTMAH	EEC
01H	MP0	CRCIN	41H	PTMRPL	[Unused]
02H	IAR1	CRCDL	42H	PTMRPH	
03H	MP1L	CRCDH	43H	TKTMR	
04H	MP1H	FC0	44H	TKC0	
05H	ACC	FC1	45H	TKC1	
06H	PCL	FC2	46H	TK16DL	
07H	TBLP	FARL	47H	TK16DH	
08H	TBLH	FARH	48H	TKM0C0	
09H	TBHP	FD0L	49H	TKM0C1	
0AH	STATUS	FD0H	4AH	TKM016DL	
0BH	[Unused]	FD1L	4BH	TKM016DH	
0CH	IAR2	FD1H	4CH	TKM0ROL	
0DH	MP2L	FD2L	4DH	TKM0ROH	
0EH	MP2H	FD2H	4EH	[Reserved]	
0FH	RSTFC	FD3L	4FH	[Reserved]	
10H	INTC0	FD3H	50H	[Reserved]	
11H	INTC1	[Unused]	51H	[Reserved]	
12H	INTC2				
13H	LVRC				
14H	PA				
15H	PAC				
16H	PAPU				
17H	PAWU				
18H	MF10				
19H	MF11				
1AH	WDTC				
1BH	TB0C				
1CH	PSC0R				
1DH	TB1C				
1EH	PSC1R				
1FH	LVPUC				
20H	PB				
21H	PBC				
22H	PBPU				
23H	SIMC0				
24H	SIMC1				
25H	SIMD				
26H	SIMA				
27H	SIMTOC				
28H	CTMC0				
29H	CTMC1				
2AH	CTMDL				
2BH	CTMDH				
2CH	CTMAL				
2DH	CTMAH				
2EH	SADC0				
2FH	SADC1				
30H	SADC2				
31H	SADOH				
32H	SADOL				
33H	SLEDC0				
34H	SLEDC1				
35H	PD				
36H	PDC				
37H	PDPU				
38H	[Reserved]				
39H	PCC				
3AH	[Reserved]				
3BH	PTMC0				
3CH	PTMC1				
3DH	PTMDL				
3EH	PTMDH				
3FH	PTMAL				
			52H	[Reserved]	
			53H	[Reserved]	
			54H	[Reserved]	
			55H	[Reserved]	
			56H	[Reserved]	
			57H	[Reserved]	
			58H	[Reserved]	
			59H	[Reserved]	
			5AH	[Reserved]	
			5BH	RSTC	
			5CH	INTEG	
			5DH	PAS0	
			5EH	PAS1	
			5FH	PBS0	
			60H	[Reserved]	
			61H	[Reserved]	
			62H	PDS0	
			63H	[Reserved]	
			64H	IFS	
			65H	EEAL	
			66H	EEAH	
			67H	EED	
			68H	USR	
			69H	UCR1	
			6AH	UCR2	
			6BH	UCR3	
			6CH	BRDH	
			6DH	BRDL	
			6EH	UFCR	
			6FH	TXR_RXR	
			70H	RxCNT	
			71H	[Reserved]	
			72H	LVDC	
			73H	TLVRC	
			74H	SCC	
			75H	HIRCC	
			76H	VBGRC	
			77H	ORMC	
			78H	PCRL	
			79H	PCRH	
			7AH	STKPTR	
			7BH	IECC	
			7CH	[Reserved]	
			7DH	[Reserved]	
			7EH	[Reserved]	
			7FH	[Reserved]	

[Unused] : Unused, read as 00H

[Reserved] : Reserved, cannot be changed

**Special Purpose Data Memory Structure**

## Special Function Register Description

Most of the Special Function Register details will be described in the relevant functional section; however several registers require a separate description in this section.

### Indirect Addressing Registers – IAR0, IAR1, IAR2

The Indirect Addressing Registers, IAR0, IAR1 and IAR2, although having their locations in normal RAM register space, do not actually physically exist as normal registers. The method of indirect addressing for RAM data manipulation uses these Indirect Addressing Registers and Memory Pointers, in contrast to direct memory addressing, where the actual memory address is specified. Actions on the IAR0, IAR1 and IAR2 registers will result in no actual read or write operation to these registers but rather to the memory location specified by their corresponding Memory Pointers, MP0, MP1L/MP1H or MP2L/MP2H. Acting as a pair, IAR0 and MP0 can together access data only from Sector 0 while the IAR1 register together with the MP1L/MP1H register pair and IAR2 register together with the MP2L/MP2H register pair can access data from any Data Memory Sector. As the Indirect Addressing Registers are not physically implemented, reading the Indirect Addressing Registers will return a result of “00H” and writing to the registers will result in no operation.

### Memory Pointers – MP0, MP1L/MP1H, MP2L/MP2H

Five Memory Pointers, known as MP0, MP1L/MP1H, MP2L/MP2H, are provided. These Memory Pointers are physically implemented in the Data Memory and can be manipulated in the same way as normal registers providing a convenient way with which to address and track data. When any operation to the relevant Indirect Addressing Registers is carried out, the actual address that the microcontroller is directed to is the address specified by the related Memory Pointer. MP0, together with Indirect Addressing Register, IAR0, are used to access data from Sector 0, while MP1L/MP1H together with IAR1 and MP2L/MP2H together with IAR2 are used to access data from all sectors according to the corresponding MP1H or MP2H register. Direct Addressing can be used in all sectors using the extended instruction which can address all available data memory space.

The following example shows how to clear a section of four Data Memory locations already defined as locations adres1 to adres4.

### Indirect Addressing Program Example

#### Example 1

```

data .section 'data'
adres1 db ?
adres2 db ?
adres3 db ?
adres4 db ?
block db ?
code .section at 0 'code'
org 00h
start:
    mov a, 04h           ; setup size of block
    mov block, a
    mov a, offset adres1 ; Accumulator loaded with first RAM address
    mov mp0, a          ; setup memory pointer with first RAM address
loop:
    clr IAR0            ; clear the data at address defined by MP0
    inc mp0             ; increment memory pointer
    sdz block           ; check if last memory location has been cleared
    jmp loop
continue:

```

### Example 2

```
data .section 'data'
adres1 db ?
adres2 db ?
adres3 db ?
adres4 db ?
block db ?
code .section at 0 'code'
org 00h
start:
    mov a, 04h           ; setup size of block
    mov block, a
    mov a, 01h           ; setup the memory sector
    mov mplh, a
    mov a, offset adres1 ; Accumulator loaded with first RAM address
    mov mp1l, a          ; setup memory pointer with first RAM address
loop:
    clr IAR1             ; clear the data at address defined by MP1L
    inc mp1l             ; increment memory pointer MP1L
    sdz block            ; check if last memory location has been cleared
    jmp loop
continue:
:
```

The important point to note here is that in the example shown above, no reference is made to specific Data Memory addresses.

### Direct Addressing Program Example Using Extended Instructions

```
data .section 'data'
temp db ?
code .section at 0 'code'
org 00h
start:
    lmov a, [m]          ; move [m] data to acc
    lsub a, [m+1]        ; compare [m] and [m+1] data
    snz c                ; [m]>[m+1]?
    jmp continue        ; no
    lmov a, [m]          ; yes, exchange [m] and [m+1] data
    mov temp, a
    lmov a, [m+1]
    lmov [m], a
    mov a, temp
    lmov [m+1], a
continue:
:
```

Note: Here “m” is a data memory address located in any data memory sectors. For example, m=1F0H, it indicates address 0F0H in Sector 1.

### Accumulator – ACC

The Accumulator is central to the operation of any microcontroller and is closely related with operations carried out by the ALU. The Accumulator is the place where all intermediate results from the ALU are stored. Without the Accumulator it would be necessary to write the result of each calculation or logical operation such as addition, subtraction, shift, etc., to the Data Memory resulting in higher programming and timing overheads. Data transfer operations usually involve the temporary storage function of the Accumulator; for example, when transferring data between one user-defined register and another, it is necessary to do this by passing the data through the Accumulator as no direct transfer between two registers is permitted.

### Program Counter Low Byte Register – PCL

To provide additional program control functions, the low byte of the Program Counter is made accessible to programmers by locating it within the Special Purpose area of the Data Memory. By manipulating this register, direct jumps to other program locations are easily implemented. Loading a value directly into this PCL register will cause a jump to the specified Program Memory location. However, as the register is only 8-bit wide, only jumps within the current Program Memory page are permitted. When such operations are used, note that a dummy cycle will be inserted.

### Look-up Table Registers – TBLP, TBHP, TBLH

These three special function registers are used to control operation of the look-up table which is stored in the Program Memory. TBLP and TBHP are the table pointers and indicate the location where the table data is located. Their value must be setup before any table read commands are executed. Their value can be changed, for example using the “INC” or “DEC” instructions, allowing for easy table data pointing and reading. TBLH is the location where the high order byte of the table data is stored after a table read data instruction has been executed. Note that the lower order table data byte is transferred to a user defined location.

### Option Memory Mapping Register – ORMC

The ORMC register is used to enable Option Memory Mapping function. The Option Memory capacity is 64 words. When a specific pattern of 55H and AAH is consecutively written into this register, the Option Memory Mapping function will be enabled and then the Option Memory code can be read by using the table read instruction. The Option Memory addresses 00H~3FH will be mapped to Program Memory last page addresses C0H~FFH.

To successfully enable the Option Memory Mapping function, the specific pattern of 55H and AAH must be written into the ORMC register in two consecutive instruction cycles. It is therefore recommended that the global interrupt bit EMI should first be cleared before writing the specific pattern, and then set high again at a proper time according to users' requirements after the pattern is successfully written. An internal timer will be activated when the pattern is successfully written. The mapping operation will be automatically finished after a period of  $4 \times t_{LIRC}$ . Therefore, users should read the data in time, otherwise the Option Memory Mapping function needs to be restarted. After the completion of each consecutive write operation to the ORMC register, the timer will recount.

When the table read instructions are used to read the Option Memory code, both “TABRD [m]” and “TABRDL [m]” instructions can be used. However, care must be taken if the “TABRD [m]” instruction is used, the table pointer defined by the TBHP register must be referenced to the last page. Refer to corresponding sections about the table read instruction for more details.

• **ORMC Register**

Bit	7	6	5	4	3	2	1	0
Name	ORMC7	ORMC6	ORMC5	ORMC4	ORMC3	ORMC2	ORMC1	ORMC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **ORMC7~ORMC0**: Option Memory Mapping special pattern  
 When a special pattern of 55H and AAH is written into this register, the Option Memory access will be enabled. Note that the register content will be cleared after the MCU is woken up from the IDLE/SLEEP mode.

**Status Register – STATUS**

This 8-bit register contains the SC flag, CZ flag, zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). These arithmetic/logical operation and system management flags are used to record the status and operation of the microcontroller.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition, operations related to the status register may give different results due to the different instruction operations. The TO flag can be affected only by a system power-up, a WDT time-out or by executing the “CLR WDT” or “HALT” instruction. The PDF flag is affected only by executing the “HALT” or “CLR WDT” instruction or during a system power-up.

The Z, OV, AC, C, SC and CZ flags generally reflect the status of the latest operations.

- C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. C is also affected by a rotate through carry instruction.
- AC is set if an operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
- Z is set if the result of an arithmetic or logical operation is zero; otherwise Z is cleared.
- OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
- PDF is cleared by a system power-up or executing the “CLR WDT” instruction. PDF is set by executing the “HALT” instruction.
- TO is cleared by a system power-up or executing the “CLR WDT” or “HALT” instruction. TO is set by a WDT time-out.
- CZ is the operational result of different flags for different instructions. Refer to register definitions for more details.
- SC is the result of the “XOR” operation which is performed by the OV flag and the MSB of the current instruction operation result.

In addition, on entering an interrupt sequence or executing a subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status registers are important and if the subroutine can corrupt the status register, precautions must be taken to correctly save it.

• **STATUS Register**

Bit	7	6	5	4	3	2	1	0
Name	SC	CZ	TO	PDF	OV	Z	AC	C
R/W	R/W	R/W	R	R	R/W	R/W	R/W	R/W
POR	x	x	0	0	x	x	x	x

“x”: unknown

- Bit 7     **SC**: The result of the “XOR” operation which is performed by the OV flag and the MSB of the instruction operation result.
- Bit 6     **CZ**: The operational result of different flags for different instructions.  
 For SUB/SUBM/LSUB/LSUBM instructions, the CZ flag is equal to the Z flag.  
 For SBC/SBCM/LSBC/LSBCM instructions, the CZ flag is the “AND” operation result which is performed by the previous operation CZ flag and current operation zero flag.  
 For other instructions, the CZ flag will not be affected.
- Bit 5     **TO**: Watchdog time-out flag  
 0: After power up or executing the “CLR WDT” or “HALT” instruction  
 1: A watchdog time-out occurred.
- Bit 4     **PDF**: Power down flag  
 0: After power up or executing the “CLR WDT” instruction  
 1: By executing the “HALT” instruction
- Bit 3     **OV**: Overflow flag  
 0: No overflow  
 1: An operation results in a carry into the highest-order bit but not a carry out of the highest-order bit or vice versa.
- Bit 2     **Z**: Zero flag  
 0: The result of an arithmetic or logical operation is not zero  
 1: The result of an arithmetic or logical operation is zero
- Bit 1     **AC**: Auxiliary flag  
 0: No auxiliary carry  
 1: An operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction
- Bit 0     **C**: Carry flag  
 0: No carry-out  
 1: An operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation  
 The “C” flag is also affected by a rotate through carry instruction.

## EEPROM Data Memory

The device contains an area of internal EEPROM Data Memory. EEPROM is by its nature a non-volatile form of re-programmable memory, with data retention even when its power supply is removed. By incorporating this kind of data memory, a whole new host of application possibilities are made available to the designer. The availability of EEPROM storage allows information such as product identification numbers, calibration values, specific user data, system setup data or other product information to be stored directly within the product microcontroller. The process of reading and writing data to the EEPROM memory has been reduced to a very trivial affair.

### EEPROM Data Memory Structure

The EEPROM Data Memory capacity is 512×8 bits for the device. Unlike the Program Memory and RAM Data Memory, the EEPROM Data Memory is not directly mapped into memory space and is therefore not directly addressable in the same way as the other types of memory. Read and Write operations to the EEPROM are carried out in single byte operations using an address register pair and a data register in Sector 0 and a single control register in Sector 1.

### EEPROM Registers

Four registers control the overall operation of the internal EEPROM Data Memory. These are the address registers, EEAL and EEAH, the data register, EED and a single control register, EEC. As both the EEAH, EEAL and EED registers are located in Sector 0, they can be directly accessed in the same way as any other Special Function Register. The EEC register however, being located in Sector 1, can only be read from or written to indirectly using the MP1L/MP1H or MP2L/MP2H Memory Pointer and Indirect Addressing Register, IAR1/IAR2. Because the EEC control register is located at address 40H in Sector 1, the MP1L or MP2L Memory Pointer must first be set to the value 40H and the MP1H or MP2H Memory Pointer high byte set to the value, 01H, before any operations on the EEC register are executed.

Register Name	Bit							
	7	6	5	4	3	2	1	0
EEAL	EEAL7	EEAL6	EEAL5	EEAL4	EEAL3	EEAL2	EEAL1	EEAL0
EEAH	—	—	—	—	—	—	—	EEAH0
EED	D7	D6	D5	D4	D3	D2	D1	D0
EEC	EWERTS	EREN	ER	MODE	WREN	WR	RDEN	RD

EEPROM Register List

#### • EEAL Register

Bit	7	6	5	4	3	2	1	0
Name	EEAL7	EEAL6	EEAL5	EEAL4	EEAL3	EEAL2	EEAL1	EEAL0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0      **EEAL7~EEAL0**: Data EEPROM low byte address bit 7 ~ bit 0

#### • EEAH Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	EEAH0
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1      Unimplemented, read as “0”

Bit 0      **EEAH0**: Data EEPROM high byte address bit 0

• **EED Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0      **D7~D0**: Data EEPROM data bit 7 ~ bit 0

• **EEC Register**

Bit	7	6	5	4	3	2	1	0
Name	EWERTS	EREN	ER	MODE	WREN	WR	RDEN	RD
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7      **EWERTS**: EEPROM Erase time and Write time select

0: Erase time is 3.2ms ( $t_{EEER}$ )/Write time is 2.2ms ( $t_{EEWR}$ )

1: Erase time is 3.7ms ( $t_{EEER}$ )/Write time is 3.0ms ( $t_{EEWR}$ )

Bit 6      **EREN**: Data EEPROM erase enable

0: Disable

1: Enable

This bit is used to enable data EEPROM erase function and must be set high before erase operations are carried out. This bit will be automatically reset to zero by the hardware after the erase cycle has finished. Clearing this bit to zero will inhibit data EEPROM erase operations.

Bit 5      **ER**: EEPROM erase control

0: Erase cycle has finished

1: Activate an erase cycle

When this bit is set high by the application program, an erase cycle will be activated. This bit will be automatically reset to zero by the hardware after the erase cycle has finished. Setting this bit high will have no effect if the EREN has not first been set high.

Bit 4      **MODE**: EEPROM Operation mode select

0: Byte operation mode

1: Page operation mode

This is the EEPROM Page operation mode select bit and when set high by the application program will select the Page write or erase or read function. Otherwise, the EEPROM is the byte write or read function. The EEPROM page buffer size is 16-byte.

Bit 3      **WREN**: Data EEPROM write enable

0: Disable

1: Enable

This is the Data EEPROM Write Enable Bit which must be set high before Data EEPROM write operations are carried out. Clearing this bit to zero will inhibit Data EEPROM write operations. Note that this bit will automatically be reset to zero by hardware after the write cycle has finished.

Bit 2      **WR**: EEPROM write control

0: Write cycle has finished

1: Activate a write cycle

This is the Data EEPROM Write Control Bit and when set high by the application program will activate a write cycle. This bit will be automatically reset to zero by the hardware after the write cycle has finished. Setting this bit high will have no effect if the WREN has not first been set high.

Bit 1      **RDEN**: Data EEPROM read enable

0: Disable

1: Enable

This is the Data EEPROM Read Enable Bit which must be set high before Data EEPROM read operations are carried out. Clearing this bit to zero will inhibit Data EEPROM read operations.

Bit 0 **RD**: EEPROM read control  
0: Read cycle has finished  
1: Activate a read cycle

This is the Data EEPROM Read Control Bit and when set high by the application program will activate a read cycle. This bit will be automatically reset to zero by the hardware after the read cycle has finished. Setting this bit high will have no effect if the RDEN bit has not first been set high.

- Note: 1. The EREN, ER, WREN, WR, RDEN and RD cannot be set high at the same time in one instruction.  
2. Ensure that the  $f_{SUB}$  clock is stable before executing the erase/write operation.  
3. Ensure that the erase/write operation is totally complete before changing the contents of the EEPROM related registers or activating the IAP function.

## Reading Operation from the EEPROM

Reading data from the EEPROM can be implemented by two modes for this device, byte read mode or page read mode, which is controlled by the EEPROM operation mode selection bit, MODE, in the EEC register.

### Byte Read Mode

The EEPROM byte read operation can be executed when the mode selection bit, MODE, is cleared to zero. For a byte read operation the desired EEPROM address should first be placed in the EEAH and EEAL registers, as well as the read enable bit, RDEN, in the EEC register should be set high to enable the read function. Then setting the RD bit high will initiate the EEPROM byte read operation. Note that setting the RD bit high only will not initiate a read operation if the RDEN bit is not set high. When the read cycle terminates, the RD bit will automatically be cleared to zero and the EEPROM data can be read from the EED register. The data will remain in the EED register until another read or write operation is executed. The application program can poll the RD bit to determine when the data is valid for reading.

### Page Read Mode

The EEPROM page read operation can be executed when the mode selection bit, MODE, is set high. The page size can be up to 16 bytes for the page read operation. For a page read operation the start address of the desired EEPROM page should first be placed in the EEAH and EEAL registers, as well as the read enable bit, RDEN, in the EEC register should be set high to enable the read function. Then setting the RD bit high will initiate the EEPROM page read operation. Note that setting the RD bit high only will not initiate a read operation if the RDEN bit is not set high. When the current byte read cycle terminates, the RD bit will automatically be cleared indicating that the EEPROM data can be read from the EED register, and the current address will be incremented by one by hardware. The data which is stored in the next EEPROM address can continuously be read when the RD bit is again set high without reconfiguring the EEPROM address and RDEN control bit. The application program can poll the RD bit to determine when the data is valid for reading.

The EEPROM address higher 5 bits are used to specify the desired page location while the lower 4 bits are used to point to the actual address. In the page read operation mode the lower 4-bit address value will automatically be incremented by one. However, the higher 5-bit address value will not be incremented by hardware. When the EEPROM address lower 4-bit value which is internally incremented by one in the page mode reaches the page boundary, known as 0FH, the EEPROM address lower 4-bit value will stop at 0FH. The EEPROM address will not “roll over”.

## Page Erase Operation to the EEPROM

The EEPROM page erase operation can be executed when the mode selection bit, MODE, is set high. The EEPROM is capable of a 16-byte page erase. The internal page buffer will be cleared by hardware after power on reset. When the EEPROM erase enable control bit, namely EREN, is changed from “1” to “0”, the internal page buffer will also be cleared. Note that when the EREN bit is changed from “0” to “1”, the internal page buffer will not be cleared. The EEPROM address higher 5 bits are used to specify the desired page location while the lower 4 bits are used to point to the actual address. In the page erase operation mode the lower 4-bit address value will automatically be incremented by one after each dummy data byte is written into the EED register. However, the higher 5-bit address value will not be incremented by hardware. When the EEPROM address lower 4-bit value which is internally incremented by one in the page mode reaches the page boundary, known as 0FH, the EEPROM address lower 4-bit value will stop at 0FH. The EEPROM address will not “roll over”.

For page erase operations the start address of the desired EEPROM page should first be placed in the EEAH and EEAL registers, then the dummy data to be written should be placed in the EED register. The maximum data length for a page is 16 bytes. Note that the write operation to the EED register is used to tag address, it must be implemented to determine which addresses to be erased. When the page dummy data is completely written, then the EREN bit in the EEC register should be set high to enable erase operations and the ER bit must be immediately set high to initiate the EEPROM erase process. These two instructions must be executed in two consecutive instruction cycles to activate an erase operation successfully. The global interrupt enable bit EMI should also first be cleared before implementing an erase operation and then set again after a valid erase activation procedure has completed.

Note: The above steps must be executed sequentially to successfully complete the page erase operation, refer to the corresponding programming example.

As the EEPROM erase cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been erased from the EEPROM. Detecting when the erase cycle has finished can be implemented either by polling the ER bit in the EEC register or by using the EEPROM interrupt. When the erase cycle terminates, the ER bit will be automatically cleared to zero by the microcontroller, informing the user that the page data has been erased. The application program can therefore poll the ER bit to determine when the erase cycle has ended. After the erase operation is finished, the EREN bit will be set low by hardware. The Data EEPROM erased page content will all be zero after a page erase operation.

## Write Operation to the EEPROM

Writing data to the EEPROM can be implemented by two modes for this device, byte write mode or page write mode, which is controlled by the EEPROM operation mode selection bit, MODE, in the EEC register.

### Byte Write Mode

The EEPROM byte write operation can be executed when the mode selection bit, MODE, is cleared to zero. For byte write operations the desired EEPROM address should first be placed in the EEAH and EEAL registers, then the data to be written should be placed in the EED register. To write data to the EEPROM, the write enable bit, WREN, in the EEC register must first be set high to enable the write function. After this, the WR bit in the EEC register must be immediately set high to initiate a write cycle. These two instructions must be executed in two consecutive instruction cycles to activate a write operation successfully. The global interrupt bit EMI should also first be cleared before implementing any write operations, and then set high again after a valid write activation

procedure has completed. Note that setting the WR bit high only will not initiate a write cycle if the WREN bit is not set.

Note: The above steps must be executed sequentially to successfully complete the byte write operation, refer to the corresponding programming example.

As the EEPROM write cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been written into the EEPROM. Detecting when the write cycle has finished can be implemented either by polling the WR bit in the EEC register or by using the EEPROM interrupt. When the write cycle terminates, the WR bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been written to the EEPROM. The application program can therefore poll the WR bit to determine when the write cycle has ended. After the write operation is finished, the WREN bit will be set low by hardware. Note that a byte erase operation will automatically be executed before a byte write operation is successfully activated.

### **Page Write Mode**

Before a page write operation is executed, it is important to ensure that a relevant page erase operation has been successfully executed. The EEPROM page write operation can be executed when the mode selection bit, MODE, is set high. The EEPROM is capable of a 16-byte page write. The internal page buffer will be cleared by hardware after power on reset. When the EEPROM write enable control bit, namely WREN, is changed from “1” to “0”, the internal page buffer will also be cleared. Note that when the WREN bit is changed from “0” to “1”, the internal page buffer will not be cleared. A page write is initiated in the same way as a byte write initiation except that the EEPROM data can be written up to 16 bytes. The EEPROM address higher 5 bits are used to specify the desired page location while the lower 4 bits are used to point to the actual address. In the page write operation mode the lower 4-bit address value will automatically be incremented by one after each data byte is written into the EED register. However, the higher 5-bit address value will not be incremented by hardware. When the EEPROM address lower 4-bit value which is internally incremented by one in the page mode reaches the page boundary, known as 0FH, the EEPROM address lower 4-bit value will stop at 0FH. The EEPROM address will not “roll over”. At this point any data write operations to the EED register will be invalid.

For page write operations the start address of the desired EEPROM page should first be placed in the EEAH and EEAL registers, then the data to be written should be placed in the EED register. The maximum data length for a page is 16 bytes. Note that when a data byte is written into the EED register, then the data in the EED register will be loaded into the internal page buffer and the current address value will automatically be incremented by one. When the page data is completely written into the page buffer, then the WREN bit in the EEC register should be set high to enable write operations and the WR bit must be immediately set high to initiate the EEPROM write process. These two instructions must be executed in two consecutive instruction cycles to activate a write operation successfully. The global interrupt enable bit EMI should also first be cleared before implementing any write operations, and then set high again after a valid write activation procedure has completed. Note that setting the WR bit high only will not initiate a write cycle if the WREN bit is not set.

Note: The above steps must be executed sequentially to successfully complete the page write operation, refer to the corresponding programming example.

As the EEPROM write cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been written into the EEPROM. Detecting when the write cycle has finished can be implemented either by polling the WR bit in the EEC register or by using the EEPROM interrupt. When the write cycle terminates, the WR bit will be automatically cleared to zero by the microcontroller, informing the user that the

data has been written to the EEPROM. The application program can therefore poll the WR bit to determine when the write cycle has ended. After the write operation is finished, the WREN bit will be set low by hardware.

### Write Protection

Protection against inadvertent write operation is provided in several ways. After the device is powered-on the Write Enable bit in the control register will be cleared preventing any write operations. Also at power-on the Memory Pointer high byte register, MP1H or MP2H, will be reset to zero, which means that Data Memory Sector 0 will be selected. As the EEPROM control register is located in Sector 1, this adds a further measure of protection against spurious write operations. During normal program operation, ensuring that the Write Enable bit in the control register is cleared will safeguard against incorrect write operations.

### EEPROM Interrupt

The EEPROM interrupt is generated when an EEPROM erase or write cycle has ended. The EEPROM interrupt must first be enabled by setting the DEE bit in the relevant interrupt register. When an EEPROM erase or write cycle ends, the DEF request flag will be set. If the EEPROM interrupts is enabled and the stack is not full, a jump to the EEPROM Interrupt vector will take place. When the interrupt is serviced, the EEPROM interrupt flag must be manually reset by the application program. More details can be obtained in the Interrupt section.

### Programming Considerations

Care must be taken that data is not inadvertently written to the EEPROM. Protection can be enhanced by ensuring that the Write Enable bit is normally cleared to zero when not writing. Also the Memory Pointer high byte register, MP1H or MP2H, could be normally cleared to zero as this would inhibit access to Sector 1 where the EEPROM control register exists. Although certainly not necessary, consideration might be given in the application program to the checking of the validity of new write data by a simple read back process.

When writing data the WR bit must be set high immediately after the WREN bit has been set high, to ensure the write cycle executes correctly. When erasing data the ER bit must be set high immediately after the EREN bit has been set high, to ensure the erase cycle executes correctly. The global interrupt bit EMI should also be cleared before a write or erase cycle is executed and then set again after a valid write or erase activation procedure has completed. Note that the device should not enter the IDLE or SLEEP mode until the EEPROM read, erase or write operation is totally complete. Otherwise, the EEPROM read, erase or write operation will fail.

### Programming Examples

#### Reading a Data Byte from the EEPROM – Polling Method

```
MOV A, 040H           ; setup memory pointer low byte MP1L
MOV MP1L, A           ; MP1 points to EEC register
MOV A, 01H            ; setup memory pointer high byte MP1H
MOV MP1H, A
CLR IAR1.4            ; clear MODE bit, select byte operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L ; user defined low byte address
MOV EEAL, A
SET IAR1.1            ; set RDEN bit, enable read operations
SET IAR1.0            ; start Read Cycle - set RD bit
BACK:
```

```
SZ IAR1.0          ; check for read cycle end
JMP BACK
CLR IAR1           ; disable EEPROM read function
CLR MP1H
MOV A, EED         ; move read data to register
MOV READ_DATA, A
```

#### **Reading a Data Page from the EEPROM – Polling Method**

```
MOV A, 040H       ; setup memory pointer low byte MP1L
MOV MP1L, A       ; MP1 points to EEC register
MOV A, 01H        ; setup memory pointer high byte MP1H
MOV MP1H, A
SET IAR1.4        ; set MODE bit, select page operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L ; user defined low byte address
MOV EEAL, A
SET IAR1.1        ; set RDEN bit, enable read operations
; ~~~~ The data length can be up to 16 bytes (Start) ~~~~
CALL READ
CALL READ
:
:
JMP PAGE_READ_FINISH
; ~~~~ The data length can be up to 16 bytes (End) ~~~~
READ:
SET IAR1.0        ; start Read Cycle - set RD bit
BACK:
SZ IAR1.0         ; check for read cycle end
JMP BACK
MOV A, EED        ; move read data to register
MOV READ_DATA, A
RET
:
PAGE_READ_FINISH:
CLR IAR1          ; disable EEPROM read function
CLR MP1H
```

#### **Erasing a Data Page to the EEPROM – Polling Method**

```
MOV A, 040H       ; setup memory pointer low byte MP1L
MOV MP1L, A       ; MP1 points to EEC register
MOV A, 01H        ; setup memory pointer high byte MP1H
MOV MP1H, A
SET IAR1.4        ; set MODE bit, select page operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L ; user defined low byte address
MOV EEAL, A
; ~~~~ The data length can be up to 16 bytes (Start) ~~~~
CALL WRITE_BUF
CALL WRITE_BUF
:
:
JMP Erase_START
; ~~~~ The data length can be up to 16 bytes (End) ~~~~
WRITE_BUF:
MOV A, EEPROM_DATA ; user defined data, erase mode don't care data value
MOV EED, A
```

```

RET
:
Erase_START:
CLR EMI
SET IAR1.6           ; set EREN bit, enable erase operations
SET IAR1.5           ; start Erase Cycle - set ER bit - executed immediately
                    ; after setting EREN bit

SET EMI
BACK:
SZ IAR1.5           ; check for erase cycle end
JMP BACK
CLR MP1H

```

**Writing a Data Byte to the EEPROM – Polling Method**

```

MOV A, 040H         ; setup memory pointer low byte MP1L
MOV MP1L, A         ; MP1 points to EEC register
MOV A, 01H          ; setup memory pointer high byte MP1H
MOV MP1H, A
CLR IAR1.4          ; clear MODE bit, select byte operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L ; user defined low byte address
MOV EEAL, A
MOV A, EEPROM_DATA  ; user defined data
MOV EED, A
CLR EMI
SET IAR1.3          ; set WREN bit, enable write operations
SET IAR1.2          ; start Write Cycle - set WR bit - executed immediately
                    ; after setting WREN bit

SET EMI
BACK:
SZ IAR1.2          ; check for write cycle end
JMP BACK
CLR MP1H

```

**Writing a Data Page to the EEPROM – Polling Method**

```

MOV A, 040H         ; setup memory pointer low byte MP1L
MOV MP1L, A         ; MP1 points to EEC register
MOV A, 01H          ; setup memory pointer high byte MP1H
MOV MP1H, A
SET IAR1.4          ; set MODE bit, select page operation mode
MOV A, EEPROM_ADRES_H ; user defined high byte address
MOV EEAH, A
MOV A, EEPROM_ADRES_L ; user defined low byte address
MOV EEAL, A
; ~~~~ The data length can be up to 16 bytes (Start) ~~~~
CALL WRITE_BUF
CALL WRITE_BUF
:
:
JMP WRITE_START
; ~~~~ The data length can be up to 16 bytes (End) ~~~~
WRITE_BUF:
MOV A, EEPROM_DATA  ; user defined data
MOV EED, A
RET
:

```

```
WRITE_START:
CLR EMI
SET IAR1.3          ; set WREN bit, enable write operations
SET IAR1.2          ; start Write Cycle - set WR bit - executed immediately
                   ; after setting WREN bit

SET EMI
BACK:
SZ IAR1.2           ; check for write cycle end
JMP BACK
CLR MPIH
```

## Oscillators

Various oscillator types offer the user a wide range of functions according to their various application requirements. The flexible features of the oscillator functions ensure that the best optimisation can be achieved in terms of speed and power saving. Oscillator selections and operation are selected through a combination of configuration options and relevant control registers.

### Oscillator Overview

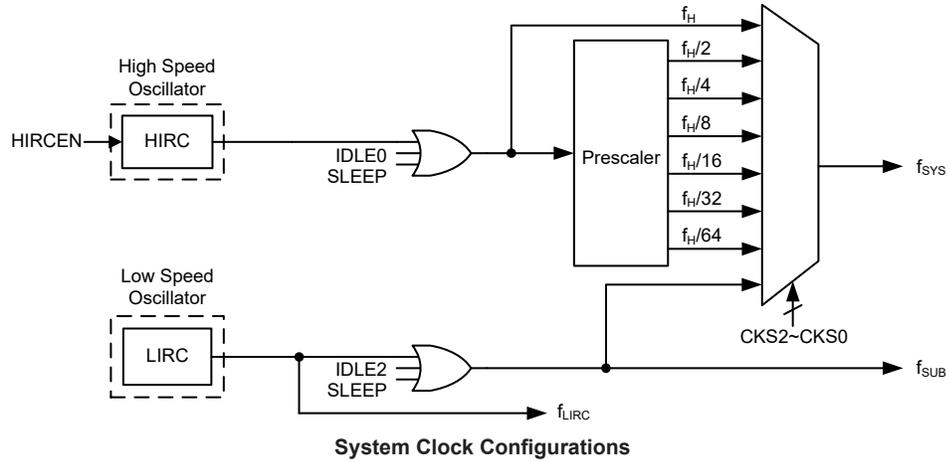
In addition to being the source of the main system clock the oscillators also provide clock sources for the Watchdog Timer and Time Base Interrupts. Two fully integrated internal oscillators, requiring no external components, are provided to form a wide range of both fast and slow system oscillators. The higher frequency oscillator provides higher performance but carry with it the disadvantage of higher power requirements, while the opposite is of course true for the lower frequency oscillator. With the capability of dynamically switching between fast and slow system clock, the device has the flexibility to optimize the performance/power ratio, a feature especially important in power sensitive portable applications.

Type	Name	Frequency
Internal High Speed RC	HIRC	8/12/16MHz
Internal Low Speed RC	LIRC	32kHz

**Oscillator Types**

### System Clock Configurations

There are two oscillator sources, one high speed oscillator and one low speed oscillator. The high speed system clocks is sourced from the internal 8/12/16MHz RC oscillator, HIRC. The low speed oscillator is the internal 32kHz RC oscillator, LIRC. Selecting whether the low or high speed oscillator is used as the system oscillator is implemented using the CKS2~CKS0 bits in the SCC register and as the system clock can be dynamically selected.



### Internal High Speed RC Oscillator – HIRC

The internal RC oscillator is a fully integrated system oscillator requiring no external components. The internal RC oscillator has three fixed frequencies of 8MHz, 12MHz and 16MHz, which are selected using a configuration option. The HIRC1~HIRC0 bits in the HIRCC register must also be setup to match the selected configuration option frequency. Setting up these bits is necessary to ensure that the HIRC frequency accuracy specified in the A.C. Characteristics is achieved. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

### Internal 32kHz Oscillator – LIRC

The Internal 32kHz System Oscillator is a fully integrated RC oscillator with a typical frequency of 32kHz, requiring no external components for its implementation. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

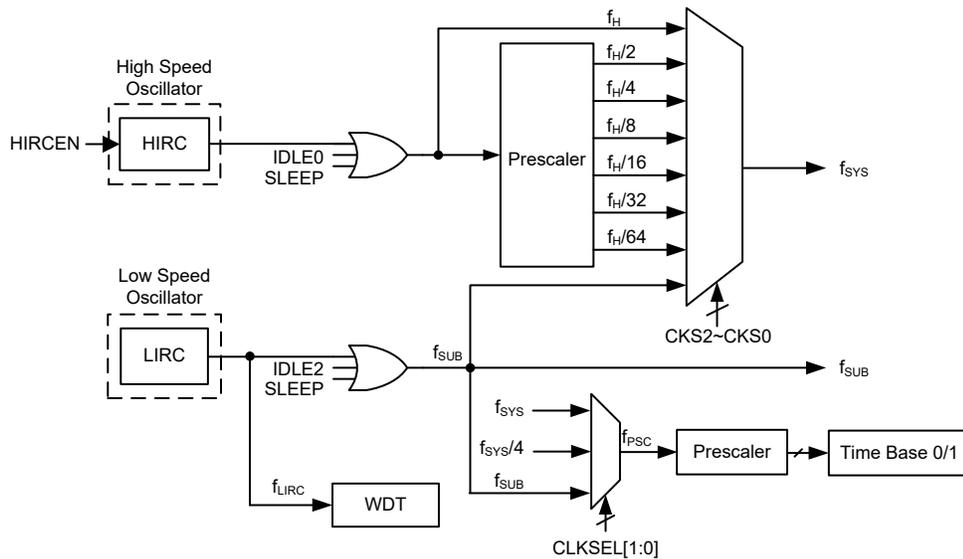
## Operating Modes and System Clocks

Present day applications require that their microcontrollers have high performance but often still demand that they consume as little power as possible, conflicting requirements that are especially true in battery powered portable applications. The fast clocks required for high performance will by their nature increase current consumption and of course vice-versa lower speed clocks reduce current consumption. As Holtek has provided the device with both high and low speed clock sources and the means to switch between them dynamically, the user can optimise the operation of their microcontroller to achieve the best performance/power ratio.

### System Clocks

The device has different clock sources for both the CPU and peripheral function operation. By providing the user with a wide range of clock options using register programming, a clock system can be configured to obtain maximum application performance.

The main system clock, can come from a high frequency,  $f_H$ , or low frequency,  $f_{SUB}$ , source, and is selected using the CKS2~CKS0 bits in the SCC register. The high speed system clock is sourced from the HIRC oscillator. The low speed system clock is sourced from the LIRC oscillator. The other choice, which is a divided version of the high speed system oscillator has a range of  $f_H/2 \sim f_H/64$ .



**Device Clock Configurations**

Note: When the system clock source  $f_{SYS}$  is switched to  $f_{SUB}$  from  $f_H$ , the high speed oscillation will stop to conserve the power. Thus there is no  $f_H \sim f_H/64$  for peripheral circuit to use, which is determined by configuring the corresponding high speed oscillator enable control bit.

### System Operation Modes

There are six different modes of operation for the microcontroller, each one with its own special characteristics and which can be chosen according to the specific performance and power requirements of the application. There are two modes allowing normal operation of the microcontroller, the FAST Mode and SLOW Mode. The remaining four modes, the SLEEP, IDLE0, IDLE1 and IDLE2 Mode are used when the microcontroller CPU is switched off to conserve power.

Operation Mode	CPU	Register Setting			f <sub>sys</sub>	f <sub>H</sub>	f <sub>sub</sub>	f <sub>LIRC</sub>
		FHIDEN	FSIDEN	CKS2~CKS0				
FAST	On	x	x	000~110	f <sub>H</sub> ~f <sub>H</sub> /64	On	On	On
SLOW	On	x	x	111	f <sub>sub</sub>	On/Off <sup>(1)</sup>	On	On
IDLE0	Off	0	1	000~110	Off	Off	On	On
				111	On			
IDLE1	Off	1	1	xxx	On	On	On	On
IDLE2	Off	1	0	000~110	On	On	Off	On
				111	Off			
SLEEP	Off	0	0	xxx	Off	Off	Off	On <sup>(2)</sup>

"x": Don't care

Note: 1. The f<sub>H</sub> clock will be switched on or off by configuring the corresponding oscillator enable bit in the SLOW mode.

2. The f<sub>LIRC</sub> can be on since the WDT function is always enabled even in the SLEEP mode.

### FAST Mode

This is one of the main operating modes where the microcontroller has all of its functions operational and where the system clock is provided by the internal high speed oscillator. This mode operates allowing the microcontroller to operate normally with a clock source coming from the HIRC oscillator. The high speed oscillator will however first be divided by a ratio ranging from 1 to 64, the actual ratio being selected by the CKS2~CKS0 bits in the SCC register. Although a high speed oscillator is used, running the microcontroller at a divided clock ratio reduces the operating current.

### SLOW Mode

This is also a mode where the microcontroller operates normally although now with a slower speed clock source. The clock source used will be from f<sub>sub</sub>. The f<sub>sub</sub> clock is derived from the LIRC oscillator.

### SLEEP Mode

The SLEEP Mode is entered when a HALT instruction is executed and when the FHIDEN and FSIDEN bit are low. In the SLEEP mode the CPU will be stopped. The f<sub>sub</sub> clock provided to the peripheral function will also be stopped, too. However the f<sub>LIRC</sub> clock can still continue to operate if the WDT function is always enabled.

### IDLE0 Mode

The IDLE0 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is low and the FSIDEN bit in the SCC register is high. In the IDLE0 Mode the CPU will be switched off but the low speed oscillator will be turned on to drive some peripheral functions.

### IDLE1 Mode

The IDLE1 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is high. In the IDLE1 Mode the CPU will be switched off but both the high and low speed oscillators will be turned on to provide a clock source to keep some peripheral functions operational.

### IDLE2 Mode

The IDLE2 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is low. In the IDLE2 Mode the CPU

will be switched off but the high speed oscillator will be turned on to provide a clock source to keep some peripheral functions operational.

### Control Registers

The registers, SCC and HIRCC, are used to control the system clock and the corresponding oscillator configurations.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SCC	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
HIRCC	—	—	—	—	HIRC1	HIRC0	HIRCF	HIRCEN

**System Operating Mode Control Register List**

#### • SCC Register

Bit	7	6	5	4	3	2	1	0
Name	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
R/W	R/W	R/W	R/W	—	—	—	R/W	R/W
POR	0	0	0	—	—	—	0	0

Bit 7~5 **CKS2~CKS0**: System clock selection

- 000:  $f_H$
- 001:  $f_H/2$
- 010:  $f_H/4$
- 011:  $f_H/8$
- 100:  $f_H/16$
- 101:  $f_H/32$
- 110:  $f_H/64$
- 111:  $f_{SUB}$

These three bits are used to select which clock is used as the system clock source. In addition to the system clock source directly derived from  $f_H$  or  $f_{SUB}$ , a divided version of the high speed system oscillator can also be chosen as the system clock source.

Bit 4~2 Unimplemented, read as “0”

Bit 1 **FHIDEN**: High frequency oscillator control when CPU is switched off

- 0: Disable
- 1: Enable

This bit is used to control whether the high speed oscillator is activated or stopped when the CPU is switched off by executing a “HALT” instruction.

Bit 0 **FSIDEN**: Low frequency oscillator control when CPU is switched off

- 0: Disable
- 1: Enable

This bit is used to control whether the low speed oscillator is activated or stopped when the CPU is switched off by executing a “HALT” instruction.

Note: A certain delay is required before the relevant clock is successfully switched to the target clock source after any clock switching setup using the CKS2~CKS0 bits. A proper delay time must be arranged before executing the following operations which require immediate reaction with the target clock source.

Clock switching delay time= $4 \times t_{SYS} + [0 \sim (1.5 \times t_{curr.} + 0.5 \times t_{Tar.})]$ , Where  $t_{curr.}$  indicates the current clock period,  $t_{Tar.}$  indicates the target clock period and the  $t_{SYS}$  indicates the current system clock period.

• **HIRCC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	HIRC1	HIRC0	HIRCF	HIRCEN
R/W	—	—	—	—	R/W	R/W	R	R/W
POR	—	—	—	—	0	0	0	1

Bit 7~4 Unimplemented, read as “0”

Bit 3~2 **HIRC1~HIRC0**: HIRC frequency selection

00: 8MHz

01: 12MHz

10: 16MHz

11: 8MHz

When the HIRC oscillator is enabled or the HIRC frequency selection is changed by the application program, the clock frequency will automatically be changed after the HIRCF flag is set to 1. It is recommended that the HIRC frequency selected by these bits is the same as the frequency determined by the configuration option to keep the HIRC frequency accuracy specified in the A.C. characteristics.

Bit 1 **HIRCF**: HIRC oscillator stable flag

0: HIRC unstable

1: HIRC stable

This bit is used to indicate whether the HIRC oscillator is stable or not. When the HIRCEN bit is set to 1 to enable the HIRC oscillator or the HIRC frequency selection is changed by the application program, the HIRCF bit will first be cleared to 0 and then set to 1 after the HIRC oscillator is stable.

Bit 0 **HIRCEN**: HIRC oscillator enable control

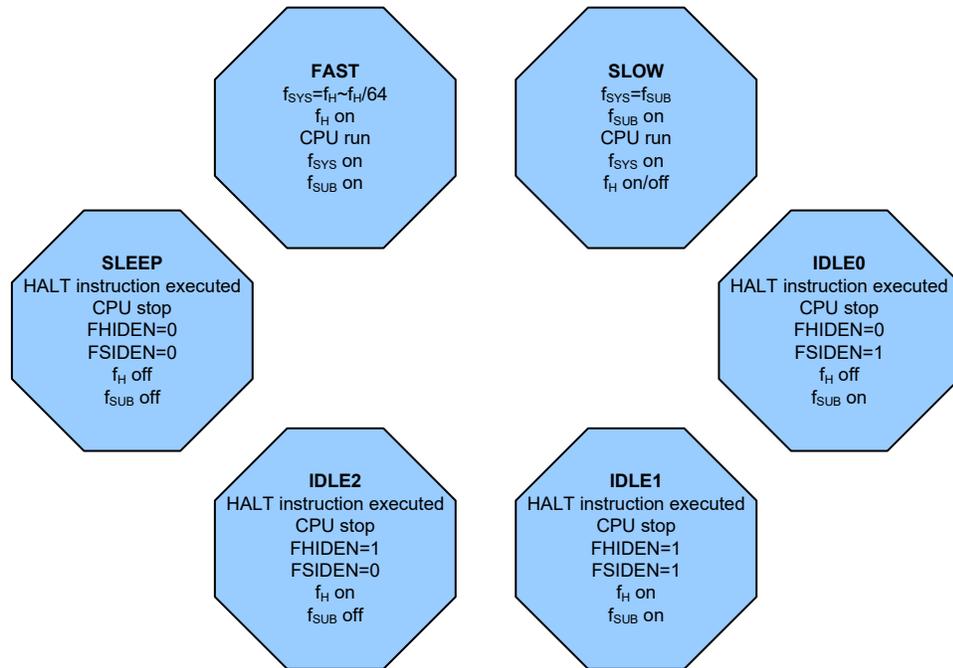
0: Disable

1: Enable

## Operating Mode Switching

The device can switch between operating modes dynamically allowing the user to select the best performance/power ratio for the present task in hand. In this way microcontroller operations that do not require high performance can be executed using slower clocks thus requiring less operating current and prolonging battery life in portable applications.

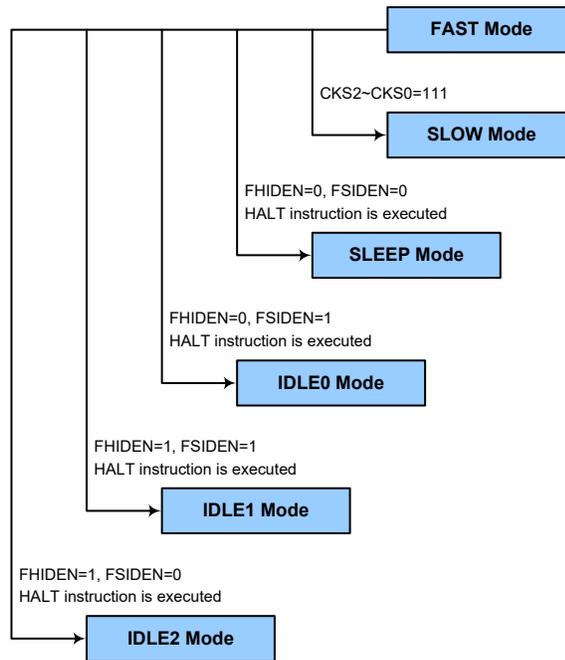
In simple terms, Mode Switching between the FAST Mode and SLOW Mode is executed using the CKS2~CKS0 bits in the SCC register while Mode Switching from the FAST/SLOW Mode to the SLEEP/IDLE Mode is executed via the HALT instruction. When a HALT instruction is executed, whether the device enter the IDLE Mode or the SLEEP Mode is determined by the condition of the FHIDEN and FSIDEN bits in the SCC register.



**FAST Mode to SLOW Mode Switching**

When running in the FAST Mode, which uses the high speed system oscillator, and therefore consumes more power, the system clock can switch to run in the SLOW Mode by set the CKS2~CKS0 bits to “111” in the SCC register. This will then use the low speed system oscillator which will consume less power. Users may decide to do this for certain operations which do not require high performance and can subsequently reduce power consumption.

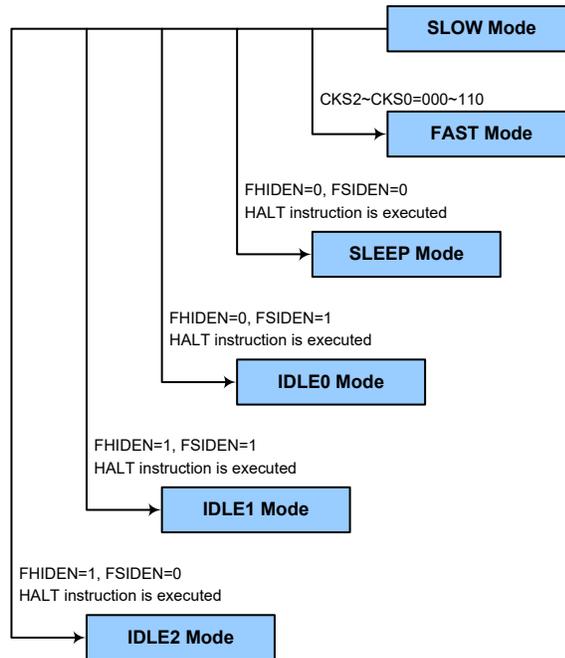
The SLOW Mode is sourced from the LIRC oscillator and therefore requires this oscillator to be stable before full mode switching occurs.



### SLOW Mode to FAST Mode Switching

In SLOW mode the system clock is derived from  $f_{SUB}$ . When system clock is switched back to the FAST mode from  $f_{SUB}$ , the CKS2~CKS0 bits should be set to “000”~“110” and then the system clock will respectively be switched to  $f_H \sim f_H/64$ .

However, if  $f_H$  is not used in SLOW mode and thus switched off, it will take some time to re-oscillate and stabilise when switching to the FAST mode from the SLOW Mode. This is monitored using the HIRCF bit in the HIRCC register. The time duration required for the high speed system oscillator stabilization is specified in the System Start Up Time Characteristics.



### Entering the SLEEP Mode

There is only one way for the device to enter the SLEEP Mode and that is to execute the “HALT” instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to “0”. In this mode all the clocks and functions will be switched off except the WDT function. When this instruction is executed under the conditions described above, the following will occur:

- The system clock will be stopped and the application program will stop at the “HALT” instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

### Entering the IDLE0 Mode

There is only one way for the device to enter the IDLE0 Mode and that is to execute the “HALT” instruction in the application program with the FHIDEN bit in the SCC register equal to “0” and the FSIDEN bit in the SCC register equal to “1”. When this instruction is executed under the conditions described above, the following will occur:

- The  $f_{\text{H}}$  clock will be stopped and the application program will stop at the “HALT” instruction, but the  $f_{\text{SUB}}$  clock will be on.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

### **Entering the IDLE1 Mode**

There is only one way for the device to enter the IDLE1 Mode and that is to execute the “HALT” instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to “1”. When this instruction is executed under the conditions described above, the following will occur:

- The  $f_{\text{H}}$  and  $f_{\text{SUB}}$  clocks will be on but the application program will stop at the “HALT” instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

### **Entering the IDLE2 Mode**

There is only one way for the device to enter the IDLE2 Mode and that is to execute the “HALT” instruction in the application program with the FHIDEN bit in the SCC register equal to “1” and the FSIDEN bit in the SCC register equal to “0”. When this instruction is executed under the conditions described above, the following will occur:

- The  $f_{\text{H}}$  clock will be on but the  $f_{\text{SUB}}$  clock will be off and the application program will stop at the “HALT” instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag, PDF, will be set and the Watchdog time-out flag, TO, will be cleared.
- The WDT will be cleared and resume counting as the WDT function is always enabled.

### **Standby Current Considerations**

As the main reason for entering the SLEEP or IDLE Mode is to keep the current consumption of the device to as low a value as possible, perhaps only in the order of several micro-amps in the SLEEP and IDLE0 modes, there are other considerations which must also be taken into account by the circuit designer if the power consumption is to be minimised. Special attention must be made to the I/O pins on the device. All high-impedance input pins must be connected to either a fixed high or low level as any floating input pins could create internal oscillations and result in increased current consumption. This also applies to the device which has different package types, as there may be unbonded pins. These must either be setup as outputs or if setup as inputs must have pull-high resistors connected.

Care must also be taken with the loads, which are connected to I/O pins, which are setup as outputs. These should be placed in a condition in which minimum current is drawn or connected only to external circuits that do not draw current, such as other CMOS inputs.

In the IDLE1 and IDLE2 modes the high speed oscillator is on, if the peripheral function clock source is derived from the high speed oscillator, the additional standby current will also be perhaps in the order of several hundred micro-amps.

### Wake-up

To minimise power consumption the device can enter the SLEEP or any IDLE Mode, where the CPU will be switched off. However, when the device is woken up again, it will take a considerable time for the original system oscillator to restart, stabilise and allow normal operation to resume.

After the system enters the SLEEP or IDLE Mode, it can be woken up from one of various sources listed as follows:

- An external falling edge on Port A
- A system interrupt
- A WDT overflow

When the device executes the “HALT” instruction, the PDF flag will be set high. The PDF flag will be cleared to 0 if the device experiences a system power-up or executes the clear Watchdog Timer instruction. If the system is woken up by a WDT overflow, a Watchdog Timer reset will be initiated and the TO flag will be set high. The TO flag is set if a WDT time-out occurs and causes a wake-up that only resets the Program Counter and Stack Pointer, other flags remain in their original status.

Each pin on Port A can be set using the PAWU register to permit a negative transition on the pin to wake-up the system. When a pin wake-up occurs, the program will resume execution at the instruction following the “HALT” instruction. If the system is woken up by an interrupt, then two possible situations may occur. The first is where the related interrupt is disabled or the interrupt is enabled but the stack is full, in which case the program will resume execution at the instruction following the “HALT” instruction. In this situation, the interrupt which woke-up the device will not be immediately serviced, but will rather be serviced later when the related interrupt is finally enabled or when a stack level becomes free. The other situation is where the related interrupt is enabled and the stack is not full, in which case the regular interrupt response takes place. If an interrupt request flag is set high before entering the SLEEP or IDLE Mode, the wake-up function of the related interrupt will be disabled.

### Watchdog Timer

The Watchdog Timer is provided to prevent program malfunctions or sequences from jumping to unknown locations, due to certain uncontrollable external events such as electrical noise.

#### Watchdog Timer Clock Source

The Watchdog Timer clock source is provided by the internal  $f_{LIRC}$  clock which is in turn supplied by the LIRC oscillator. The LIRC internal oscillator has an approximate frequency of 32kHz and this specified internal clock period can vary with  $V_{DD}$ , temperature and process variations. The Watchdog Timer source clock is then subdivided by a ratio of  $2^8$  to  $2^{18}$  to give longer time-outs, the actual value being chosen using the WS2~WS0 bits in the WDTC register.

### Watchdog Timer Control Register

A single register, WDTC, controls the required timeout period as well as the enable and reset operations.

#### • WDTC Register

Bit	7	6	5	4	3	2	1	0
Name	WE4	WE3	WE2	WE1	WE0	WS2	WS1	WS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	0	1	1

Bit 7~3 **WE4~WE0**: WDT function control  
 01010/10101: Enable  
 Other values: Reset MCU

When these bits are changed to any other values due to environmental noise the microcontroller will be reset; this reset operation will be activated after a delay time,  $t_{SRESET}$ , and the WRF bit in the RSTFC register will be set high.

Bit 2~0 **WS2~WS0**: WDT time-out period selection

- 000:  $2^8/f_{LIRC}$
- 001:  $2^{10}/f_{LIRC}$
- 010:  $2^{12}/f_{LIRC}$
- 011:  $2^{14}/f_{LIRC}$
- 100:  $2^{15}/f_{LIRC}$
- 101:  $2^{16}/f_{LIRC}$
- 110:  $2^{17}/f_{LIRC}$
- 111:  $2^{18}/f_{LIRC}$

These three bits determine the division ratio of the watchdog timer source clock, which in turn determines the time-out period.

#### • RSTFC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

“x”: Unknown

Bit 7~3 Unimplemented, read as “0”

Bit 2 **LVRF**: LVR function reset flag  
 Refer to the Low Voltage Reset section.

Bit 1 **LRF**: LVR control register software reset flag  
 Refer to the Low Voltage Reset section.

Bit 0 **WRF**: WDT Control register software reset flag  
 0: Not occur  
 1: Occurred

This bit is set high by the WDT Control register software reset and cleared by the application program. Note that this bit can only be cleared to zero by the application program.

### Watchdog Timer Operation

The Watchdog Timer operates by providing a device reset when its timer overflows. This means that in the application program and during normal operation the user has to strategically clear the Watchdog Timer before it overflows to prevent the Watchdog Timer from executing a reset. This is done using the clear watchdog instruction. If the program malfunctions for whatever reason, jumps to an unknown location, or enters an endless loop, the clear instruction will not be executed in the correct manner, in which case the Watchdog Timer will overflow and reset the device. There are five bits, WE4~WE0, in the WDTC register to offer the Watchdog Timer enable control and the MCU reset. The WDT function will be enabled if the WE4~WE0 bits are set to a value of 01010B or 10101B. If the WE4~WE0 bits are set to any other values, other than 01010B and 10101B, it will reset the device after a delay time,  $t_{\text{RESET}}$ . After power on these bits will have a value of 01010B.

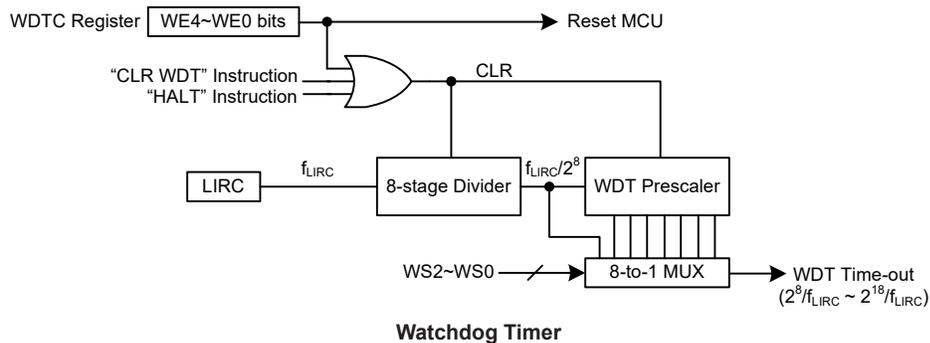
WE4~WE0 Bits	WDT Function
01010B or 10101B	Enable
Any other value	Reset MCU

#### Watchdog Timer Enable/Reset Control

Under normal program operation, a Watchdog Timer time-out will initialise a device reset and set the status bit TO. However, if the system is in the SLEEP or IDLE Mode, when a Watchdog Timer time-out occurs, the TO bit in the status register will be set and only the Program Counter and Stack Pointer will be reset. Three methods can be adopted to clear the contents of the Watchdog Timer. The first is a WDTC software reset, which means a certain value except 01010B and 10101B written into the WE4~WE0 bit filed, the second is using the Watchdog Timer software clear instruction and the third is via a HALT instruction.

There is only one method of using software instruction to clear the Watchdog Timer. That is to use the single “CLR WDT” instruction to clear the WDT.

The maximum time out period is when the  $2^{18}$  division ratio is selected. As an example, with a 32kHz LIRC oscillator as its source clock, this will give a maximum watchdog period of around 8 seconds for the  $2^{18}$  division ratio, and a minimum timeout of 8ms for the  $2^8$  division ratio.



## Reset and Initialisation

A reset function is a fundamental part of any microcontroller ensuring that the device can be set to some predetermined condition irrespective of outside parameters. The most important reset condition is after power is first applied to the microcontroller. In this case, internal circuitry will ensure that the microcontroller, after a short delay, will be in a well-defined state and ready to execute the first program instruction. After this power-on reset, certain important internal registers will be set to defined states before the program commences. One of these registers is the Program Counter, which will be reset to zero forcing the microcontroller to begin program execution from the lowest Program Memory address.

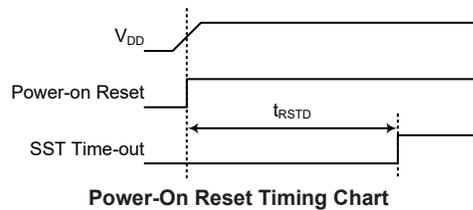
Another reset exists in the form of a Low Voltage Reset, LVR, where a full reset, is implemented in situations where the power supply voltage falls below a certain threshold. Another type of reset is when the Watchdog Timer overflows and resets the microcontroller. All types of reset operations result in different register conditions being setup.

### Reset Functions

There are several ways in which a microcontroller reset can occur, through events occurring internally.

#### Power-on Reset

The most fundamental and unavoidable reset is the one that occurs after power is first applied to the microcontroller. As well as ensuring that the Program Memory begins execution from the first memory address, a power-on reset also ensures that certain other registers are preset to known conditions. All the I/O port and port control registers will power up in a high condition ensuring that all pins will be first set to inputs.



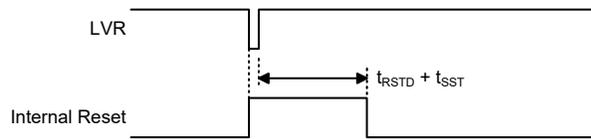
**Power-On Reset Timing Chart**

#### Low Voltage Reset – LVR

The microcontroller contains a low voltage reset circuit in order to monitor the supply voltage of the device and provides an MCU reset should the value fall below a certain predefined level.

The LVR function is always enabled in FAST and SLOW Mode with a specific LVR voltage  $V_{LVR}$ . If the supply voltage of the device drops to within a range of  $0.9V \sim V_{LVR}$  such as might occur when changing the battery, the LVR will automatically reset the device internally and the LVRF bit in the RSTFC register will also be set high. For a valid LVR signal, a low voltage, i.e., a voltage in the range between  $0.9V \sim V_{LVR}$  must exist for greater than the value  $t_{LVR}$  specified in the LVD/LVR Electrical Characteristics. If the low voltage state does not exceed this value, the LVR will ignore the low supply voltage and will not perform a reset function. The actual  $t_{LVR}$  value can be selected by the TLVR1~TLVR0 bits in the TLVRC register.

The actual  $V_{LVR}$  value can be selected by the LVS7~LVS0 bits in the LVRC register. If the LVS7~LVS0 bits are changed to some different values by environmental noise, the LVR will reset the device after a delay time,  $t_{SRESET}$ . When this happens, the LRF bit in the RSTFC register will be set high. After power on the register will have the value of 01100110B. Note that the LVR function will be automatically disabled when the device enters the IDLE or SLEEP mode.



**Low Voltage Reset Timing Chart**

• **Low Voltage Reset Registers**

The LVRC and TLVRC registers are used to control the Low Voltage Reset function.

Register Name	Bit							
	7	6	5	4	3	2	1	0
LVRC	LVS7	LVS6	LVS5	LVS4	LVS3	LVS2	LVS1	LVS0
TLVRC	—	—	—	—	—	—	TLVR1	TLVR0

**Low Voltage Reset Register List**

• **LVRC Register**

Bit	7	6	5	4	3	2	1	0
Name	LVS7	LVS6	LVS5	LVS4	LVS3	LVS2	LVS1	LVS0
R/W								
POR	0	1	1	0	0	1	1	0

Bit 7~0 **LVS7~LVS0**: LVR voltage select

01100110: 1.7V

01010101: 1.9V

00110011: 2.55V

10011001: 3.15V

10101010: 3.8V

Other values: Generates a MCU reset – register is reset to POR value

When an actual low voltage condition occurs, as specified by one of the defined LVR voltage values above, an MCU reset will be generated. The reset operation will be activated after the low voltage condition keeps more than a  $t_{LVR}$  time. The actual  $t_{LVR}$  value can be selected by the TLVR1~TLVR0 bits in the TLVRC register. In this situation the register contents will remain the same after such a reset occurs.

Any register value, other than the defined LVR values above, will also result in the generation of an MCU reset. The reset operation will be activated after a delay time,  $t_{SRESET}$ . However in this situation the register contents will be reset to the POR value.

• **TLVRC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	TLVR1	TLVR0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	1

Bit 7~2 Unimplemented, read as “0”

Bit 1~0 **TLVR1~TLVR0**: Minimum low voltage width to reset time,  $t_{LVR}$ , selection

00:  $(7\sim8) \times t_{LIRC}$

01:  $(31\sim32) \times t_{LIRC}$

10:  $(63\sim64) \times t_{LIRC}$

11:  $(127\sim128) \times t_{LIRC}$

• **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

“x”: Unknown

Bit 7~3 Unimplemented, read as “0”

Bit 2 **LVRF**: LVR function reset flag  
 0: Not occur  
 1: Occurred

This bit is set high when a specific Low Voltage Reset situation occurs. This bit can only be cleared to zero by the application program.

Bit 1 **LRF**: LVR control register software reset flag  
 0: Not occur  
 1: Occurred

This bit is set high if the LVRC register contains any non-defined LVR voltage register values. This in effect acts like a software-reset function. This bit can only be cleared to zero by the application program.

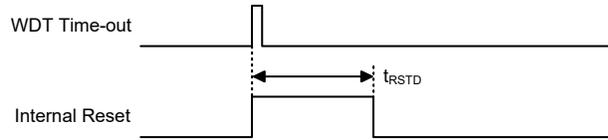
Bit 0 **WRF**: WDT control register software reset flag  
 Refer to the “Watchdog Timer Control Register” section

**In Application Programming Reset**

When a specific value of “55H” is written into the FC1 register, a reset signal will be generated to reset the whole device. Refer to the IAP section for more associated details.

**Watchdog Time-out Reset during Normal Operation**

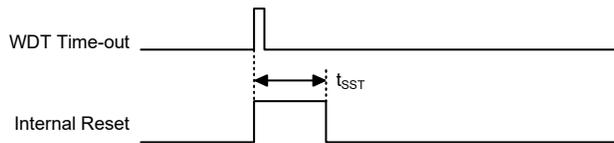
When a Watchdog time-out Reset occurs during normal operation in the FAST or SLOW mode, the Watchdog time-out flag TO will be set to “1”.



**WDT Time-out Reset during Normal Operation Timing Chart**

**Watchdog Time-out Reset during SLEEP or IDLE Mode**

The Watchdog time-out Reset during SLEEP or IDLE Mode is a little different from other kinds of reset. Most of the conditions remain unchanged except that the Program Counter and the Stack Pointer will be cleared to “0” and the TO and PDF flags will be set to “1”. Refer to the System Start Up Time Characteristics for  $t_{SST}$  details.



**WDT Time-out Reset during SLEEP or IDLE Mode Timing Chart**

### Reset Initial Conditions

The different types of reset described affect the reset flags in different ways. These flags, known as PDF and TO are located in the status register and are controlled by various microcontroller operations, such as the SLEEP or IDLE Mode function or Watchdog Timer. The reset flags are shown in the table:

TO	PDF	Reset Conditions
0	0	Power-on reset
u	u	LVR reset during FAST or SLOW Mode operation
1	u	WDT time-out reset during FAST or SLOW Mode operation
1	1	WDT time-out reset during IDLE or SLEEP Mode operation

“u” stands for unchanged

The following table indicates the way in which the various components of the microcontroller are affected after a power-on reset occurs.

Item	Condition after Reset
Program Counter	Reset to zero
Interrupts	All interrupts will be disabled
WDT, Time Bases	Clear after reset, WDT begins counting
Timer Modules	All Timer Modules will be turned off
Input/Output Ports	I/O ports will be setup as inputs
Stack Pointer	Stack Pointer will point to the top of the stack

The different kinds of resets all affect the internal registers of the microcontroller in different ways. To ensure reliable continuation of normal program execution after a reset occurs, it is important to know what condition the microcontroller is in after a particular reset occurs. The following table describes how each type of reset affects the microcontroller internal registers.

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
IAR0	0000 0000	0000 0000	uuuu uuuu
MP0	0000 0000	0000 0000	uuuu uuuu
IAR1	0000 0000	0000 0000	uuuu uuuu
MP1L	0000 0000	0000 0000	uuuu uuuu
MP1H	0000 0000	0000 0000	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBHP	---- xxxx	---- uuuu	---- uuuu
STATUS	xx00 xxxx	uu1u uuuu	uu11 uuuu
IAR2	0000 0000	0000 0000	uuuu uuuu
MP2L	0000 0000	0000 0000	uuuu uuuu
MP2H	0000 0000	0000 0000	uuuu uuuu
RSTFC	---- -x00	---- -uuu	---- -uuu
INTC0	-000 0000	-000 0000	-uuu uuuu
INTC1	0000 0000	0000 0000	uuuu uuuu
INTC2	0000 0000	0000 0000	uuuu uuuu
LVRC	0110 0110	0110 0110	uuuu uuuu
PA	1--1 1111	1--1 1111	u--u uuuu
PAC	1--1 1111	1--1 1111	u--u uuuu
PAPU	0--0 0000	0--0 0000	u--u uuuu

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
PAWU	0--0 0000	0--0 0000	u--u uuuu
MFIO	--00 --00	--00 --00	--uu --uu
MF11	--00 --00	--00 --00	--uu --uu
WDTC	0101 0011	0101 0011	uuuu uuuu
TB0C	0--- -000	0--- -000	u--- -uuu
PSC0R	---- --00	---- --00	---- --uu
TB1C	0--- -000	0--- -000	u--- -uuu
PSC1R	---- --00	---- --00	---- --uu
LVPUC	---- ---0	---- ---0	---- ---u
PB	1111 1111	1111 1111	uuuu uuuu
PBC	1111 1111	1111 1111	uuuu uuuu
PBPU	0000 0000	0000 0000	uuuu uuuu
SIMC0	111- 0000	111- 0000	uuu- uuuu
SIMC1	1000 0001	1000 0001	uuuu uuuu
SIMD	xxxx xxxx	xxxx xxxx	uuuu uuuu
SIMA	0000 0000	0000 0000	uuuu uuuu
SIMTOC	0000 0000	0000 0000	uuuu uuuu
CTMC0	0000 0000	0000 0000	uuuu uuuu
CTMC1	0000 0000	0000 0000	uuuu uuuu
CTMDL	0000 0000	0000 0000	uuuu uuuu
CTMDH	---- --00	---- --00	---- --uu
CTMAL	0000 0000	0000 0000	uuuu uuuu
CTMAH	---- --00	---- --00	---- --uu
SADC0	0000 0000	0000 0000	uuuu uuuu
SADC1	0000 -000	0000 -000	uuuu -uuu
SADC2	0--0 0000	0--0 0000	u--u uuuu
SADOH	xxxx xxxx	xxxx xxxx	uuuu uuuu (ADRF5=0)
			---- uuuu (ADRF5=1)
SADOL	xxxx ----	xxxx ----	uuuu ---- (ADRF5=0)
			uuuu uuuu (ADRF5=1)
SLEDC0	0000 0000	0000 0000	uuuu uuuu
SLEDC1	--00 0000	--00 0000	--uu uuuu
PD	1111 1111	1111 1111	uuuu uuuu
PDC	1111 1111	1111 1111	uuuu uuuu
PDPU	0000 0000	0000 0000	uuuu uuuu
PCC	---- 1111	---- 1111	---- uuuu
PTMC0	0000 0---	0000 0---	uuuu u---
PTMC1	0000 0000	0000 0000	uuuu uuuu
PTMDL	0000 0000	0000 0000	uuuu uuuu
PTMDH	---- --00	---- --00	---- --uu
PTMAL	0000 0000	0000 0000	uuuu uuuu
PTMAH	---- --00	---- --00	---- --uu
PTMRPL	0000 0000	0000 0000	uuuu uuuu
PTMRPH	---- --00	---- --00	---- --uu

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
TKTMR	0000 0000	0000 0000	uuuu uuuu
TKC0	-000 0000	-000 0000	-uuu uuuu
TKC1	---- --11	---- --11	---- --uu
TK16DL	0000 0000	0000 0000	uuuu uuuu
TK16DH	0000 0000	0000 0000	uuuu uuuu
TKM0C0	0000 0000	0000 0000	uuuu uuuu
TKM0C1	0-00 0000	0-00 0000	u-uu uuuu
TKM016DL	0000 0000	0000 0000	uuuu uuuu
TKM016DH	0000 0000	0000 0000	uuuu uuuu
TKM0ROL	0000 0000	0000 0000	uuuu uuuu
TKM0ROH	---- --00	---- --00	---- --uu
INTEG	---- --00	---- --00	---- --uu
PAS0	0000 0000	0000 0000	uuuu uuuu
PAS1	00-- --00	00-- --00	uu-- --uu
PBS0	0000 0000	0000 0000	uuuu uuuu
PDS0	0000 0000	0000 0000	uuuu uuuu
IFS	---0 0000	---0 0000	---u uuuu
EEAL	0000 0000	0000 0000	uuuu uuuu
EEAH	---- ---0	---- ---0	---- ---u
EED	0000 0000	0000 0000	uuuu uuuu
USR	0000 1011	0000 1011	uuuu uuuu
UCR1	0000 00x0	0000 00x0	uuuu uuuu
UCR2	0000 0000	0000 0000	uuuu uuuu
UCR3	---- ---0	---- ---0	---- ---u
BRDH	0000 0000	0000 0000	uuuu uuuu
BRDL	0000 0000	0000 0000	uuuu uuuu
UFCR	--00 0000	--00 0000	--uu uuuu
TXR_RXR	xxxx xxxx	xxxx xxxx	uuuu uuuu
RxCNT	---- -000	---- -000	---- -uuu
LVDC	--00 -000	--00 -000	--uu -uuu
TLVRC	---- --01	---- --01	---- --uu
SCC	000- --00	000- --00	uuu- --uu
HIRCC	---- 0001	---- 0001	---- uuuu
VBGRC	---- ---0	---- ---0	---- ---u
ORMC	0000 0000	0000 0000	0000 0000
PCRL	0000 0000	0000 0000	uuuu uuuu
PCRH	---- 0000	---- 0000	---- uuuu
STKPTR	---- -000	---- -000	---- -uuu
IECC	0000 0000	0000 0000	uuuu uuuu
CRCCR	---- ---0	---- ---0	---- ---u
CRCIN	0000 0000	0000 0000	uuuu uuuu
CRCDL	0000 0000	0000 0000	uuuu uuuu
CRCDH	0000 0000	0000 0000	uuuu uuuu
FC0	0000 0000	0000 0000	uuuu uuuu
FC1	0000 0000	0000 0000	uuuu uuuu
FC2	---- --00	---- --00	---- --uu
FARL	0000 0000	0000 0000	uuuu uuuu

Register	Power On Reset	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
FARH	0000 0000	0000 0000	uuuu uuuu
FD0L	0000 0000	0000 0000	uuuu uuuu
FD0H	0000 0000	0000 0000	uuuu uuuu
FD1L	0000 0000	0000 0000	uuuu uuuu
FD1H	0000 0000	0000 0000	uuuu uuuu
FD2L	0000 0000	0000 0000	uuuu uuuu
FD2H	0000 0000	0000 0000	uuuu uuuu
FD3L	0000 0000	0000 0000	uuuu uuuu
FD3H	0000 0000	0000 0000	uuuu uuuu
EEC	0000 0000	0000 0000	uuuu uuuu

Note: “u” stands for unchanged  
 “x” stands for unknown  
 “-” stands for unimplemented

## Input/Output Ports

Holtek microcontrollers offer considerable flexibility on their I/O ports. With the input or output designation of every pin fully under user program control, pull-high selections for all ports and wake-up selections on certain pins, the user is provided with an I/O structure to meet the needs of a wide range of application possibilities.

The device provides bidirectional input/output lines labeled with port names PA~PB and PD. These I/O ports are mapped to the RAM Data Memory with specific addresses as shown in the Special Purpose Data Memory Structure diagram. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, which means the inputs must be ready at the T2 rising edge of instruction “MOV A, [m]”, where “m” denotes the port address. For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PA	PA7	—	—	PA4	PA3	PA2	PA1	PA0
PAC	PAC7	—	—	PAC4	PAC3*	PAC2	PAC1	PAC0
PAPU	PAPU7	—	—	PAPU4	PAPU3**	PAPU2	PAPU1	PAPU0
PAWU	PAWU7	—	—	PAWU4	PAWU3**	PAWU2	PAWU1	PAWU0
PB	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
PBC	PBC7	PBC6	PBC5	PBC4	PBC3*	PBC2	PBC1	PBC0
PBPU	PBPU7	PBPU6	PBPU5	PBPU4	PBPU3**	PBPU2	PBPU1	PBPU0
PCC	—	—	—	—	PCC3*	PCC2*	PCC1*	PCC0*
PD	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
PDC	PDC7*	PDC6*	PDC5*	PDC4*	PDC3*	PDC2	PDC1	PDC0
PDPU	PDPU7**	PDPU6**	PDPU5**	PDPU4**	PDPU3**	PDPU2	PDPU1	PDPU0
LVPUC	—	—	—	—	—	—	—	LVPU

“—”: Unimplemented, read as “0”

### I/O Logic Function Register List

Note: The control bit with an asterisk \* should be cleared to 0 and the control bit with an asterisk \*\* should remain the POR value after power-on reset. This can set these unbonded and not internally used lines as outputs to prevent additional power consumption.

## Pull-high Resistors

Many product applications require pull-high resistors for their switch inputs usually requiring the use of an external resistor. To eliminate the need for these external resistors, all I/O pins, when configured as a digital input have the capability of being connected to an internal pull-high resistor. These pull-high resistors are selected using the PxPU and LVPUC registers, and are implemented using weak PMOS transistors. The PxPU register is used to determine whether the pull-high function is enabled or not while the LVPUC register is used to select the pull-high resistors value for low voltage power supply applications.

Note that the pull-high resistor can be controlled by the relevant pull-high control register only when the pin-shared functional pin is selected as a digital input or NMOS output. Otherwise, the pull-high resistors cannot be enabled.

### • PxPU Register

Bit	7	6	5	4	3	2	1	0
Name	PxPU7	PxPU6	PxPU5	PxPU4	PxPU3	PxPU2	PxPU1	PxPU0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

**PxPUn:** I/O Port x Pin pull-high function control

0: Disable  
1: Enable

The PxPUn bit is used to control the pin pull-high function. Here the “x” is the Port name which can be A, B or D. However, the actual available bits for each I/O Port may be different.

### • LVPUC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	LVPU
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as “0”

Bit 0 **LVPU:** Pull-high resistor selection for low voltage power supply

0: All pin pull-high resistors are 60kΩ @ 3V  
1: All pin pull-high resistors are 15kΩ @ 3V

This bit is used to select the pull-high resistor value for low voltage power supply applications. The LVPU bit is only available when the corresponding pin pull-high function is enabled by setting the relevant pull-high control bit high. This bit will have no effect when the pull-high function is disabled.

## Port A Wake-up

The HALT instruction forces the microcontroller into the SLEEP or IDLE Mode which preserves power, a feature that is important for battery and other low-power applications. Various methods exist to wake-up the microcontroller, one of which is to change the logic condition on one of the Port A pins from high to low. This function is especially suitable for applications that can be woken up via external switches. Each pin on Port A can be selected individually to have this wake-up feature using the PAWU register.

Note that the wake-up function can be controlled by the wake-up control registers only when the pin is selected as general purpose input and the MCU enters the IDLE or SLEEP mode.

• **PAWU Register**

Bit	7	6	5	4	3	2	1	0
Name	PAWU7	—	—	PAWU4	PAWU3	PAWU2	PAWU1	PAWU0
R/W	R/W	—	—	R/W	R/W	R/W	R/W	R/W
POR	0	—	—	0	0	0	0	0

Bit 7, 4, 2~0 **PAWU7, PAWU4, PAWU2~PAWU0**: PA7, PA4, PA2~PA0 pin Wake-up function control  
 0: Disable  
 1: Enable

Bit 3 **PAWU3**: This bit should remain unchanged after power-on reset

Bit 6~5 Unimplemented, read as “0”

**I/O Port Control Registers**

Each I/O port has its own control register, to control the input/output configuration. With this control register, each CMOS output or input can be reconfigured dynamically under software control. Each pin of the I/O ports is directly mapped to a bit in its associated port control register. For the I/O pin to function as an input, the corresponding bit of the control register must be written as a “1”. This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a “0”, the I/O pin will be setup as a CMOS output. If the pin is currently setup as an output, instructions can still be used to read the output register.

However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin when the IECM is set to “0”.

• **PxC Register**

Bit	7	6	5	4	3	2	1	0
Name	PxC7	PxC6	PxC5	PxC4	PxC3	PxC2	PxC1	PxC0
R/W								
POR	1	1	1	1	1	1	1	1

**PxCn**: I/O Port x Pin type selection

0: Output

1: Input

The PxCn bit is used to control the pin type selection. Here the “x” is the Port name which can be A, B or D. However, the actual available bits for each I/O Port may be different.

Note that for the PB4~PB7 lines, which are internally connected to the Linear Charger SDA, FN, SCL and STDBY respectively, the corresponding control bits should be properly configured depending on the function that each line is actually used for internal connection. Set the line as an output or an input with pull-high if necessary.

**I/O Port Source Current Selection**

These device supports different output source current driving capability for each I/O port. With the selection registers, SLEDC0~SLEDC1, specific I/O port can support four levels of the source current driving capability. Users should refer to the Input/Output Characteristics section to select the desired output source current for different applications.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SLEDC0	D7	D6	SLEDC05	SLEDC04	SLEDC03	SLEDC02	SLEDC01	SLEDC00
SLEDC1	—	—	D5	D4	SLEDC13	SLEDC12	D1	D0

**I/O Port Source Current Selection Register List**

• **SLEDC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	SLEDC05	SLEDC04	SLEDC03	SLEDC02	SLEDC01	SLEDC00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **D7~D6**: Reserved bits, should remain unchanged after power-on reset

Bit 5~4 **SLEDC05~SLEDC04**: PB2~PB0 source current selection

00: Source current=Level 0 (Min.)

01: Source current=Level 1

10: Source current=Level 2

11: Source current=Level 3 (Max.)

Bit 3~2 **SLEDC03~SLEDC02**: PA7 and PA4 source current selection

00: Source current=Level 0 (Min.)

01: Source current=Level 1

10: Source current=Level 2

11: Source current=Level 3 (Max.)

Bit 1~0 **SLEDC01~SLEDC00**: PA2~PA0 source current selection

00: Source current=Level 0 (Min.)

01: Source current=Level 1

10: Source current=Level 2

11: Source current=Level 3 (Max.)

• **SLEDC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	D5	D4	SLEDC13	SLEDC12	D1	D0
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

Bit 7~6 Unimplemented, read as “0”

Bit 5~4 **D5~D4**: Reserved bits, should remain unchanged after power-on reset

Bit 3~2 **SLEDC13~SLEDC12**: PD2~PD0 source current selection

00: Source current=Level 0 (Min.)

01: Source current=Level 1

10: Source current=Level 2

11: Source current=Level 3 (Max.)

Bit 1~0 **D1~D0**: Reserved bits, should remain unchanged after power-on reset

**Pin-shared Function**

The flexibility of the microcontroller range is greatly enhanced by the use of pins that have more than one function. Limited numbers of pins can force serious design constraints on designers but by supplying pins with multi-functions, many of these difficulties can be overcome. For these pins, the desired function of the multi-function I/O pins is selected by a series of registers via the application program control.

**Pin-shared Function Selection Registers**

The limited number of supplied pins in a package can impose restrictions on the amount of functions a certain device can contain. However by allowing the same pins to share several different functions and providing a means of function selection, a wide range of different functions can be incorporated into even relatively small package sizes. The device includes Port “x” Output Function Selection register “n”, labeled as PxSn, and Input Function Selection register, labeled as IFS, which can select the desired functions of the multi-function pin-shared pins.

The most important point to note is to make sure that the desired pin-shared function is properly selected and also deselected. For most pin-shared functions, to select the desired pin-shared function, the pin-shared function should first be correctly selected using the corresponding pin-shared control register. After that the corresponding peripheral functional setting should be configured and then the peripheral function can be enabled. However, a special point must be noted for some digital input pins, such as INT, PTPI etc, which share the same pin-shared control configuration with their corresponding general purpose I/O functions when setting the relevant pin-shared control bit fields. To select these pin functions, in addition to the necessary pin-shared control and peripheral functional setup aforementioned, they must also be setup as an input by setting the corresponding bit in the I/O port control register. To correctly deselect the pin-shared function, the peripheral function should first be disabled and then the corresponding pin-shared function control register can be modified to select other pin-shared functions.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PAS0	D7	D6	PAS05	PAS04	PAS03	PAS02	PAS01	PAS00
PAS1	PAS17	PAS16	PAS15	PAS14	PAS13	PAS12	PAS11	PAS10
PBS0	D7	D6	PBS05	PBS04	PBS03	PBS02	PBS01	PBS00
PDS0	D7	D6	PDS05	PDS04	PDS03	PDS02	PDS01	PDS00
IFS	—	—	—	SDIPS	SCKPS	RXPS	PTPIPS	D0

• **PAS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	PAS05	PAS04	PAS03	PAS02	PAS01	PAS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6     **D7~D6:** Reserved bits, should remain unchanged after power-on reset

Bit 5~4     **PAS05~PAS04:** PA2 pin-shared function selection  
             00: PA2  
             01: SCL  
             10: PA2  
             11: PA2

Bit 3~2     **PAS03~PAS02:** PA1 pin-shared function selection  
             00: PA1  
             01: PTP  
             10: Reserved  
             11: RX/TX

Bit 1~0     **PAS01~PAS00:** PA0 pin-shared function selection  
             00: PA0  
             01: SDA  
             10: PA0  
             11: PA0

• **PAS1 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS17	PAS16	—	—	—	—	PAS11	PAS10
R/W	R/W	R/W	—	—	—	—	R/W	R/W
POR	0	0	—	—	—	—	0	0

Bit 7~6 **PAS17~PAS16:** PA7 pin-shared function selection

00: PA7  
01: PTPB  
10: SCL  
11: RX/TX

Bit 5~2 Unimplemented, read as “0”

Bit 1~0 **PAS11~PAS10:** PA4 pin-shared function selection

00: PA4/INT/PTPI  
01: SDA  
10: TX  
11: PA4/INT/PTPI

Note: The PA4 and PD2 share one external pin, it is important to note that PD2 should be configured as an input with the pull-high function disabled when using these bits to select the pin function on PA4 pin.

• **PBS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	PBS05	PBS04	PBS03	PBS02	PBS01	PBS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **D7~D6:** Reserved bits, should remain unchanged after power-on reset

Bit 5~4 **PBS05~PBS04:** PB2 pin-shared function selection

00: PB2  
01: KEY3  
10: PB2  
11: PB2

Bit 3~2 **PBS03~PBS02:** PB1 pin-shared function selection

00: PB1  
01: KEY2  
10: PB1  
11: PB1

Bit 1~0 **PBS01~PBS00:** PB0 pin-shared function selection

00: PB0  
01: KEY1  
10: PB0  
11: PB0

• **PDS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	PDS05	PDS04	PDS03	PDS02	PDS01	PDS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **D7~D6**: Reserved bits, should remain unchanged after power-on reset

Bit 5~4 **PDS05~PDS04**: PD2 pin-shared function selection

- 00: PD2
- 01: PTPB
- 10: AN2
- 11: PD2

Note: The PA4 and PD2 share one external pin, it is important to note that PA4 should be configured as an input with the pull-high function disabled when using these bits to select the pin function on PD2 pin.

Bit 3~2 **PDS03~PDS02**: PD1 pin-shared function selection

- 00: PD1
- 01: CTPB
- 10: AN1
- 11: VREFI

Bit 1~0 **PDS01~PDS00**: PD0 pin-shared function selection

- 00: PD0
- 01: VREF
- 10: AN0
- 11: PD0

• **IFS Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	SDIPS	SCKPS	RXPS	PTPIPS	D0
R/W	—	—	—	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	0	0	0	0	0

Bit 7~5 Unimplemented, read as “0”.

Bit 4 **SDIPS**: SDA input source pin selection

- 0: PA0
- 1: PA4

Bit 3 **SCKPS**: SCL input source pin selection

- 0: PA2
- 1: PA7

Bit 2 **RXPS**: RX/TX input source pin selection

- 0: PA1
- 1: PA7

Bit 1 **PTPIPS**: PTPI input source pin selection

- 0: PA4
- 1: Reserved

Bit 0 **D0**: Reserved bit, should remain unchanged after power-on reset



• **IECC Register**

Bit	7	6	5	4	3	2	1	0
Name	IECS7	IECS6	IECS5	IECS4	IECS3	IECS2	IECS1	IECS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

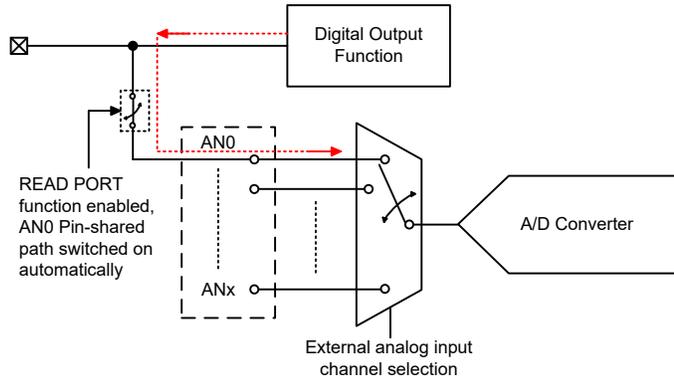
Bit 7~0 **IECS7~IECS0**: READ PORT function enable control bit 7~ bit 0  
 11001010: IECM=1 – READ PORT function is enabled  
 Others: IECM=0 – READ PORT function is disabled

READ PORT Function Port Control Register Bit – PxC.n	Disabled		Enabled	
	1	0	1	0
I/O Function	Pin value	Data latch value	Pin value	
A/D Function	0			

Note: The value on the above table is the content of the ACC register after “mov a, Px” instruction is executed where “x” means the relevant port name.

The additional function of the READ PORT mode is to check the A/D path. When the READ PORT function is disabled, the A/D path from the external pin to the internal analog input will be switched off if the A/D input pin function is not selected by the corresponding selection bits. For the MCU with A/D converter channels, the desired A/D channel can be switched on by properly configuring the external analog input channel selection bits in the A/D Control Register together with the corresponding analog input pin function is selected. However, the additional function of the READ PORT mode is to force the A/D path to be switched on. As shown in the following example, when the AN0 is selected as the analog input channel as the READ PORT function is enabled, the AN0 analog input path will be switched on even if the AN0 analog input pin function is not selected. In this way, the AN0 analog input path can be examined by internally connecting the digital output on this shared pin with the AN0 analog input pin switch and then converting the corresponding digital data without any external analog input voltage connected.

Note that the A/D converter reference voltage should be equal to the I/O power supply voltage when examining the A/D path using the READ PORT function.



**A/D Channel Input Path Internal Connection**

## Programming Considerations

Within the user program, one of the things first to consider is port initialisation. After a reset, all of the I/O data and port control registers will be set high. This means that all I/O pins will be defaulted to an input state, the level of which depends on the other connected circuitry and whether pull-high selections have been chosen. If the port control registers are then programmed to setup some pins as outputs, these output pins will have an initial high output value unless the associated port data registers are first programmed. Selecting which pins are inputs and which are outputs can be achieved byte-wide by loading the correct values into the appropriate port control register or by programming individual bits in the port control register using the “SET [m].i” and “CLR [m].i” instructions. Note that when using these bit control instructions, a read-modify-write operation takes place. The microcontroller must first read in the data on the entire port, modify it to the required new bit values and then rewrite this data back to the output ports.

Port A has the additional capability of providing wake-up functions. When the device is in the SLEEP or IDLE Mode, various methods are available to wake the device up. One of these is a high to low transition of any of the Port A pins. Single or multiple pins on Port A can be setup to have this function.

## Timer Modules – TM

One of the most fundamental functions in any microcontroller devices is the ability to control and measure time. To implement time related functions the device includes several Timer Modules, generally abbreviated to the name TM. The TMs are multi-purpose timing units and serve to provide operations such as Timer/Counter, Input Capture, Compare Match Output and Single Pulse Output as well as being the functional unit for the generation of PWM signals. Each of the TMs has two interrupts. The addition of input and output pins for each TM ensures that users are provided with timing units with a wide and flexible range of features.

The common features of the different TM types are described here with more detailed information provided in the individual Compact and Periodic type TM sections.

### Introduction

These device contains two TMs and each individual TM can be categorised as a certain type, namely Compact Type TM or Periodic Type TM. Although similar in nature, the different TM types vary in their feature complexity. The common features to all of the Compact and Periodic type TMs will be described in this section and the detailed operation regarding each of the TM types will be described in separate sections. The main features and differences between the two types of TMs are summarised in the accompanying table.

TM Function	CTM	PTM
Timer/Counter	√	√
Input Capture	—	√
Compare Match Output	√	√
PWM Output	—	√
Single Pulse Output	√	√
PWM Alignment	Edge	Edge
PWM Adjustment Period & Duty	Duty or Period	Duty or Period

**TM Function Summary**

## TM Operation

The different types of TM offer a diverse range of functions, from simple timing operations to PWM signal generation. The key to understanding how the TM operates is to see it in terms of a free running count-up counter whose value is then compared with the value of pre-programmed internal comparators. When the free running count-up counter has the same value as the pre-programmed comparator, known as a compare match situation, a TM interrupt signal will be generated which can clear the counter and perhaps also change the condition of the TM output pin. The internal TM counter is driven by a user selectable clock source, which can be an internal clock.

## TM Clock Source

The clock source which drives the main counter in each TM can originate from various sources. The selection of the required clock source is implemented using the xTCK2~xTCK0 bits in the xTM control registers, where “x” stands for C or P type TM. The clock source can be a ratio of the system clock,  $f_{SYS}$ , or the internal high clock,  $f_H$ , the  $f_{SUB}$  clock source.

## TM Interrupts

The Compact or Periodic type TM each has two internal interrupt, one for each of the internal comparator A or comparator P, which generate a TM interrupt when a compare match condition occurs. When a TM interrupt is generated, it can be used to clear the counter and also to change the state of the TM output pin.

## TM External Pins

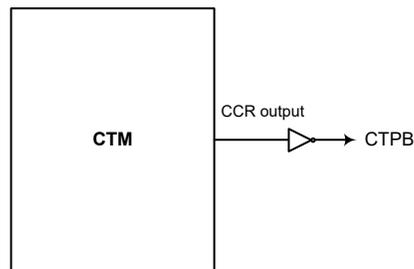
The CTM has no external input pins, while the PTM has one input pin with the label PTPI. The PTM input pin, PTPI, is the capture input whose active edge can be a rising edge, a falling edge or both rising and falling edges and the active edge transition type is selected using the PTIO1~PTIO0 bits in the PTMC1 register.

The TMs each have one or two output pins, xTP and xTPB. The xTPB pin outputs the inverted signal of the xTP. When the TM is in the Compare Match Output Mode, these pins can be controlled by the TM to switch to a high or low level or to toggle when a compare match situation occurs. The external xTP and xTPB output pins are also the pins where the xTM generates the PWM output waveform.

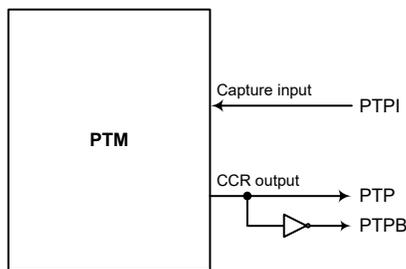
As the TM input and output pins are pin-shared with other functions, the TM input and output functions must first be setup using the relevant pin-shared function selection bits described in the Pin-shared Function section. The details of the pin-shared function selection are described in the pin-shared function section.

CTM		PTM	
Input	Output	Input	Output
—	CTPB	PTPI	PTP, PTPB

TM External Pins



CTM Function Pin Block Diagram

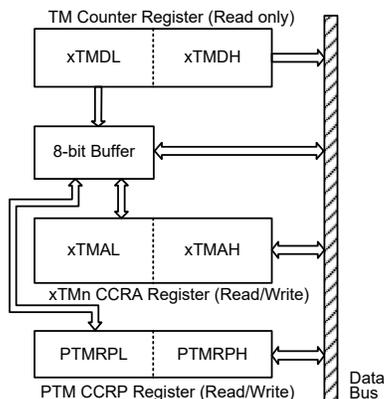


PTM Function Pin Block Diagram

### Programming Considerations

The TM Counter Registers and the Compare CCRA and CCRP register, all have a low and high byte structure. The high bytes can be directly accessed, but as the low bytes can only be accessed via an internal 8-bit buffer, reading or writing to these register pairs must be carried out in a specific way. The important point to note is that data transfer to and from the 8-bit buffer and its related low byte only takes place when a write or read operation to its corresponding high byte is executed.

As the CCRA and CCRP registers are implemented in the way shown in the following diagram and accessing these register pairs is carried out in a specific way as described above, it is recommended to use the “MOV” instruction to access the CCRA and CCRP low byte registers, named xTMAL and PTMRPL, using the following access procedures. Accessing the CCRA or CCRP low byte registers without following these access procedures will result in unpredictable values.

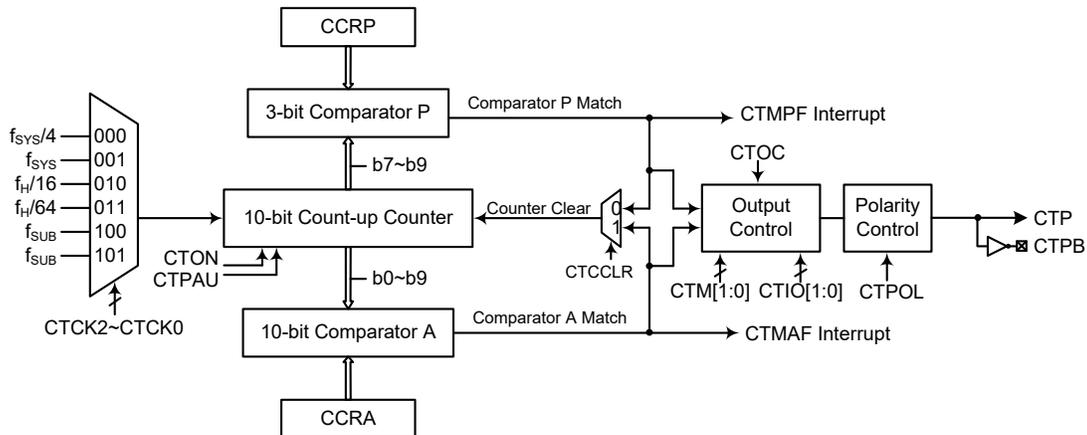


The following steps show the read and write procedures:

- Writing Data to CCRA or CCRP
  - ♦ Step 1. Write data to low byte xTMAL or PTMRPL
    - Note that here data is only written to the 8-bit buffer.
  - ♦ Step 2. Write data to high byte xTMAH or PTMRPH
    - Here data is written directly to the high byte registers and simultaneously data is latched from the 8-bit buffer to the low byte registers.
- Reading Data from the Counter Registers and CCRA or CCRP
  - ♦ Step 1. Read data from the high byte xTMDH, xTMAH or PTMRPH
    - Here data is read directly from the high byte registers and simultaneously data is latched from the Low Byte register into the 8-bit buffer.
  - ♦ Step 2. Read data from the low byte xTMDL, xTMAL or PTMRPL
    - This step reads data from the 8-bit buffer

## Compact Type TM – CTM

Although the simplest form of the TM types, the Compact TM type still contains three operating modes, which are Compare Match Output, Timer/Event Counter and PWM Output modes.



Note: 1. As the CTM external pins are pin-shared with other functions, the relevant pin-shared control bits should be properly configured before using these pins.

2. The CTPB pin is the inverted output of the CTP, but the CTP signal is not connected to the external package.

**10-bit Compact Type TM Block Diagram**

### Compact Type TM Operation

At its core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRP is 3-bit wide whose value is compared with the highest three bits in the counter while the CCRA is 10-bit wide and therefore compares with all counter bits.

The only way of changing the value of the 10-bit counter using the application program, is to clear the counter by changing the CTON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators. When these conditions occur, a CTM interrupt signal will also usually be generated. The Compact Type TM can operate in a number of different operational modes, can be driven by different clock sources and can also control an output pin. All operating setup conditions are selected using relevant internal registers.

### Compact Type TM Register Description

Overall operation of the Compact Type TM is controlled using a series of registers. A read only register pair exists to store the internal counter 10-bit value, while a read/write register pair exists to store the internal 10-bit CCRA value. The remaining two registers are control registers which setup the different operating and control modes as well as the three CCRP bits.

Register Name	Bit							
	7	6	5	4	3	2	1	0
CTMC0	CTPAU	CTCK2	CTCK1	CTCK0	CTON	CTRP2	CTRP1	CTRP0
CTMC1	CTM1	CTM0	CTIO1	CTIO0	CTOC	CTPOL	CTDPX	CTCCLR
CTMDL	D7	D6	D5	D4	D3	D2	D1	D0
CTMDH	—	—	—	—	—	—	D9	D8
CTMAL	D7	D6	D5	D4	D3	D2	D1	D0
CTMAH	—	—	—	—	—	—	D9	D8

**10-bit Compact TM Register List**

• **CTMC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	CTPAU	CTCK2	CTCK1	CTCK0	CTON	CTRP2	CTRP1	CTRP0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **CTPAU**: CTM Counter Pause Control

- 0: Run
- 1: Pause

The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the CTM will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **CTCK2~CTCK0**: Select CTM Counter clock

- 000:  $f_{SYS}/4$
- 001:  $f_{SYS}$
- 010:  $f_H/16$
- 011:  $f_H/64$
- 100:  $f_{SUB}$
- 101:  $f_{SUB}$
- 110: Reserved
- 111: Reserved

These three bits are used to select the clock source for the CTM. The clock source  $f_{SYS}$  is the system clock, while  $f_H$  and  $f_{SUB}$  are other internal clocks, the details of which can be found in the Operating Modes and System Clocks section.

Bit 3 **CTON**: CTM Counter On/Off Control

- 0: Off
- 1: On

This bit controls the overall on/off function of the CTM. Setting the bit high enables the counter to run, clearing the bit disables the CTM. Clearing this bit to zero will stop the counter from counting and turn off the CTM which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again.

If the CTM is in the Compare Match Output Mode or the PWM Output Mode then the CTM output pin will be reset to its initial condition, as specified by the CTCCLR bit, when the CTON bit changes from low to high.

Bit 2~0 **CTRP2~CTRP0**: CTM CCRP 3-bit register, compared with the CTM Counter bit 9~bit 7 Comparator P Match Period=

- 000: 1024 CTM clocks
- 001: 128 CTM clocks
- 010: 256 CTM clocks
- 011: 384 CTM clocks
- 100: 512 CTM clocks
- 101: 640 CTM clocks
- 110: 768 CTM clocks
- 111: 896 CTM clocks

These three bits are used to setup the value on the internal CCRP 3-bit register, which are then compared with the internal counter's highest three bits. The result of this comparison can be selected to clear the internal counter if the CTCCLR bit is set to zero. Setting the CTCCLR bit to zero ensures that a compare match with the CCRP values will reset the internal counter. As the CCRP bits are only compared with the highest three counter bits, the compare values exist in 128 clock cycle multiples. Clearing all three bits to zero is in effect allowing the counter to overflow at its maximum value.

• **CTMC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	CTM1	CTM0	CTIO1	CTIO0	CTOC	CTPOL	CTDPX	CTCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **CTM1~CTM0**: Select CTM Operating Mode

- 00: Compare Match Output Mode
- 01: Undefined
- 10: PWM Output Mode
- 11: Timer/Counter Mode

These bits setup the required operating mode for the CTM. To ensure reliable operation the CTM should be switched off before any changes are made to the CTM1 and CTM0 bits. In the Timer/Counter Mode, the CTM output pin state is undefined.

Bit 5~4 **CTIO1~CTIO0**: Select CTM external pin function

- Compare Match Output Mode
  - 00: No change
  - 01: Output low
  - 10: Output high
  - 11: Toggle output
- PWM Output Mode
  - 00: PWM Output inactive state
  - 01: PWM Output active state
  - 10: PWM Output
  - 11: Undefined
- Timer/Counter Mode
  - Unused

These two bits are used to determine how the CTM external pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the CTM is running.

In the Compare Match Output Mode, the CTIO1 and CTIO0 bits determine how the CTM output pin changes state when a compare match occurs from the Comparator A. The CTM output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the CTM output pin should be setup using the CTOC bit in the CTMC1 register. Note that the output level requested by the CTIO1 and CTIO0 bits must be different from the initial value setup using the CTOC bit otherwise no change will occur on the CTM output pin when a compare match occurs. After the CTM output pin changes state it can be reset to its initial level by changing the level of the CTON bit from low to high.

In the PWM Output Mode, the CTIO1 and CTIO0 bits determine how the CTM output pin changes state when a certain compare match condition occurs. The PWM output function is modified by changing these two bits. It is necessary to only change the values of the CTIO1 and CTIO0 bits only after the CTM has been switched off. Unpredictable PWM outputs will occur if the CTIO1 and CTIO0 bits are changed when The CTM is running.

- Bit 3**      **CTOC:** CTP Output control bit  
Compare Match Output Mode  
0: Initial low  
1: Initial high  
PWM Output Mode  
0: Active low  
1: Active high  
This is the output control bit for the CTM output pin. Its operation depends upon whether CTM is being used in the Compare Match Output Mode or in the PWM Output Mode. It has no effect if the CTM is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the CTM output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low.
- Bit 2**      **CTPOL:** CTP Output polarity Control  
0: Non-invert  
1: Invert  
This bit controls the polarity of the CTP output. When the bit is set high the CTM output pin will be inverted and not inverted when the bit is zero. It has no effect if the CTM is in the Timer/Counter Mode.
- Bit 1**      **CTDPX:** CTM PWM period/duty Control  
0: CCRP – period, CCRA – duty  
1: CCRP – duty; CCRA – period  
This bit determines which of the CCRA and CCRP registers are used for period and duty control of the PWM waveform.
- Bit 0**      **CTCCLR:** Select CTM Counter clear condition  
0: CTM Comparator P match  
1: CTM Comparator A match  
This bit is used to select the method which clears the counter. Remember that the Compact TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the CTCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The CTCCLR bit is not used in the PWM Output Mode.

• **CTMDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0      **D7~D0:** CTM Counter Low Byte Register bit 7 ~ bit 0  
CTM 10-bit Counter bit 7 ~ bit 0

• **CTMDH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2      Unimplemented, read as “0”  
Bit 1~0      **D9~D8:** CTM Counter High Byte Register bit 1 ~ bit 0  
CTM 10-bit Counter bit 9 ~ bit 8

• **CTMAL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0     **D7~D0**: CTM CCRA Low Byte Register bit 7 ~ bit 0  
 CTM 10-bit CCRA bit 7 ~ bit 0

• **CTMAH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2     Unimplemented, read as “0”  
 Bit 1~0     **D9~D8**: CTM CCRA High Byte Register bit 1 ~ bit 0  
 CTM 10-bit CCRA bit 9 ~ bit 8

**Compact Type TM Operating Modes**

The Compact Type TM can operate in one of three operating modes, Compare Match Output Mode, PWM Output Mode or Timer/Counter Mode. The operating mode is selected using the CTM1 and CTM0 bits in the CTMC1 register.

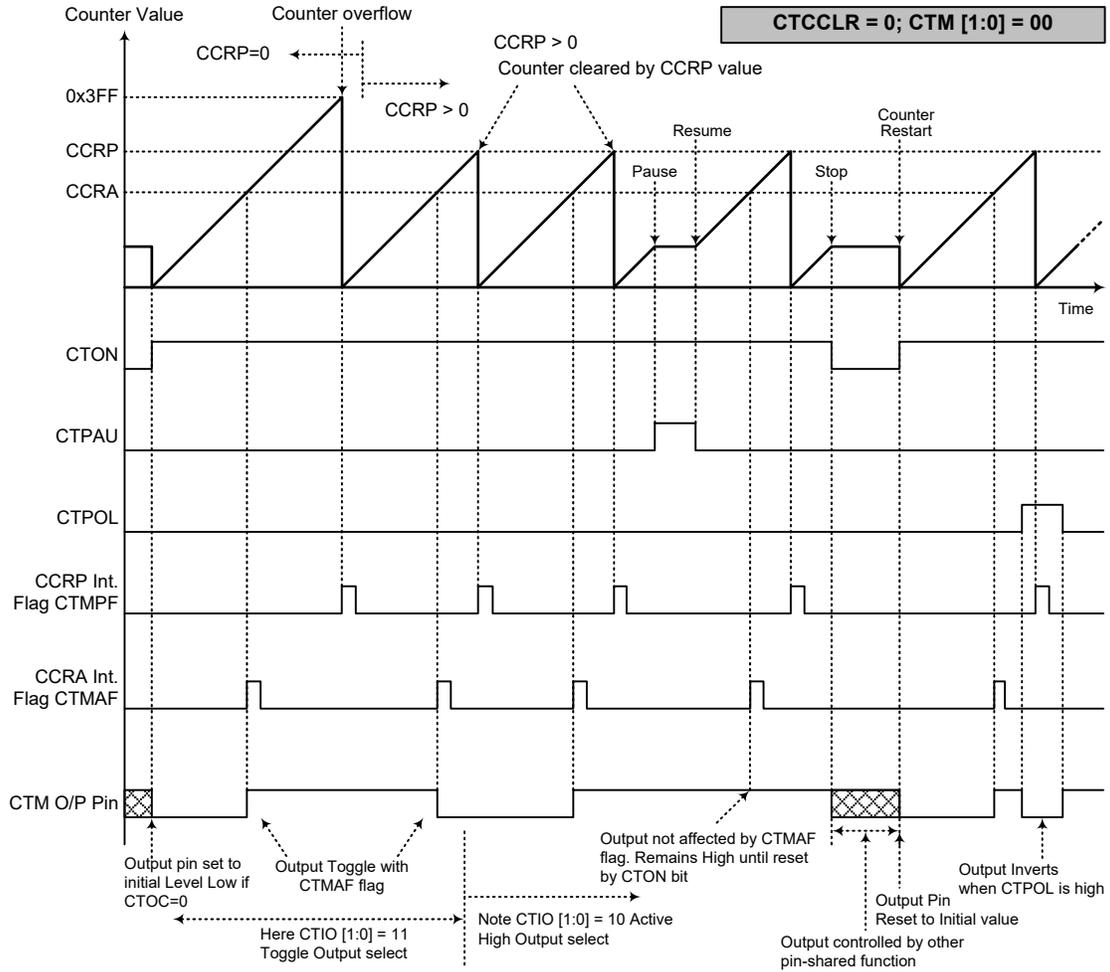
**Compare Match Output Mode**

To select this mode, bits CTM1 and CTM0 in the CTMC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the CTCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match occurs from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both CTMAF and CTMPF interrupt request flags for the Comparator A and Comparator P respectively, will both be generated.

If the CTCCLR bit in the CTMC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the CTMAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when CTCCLR is high no CTMPF interrupt request flag will be generated.

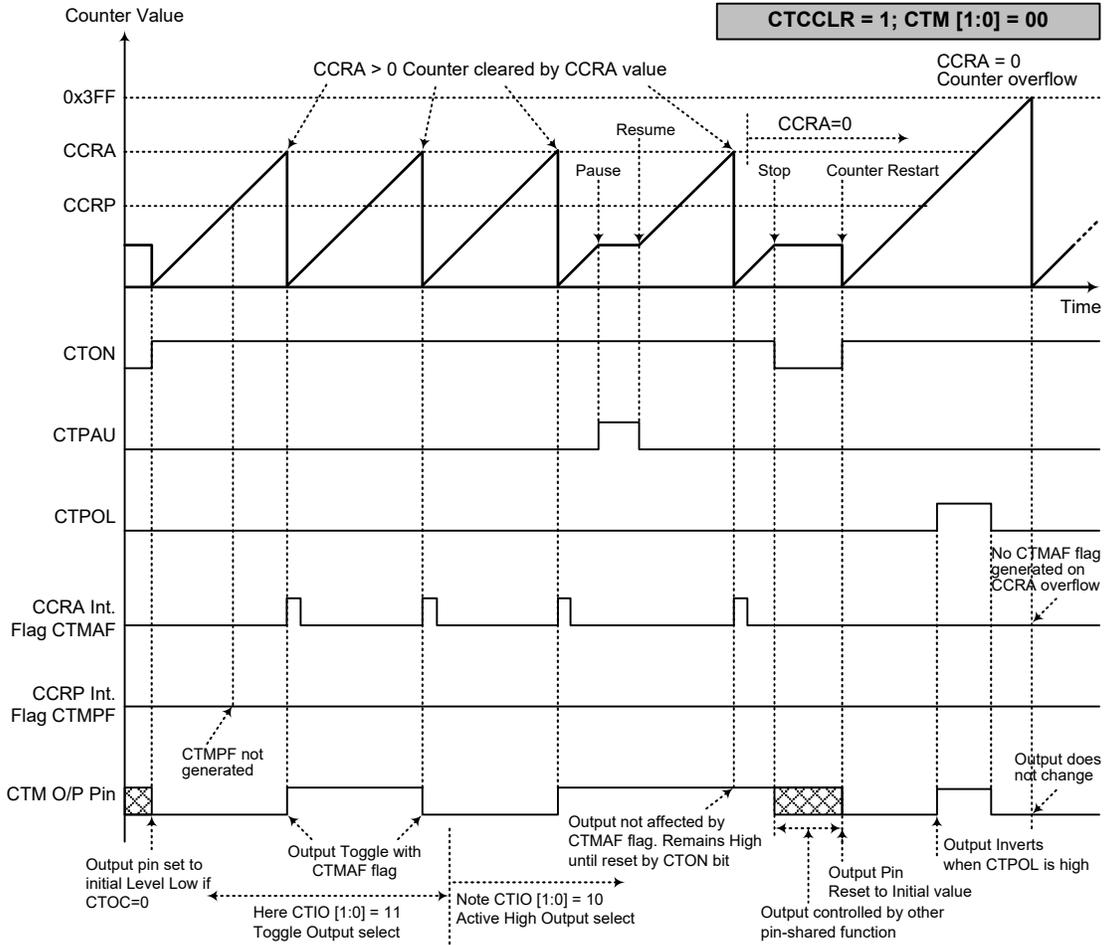
If the CCRA bits are all zero, the counter will overflow when it reaches its maximum 10-bit, 3FF Hex, value, however here the CTMAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is made, the CTM output pin will change state. The CTM output pin condition however only changes state when a CTMAF interrupt request flag is generated after a compare match occurs from Comparator A. The CTMPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the CTM output pin. The way in which the CTM output pin changes state are determined by the condition of the CTIO1 and CTIO0 bits in the CTMC1 register. The CTM output pin can be selected using the CTIO1 and CTIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the CTM output pin, which is setup after the CTON bit changes from low to high, is setup using the CTOC bit. Note that if the CTIO1 and CTIO0 bits are zero then no pin change will take place.



**Compare Match Output Mode – CTCCLR=0**

- Note: 1. With CTCCLR=0, a Comparator P match will clear the counter
2. The CTM output pin is controlled only by the CTMAF flag
3. The output pin reset to initial state by a CTON bit rising edge



**Compare Match Output Mode – CTCCLR=1**

- Note: 1. With CTCCLR=1, a Comparator A match will clear the counter  
 2. The CTM output pin is controlled only by the CTMAF flag  
 3. The output pin reset to initial state by a CTON bit rising edge  
 4. The CTMPF flags is not generated when CTCCLR=1

### Timer/Counter Mode

To select this mode, bits CTM1 and CTM0 in the CTMC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the CTM output pin is not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the CTM output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared function.

### PWM Output Mode

To select this mode, bits CTM1 and CTM0 in the CTMC1 register should be set to 10 respectively. The PWM function within the CTM is useful for applications which require functions such as motor control, heating control, illumination control etc. By providing a signal of fixed frequency but of varying duty cycle on the CTM output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the CTCCLR bit has no effect on the PWM operation. Both of the CCRA and CCRP registers are used to generate the PWM waveform, one register is used to clear the internal counter and thus control the PWM waveform frequency, while the other one is used to control the duty cycle. Which register is used to control either frequency or duty cycle is determined using the CTD PX bit in the CTMC1 register. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The CTOC bit in the CTMC1 register is used to select the required polarity of the PWM waveform while the two CTIO1 and CTIO0 bits are used to enable the PWM output or to force the CTM output pin to a fixed high or low level. The CTPOL bit is used to reverse the polarity of the PWM output waveform.

• **10-bit CTM, PWM Output Mode, Edge-aligned Mode, CTD PX=0**

CCRP	1~7	0
Period	CCRP×128	1024
Duty	CCRA	

If  $f_{SYS}=8\text{MHz}$ , CTM clock source is  $f_{SYS}/4$ , CCRP=2 and CCRA=128,

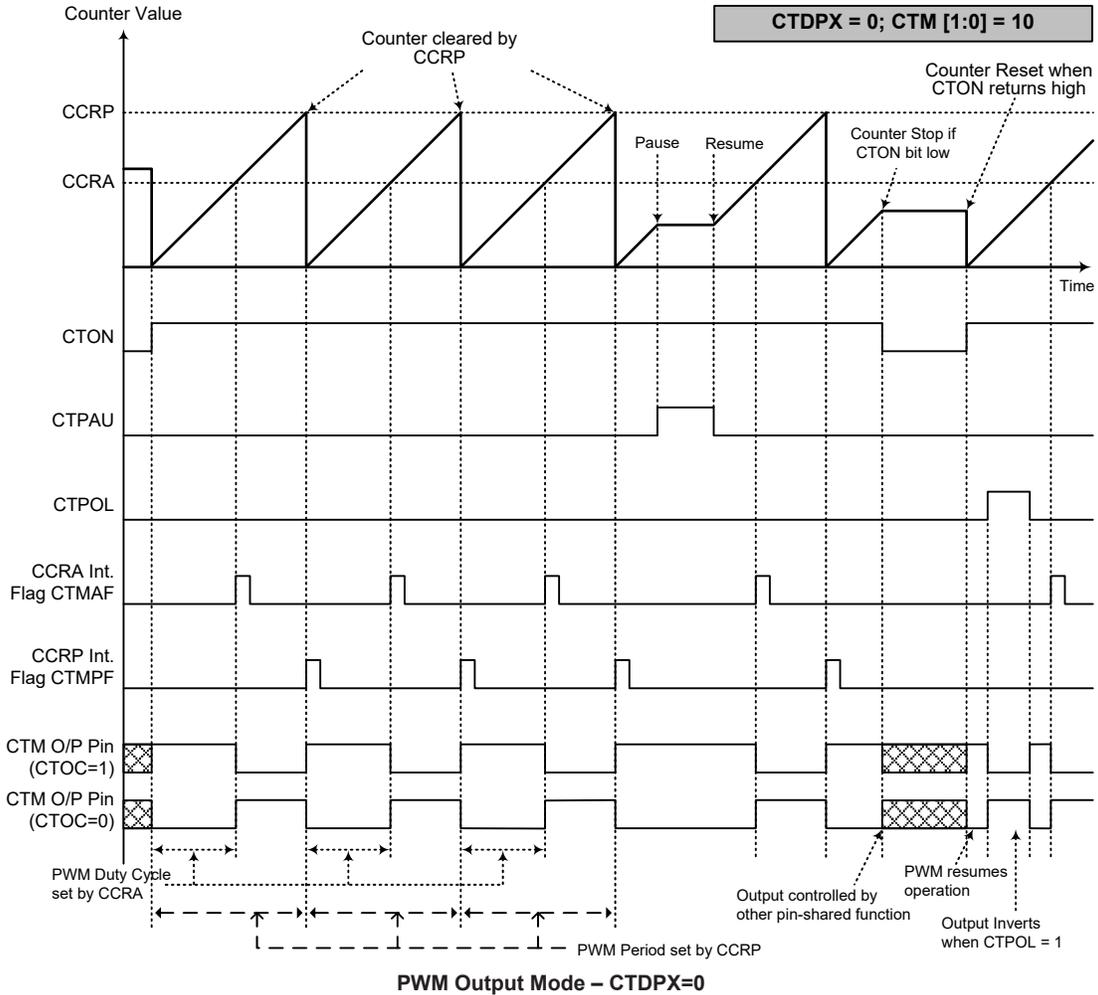
The CTM PWM output frequency= $(f_{SYS}/4)/(2\times 128)=f_{SYS}/1024=7.8125\text{kHz}$ , duty= $128/(2\times 128)=50\%$ .

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.

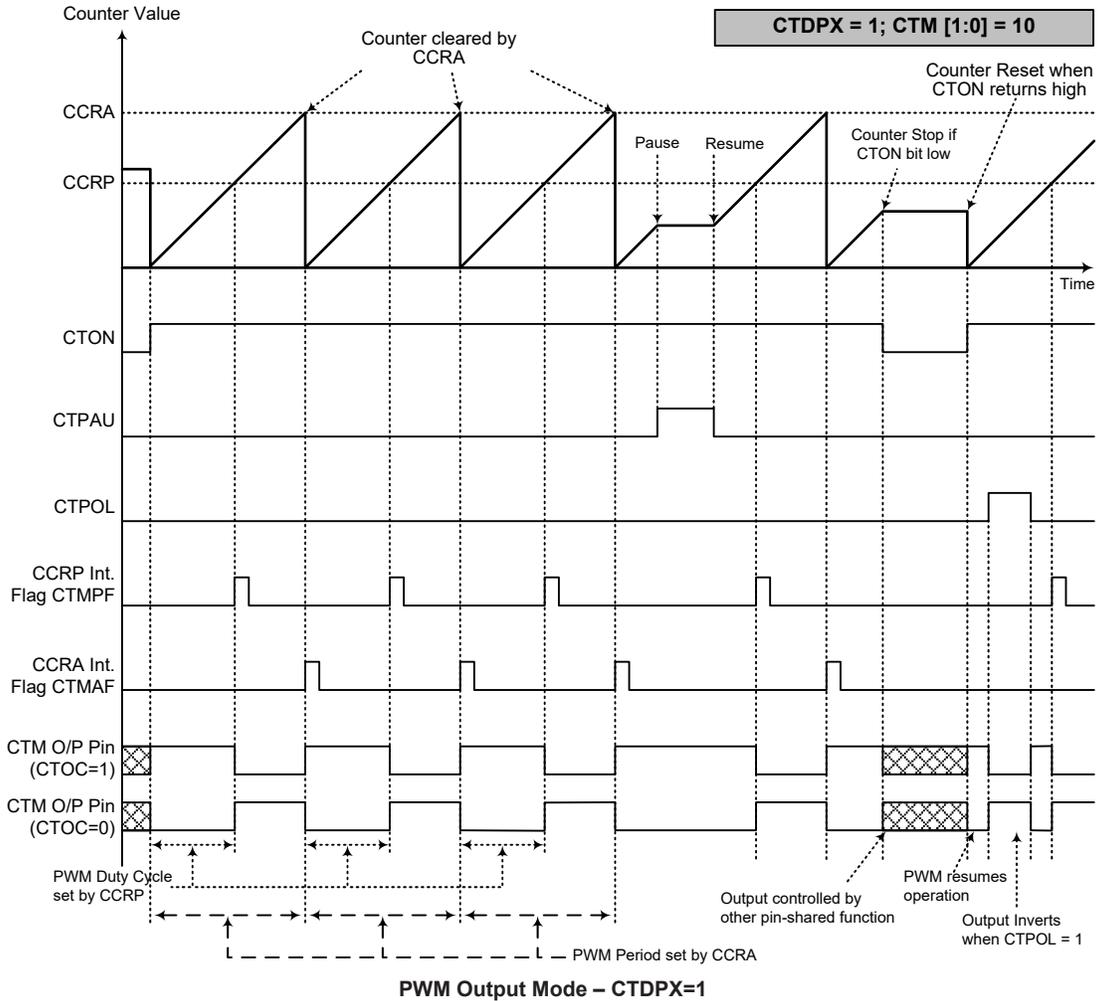
• **10-bit CTM, PWM Output Mode, Edge-aligned Mode, CTD PX=1**

CCRP	1~7	0
Period	CCRA	
Duty	CCRP×128	1024

The PWM output period is determined by the CCRA register value together with the CTM clock while the PWM duty cycle is defined by the CCRP register value.



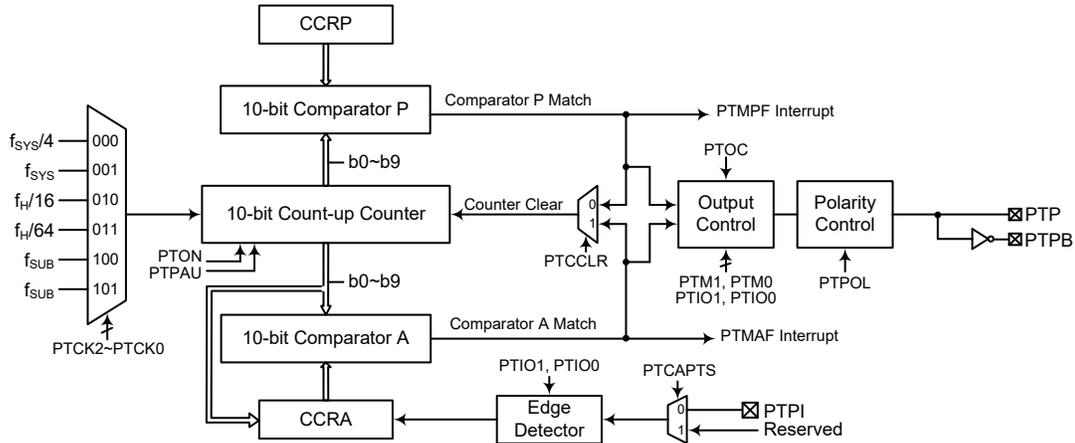
- Note: 1. Here CTDPX=0 – Counter cleared by CCRP  
 2. A counter clear sets the PWM Period  
 3. The internal PWM function continues running even when CTIO[1:0]=00 or 01  
 4. The CTCCLR bit has no influence on PWM operation



- Note: 1. Here CTD PX=1 – Counter cleared by CCRA  
 2. A counter clear sets the PWM Period  
 3. The internal PWM function continues even when CTIO[1:0]=00 or 01  
 4. The CTCCLR bit has no influence on PWM operation.

## Periodic Type TM – PTM

The Periodic Type TM contains five operating modes, which are Compare Match Output, Timer/Event Counter, Capture Input, Single Pulse Output and PWM Output modes. The Periodic TM can also be controlled with an external input pin and can drive two external output pins.



- Note: 1. The PTM external pins are pin-shared with other functions, so before using the PTM function the pin-shared function registers must be set properly to enable the PTM pin function. The PTPI pin, if used, must also be set as an input by setting the corresponding bits in the port control register.  
 2. The PTPB is the inverted output of the PTP.

**Periodic Type TM Block Diagram**

### Periodic TM Operation

The size of Periodic TM is 10-bit wide and its core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRP and CCRA comparators are 10-bit wide whose value is respectively compared with all counter bits.

The only way of changing the value of the 10-bit counter using the application program is to clear the counter by changing the PTON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators. When these conditions occur, a PTM interrupt signal will also usually be generated. The Periodic Type TM can operate in a number of different operational modes, can be driven by different clock sources and also control more than one output pins. All operating setup conditions are selected using relevant internal registers.

### Periodic Type TM Register Description

Overall operation of the Periodic Type TM is controlled using a series of registers. A read only register pair exists to store the internal 10-bit counter value, while two read/write register pairs exist to store the internal 10-bit CCRA value and CCRP value. The remaining two registers are control registers which setup the different operating and control modes.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PTMC0	PTPAU	PTCK2	PTCK1	PTCK0	PTON	—	—	—
PTMC1	PTM1	PTM0	PTIO1	PTIO0	PTOC	PTPOL	PTCAPTS	PTCCLR
PTMDL	D7	D6	D5	D4	D3	D2	D1	D0
PTMDH	—	—	—	—	—	—	D9	D8
PTMAL	D7	D6	D5	D4	D3	D2	D1	D0
PTMAH	—	—	—	—	—	—	D9	D8
PTMRPL	D7	D6	D5	D4	D3	D2	D1	D0
PTMRPH	—	—	—	—	—	—	D9	D8

**10-bit Periodic TM Register List**

• **PTMC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PTPAU	PTCK2	PTCK1	PTCK0	PTON	—	—	—
R/W	R/W	R/W	R/W	R/W	R/W	—	—	—
POR	0	0	0	0	0	—	—	—

**Bit 7 PTPAU:** PTM Counter Pause control

0: Run  
1: Pause

The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the PTM will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

**Bit 6~4 PTCK2~PTCK0:** Select PTM Counter clock

000:  $f_{SYS}/4$   
001:  $f_{SYS}$   
010:  $f_H/16$   
011:  $f_H/64$   
100:  $f_{SUB}$   
101:  $f_{SUB}$   
110: Reserved  
111: Reserved

These three bits are used to select the clock source for the PTM. The clock source  $f_{SYS}$  is the system clock, while  $f_H$  and  $f_{SUB}$  are other internal clocks, the details of which can be found in the Operating Modes and System Clocks section.

**Bit 3 PTON:** PTM Counter On/Off control

0: Off  
1: On

This bit controls the overall on/off function of the PTM. Setting the bit high enables the counter to run while clearing the bit disables the PTM. Clearing this bit to zero will stop the counter from counting and turn off the PTM which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again.

If the PTM is in the Compare Match Output Mode, PWM Output Mode or Single Pulse Output Mode then the PTM output pin will be reset to its initial condition, as specified by the PTOC bit, when the PTON bit changes from low to high.

**Bit 2~0** Unimplemented, read as “0”

• **PTMC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	PTM1	PTM0	PTIO1	PTIO0	PTOC	PTPOL	PTCAPTS	PTCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PTM1~PTM0**: Select PTM Operating Mode  
 00: Compare Match Output Mode  
 01: Capture input mode  
 10: PWM Output Mode or Single Pulse Output Mode  
 11: Timer/Counter Mode

These bits setup the required operating mode for the PTM. To ensure reliable operation the PTM should be switched off before any changes are made to the PTM1 and PTM0 bits. In the Timer/Counter Mode, the PTM output pin state is undefined.

Bit 5~4 **PTIO1~PTIO0**: Select PTM external pin function

Compare Match Output Mode  
 00: No change  
 01: Output low  
 10: Output high  
 11: Toggle output

PWM Output Mode/Single Pulse Output Mode  
 00: PWM output inactive state  
 01: PWM output active state  
 10: PWM output  
 11: Single Pulse Output

Capture Input Mode  
 00: Input capture at rising edge of PTPI  
 01: Input capture at falling edge of PTPI  
 10: Input capture at both falling and rising edges of PTPI  
 11: Input capture disabled

Timer/Counter Mode  
 Unused

These two bits are used to determine how the PTM external pin changes state when a certain condition is reached. The function that these bits select depends upon in which mode the PTM is running.

In the Compare Match Output Mode, the PTIO1 and PTIO0 bits determine how the PTM output pin changes state when a compare match occurs from the Comparator A. The PTM output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both zero, then no change will take place on the output. The initial value of the PTM output pin should be setup using the PTOC bit in the PTMC1 register. Note that the output level requested by the PTIO1 and PTIO0 bits must be different from the initial value setup using the PTOC bit otherwise no change will occur on the PTM output pin when a compare match occurs. After the PTM output pin changes state, it can be reset to its initial level by changing the level of the PTON bit from low to high.

In the PWM Output Mode, the PTIO1 and PTIO0 bits determine how the TM output pin changes state when a certain compare match condition occurs. The PTM output function is modified by changing these two bits. It is necessary to only change the values of the PTIO1 and PTIO0 bits only after the PTM has been switched off. Unpredictable PWM outputs will occur if the PTIO1 and PTIO0 bits are changed when the PTM is running.

Bit 3 **PTOC**: PTM PTP Output control  
 Compare Match Output Mode  
 0: Initial low  
 1: Initial high

PWM Output Mode/Single Pulse Output Mode

- 0: Active low
- 1: Active high

This is the output control bit for the PTM output pin. Its operation depends upon whether PTM is being used in the Compare Match Output Mode or in the PWM Output Mode/Single Pulse Output Mode. It has no effect if the PTM is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the PTM output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low. In the Single Pulse Output Mode it determines the logic level of the PTM output when the PTON bit changes from low to high.

Bit 2 **PTPOL**: PTM PTP Output polarity control

- 0: Non-inverted
- 1: Inverted

This bit controls the polarity of the PTP output pin. When the bit is set high the PTM output pin will be inverted and not inverted when the bit is zero. It has no effect if the PTM is in the Timer/Counter Mode.

Bit 1 **PTCAPTS**: PTM Capture Trigger Source Selection

- 0: From PTPI pin
- 1: Reserved

Bit 0 **PTCCLR**: PTM Counter Clear condition selection

- 0: Comparator P match
- 1: Comparator A match

This bit is used to select the method which clears the counter. Remember that the Periodic TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the PTCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The PTCCLR bit is not used in the PWM Output or Single Pulse Output.

• **PTMDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM Counter Low Byte Register bit 7 ~ bit 0  
PTM 10-bit Counter bit 7 ~ bit 0

• **PTMDH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”  
Bit 1~0 **D9~D8**: PTM Counter High Byte Register bit 1 ~ bit 0  
PTM 10-bit Counter bit 9 ~ bit 8

• **PTMAL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0     **D7~D0**: PTM CCRA Low Byte Register bit 7 ~ bit 0  
 PTM 10-bit CCRA bit 7 ~ bit 0

• **PTMAH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2     Unimplemented, read as “0”  
 Bit 1~0     **D9~D8**: PTM CCRA High Byte Register bit 1 ~ bit 0  
 PTM 10-bit CCRA bit 9 ~ bit 8

• **PTMRPL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0     **D7~D0**: PTM CCRP Low Byte Register bit 7 ~ bit 0  
 PTM 10-bit CCRP bit 7 ~ bit 0

• **PTMRPH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2     Unimplemented, read as “0”  
 Bit 1~0     **D9~D8**: PTM CCRP High Byte Register bit 1 ~ bit 0  
 PTM 10-bit CCRP bit 9 ~ bit 8

## Periodic Type TM Operation Modes

The Periodic Type TM can operate in one of five operating modes, Compare Match Output Mode, PWM Output Mode, Single Pulse Output Mode, Capture Input Mode or Timer/Counter Mode. The operating mode is selected using the PTM1 and PTM0 bits in the PTMC1 register.

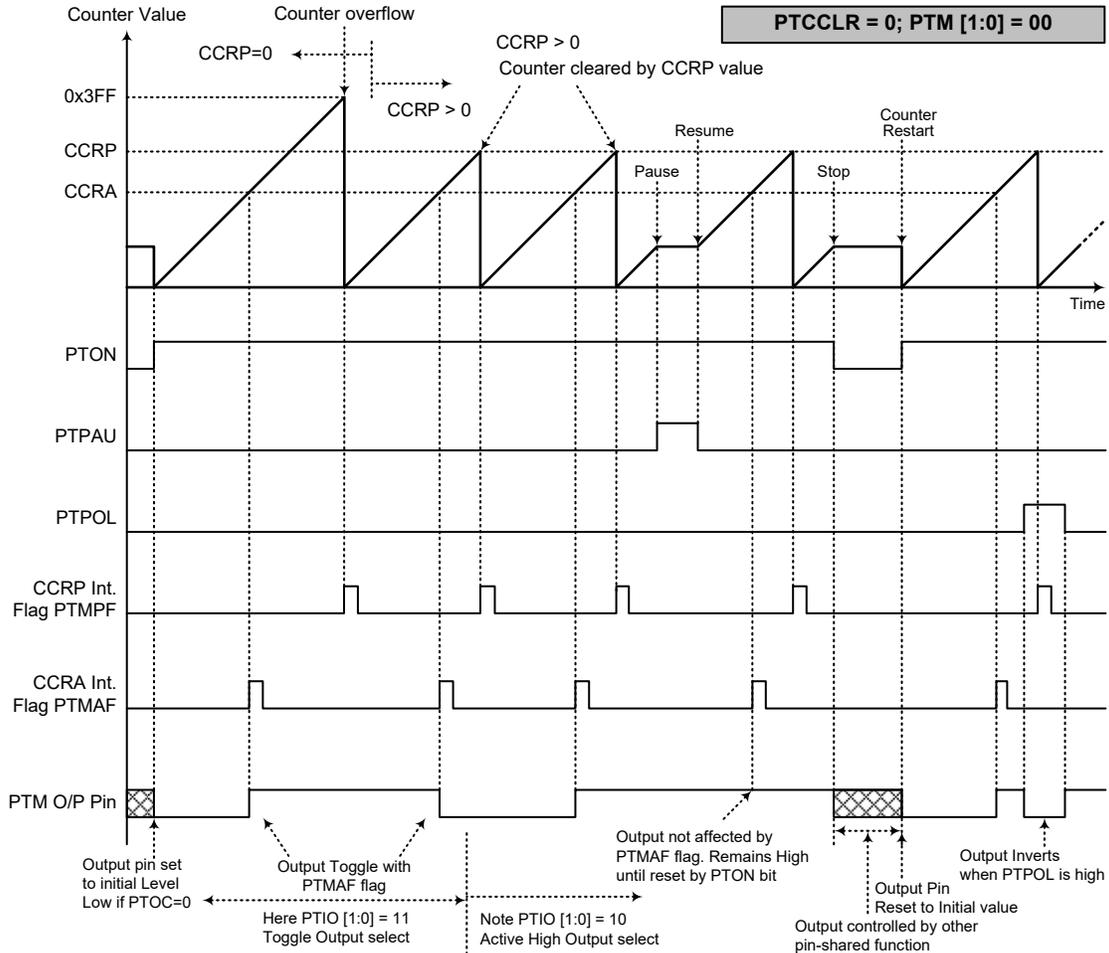
### Compare Match Output Mode

To select this mode, bits PTM1 and PTM0 in the PTMC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the PTCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both PTMAF and PTMPF interrupt request flags for Comparator A and Comparator P respectively, will both be generated.

If the PTCCLR bit in the PTMC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the PTMAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when PTCCLR is high no PTMPF interrupt request flag will be generated. In the Compare Match Output Mode, the CCRA can not be set to “0”.

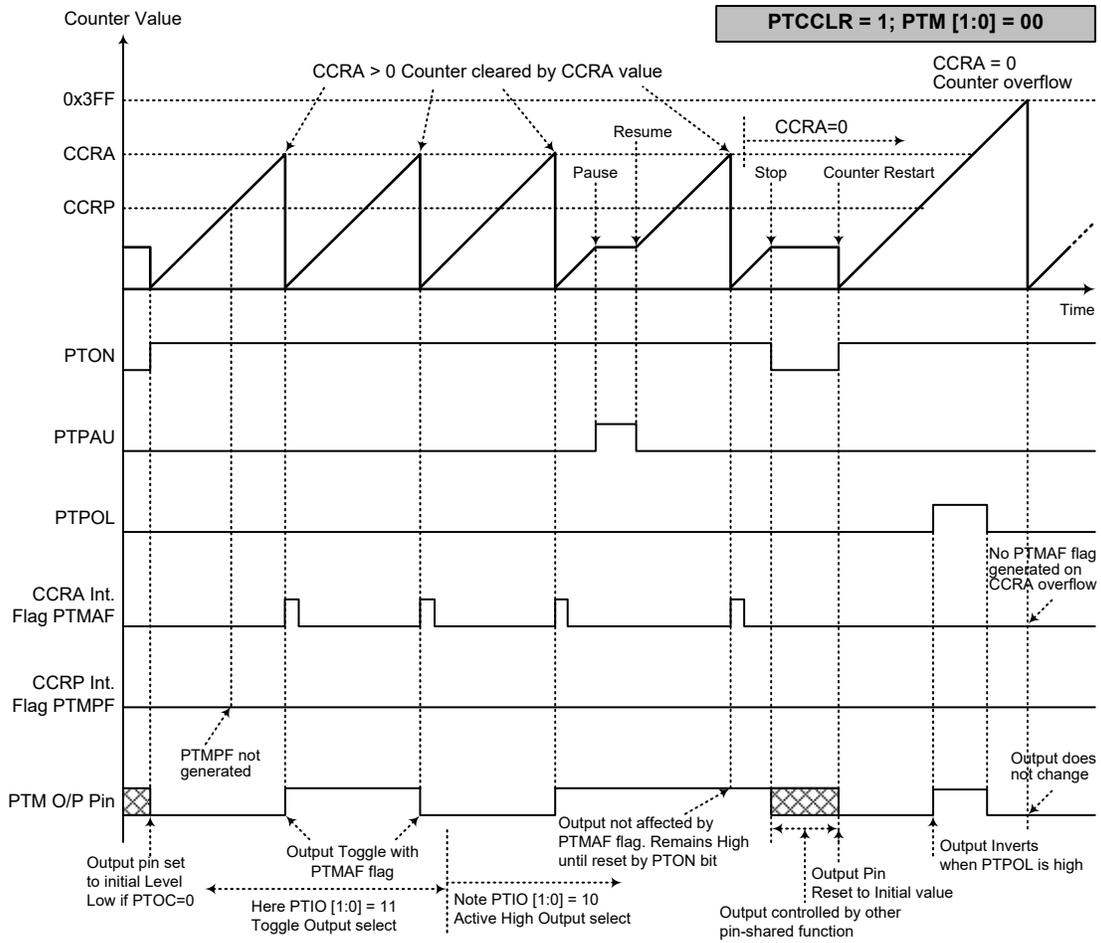
If the CCRA bits are all zero, the counter will overflow when it reaches its maximum 10-bit, 3FF Hex, value, however here the PTMAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is made, the PTM output pin will change state. The PTM output pin condition however only changes state when a PTMAF interrupt request flag is generated after a compare match occurs from Comparator A. The PTMPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the PTM output pin. The way in which the PTM output pin changes state are determined by the condition of the PTIO1 and PTIO0 bits in the PTMC1 register. The PTM output pin can be selected using the PTIO1 and PTIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the PTM output pin, which is setup after the PTON bit changes from low to high, is setup using the PTOC bit. Note that if the PTIO1 and PTIO0 bits are zero then no pin change will take place.



**Compare Match Output Mode – PTCCCLR=0**

- Note: 1. With  $PTCCCLR=0$ , a Comparator P match will clear the counter  
 2. The PTM output pin is controlled only by the PTMAF flag  
 3. The output pin is reset to its initial state by a PTON bit rising edge



**Compare Match Output Mode –  $PTCCLR=1$**

- Note: 1. With  $PTCCLR=1$ , a Comparator A match will clear the counter  
 2. The PTM output pin is controlled only by the PTMAF flag  
 3. The output pin is reset to its initial state by a  $PTON$  bit rising edge  
 4. A PTMPF flag is not generated when  $PTCCLR=1$

**Timer/Counter Mode**

To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the PTM output pin is not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the PTM output pin is not used in this mode, the pin can be used as a normal I/O pin or other pin-shared function.

**PWM Output Mode**

To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 10 respectively. The PWM function within the PTM is useful for applications which require functions such as motor control, heating control, illumination control, etc. By providing a signal of fixed frequency but of varying duty cycle on the PTM output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the PTCCLR bit has no effect as the PWM period. Both of the CCRP and CCRA registers are used to generate the PWM waveform, one register is used to clear the internal counter and thus control the PWM waveform frequency, while the other one is used to control the duty cycle. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The PTOC bit in the PTMC1 register is used to select the required polarity of the PWM waveform while the two PTIO1 and PTIO0 bits are used to enable the PWM output or to force the PTM output pin to a fixed high or low level. The PTPOL bit is used to reverse the polarity of the PWM output waveform.

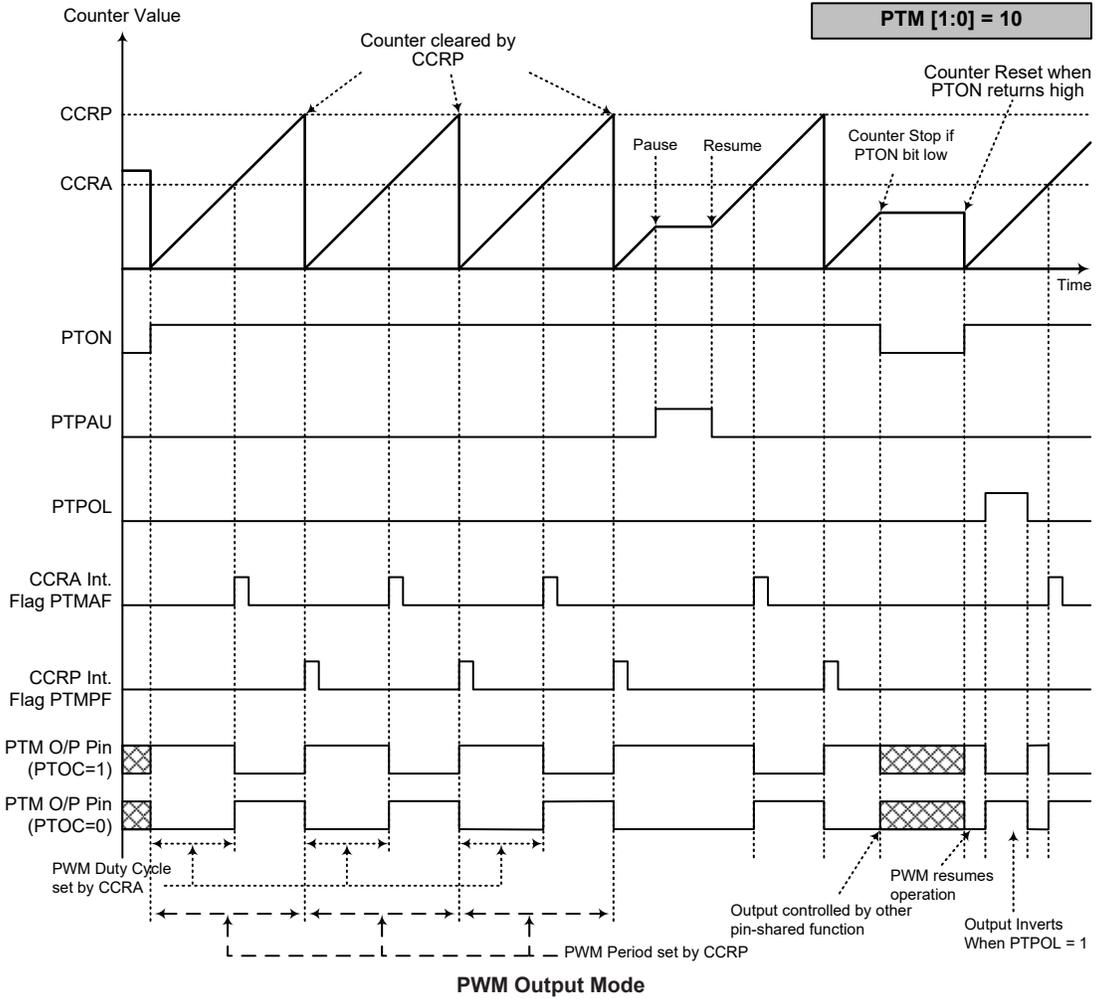
• **10-bit PTM, PWM Output Mode, Edge-aligned Mode**

CCRP	1~1023	0
Period	1~1023	1024
Duty	CCRA	

If  $f_{SYS}=8\text{MHz}$ , PTM clock source select  $f_{SYS}/4$ , CCRP=512 and CCRA=128,

The PTM PWM output frequency= $(f_{SYS}/4)/512=f_{SYS}/2048=4\text{kHz}$ , duty=128/512=25%,

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.



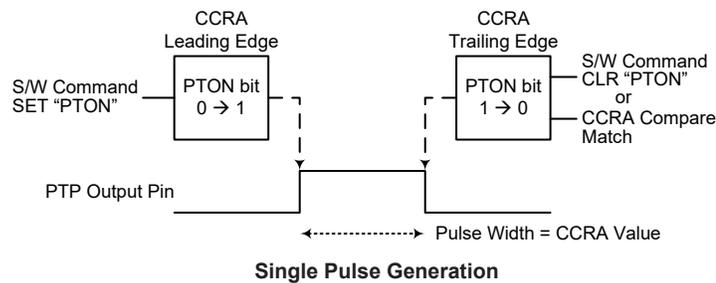
- Note: 1. The counter is cleared by CCRP  
 2. A counter clear sets the PWM Period  
 3. The internal PWM function continues running even when PTIO [1:0]=00 or 01  
 4. The PTCCLR bit has no influence on PWM operation

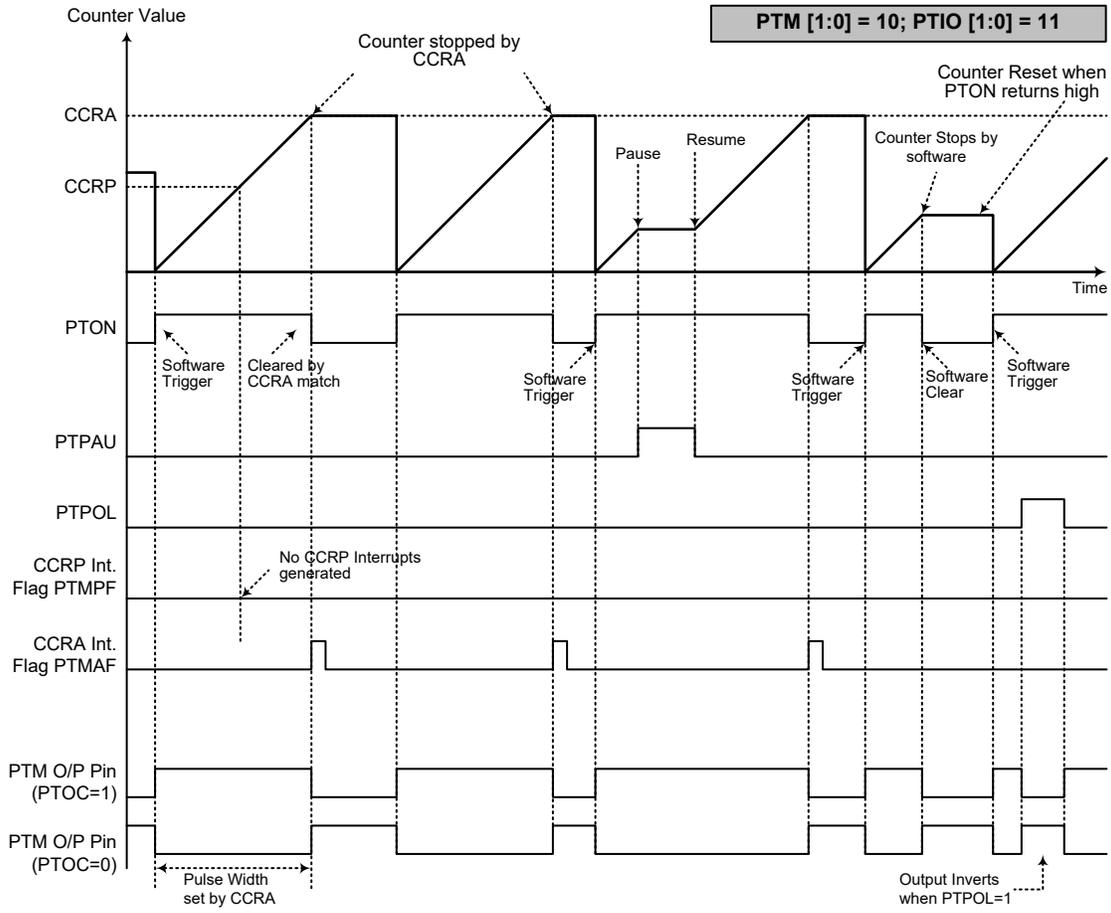
**Single Pulse Output Mode**

To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 10 respectively and also the PTIO1 and PTIO0 bits should be set to 11 respectively. The Single Pulse Output Mode, as the name suggests, will generate a single shot pulse on the PTM output pin.

The trigger for the pulse output leading edge is a low to high transition of the PTON bit, which can be implemented using the application program. When the PTON bit transitions to a high level, the counter will start running and the pulse leading edge will be generated. The PTON bit should remain high when the pulse is in its active state. The generated pulse trailing edge will be generated when the PTON bit is cleared to zero, which can be implemented using the application program or when a compare match occurs from Comparator A.

However a compare match from Comparator A will also automatically clear the PTON bit and thus generate the Single Pulse output trailing edge. In this way the CCRA value can be used to control the pulse width. A compare match from Comparator A will also generate a PTM interrupt. The counter can only be reset back to zero when the PTON bit changes from low to high when the counter restarts. In the Single Pulse Output Mode CCRP is not used. The PTCCLR is not used in this Mode.





**Single Pulse Output Mode**

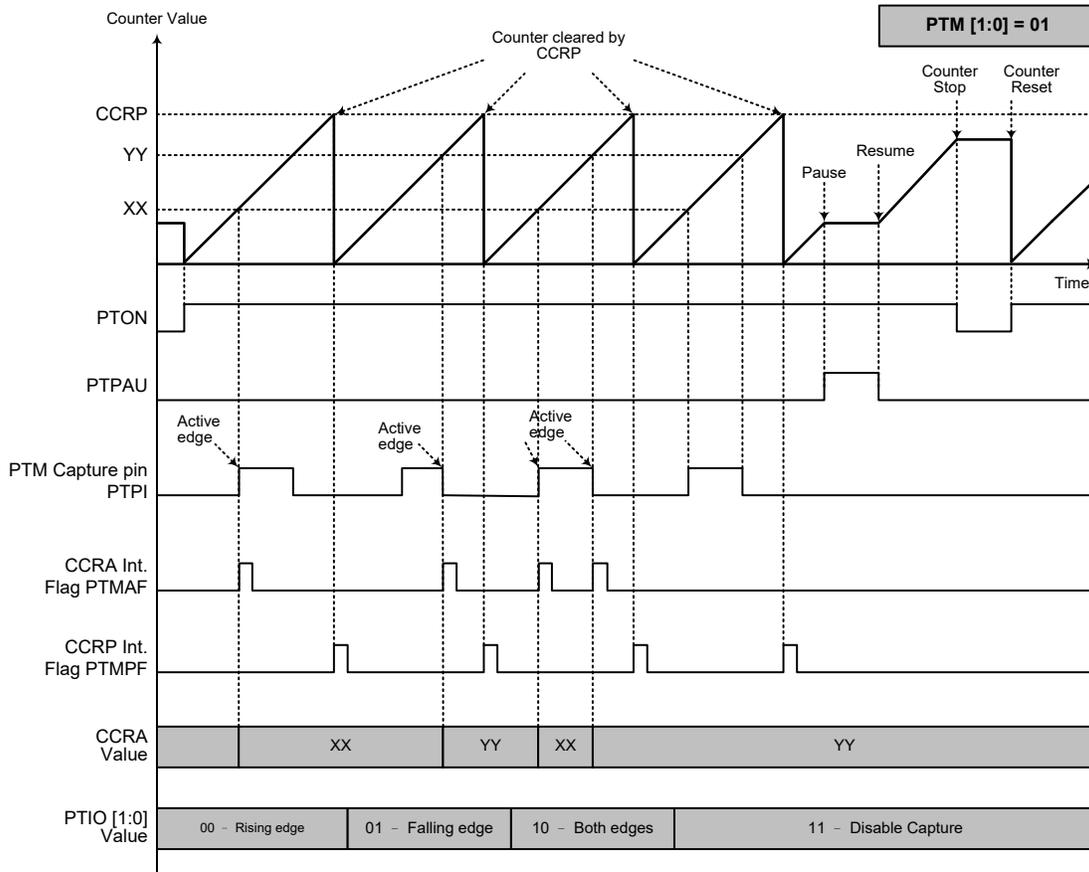
- Note: 1. Counter stopped by CCRA  
 2. CCRP is not used  
 3. The pulse triggered by setting the PTON bit high  
 4. In the Single Pulse Output Mode, PTIO [1:0] must be set to "11" and can not be changed

### **Capture Input Mode**

To select this mode bits PTM1 and PTM0 in the PTMC1 register should be set to 01 respectively. This mode enables external signals to capture and store the present value of the internal counter and can therefore be used for applications such as pulse width measurements. The external signal is supplied on the PTPI pin which is selected using the PTCAPTS bit in the PTMC1 register. The input pin active edge can be either a rising edge, a falling edge or both rising and falling edges; the active edge transition type is selected using the PTIO1 and PTIO0 bits in the PTMC1 register. The counter is started when the PTON bit changes from low to high which is initiated using the application program.

When the required edge transition appears on the PTPI pin the present value in the counter will be latched into the CCRA registers and a PTM interrupt generated. Irrespective of what events occur on the PTPI pin, the counter will continue to free run until the PTON bit changes from high to low. When a CCRP compare match occurs the counter will reset back to zero; in this way the CCRP value can be used to control the maximum counter value. When a CCRP compare match occurs from Comparator P, a PTM interrupt will also be generated. Counting the number of overflow interrupt signals from the CCRP can be a useful method in measuring long pulse widths. The PTIO1 and PTIO0 bits can select the active trigger edge on the PTPI pin to be a rising edge, falling edge or both edge types. If the PTIO1 and PTIO0 bits are both set high, then no capture operation will take place irrespective of what happens on the PTPI pin, however it must be noted that the counter will continue to run. The PTCCLR, PTOC and PTPOL bits are not used in this Mode.

There are some considerations that should be noted. If the captured pulse width is less than 2 timer clock periods, it may be ignored by hardware. After the counter value is latched to the CCRA register by an active capture edge, the PTMAF flag will be set high after 0.5 timer clock periods. The propagation time from the active capture edge received to the action of latching counter value to CCRA registers is less than 1.5 timer clock periods.



**Capture Input Mode**

- Note: 1. PTM[1:0]=01 and active edge set by the PTIO[1:0] bits  
 2. A PTM Capture input pin active edge transfers the counter value to CCRA  
 3. PTCLLR bit is not used  
 4. No output function – PTOC and PTPOL bits are not used  
 5. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero  
 6. The capture input mode cannot be used if the selected PTM counter clock is not available

## Analog to Digital Converter – ADC

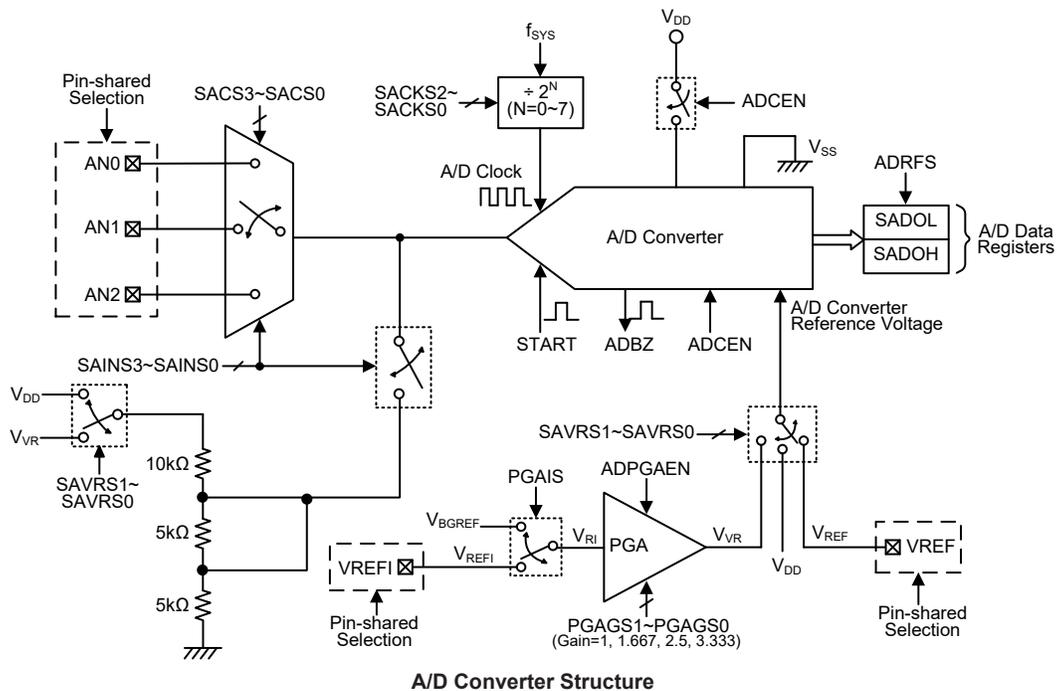
The need to interface to real world analog signals is a common requirement for many electronic systems. However, to properly process these signals by a microcontroller, they must first be converted into digital signals by A/D converters. By integrating the A/D conversion electronic circuitry into the microcontroller, the need for external components is reduced significantly with the corresponding follow-on benefits of lower costs and reduced component space requirements.

### A/D Converter Overview

The device contains a multi-channel analog to digital converter which can directly interface to external analog signals, such as that from sensors or the internal analog signals and convert these signals directly into a 12-bit digital value. The external or internal analog signal to be converted is determined by the SAINS3~SAINS0 bits together with the SACS3~SACS0 bits. Note that when the internal analog signal is selected to be converted using the SAINS bit field, the external channel analog input will automatically be switched off. More detailed information about the A/D input signal selection is described in the “A/D Converter Control Registers” and “A/D Converter Input Signals” sections respectively.

External Input Channels	Internal Signals	A/D Channel Selection Bits
AN0~AN2	V <sub>DD</sub> , V <sub>DD</sub> /2, V <sub>DD</sub> /4, V <sub>VR</sub> , V <sub>VR</sub> /2, V <sub>VR</sub> /4	SAINS3~SAINS0 SACS3~SACS0

The accompanying block diagram shows the overall internal structure of the A/D converter together with its associated registers.



**A/D Converter Structure**

### A/D Converter Register Description

Overall operation of the A/D converter is controlled using six registers. A read only register pair exists to store the A/D Converter data 12-bit value. Three registers, SADC0, SADC1 and SADC2, are the control registers which setup the operating conditions and control function of the A/D converter. The VBGRC register contains the VBGREN bit to control the bandgap reference voltage.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SADOL (ADRF5=0)	D3	D2	D1	D0	—	—	—	—
SADOL (ADRF5=1)	D7	D6	D5	D4	D3	D2	D1	D0
SAD0H (ADRF5=0)	D11	D10	D9	D8	D7	D6	D5	D4
SAD0H (ADRF5=1)	—	—	—	—	D11	D10	D9	D8
SADC0	START	ADBZ	ADCEN	ADRF5	SACS3	SACS2	SACS1	SACS0
SADC1	SAINS3	SAINS2	SAINS1	SAINS0	—	SACKS2	SACKS1	SACKS0
SADC2	ADPGAEN	—	—	PGAIS	SAVRS1	SAVRS0	PGAGS1	PGAGS0
VBGRC	—	—	—	—	—	—	—	VBGREN

**A/D Converter Register List**

### A/D Converter Data Registers – SADOL, SAD0H

As the device contains an internal 12-bit A/D converter, it requires two data registers to store the converted value. These are a high byte register, known as SAD0H, and a low byte register, known as SADOL. After the conversion process takes place, these registers can be directly read by the microcontroller to obtain the digitised conversion value. As only 12 bits of the 16-bit register space is utilised, the format in which the data is stored is controlled by the ADRF5 bit in the SADC0 register as shown in the accompanying table. D0~D11 are the A/D conversion result data bits. Any unused bits will be read as zero. The A/D data registers contents will be unchanged if the A/D converter is disabled.

ADRF5	SAD0H								SADOL							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	0	0	0	0
1	0	0	0	0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

**A/D Converter Data Registers**

### A/D Converter Control Registers – SADC0, SADC1, SADC2

To control the function and operation of the A/D converter, three control registers known as SADC0, SADC1 and SADC2 are provided. These 8-bit registers define functions such as the selection of which analog signal is connected to the internal A/D converter, the digitised data format, the A/D clock source as well as controlling the start function and monitoring the A/D converter busy status. As the device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SAINS bit field in the SADC1 register and SACS bit field in the SADC0 register are used to determine which analog signal derived from the external or internal signals will be connected to the A/D converter. The A/D converter also contains a programmable gain amplifier, PGA, to generate the A/D converter internal reference voltage. The overall operation of the PGA is controlled using the SADC2 register.

The relevant pin-shared function selection bits determine which pins on I/O Ports are used as analog inputs for the A/D converter input and which pins are not. When the pin is selected to be an A/D input, its original function whether it is an I/O or other pin-shared function will be removed. In addition, any internal pull-high resistor connected to the pin will be automatically removed if the pin is selected to be an A/D converter input.

• **SADC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	START	ADBZ	ADCEN	ADRFS	SACS3	SACS2	SACS1	SACS0
R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7 **START**: Start the A/D Conversion  
 0→1→0: Start  
 This bit is used to initiate an A/D conversion process. The bit is normally low but if set high and then cleared low again, the A/D converter will initiate a conversion process.
- Bit 6 **ADBZ**: A/D Converter busy flag  
 0: No A/D conversion is in progress  
 1: A/D conversion is in progress  
 This read only flag is used to indicate whether the A/D conversion is in progress or not. When the START bit is set from low to high and then to low again, the ADBZ flag will be set to 1 to indicate that the A/D conversion is initiated. The ADBZ flag will be cleared to 0 after the A/D conversion is complete.
- Bit 5 **ADCEN**: A/D Converter function enable control  
 0: Disable  
 1: Enable  
 This bit controls the A/D internal function. This bit should be set to one to enable the A/D converter. If the bit is set low, then the A/D converter will be switched off reducing the device power consumption. When the A/D converter function is disabled, the contents of the A/D data register pair known as SADOH and SADOL will be unchanged.
- Bit 4 **ADRFS**: A/D conversion data format select  
 0: A/D converter data format → SADOH=D [11:4]; SADOL=D [3:0]  
 1: A/D converter data format → SADOH=D [11:8]; SADOL=D [7:0]  
 This bit controls the format of the 12-bit converted A/D value in the two A/D data registers. Details are provided in the A/D converter data register section.
- Bit 3~0 **SACS3~SACS0**: A/D converter external analog input channel select  
 0000: AN0  
 0001: AN1  
 0010: AN2  
 0011~0111: Reserved  
 1000~1111: Undefined, input floating if selected

• **SADC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	SAINS3	SAINS2	SAINS1	SAINS0	—	SACKS2	SACKS1	SACKS0
R/W	R/W	R/W	R/W	R/W	—	R/W	R/W	R/W
POR	0	0	0	0	—	0	0	0

- Bit 7~4 **SAINS3~SAINS0**: A/D converter input signal select  
 0000: External source – External analog channel input, ANn  
 0001: Internal source – A/D converter power supply voltage,  $V_{DD}$   
 0010: Internal source – A/D converter power supply voltage/2,  $V_{DD}/2$   
 0011: Internal source – A/D converter power supply voltage/4,  $V_{DD}/4$   
 0100: External source – External analog channel input, ANn  
 0101: Internal source – Internal A/D converter PGA output voltage,  $V_{VR}$   
 0110: Internal source – Internal A/D converter PGA output voltage/2,  $V_{VR}/2$   
 0111: Internal source – Internal A/D converter PGA output voltage/4,  $V_{VR}/4$   
 10xx: Internal source – Ground  
 11xx: External source – External analog channel input, ANn  
 When the internal analog signal is selected to be converted, the external channel signal

input will automatically be switched off regardless of the SACS field value. It will prevent the external channel input from being connected together with the internal analog signal.

- Bit 3 Unimplemented, read as “0”
- Bit 2~0 **SACKS2~SACKS0**: A/D conversion clock source select  
 000:  $f_{SYS}$   
 001:  $f_{SYS}/2$   
 010:  $f_{SYS}/4$   
 011:  $f_{SYS}/8$   
 100:  $f_{SYS}/16$   
 101:  $f_{SYS}/32$   
 110:  $f_{SYS}/64$   
 111:  $f_{SYS}/128$

• **SADC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	ADPGAEN	—	—	PGAIS	SAVRS1	SAVRS0	PGAGS1	PGAGS0
R/W	R/W	—	—	R/W	R/W	R/W	R/W	R/W
POR	0	—	—	0	0	0	0	0

- Bit 7 **ADPGAEN**: PGA enable control  
 0: Disable  
 1: Enable  
 This bit is used to control the A/D converter internal PGA function. When the PGA output voltage is selected as A/D input or A/D reference voltage, the PGA needs to be enabled by setting this bit high. Otherwise the PGA needs to be disabled by clearing the ADPGAEN bit to zero to conserve power.
- Bit 6~5 Unimplemented, read as “0”
- Bit 4 **PGAIS**: PGA input voltage selection  
 0: From VREFI pin  
 1: From internal reference voltage,  $V_{BGREF}$   
 When the internal independent reference voltage  $V_{BGREF}$  is selected as the PGA input, the external reference voltage on the VREFI pin will be automatically switched off. In addition, the internal bandgap reference  $V_{BGREF}$  should be enabled by setting the VBGREN bit in the VBGRC register to “1”.
- Bit 3~2 **SAVRS1~SAVRS0**: A/D converter reference voltage select  
 00: Internal A/D converter power,  $V_{DD}$   
 01: External VREF pin  
 1x: Internal PGA output voltage,  $V_{VR}$   
 These bits are used to select the A/D converter reference voltage source. When the internal reference voltage source is selected, the reference voltage derived from the external VREF pin will automatically be switched off.
- Bit 1~0 **PGAGS1~PGAGS0**: PGA gain select  
 00: Gain=1  
 01: Gain=1.667 –  $V_{VR}=2V$  as  $V_{RI}=1.2V$   
 10: Gain=2.5 –  $V_{VR}=3V$  as  $V_{RI}=1.2V$   
 11: Gain=3.333 –  $V_{VR}=4V$  as  $V_{RI}=1.2V$   
 These bits are used to select the PGA gain. Note that here the gain is guaranteed only when the PGA input voltage is equal to 1.2V.

• **VBGRC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	VBGREN
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as “0”

Bit 0 **VBGREN**: Bandgap reference voltage control  
 0: Disable  
 1: Enable

This bit is used to enable the internal Bandgap reference circuit. The internal Bandgap reference circuit should first be enabled before the  $V_{BGREF}$  voltage is selected to be used. A specific start-up time is necessary for the Bandgap circuit to become stable and accurate.

**A/D Converter Reference Voltage**

The actual reference voltage supply to the A/D Converter can be supplied from the positive power supply,  $V_{DD}$ , an external reference source supplied on pin VREF or an internal reference voltage  $V_{VR}$  determined by the SAVRS1~SAVRS0 bits in the SADC2 register. The internal reference voltage  $V_{VR}$  is an amplified signal through a programmable gain amplifier, PGA, which is controlled by the ADPGAEN bit in the SADC2 register. The PGA gain can be equal to 1, 1.667, 2.5 or 3.333 and selected using the PGAGS1~PGAGS0 bits in the SADC2 register. The PGA input can come from the external reference input pin, VREFI, or an internal Bandgap reference voltage,  $V_{BGREF}$ , selected by the PG AIS bit in the SADC2 register. As the VREFI and VREF pins both are pin-shared with other functions, when the VREFI or VREF pin is selected as the reference voltage pin, the VREFI or VREF pin-shared function selection bits should first be properly configured to disable other pin-shared functions. However, if the internal reference signal is selected as the reference source, the external reference input from the VREFI or VREF pin will automatically be switched off by hardware.

Note that the internal Bandgap reference circuit should first be enabled before the  $V_{BGREF}$  is selected to be used. A specific start-up time is necessary for the Bandgap circuit to become stable and accurate.

**A/D Converter Input Signals**

All of the external A/D analog input pins are pin-shared with the I/O pins as well as other functions. The corresponding pin-shared function selection bits in the PxS1 and PxS0 registers, determine whether the external input pins are setup as A/D converter analog channel inputs or whether they have other functions. If the corresponding pin is setup to be an A/D converter analog channel input, the original pin function will be disabled. In this way, pins can be changed under program control to change their function between A/D inputs and other functions. All pull-high resistors, which are setup through register programming, will be automatically disconnected if the pins are setup as A/D inputs. Note that it is not necessary to first setup the A/D pin as an input in the port control register to enable the A/D input as when the relevant A/D input function selection bits enable an A/D input, the status of the port control register will be overridden.

As the device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SAINS3~SAINS0 bits in the SADC1 register are used to determine that the analog signal to be converted comes from the external channel input or internal analog signal. The SACS3~SACS0 bits in the SADC0 register are used to determine which external channel input is selected to be converted. If the SAINS3~SAINS0 bits are set to “0000”, the external channel input will be selected to be converted and the SACS3~SACS0 bits can determine which external channel is selected.

When the SAINS bit field is set to the value of “0x01”, “0x10” “0x11” or “10xx”, the internal analog signal will be selected. If the internal analog signal is selected to be converted, the external channel signal input will automatically be switched off regardless of the SACS field value. It will prevent the external channel input from being connected together with the internal analog signal.

SAINS [3:0]	SACS [3:0]	Input Signals	Description
0000, 0100, 11xx	0000~0010 1000~1111	AN0~AN2 —	External channel analog input ANn Floating, no external channel is selected
0001	xxxx	V <sub>DD</sub>	Internal A/D converter power supply voltage, V <sub>DD</sub>
0010	xxxx	V <sub>DD</sub> /2	Internal A/D converter power supply voltage/2, V <sub>DD</sub> /2
0011	xxxx	V <sub>DD</sub> /4	Internal A/D converter power supply voltage/4, V <sub>DD</sub> /4
0101	xxxx	V <sub>VR</sub>	Internal A/D converter PGA output voltage, V <sub>VR</sub>
0110	xxxx	V <sub>VR</sub> /2	Internal A/D converter PGA output voltage/2, V <sub>VR</sub> /2
0111	xxxx	V <sub>VR</sub> /4	Internal A/D converter PGA output voltage/4, V <sub>VR</sub> /4
10xx	xxxx	GND	Connected to the ground

**A/D Converter Input Signal Selection**

### A/D Conversion Operation

The START bit in the SADC0 register is used to start the AD conversion. When the microcontroller sets this bit from low to high and then low again, an analog to digital conversion cycle will be initiated.

The ADBZ bit in the SADC0 register is used to indicate whether the analog to digital conversion process is in progress or not. This bit will be automatically set to 1 by the microcontroller after an A/D conversion is successfully initiated. When the A/D conversion is complete, the ADBZ bit will be cleared to 0. In addition, the corresponding A/D interrupt request flag will be set in the interrupt control register, and if the interrupts are enabled, an internal interrupt signal will be generated. This A/D internal interrupt signal will direct the program flow to the associated A/D internal interrupt address for processing. If the A/D internal interrupt is disabled, the microcontroller can poll the ADBZ bit in the SADC0 register to check whether it has been cleared as an alternative method of detecting the end of an A/D conversion cycle.

The clock source for the A/D converter, which originates from the system clock  $f_{SYS}$ , can be chosen to be either  $f_{SYS}$  or a subdivided version of  $f_{SYS}$ . The division ratio value is determined by the SACKS2~SACKS0 bits in the SADC1 register. Although the A/D clock source is determined by the system clock  $f_{SYS}$  and by bits SACKS2~SACKS0, there are some limitations on the maximum A/D clock source speed that can be selected. As the recommended range of permissible A/D clock period,  $t_{ADCK}$ , is from 0.5 $\mu$ s to 10 $\mu$ s @ 2.0V $\leq$ V<sub>DD</sub> $\leq$ 5.5V, care must be taken for system clock frequencies. For example, if the system clock operates at a frequency of 8MHz, the SACKS2~SACKS0 bits should not be set to 000, 001 or 111. Doing so will give A/D clock periods that are less than the minimum A/D clock period or greater than the maximum A/D clock period which may result in inaccurate A/D conversion values. Refer to the following table for examples, where values marked with an asterisk \* show where, special care must be taken, as the values may be exceed the specified A/D Clock Period range.

f <sub>sys</sub>	A/D Clock Period (t <sub>ADCK</sub> )							
	SACKS[2:0]=000 (f <sub>sys</sub> )	SACKS[2:0]=001 (f <sub>sys</sub> /2)	SACKS[2:0]=010 (f <sub>sys</sub> /4)	SACKS[2:0]=011 (f <sub>sys</sub> /8)	SACKS[2:0]=100 (f <sub>sys</sub> /16)	SACKS[2:0]=101 (f <sub>sys</sub> /32)	SACKS[2:0]=110 (f <sub>sys</sub> /64)	SACKS[2:0]=111 (f <sub>sys</sub> /128)
1MHz	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *	128μs *
2MHz	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *
4MHz	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *
8MHz	125ns *	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *
12MHz	83ns *	167ns *	333ns *	667ns	1.33μs	2.67μs	5.33μs	10.67μs *
16MHz	62.5ns *	125ns *	250ns *	500ns	1μs	2μs	4μs	8μs

**A/D Clock Period Examples**

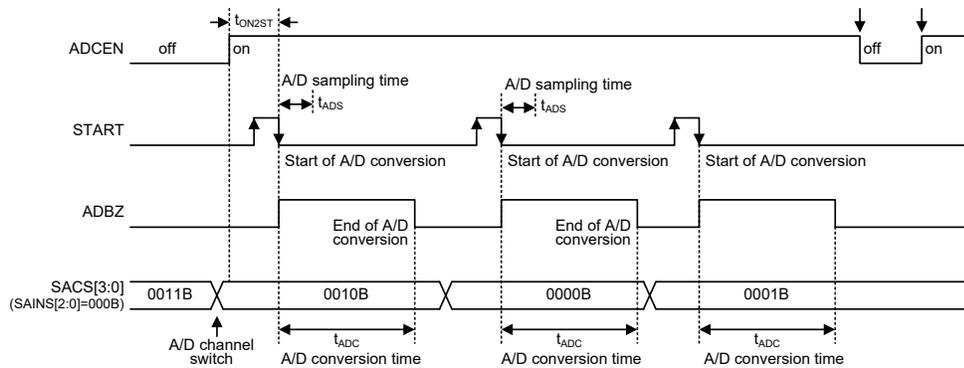
Controlling the power on/off function of the A/D converter circuitry is implemented using the ADCEN bit in the SADC0 register. This bit must be set high to power on the A/D converter. When the ADCEN bit is set high to power on the A/D converter internal circuitry, a certain delay as indicated in the timing diagram must be allowed before an A/D conversion is initiated. Even if no pins are selected for use as A/D inputs, if the ADCEN bit is high, then some power will still be consumed. In power conscious applications it is therefore recommended that the ADCEN is set low to reduce power consumption when the A/D converter function is not being used.

**Conversion Rate and Timing Diagram**

A complete A/D conversion contains two parts, data sampling and data conversion. The data sampling which is defined as t<sub>ADS</sub> takes 4 A/D clock periods and the data conversion takes 12 A/D clock periods. Therefore a total of 16 A/D clock periods for an analog signal A/D conversion which is defined as t<sub>ADC</sub> are necessary.

$$\text{Maximum single A/D conversion rate} = 1 \div (\text{A/D clock period} \times 16)$$

The accompanying diagram shows graphically the various stages involved in an external channel input signal analog to digital conversion process and its associated timing. After an A/D conversion process has been initiated by the application program, the microcontroller internal hardware will begin to carry out the conversion, during which time the program can continue with other functions. The time taken for the A/D conversion is 16 t<sub>ADCK</sub> where t<sub>ADCK</sub> is equal to the A/D clock period.



**A/D Conversion Timing – External Channel Input**

## Summary of A/D Conversion Steps

The following summarises the individual steps that should be executed in order to implement an A/D conversion process.

- Step 1  
Select the required A/D conversion clock by properly programming the SACKS2~SACKS0 bits in the SADC1 register.
- Step 2  
Enable the A/D converter by setting the ADCEN bit in the SADC0 register to “1”.
- Step 3  
Select which signal is to be connected to the internal A/D converter by correctly configuring the SAINS3~SAINS0 bits in the SADC1 register.  
Selecting the external channel input to be converted, go to Step 4.  
Selecting the internal analog signal to be converted, go to Step 5.
- Step 4  
If the A/D input signal comes from the external channel input selected by configuring the SAINS3~SAINS0 bits, the corresponding pin should be configured as A/D input function by configuring the relevant pin-shared function control bits. The desired analog channel then should be selected by configuring the SACS3~SACS0 bits. After this step, go to Step 6.
- Step 5  
If the SAINS3~SAINS0 bits are set to 0x01, 0x10, 0x11 or 10xx, the relevant internal analog signal will be selected. When the internal analog signal is selected to be converted, the external channel analog input will automatically be disconnected. Then go to Step 6.
- Step 6  
Select the A/D converter output data format by configuring the ADRFS bit.
- Step 7  
Select the A/D converter reference voltage source by configuring the SAVRS1~SAVRS0 bits in the SADC1 register.  
Select the PGA input signal and the desired PGA gain if the PGA output voltage,  $V_{VR}$ , is selected as the A/D converter reference voltage.
- Step 8  
If A/D conversion interrupt is used, the interrupt control registers must be correctly configured to ensure the A/D interrupt function is active. The master interrupt control bit, EMI, and the A/D conversion interrupt control bit, ADE, must both be set high in advance.
- Step 9  
The A/D conversion procedure can now be initialized by setting the START bit from low to high and then low again.
- Step 10  
If A/D conversion is in progress, the ADBZ flag will be set high. After the A/D conversion process is complete, the ADBZ flag will go low and then the output data can be read from SADOH and SADOL registers.

Note: When checking for the end of the conversion process, if the method of polling the ADBZ bit in the SADC0 register is used, the interrupt enable step above can be omitted.

## Programming Considerations

During microcontroller operations where the A/D converter is not being used, the A/D internal circuitry can be switched off to reduce power consumption, by setting bit ADCEN low in the SADC0 register. When this happens, the internal A/D converter circuits will not consume power irrespective of what analog voltage is applied to their input lines. If the A/D converter input lines are used as normal I/Os, then care must be taken as if the input voltage is not at a valid logic level, then this may lead to some increase in power consumption.

## A/D Conversion Function

As the device contains a 12-bit A/D converter, its full-scale converted digitised value is equal to FFFH. Since the full-scale analog input value is equal to the actual A/D converter reference voltage,  $V_{REF}$ , this gives a single bit analog input value of reference voltage value divided by 4096.

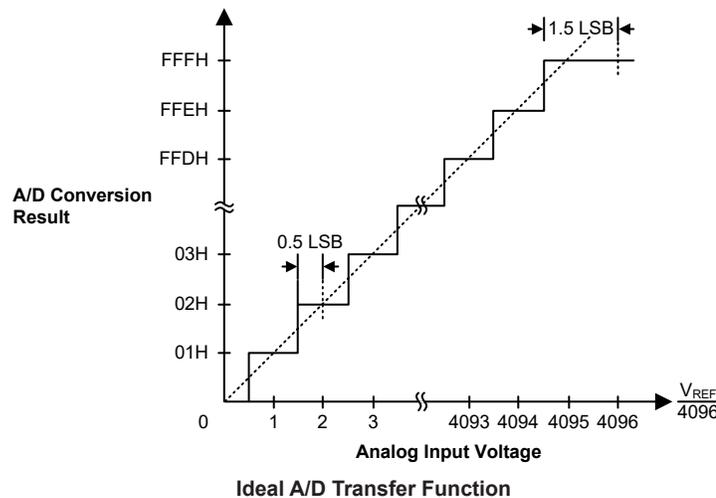
$$1 \text{ LSB} = V_{REF} \div 4096$$

The A/D Converter input voltage value can be calculated using the following equation:

$$\text{A/D input voltage} = \text{A/D output digital value} \times (V_{REF} \div 4096)$$

The diagram shows the ideal transfer function between the analog input value and the digitised output value for the A/D converter. Except for the digitised zero value, the subsequent digitised values will change at a point 0.5 LSB below where they would change without the offset, and the last full scale digitised value will change at a point 1.5 LSB below the  $V_{REF}$  level.

Note that here the  $V_{REF}$  voltage is the actual A/D converter reference voltage determined by the SAVRS1~SAVRS0 bits.



## A/D Programming Examples

The following two programming examples illustrate how to setup and implement an A/D conversion. In the first example, the method of polling the ADBZ bit in the SADC0 register is used to detect when the conversion cycle is complete, whereas in the second example, the A/D interrupt is used to determine when the conversion is complete.

### Example: using an ADBZ polling method to detect the end of conversion

```
clr ADE           ; disable ADC interrupt
mov a,03H        ; select fsys/8 as A/D clock and A/D input
mov SADC1,a      ; signal comes from external channel
mov a,00H        ; select VDD as the A/D reference voltage source
```

```

mov SADC2,a
mov a,02H          ; setup PDS0 to configure pin AN0
mov PDS0,a
mov a,20H          ; enable A/D converter and select AN0 as the A/D external
                    ; channel input

mov SADC0,a
:
start_conversion:
clr START          ; high pulse on start bit to initiate conversion
set START          ; reset A/D
clr START          ; start A/D
:
polling_EOC:
sz ADBZ            ; poll the SADC0 register ADBZ bit to detect end of A/D
                    ; conversion
jmp polling_EOC    ; continue polling
:
mov a,SADOL        ; read low byte conversion result value
mov SADOL_buffer,a ; save result to user defined register
mov a,SAD0H        ; read high byte conversion result value
mov SADOH_buffer,a ; save result to user defined register
:
jmp start_conversion ; start next A/D conversion

```

**Example: using the interrupt method to detect the end of conversion**

```

clr ADE            ; disable ADC interrupt
mov a,03H          ; select fSYS/8 as A/D clock and A/D input
mov SADC1,a        ; signal comes from external channel
mov a,00H          ; select VDD as the A/D reference voltage source
mov SADC2,a
mov a,02h          ; setup PDS0 to configure pin AN0
mov PDS0,a
mov a,20h          ; enable A/D converter and select AN0 as the A/D external
mov SADC0,a        ; channel input
:
Start_conversion:
clr START          ; high pulse on START bit to initiate conversion
set START          ; reset A/D
clr START          ; start A/D
clr ADF            ; clear ADC interrupt request flag
set ADE            ; enable ADC interrupt
set EMI            ; enable global interrupt
:
:
ADC_ISR:           ; ADC interrupt service routine
mov acc_stack,a   ; save ACC to user defined memory
mov a,STATUS
mov status_stack,a ; save STATUS to user defined memory
:
mov a,SADOL        ; read low byte conversion result value
mov SADOL_buffer,a ; save result to user defined register
mov a,SAD0H        ; read high byte conversion result value
mov SADOH_buffer,a ; save result to user defined register
:
EXIT_INT_ISR:
mov a,status_stack
mov STATUS,a      ; restore STATUS from user defined memory
mov a,acc_stack   ; restore ACC from user defined memory
reti

```

## Touch Key Function

The device provides multiple touch key functions. The touch key function is fully integrated and requires no external components, allowing touch key functions to be implemented by the simple manipulation of internal registers.

### Touch Key Structure

The touch keys are pin-shared with the I/O pins, with the desired function chosen via the corresponding pin-shared selection register bits. Keys are organised into one group, known as Module 0. The module is a fully independent set of three Touch Keys and each key has its own oscillator. The key module contains its own control logic circuits and register set.

Total Key Number	Touch Key Module	Touch Key	Shared I/O Pin
3	M0	KEY1~KEY3	PB0~PB2

**Touch Key Structure**

### Touch Key Register Definition

The touch key module, which contains three touch key functions, has its own suite registers. The following table shows the register set for the touch key module. The Mn within the register name refers to the Touch Key module number. The device has one Touch Key Module.

Register Name	Description
TKTMR	Touch key time slot 8-bit counter preload register
TKC0	Touch key function Control register 0
TKC1	Touch key function Control register 1
TK16DL	Touch key function 16-bit counter low byte
TK16DH	Touch key function 16-bit counter high byte
TKMn16DL	Touch key module n 16-bit C/F counter low byte
TKMn16DH	Touch key module n 16-bit C/F counter high byte
TKMnROL	Touch key module n reference oscillator capacitor select low byte
TKMnROH	Touch key module n reference oscillator capacitor select high byte
TKMnC0	Touch key module n Control register 0
TKMnC1	Touch key module n Control register 1

**Touch Key Function Register Definition (n=0)**

Register Name	Bit							
	7	6	5	4	3	2	1	0
TKTMR	D7	D6	D5	D4	D3	D2	D1	D0
TKC0	—	TKRCOV	TKST	TKCFOV	TK16OV	TSCS	TK16S1	TK16S0
TKC1	—	—	—	—	—	—	TKFS1	TKFS0
TK16DL	D7	D6	D5	D4	D3	D2	D1	D0
TK16DH	D15	D14	D13	D12	D11	D10	D9	D8
TKMn16DL	D7	D6	D5	D4	D3	D2	D1	D0
TKMn16DH	D15	D14	D13	D12	D11	D10	D9	D8
TKMnROL	D7	D6	D5	D4	D3	D2	D1	D0
TKMnROH	—	—	—	—	—	—	D9	D8
TKMnC0	MnMXS1	MnMXS0	MnDFEN	MnFILEN	MnSOFC	MnSOF2	MnSOF1	MnSOF0
TKMnC1	MnTSS	—	MnROEN	MnKOEN	D3	MnK3EN	MnK2EN	MnK1EN

**Touch Key Function Register List (n=0)**

• **TKTMR Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Touch key time slot 8-bit counter preload register

The touch key time slot counter preload register is used to determine the touch key time slot overflow time. The time slot unit period is obtained by a 5-bit counter and equal to 32 time slot clock cycles. Therefore, the time slot counter overflow time is equal to the following equation shown.

Time slot counter overflow time =  $(256 - \text{TKTMR}[7:0]) \times 32 t_{\text{TSC}}$ , where  $t_{\text{TSC}}$  is the time slot counter clock period.

• **TKC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	TKRCOV	TKST	TKCFOV	TK16OV	TSCS	TK16S1	TK16S0
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as “0”

Bit 6 **TKRCOV**: Touch key time slot counter overflow flag

0: No overflow occurs

1: Overflow occurs

This bit can be accessed by application program. When this bit is set by touch key time slot counter overflow, the corresponding touch key interrupt request flag will be set. However, if this bit is set by application program, the touch key interrupt request flag will not be affected. Therefore, this bit cannot be set by application program but must be cleared to 0 by application program.

If the module 0 or all module (selected by the TSCS bit) time slot counter is overflow, the TKRCOV bit and the Touch Key Interrupt request flag, TKMF, will be set and all module key oscillators and reference oscillators will automatically stop. The touch key module 16-bit C/F counter, touch key function 16-bit counter, 5-bit time slot unit period counter and 8-bit time slot counter will be automatically switched off.

Bit 5 **TKST**: Touch key detection Start control

0: Stopped or no operation

0→1: Start detection

In all modules the touch key module 16-bit C/F counter, touch key function 16-bit counter and 5-bit time slot unit period counter will automatically be cleared when this bit is cleared to zero. However, the 8-bit programmable time slot counter will not be cleared. When this bit is changed from low to high, the touch key module 16-bit C/F counter, touch key function 16-bit counter, 5-bit time slot unit period counter and 8-bit time slot counter will be switched on together with the key and reference oscillators to drive the corresponding counters.

Bit 4 **TKCFOV**: Touch key module 16-bit C/F counter overflow flag

0: No overflow occurs

1: Overflow occurs

This bit is set high by the touch key module 16-bit C/F counter overflow and must be cleared to 0 by application programs.

Bit 3 **TK16OV**: Touch key function 16-bit counter overflow flag

0: No overflow occurs

1: Overflow occurs

This bit is set high by the touch key function 16-bit counter overflow and must be cleared to 0 by application programs.

- Bit 2      **TSCS**: Touch key time slot counter select  
           0: Each touch key module uses its own time slot counter  
           1: All touch key modules use Module 0 time slot counter
- Bit 1~0    **TK16S1~TK16S0**: Touch key function 16-bit counter clock source select  
           00:  $f_{SYS}$   
           01:  $f_{SYS}/2$   
           10:  $f_{SYS}/4$   
           11:  $f_{SYS}/8$

• **TKC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	TKFS1	TKFS0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	1	1

- Bit 7~2    Unimplemented, read as “0”
- Bit 1~0    **TKFS1~TKFS0**: Touch Key oscillator and Reference oscillator frequency select  
           00: 1MHz  
           01: 3MHz  
           10: 7MHz  
           11: 11MHz

• **TK16DH/TK16DL – Touch Key Function 16-bit Counter Register Pair**

Register	TK16DH								TK16DL							
Bit	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

This register pair is used to store the touch key function 16-bit counter value. This 16-bit counter can be used to calibrate the reference or key oscillator frequency. When the touch key time slot counter overflows, this 16-bit counter will be stopped and the counter content will be unchanged. This register pair will be cleared to zero when the TKST bit is cleared to zero.

• **TKMn16DH/TKMn16DL – Touch Key Module n 16-bit C/F Counter Register Pair**

Register	TKMn16DH								TKMn16DL							
Bit	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

This register pair is used to store the touch key module n 16-bit C/F counter value. This 16-bit C/F counter will be stopped and the counter content will be kept unchanged when the touch key time slot counter overflows. This register pair will be cleared to zero when the TKST bit is cleared to zero.

• **TKMnROH/TKMnROL – Touch Key Module n Reference Oscillator Capacitor Select Register Pair**

Register	TKMnROH								TKMnROL							
Bit	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
R/W	—	—	—	—	—	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	—	—	—	0	0	0	0	0	0	0	0	0	0

This register pair is used to store the touch key module n reference oscillator capacitor value.

The reference oscillator internal capacitor value=(TKMnRO[9:0]×50pF)/1024

• **TKMnC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	MnMXS1	MnMXS0	MnDFEN	MnFILEN	MnSOFC	MnSOF2	MnSOF1	MnSOF0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **MnMXS1~MnMXS0**: Multiplexer Key Select

Bit	Touch Key Module Number
<b>MnMXS[1:0]</b>	<b>M0</b>
00	KEY1
01	KEY2
10	KEY3
11	Reserved

Bit 5 **MnDFEN**: Touch key module n multi-frequency control

0: Disable  
1: Enable

This bit is used to control the touch key oscillator frequency doubling function. When this bit is set to 1, the key oscillator frequency will be doubled.

Bit 4 **MnFILEN**: Touch key module n filter function control

0: Disable  
1: Enable

Bit 3 **MnSOFC**: Touch key module n C-to-F oscillator frequency hopping function control select

0: Controlled by the MnSOF2~MnSOF0  
1: Controlled by hardware circuit

This bit is used to select the touch key oscillator frequency hopping function control method. When this bit is set to 1, the key oscillator frequency hopping function is controlled by the hardware circuit regardless of the MnSOF2~MnSOF0 bits value.

Bit 2~0 **MnSOF2~MnSOF0**: Touch key module n Reference and Key oscillators hopping frequency select (MnSOFC=0)

000: 1.020MHz  
001: 1.040MHz  
010: 1.059MHz  
011: 1.074MHz  
100: 1.085MHz  
101: 1.099MHz  
110: 1.111MHz  
111: 1.125MHz

These bits are used to select the touch key oscillator frequency for the hopping function. Note that these bits are only available when the MnSOFC bit is cleared to 0.

The frequency mentioned here will be changed when the external or internal capacitor is with different values. If the touch key operates at 1MHz frequency, users can adjust the frequency in scale when any other frequency is selected.

• **TKMnC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	MnTSS	—	MnROEN	MnKOEN	D3	MnK3EN	MnK2EN	MnK1EN
R/W	R/W	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	—	0	0	0	0	0	0

Bit 7 **MnTSS**: Touch key module n time slot counter clock source select  
 0: Touch key module n reference oscillator  
 1:  $f_{sys}/4$

Bit 6 Unimplemented, read as “0”

Bit 5 **MnROEN**: Touch key module n Reference oscillator enable control  
 0: Disable  
 1: Enable

Bit 4 **MnKOEN**: Touch key module n Key oscillator enable control  
 0: Disable  
 1: Enable

Bit 3 **D3**: Reserved bit, should remain unchanged after power-on reset

Bit 2 **MnK3EN**: Touch key module n Key 3 enable control

MnK3EN	Touch Key Module n – Mn
	M0
0: Disable	I/O or other functions
1: Enable	KEY3

Bit 1 **MnK2EN**: Touch key module n Key 2 enable control

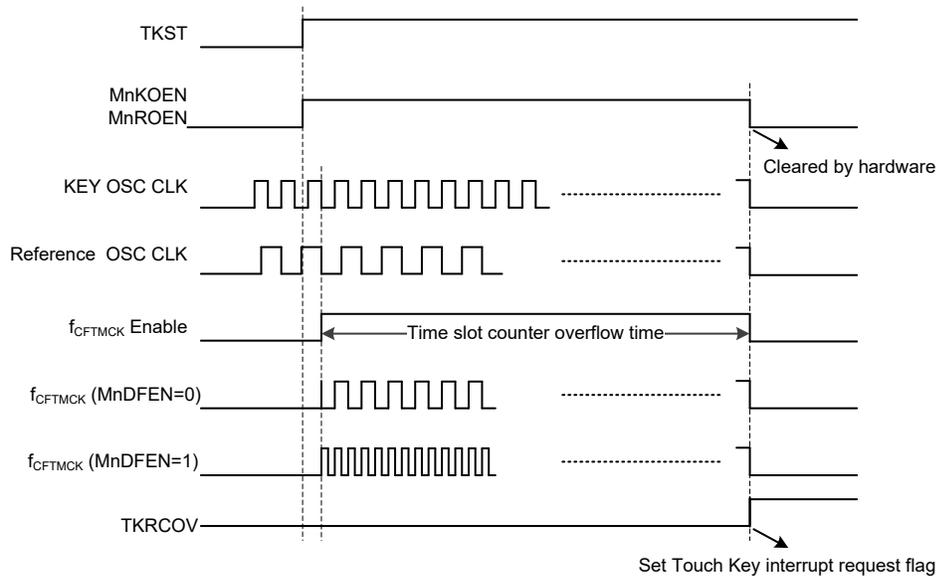
MnK2EN	Touch Key Module n – Mn
	M0
0: Disable	I/O or other functions
1: Enable	KEY2

Bit 0 **MnK1EN**: Touch key module n Key 1 enable control

MnK1EN	Touch Key Module n – Mn
	M0
0: Disable	I/O or other functions
1: Enable	KEY1

**Touch Key Operation**

When a finger touches or is in proximity to a touch pad, the capacitance of the pad will increase. By using this capacitance variation to change slightly the frequency of the internal sensing oscillator, touch actions can be sensed by measuring these frequency changes. Using an internal programmable divider the reference clock is used to generate a fixed time period. By counting a number of generated clock cycles from the sensing oscillator during this fixed time period touch key actions can be determined.



**Touch Key Timing Diagram**

The touch key module contains three touch key inputs which are shared with logical I/O pins, and the desired function is selected using the relevant pin-shared control register bits. Each touch key has its own independent sensing oscillator. Therefore, there are three sensing oscillators within the touch key module.

During the reference clock fixed interval, the number of clock cycles generated by the sensing oscillator is measured, and it is this value that is used to determine if a touch action has been made or not. At the end of the fixed reference clock time interval a Touch Key interrupt signal will be generated.

Using the TSCS bit in the TKC0 register can select the module 0 time slot counter as the time slot counter for all modules. All modules use the same started signal, TKST, in the TKC0 register. The touch key module 16-bit C/F counter, touch key function 16-bit counter, 5-bit time slot unit period counter in all modules will be automatically cleared when the TKST bit is cleared to zero, but the 8-bit programmable time slot counter will not be cleared. The overflow time is setup by user. When the TKST bit changes from low to high, the 16-bit C/F counter, touch key function 16-bit counter, 5-bit time slot unit period counter and 8-bit time slot timer counter will be automatically switched on.

The key oscillator and reference oscillator in all modules will be automatically stopped and the 16-bit C/F counter, touch key function 16-bit counter, 5-bit time slot unit period counter and 8-bit time slot timer counter will be automatically switched off when the time slot counter overflows. The clock source for the time slot counter is sourced from the reference oscillator or  $f_{SYS}/4$  which is selected using the MnTSS bit in the TKMnC1 register. The reference oscillator and key oscillator will be enabled by setting the MnROEN bit and MnKOEN bits in the TKMnC1 register.

When the time slot counter in all the touch key modules or in the touch key module 0 overflows, an actual touch key interrupt will take place. The touch keys mentioned here are the keys which are enabled.

## Touch Key Interrupt

The touch key only has single interrupt, when the time slot counter in all the touch key modules or in the touch key module 0 overflows, an actual touch key interrupt will take place. The touch keys mentioned here are the keys which are enabled. The 16-bit C/F counter, 16-bit counter, 5-bit time slot unit period counter and 8-bit time slot counter in all modules will be automatically cleared. More details regarding the touch key interrupt is located in the interrupt section of the datasheet.

## Programming Considerations

After the relevant registers are setup, the touch key detection process is initiated by changing the TKST bit from low to high. This will enable and synchronise all relevant oscillators. The TKRCOV flag which is the time slot counter flag will go high when the counter overflows. When this happens an interrupt signal will be generated. As the TKRCOV flag will not be automatically cleared, it has to be cleared by the application program.

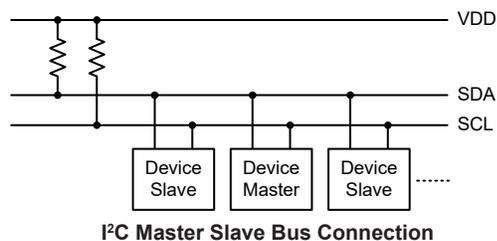
The TKCFOV flag which is the 16-bit C/F counter overflow flag will go high when any of the Touch Key Module 16-bit C/F counter overflows. As this flag will not be automatically cleared, it has to be cleared by the application program.

The TK16OV flag which is the 16-bit counter overflow flag will go high when the 16-bit counter overflows. As this flag will not be automatically cleared, it has to be cleared by the application program.

When the external touch key size and layout are defined, their related capacitances will then determine the sensor oscillator frequency.

## I<sup>2</sup>C Interface

The I<sup>2</sup>C interface is used to communicate with external peripheral devices such as sensors, EEPROM memory etc. Originally developed by Philips, it is a two line low speed serial interface for synchronous serial data transfer. The advantage of only two lines for communication, relatively simple communication protocol and the ability to accommodate multiple devices on the same bus has made it an extremely popular interface type for many applications.

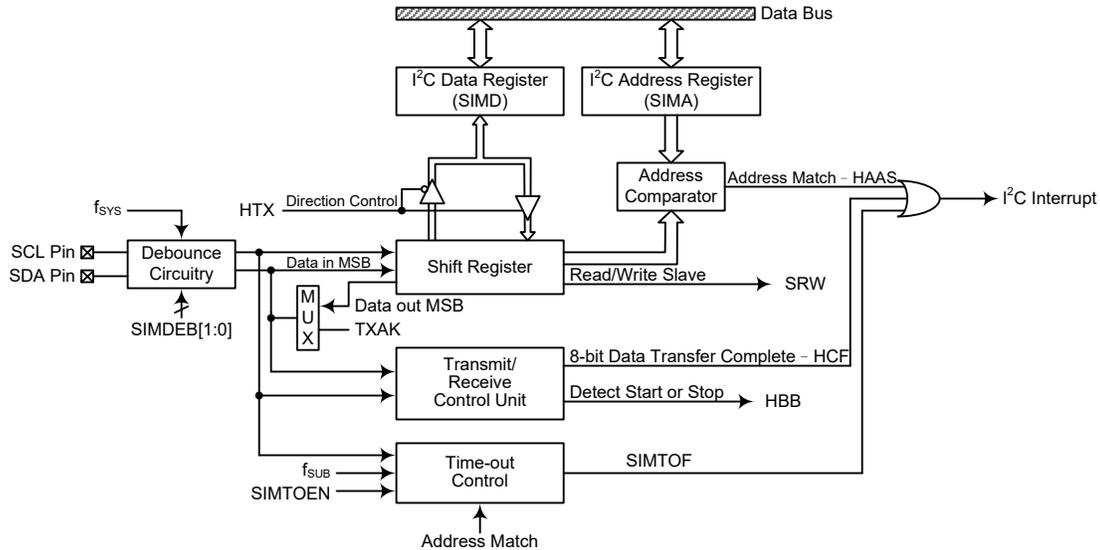


## I<sup>2</sup>C Interface Operation

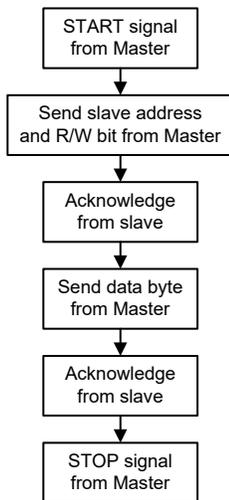
The I<sup>2</sup>C serial interface is a two line interface, a serial data line, SDA, and serial clock line, SCL. As many devices may be connected together on the same bus, their outputs are both open drain types. For this reason it is necessary that external pull-high resistors are connected to these outputs. Note that no chip select line exists, as each device on the I<sup>2</sup>C bus is identified by a unique address which will be transmitted and received on the I<sup>2</sup>C bus.

When two devices communicate with each other on the bidirectional I<sup>2</sup>C bus, one is known as the master device and one as the slave device. Both master and slave can transmit and receive data, however, it is the master device that has overall control of the bus. For the device, which only operates in slave mode, there are two methods of transferring data on the I<sup>2</sup>C bus, the slave transmit

mode and the slave receive mode. The pull-high control function pin-shared with SCL/SDA pin is still applicable even if I<sup>2</sup>C device is activated and the related internal pull-high function could be controlled by its corresponding pull-high control register.



I<sup>2</sup>C Block Diagram



I<sup>2</sup>C Interface Operation

The SIMDEB1 and SIMDEB0 bits determine the debounce time of the I<sup>2</sup>C interface. This uses the internal clock to in effect add a debounce time to the external clock to reduce the possibility of glitches on the clock line causing erroneous operation. The debounce time, if selected, can be chosen to be either 2 or 4 system clocks. To achieve the required I<sup>2</sup>C data transfer speed, there exists a relationship between the system clock,  $f_{SYS}$ , and the I<sup>2</sup>C debounce time. For either the I<sup>2</sup>C Standard or Fast mode operation, users must take care of the selected system clock frequency and the configured debounce time to match the criterion shown in the following table.

I <sup>2</sup> C Debounce Time Selection	I <sup>2</sup> C Standard Mode (100kHz)	I <sup>2</sup> C Fast Mode (400kHz)
No Debounce	f <sub>sys</sub> >2MHz	f <sub>sys</sub> >4MHz
2 system clock debounce	f <sub>sys</sub> >4MHz	f <sub>sys</sub> >8MHz
4 system clock debounce	f <sub>sys</sub> >4MHz	f <sub>sys</sub> >8MHz

**I<sup>2</sup>C Minimum f<sub>sys</sub> Frequency Requirements**

### I<sup>2</sup>C Registers

There are three control registers associated with the I<sup>2</sup>C bus, SIMC0, SIMC1 and SIMTOC, one address register SIMA and one data register, SIMD.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SIMC0	SIM2	SIM1	SIM0	—	SIMDEB1	SIMDEB0	SIMEN	D0
SIMC1	HCF	HAAS	HBB	HTX	TXAK	SRW	IAMWU	RXAK
SIMD	D7	D6	D5	D4	D3	D2	D1	D0
SIMA	SIMA6	SIMA5	SIMA4	SIMA3	SIMA2	SIMA1	SIMA0	D0
SIMTOC	SIMTOEN	SIMTOF	SIMTOS5	SIMTOS4	SIMTOS3	SIMTOS2	SIMTOS1	SIMTOS0

**I<sup>2</sup>C Register List**

### I<sup>2</sup>C Data Register

The SIMD register is used to store the data being transmitted and received. Before the device writes data to the I<sup>2</sup>C bus, the actual data to be transmitted must be placed in the SIMD register. After the data is received from the I<sup>2</sup>C bus, the device can read it from the SIMD register. Any transmission or reception of data from the I<sup>2</sup>C bus must be made via the SIMD register.

#### • SIMD Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	x	x	x	x	x	x	x	x

“x”: Unknown

Bit 7~0     **D7~D0**: I<sup>2</sup>C data register bit 7 ~ bit 0

### I<sup>2</sup>C Address Register

The SIMA register is the location where the 7-bit slave address of the slave device is stored. Bits 7~1 of the SIMA register define the device slave address. Bit 0 is not defined. When a master device, which is connected to the I<sup>2</sup>C bus, sends out an address, which matches the slave address in the SIMA register, the slave device will be selected.

#### • SIMA Register

Bit	7	6	5	4	3	2	1	0
Name	SIMA6	SIMA5	SIMA4	SIMA3	SIMA2	SIMA1	SIMA0	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~1     **SIMA6~SIMA0**: I<sup>2</sup>C slave address

SIMA6~SIMA0 is the I<sup>2</sup>C slave address bit 6 ~ bit 0.

Bit 0     **D0**: Reserved bit, can be read or written

### I<sup>2</sup>C Control Registers

There are three control registers for the I<sup>2</sup>C interface, SIMC0, SIMC1 and SIMTOC. The SIMC0 register is used to control the enable/disable function and to select the I<sup>2</sup>C slave mode and debounce time. The SIMC1 register contains the relevant flags which are used to indicate the I<sup>2</sup>C communication status. Another register, SIMTOC, is used to control the I<sup>2</sup>C time-out function and is described in the corresponding section.

#### • SIMC0 Register

Bit	7	6	5	4	3	2	1	0
Name	SIM2	SIM1	SIM0	—	SIMDEB1	SIMDEB0	SIMEN	D0
R/W	R/W	R/W	R/W	—	R/W	R/W	R/W	R/W
POR	1	1	1	—	0	0	0	0

Bit 7~5 **SIM2~SIM0**: I<sup>2</sup>C operating mode control

000~101, 111: Unused mode

110: I<sup>2</sup>C slave mode

These bits setup the I<sup>2</sup>C operating mode.

Bit 4 Unimplemented, read as “0”

Bit 3~2 **SIMDEB1~SIMDEB0**: I<sup>2</sup>C debounce time selection

00: No debounce

01: 2 system clock debounce

1x: 4 system clock debounce

These bits are used to select the I<sup>2</sup>C debounce time when the I<sup>2</sup>C interface function is selected by setting the SIM2~SIM0 bits to “110”.

Bit 1 **SIMEN**: I<sup>2</sup>C enable control

0: Disable

1: Enable

The bit is the overall on/off control for the I<sup>2</sup>C interface. When the SIMEN bit is cleared to zero to disable the I<sup>2</sup>C interface, the SDA and SCL lines will lose their I<sup>2</sup>C function and the I<sup>2</sup>C operating current will be reduced to a minimum value. When the bit is high the I<sup>2</sup>C interface is enabled. If the I<sup>2</sup>C interface function is selected via the SIM2~SIM0 bits and the SIMEN bit changes from low to high, the contents of the I<sup>2</sup>C control bits such as HTX and TXAK will remain at the previous settings and should therefore be first initialised by the application program while the relevant I<sup>2</sup>C flags such as HCF, HAAS, HBB, SRW and RXAK will be set to their default states.

Bit 0 **D0**: Reserved, cannot be used

#### • SIMC1 Register

Bit	7	6	5	4	3	2	1	0
Name	HCF	HAAS	HBB	HTX	TXAK	SRW	IAMWU	RXAK
R/W	R	R	R	R/W	R/W	R	R/W	R
POR	1	0	0	0	0	0	0	1

Bit 7 **HCF**: I<sup>2</sup>C bus data transfer completion flag

0: Data is being transferred

1: Completion of an 8-bit data transfer

The HCF flag is the data transfer flag. This flag will be zero when data is being transferred. Upon completion of an 8-bit data transfer the flag will go high and an interrupt will be generated. Below is an example of the flow of a two-byte I<sup>2</sup>C data transfer.

First, the I<sup>2</sup>C slave device receives a start signal from I<sup>2</sup>C master and then HCF bit is automatically cleared to zero. Second, the I<sup>2</sup>C slave device finishes receiving the 1st data byte and then the HCF bit is automatically set high. Third, users read the 1st data byte from SIMD register by the application program and then the HCF bit is

automatically cleared to zero. Fourth, the I<sup>2</sup>C slave device finishes receiving the 2nd data byte and then HCF bit is automatically set high and so on. Finally, the I<sup>2</sup>C slave device receives a stop signal from the I<sup>2</sup>C master and then the HCF bit is automatically set high.

- Bit 6 **HAAS**: I<sup>2</sup>C bus address match flag  
0: Not address match  
1: Address match

This flag is used to determine if the slave device address is the same as the master transmit address. If the addresses match then this bit will be high, if there is no match then the flag will be low.

- Bit 5 **HBB**: I<sup>2</sup>C bus busy flag  
0: I<sup>2</sup>C Bus is not busy  
1: I<sup>2</sup>C Bus is busy

The HBB flag is the I<sup>2</sup>C busy flag. This flag will be “1” when the I<sup>2</sup>C bus is busy which will occur when a START signal is detected. The flag will be set to “0” when the bus is free which will occur when a STOP signal is detected.

- Bit 4 **HTX**: I<sup>2</sup>C slave device is transmitter or receiver selection  
0: Slave device is the receiver  
1: Slave device is the transmitter

- Bit 3 **TXAK**: I<sup>2</sup>C bus transmit acknowledge flag  
0: Slave send acknowledge flag  
1: Slave do not send acknowledge flag

The TXAK bit is the transmit acknowledge flag. After the slave device receipt of 8 bits of data, this bit will be transmitted to the bus on the 9th clock from the slave device. The slave device must always set TXAK bit to “0” before further data is received.

- Bit 2 **SRW**: I<sup>2</sup>C slave read/write flag  
0: Slave device should be in receive mode  
1: Slave device should be in transmit mode

The SRW flag is the I<sup>2</sup>C Slave Read/Write flag. This flag determines whether the master device wishes to transmit or receive data from the I<sup>2</sup>C bus. When the transmitted address and slave address is match, that is when the HAAS flag is set high, the slave device will check the SRW flag to determine whether it should be in transmit mode or receive mode. If the SRW flag is high, the master is requesting to read data from the bus, so the slave device should be in transmit mode. When the SRW flag is zero, the master will write data to the bus, therefore the slave device should be in receive mode to read this data.

- Bit 1 **IAMWU**: I<sup>2</sup>C address match wake-up control  
0: Disable  
1: Enable

This bit should be set to 1 to enable the I<sup>2</sup>C address match wake up from the SLEEP or IDLE Mode. If the IAMWU bit has been set before entering either the SLEEP or IDLE mode to enable the I<sup>2</sup>C address match wake up, then this bit must be cleared by the application program after wake-up to ensure correction device operation.

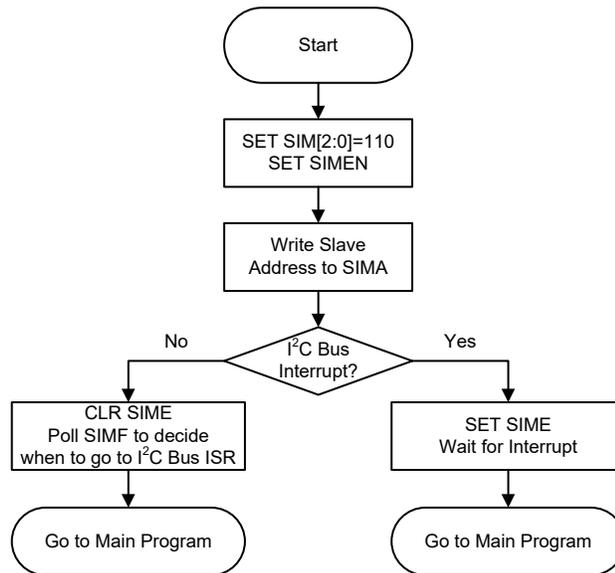
- Bit 0 **RXAK**: I<sup>2</sup>C bus receive acknowledge flag  
0: Slave receive acknowledge flag  
1: Slave does not receive acknowledge flag

The RXAK flag is the receiver acknowledge flag. When the RXAK flag is “0”, it means that a acknowledge signal has been received at the 9th clock, after 8 bits of data have been transmitted. When the slave device in the transmit mode, the slave device checks the RXAK flag to determine if the master receiver wishes to receive the next byte. The slave transmitter will therefore continue sending out data until the RXAK flag is “1”. When this occurs, the slave transmitter will release the SDA line to allow the master to send a STOP signal to release the I<sup>2</sup>C Bus.

## I<sup>2</sup>C Bus Communication

Communication on the I<sup>2</sup>C bus requires four separate steps, a START signal, a slave device address transmission, a data transmission and finally a STOP signal. When a START signal is placed on the I<sup>2</sup>C bus, all devices on the bus will receive this signal and be notified of the imminent arrival of data on the bus. The first seven bits of the data will be the slave address with the first bit being the MSB. If the address of the slave device matches that of the transmitted address, the HAAS bit in the SIMC1 register will be set and an I<sup>2</sup>C interrupt will be generated. After entering the interrupt service routine, the slave device must first check the condition of the HAAS and SIMTOF bits to determine whether the interrupt source originates from an address match or from the completion of an 8-bit data transfer completion or from the I<sup>2</sup>C bus time-out occurrence. During a data transfer, note that after the 7-bit slave address has been transmitted, the following bit, which is the 8th bit, is the read/write bit whose value will be placed in the SRW bit. This bit will be checked by the slave device to determine whether to go into transmit or receive mode. Before any transfer of data to or from the I<sup>2</sup>C bus, the microcontroller must initialise the bus, the following are steps to achieve this:

- Step 1  
Set the SIM2~SIM0 and SIMEN bits in the SIMC0 register to “110” and “1” respectively to enable the I<sup>2</sup>C bus.
- Step 2  
Write the slave address of the device to the I<sup>2</sup>C bus address register SIMA.
- Step 3  
Set the I<sup>2</sup>C interrupt enable bit of the interrupt control register to enable the I<sup>2</sup>C interrupt.



**I<sup>2</sup>C Bus Initialisation Flow Chart**

## I<sup>2</sup>C Bus Start Signal

The START signal can only be generated by the master device connected to the I<sup>2</sup>C bus and not by the slave device. This START signal will be detected by all devices connected to the I<sup>2</sup>C bus. When detected, this indicates that the I<sup>2</sup>C bus is busy and therefore the HBB bit will be set. A START condition occurs when a high to low transition on the SDA line takes place when the SCL line remains high.

### **I<sup>2</sup>C Slave Address**

The transmission of a START signal by the master will be detected by all devices on the I<sup>2</sup>C bus. To determine which slave device the master wishes to communicate with, the address of the slave device will be sent out immediately following the START signal. All slave devices, after receiving this 7-bit address data, will compare it with their own 7-bit slave address. If the address sent out by the master matches the internal address of the microcontroller slave device, then an internal I<sup>2</sup>C bus interrupt signal will be generated. The next bit following the address, which is the 8th bit, defines the read/write status and will be saved to the SRW bit of the SIMC1 register. The slave device will then transmit an acknowledge bit, which is a low level, as the 9th bit. The slave device will also set the status flag HAAS when the addresses match.

As an I<sup>2</sup>C bus interrupt can come from three sources, when the program enters the interrupt subroutine, the HAAS and SIMTOF bits should be examined to see whether the interrupt source has come from a matching slave address or from the completion of a data byte transfer or from the I<sup>2</sup>C bus time-out occurrence. When a slave address is matched, the device must be placed in either the transmit mode and then write data to the SIMD register, or in the receive mode where it must implement a dummy read from the SIMD register to release the SCL line.

### **I<sup>2</sup>C Bus Read/Write Signal**

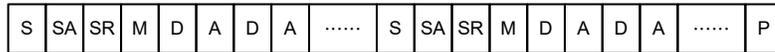
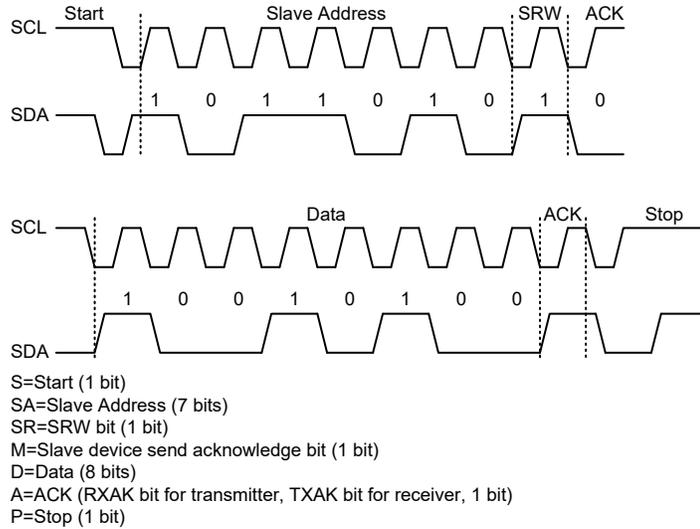
The SRW bit in the SIMC1 register defines whether the master device wishes to read data from the I<sup>2</sup>C bus or write data to the I<sup>2</sup>C bus. The slave device should examine this bit to determine if it is to be a transmitter or a receiver. If the SRW flag is “1” then this indicates that the master device wishes to read data from the I<sup>2</sup>C bus, therefore the slave device must be setup to send data to the I<sup>2</sup>C bus as a transmitter. If the SRW flag is “0” then this indicates that the master wishes to send data to the I<sup>2</sup>C bus, therefore the slave device must be setup to read data from the I<sup>2</sup>C bus as a receiver.

### **I<sup>2</sup>C Bus Slave Address Acknowledge Signal**

After the master has transmitted a calling address, any slave device on the I<sup>2</sup>C bus, whose own internal address matches the calling address, must generate an acknowledge signal. The acknowledge signal will inform the master that a slave device has accepted its calling address. If no acknowledge signal is received by the master then a STOP signal must be transmitted by the master to end the communication. When the HAAS flag is high, the addresses have matched and the slave device must check the SRW flag to determine if it is to be a transmitter or a receiver. If the SRW flag is high, the slave device should be setup to be a transmitter so the HTX bit in the SIMC1 register should be set to “1”. If the SRW flag is low, then the microcontroller slave device should be setup as a receiver and the HTX bit in the SIMC1 register should be set to “0”.

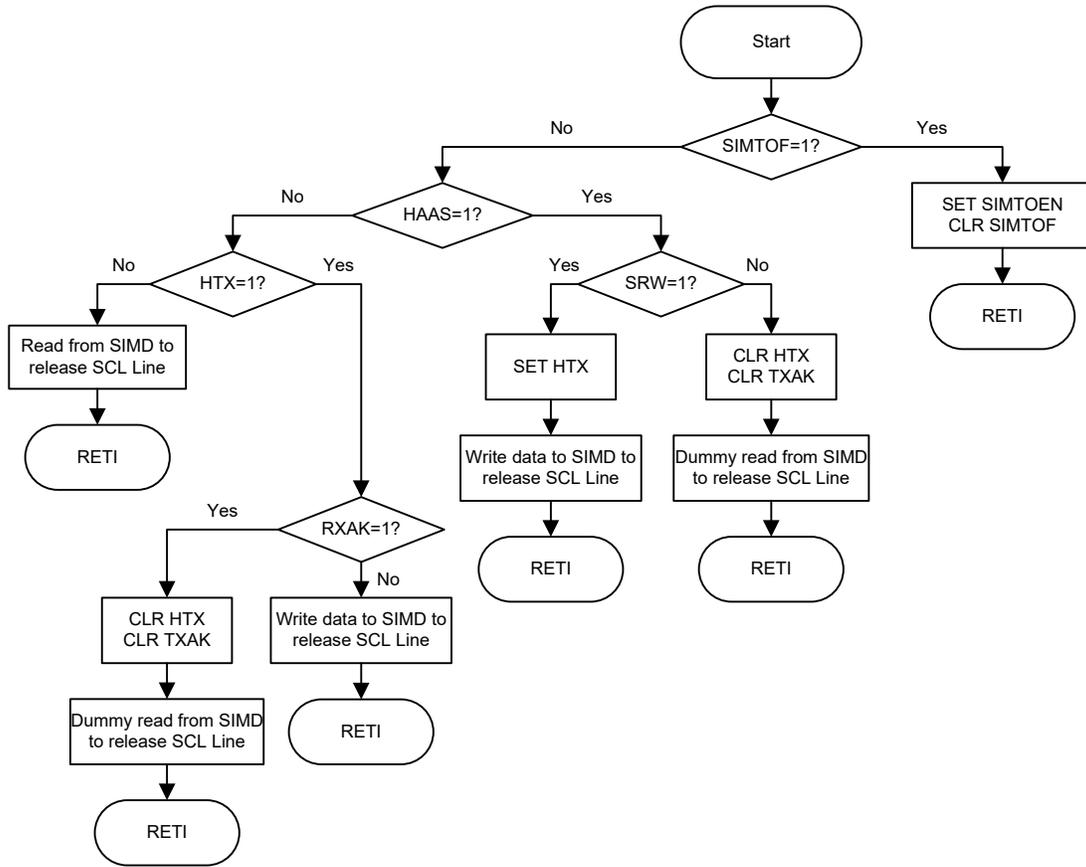
### **I<sup>2</sup>C Bus Data and Acknowledge Signal**

The transmitted data is 8-bit wide and is transmitted after the slave device has acknowledged receipt of its slave address. The order of serial bit transmission is the MSB first and the LSB last. After receipt of 8 bits of data, the receiver must transmit an acknowledge signal, level “0”, before it can receive the next data byte. If the slave transmitter does not receive an acknowledge bit signal from the master receiver, then the slave transmitter will release the SDA line to allow the master to send a STOP signal to release the I<sup>2</sup>C Bus. The corresponding data will be stored in the SIMD register. If setup as a transmitter, the slave device must first write the data to be transmitted into the SIMD register. If setup as a receiver, the slave device must read the transmitted data from the SIMD register. When the slave receiver receives the data byte, it must generate an acknowledge bit, known as TXAK, on the 9th clock. The slave device, which is setup as a transmitter will check the RXAK bit in the SIMC1 register to determine if it is to send another data byte, if not then it will release the SDA line and await the receipt of a STOP signal from the master.



Note: When a slave address is matched, the device must be placed in either the transmit mode and then write data to the SIMD register, or in the receive mode where it must implement a dummy read from the SIMD register to release the SCL line.

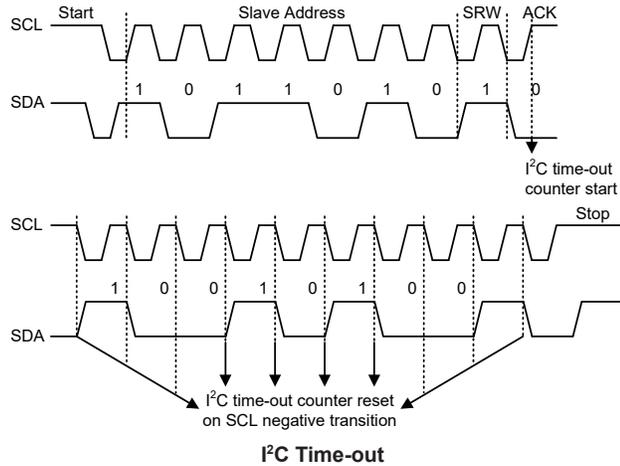
**I<sup>2</sup>C Communication Timing Diagram**



**I<sup>2</sup>C Bus ISR Flow Chart**

### I<sup>2</sup>C Time-out Control

In order to reduce the problem of I<sup>2</sup>C lockup due to reception of erroneous clock sources, a time-out function is provided. If the clock source to the I<sup>2</sup>C is not received for a while, then the I<sup>2</sup>C circuitry and registers will be reset after a certain time-out period. The time-out counter starts counting on an I<sup>2</sup>C bus “START” & “address match” condition, and is cleared by an SCL falling edge. Before the next SCL falling edge arrives, if the time elapsed is greater than the time-out setup by the SIMTOC register, then a time-out condition will occur. The time-out function will stop when an I<sup>2</sup>C “STOP” condition occurs.



When an I<sup>2</sup>C time-out counter overflow occurs, the counter will stop and the SIMTOEN bit will be cleared to zero and the SIMTOF bit will be set high to indicate that a time-out condition has occurred. The time-out condition will also generate an interrupt which uses the I<sup>2</sup>C interrupt vector. When an I<sup>2</sup>C time-out occurs, the I<sup>2</sup>C internal circuitry will be reset and the registers will be reset into the following condition:

Registers	After I <sup>2</sup> C Time-out
SIMD, SIMA, SIMC0	No change
SIMC1	Reset to POR condition

**I<sup>2</sup>C Registers after Time-out**

The SIMTOF flag can be cleared by the application program. There are 64 time-out periods which can be selected using SIMTOS bit field in the SIMTOC register. The time-out time is given by the formula:  $((1\sim64)\times32)/f_{SUB}$ . This gives a time-out period which ranges from about 1ms to 64ms.

#### • SIMTOC Register

Bit	7	6	5	4	3	2	1	0
Name	SIMTOEN	SIMTOF	SIMTOS5	SIMTOS4	SIMTOS3	SIMTOS2	SIMTOS1	SIMTOS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **SIMTOEN**: I<sup>2</sup>C time-out control  
 0: Disable  
 1: Enable

Bit 6 **SIMTOF**: I<sup>2</sup>C time-out flag  
 0: No time-out occurred  
 1: Time-out occurred

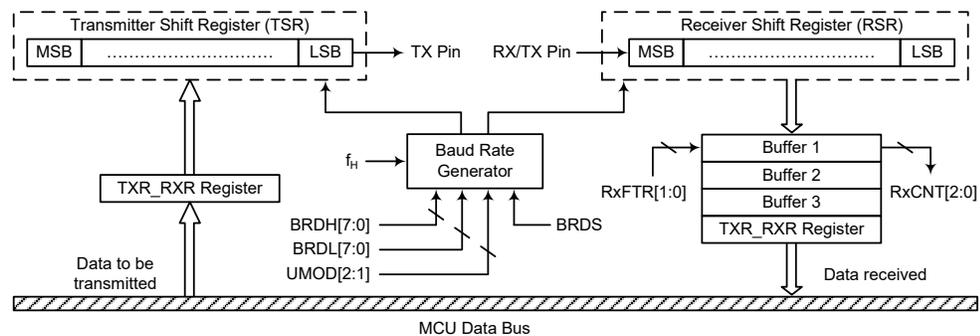
Bit 5~0 **SIMTOS5~SIMTOS0**: I<sup>2</sup>C time-out period selection  
 I<sup>2</sup>C time-out clock source is  $f_{SUB}/32$ .  
 I<sup>2</sup>C time-out time is equal to  $(SIMTOS[5:0]+1)\times(32/f_{SUB})$ .

## UART Interface

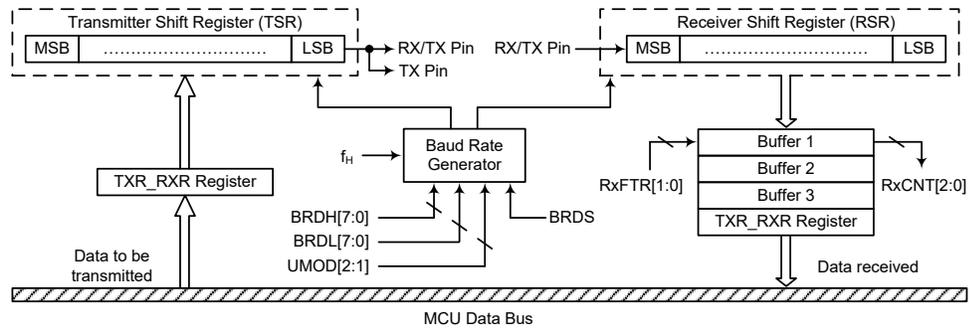
The device contains an integrated full-duplex or half-duplex asynchronous serial communications UART interface that enables communication with external devices that contain a serial interface. The UART function has many features and can transmit and receive data serially by transferring a frame of data with eight or nine data bits per transmission as well as being able to detect errors when the data is overwritten or incorrectly framed. The UART function possesses its own internal interrupt which can be used to indicate when a reception occurs or when a transmission terminates.

The integrated UART function contains the following features:

- Full-duplex or half-duplex (single wire mode) asynchronous communication
- 8 or 9 bits character length
- Even, odd, mark, space or no parity options
- One or two stop bits configurable for receiver
- Two stop bits for transmitter
- Baud rate generator with 16-bit prescaler
- Parity, framing, noise and overrun error detection
- Support for interrupt on address detect (last character bit=1)
- Separately enabled transmitter and receiver
- 4-byte Deep FIFO Receive Data Buffer
- 1-byte Deep FIFO Transmit Data Buffer
- RX/TX pin wake-up function
- Transmit and receive interrupts
- Interrupts can be triggered by the following conditions:
  - ♦ Transmitter Empty
  - ♦ Transmitter Idle
  - ♦ Receiver reaching FIFO trigger level
  - ♦ Receiver Overrun
  - ♦ Address Mode Detect



**UART Data Transfer Block Diagram – SWM=0**



**UART Data Transfer Block Diagram – SWM=1**

### UART External Pins

To communicate with an external serial interface, the internal UART has two external pins known as TX and RX/TX, which are pin-shared with I/O or other pin functions. The TX and RX/TX pin function should first be selected by the corresponding pin-shared function selection register before the UART function is used. Along with the UARTEN bit, the TXEN and RXEN bits, if set, will configure these pins to transmitter output and receiver input conditions. At this time the internal pull-high resistor related to the transmitter output pin will be disabled, while the internal pull-high resistor related to the receiver input pin is controlled by the corresponding I/O pull-high function control bit. When the TX or RX/TX pin function is disabled by clearing the UARTEN, TXEN or RXEN bit, the TX or RX/TX pin will be set to a floating state. At this time whether the internal pull-high resistor is connected to the TX or RX/TX pin or not is determined by the corresponding I/O pull-high function control bit.

### UART Single Wire Mode

The UART function also supports the Single Wire Mode communication which is selected using the SWM bit in the UCR3 register. When the SWM bit is set high, the UART function will be in the single wire mode. In the single wire mode, a single RX/TX pin can be used to transmit and receive data depending upon the corresponding control bits. When the RXEN bit is set high, the RX/TX pin is used as a receiver pin. When the RXEN bit is cleared to zero and the TXEN bit is set high, the RX/TX pin will act as a transmitter pin.

It is recommended not to set both the RXEN and TXEN bits high in the single wire mode. If both the RXEN and TXEN bits are set high, the RXEN bit will have the priority and the UART will act as a receiver.

It is important to note that the functional description in this UART chapter, which is described from the full-duplex communication standpoint, also applies to the half-duplex (single wire mode) communication except the pin usage. In the single wire mode, the TX pin mentioned in this chapter should be replaced by the RX/TX pin to understand the whole UART single wire mode function.

In the single wire mode, the data can also be transmitted on the TX pin in a transmission operation with proper software configurations. Therefore, the data will be output on the RX/TX and TX pins.

### UART Data Transfer Scheme

The UART Data Transfer Block Diagram shows the overall data transfer structure arrangement for the UART. The actual data to be transmitted from the MCU is first transferred to the TXR\_RXR register by the application program. The data will then be transferred to the Transmit Shift Register from where it will be shifted out, LSB first, onto the TX pin at a rate controlled by the Baud Rate Generator. Only the TXR\_RXR register is mapped onto the MCU Data Memory, the Transmit Shift Register is not mapped and is therefore inaccessible to the application program.

Data to be received by the UART is accepted on the external RX/TX pin, from where it is shifted in, LSB first, to the Receiver Shift Register at a rate controlled by the Baud Rate Generator. When the shift register is full, the data will then be transferred from the shift register to the internal TXR\_RXR register, where it is buffered and can be manipulated by the application program. Only the TXR\_RXR register is mapped onto the MCU Data Memory, the Receiver Shift Register is not mapped and is therefore inaccessible to the application program.

It should be noted that the actual register for data transmission and reception only exists as a single shared register in the Data Memory. This shared register known as the TXR\_RXR register is used for both data transmission and data reception.

## UART Status and Control Registers

There are nine control registers associated with the UART function. The SWM bit in the UCR3 register is used to enable/disable the UART Single Wire Mode. The USR, UCR1, UCR2, UFCR and RxCNT registers control the overall function of the UART, while the BRDH and BRDL registers control the Baud rate. The actual data to be transmitted and received on the serial interface is managed through the TXR\_RXR data register.

Register Name	Bit							
	7	6	5	4	3	2	1	0
USR	PERR	NF	FERR	OERR	RIDLE	RXIF	TIDLE	TXIF
UCR1	UARTEN	BNO	PREN	PRT1	PRT0	TXBRK	RX8	TX8
UCR2	TXEN	RXEN	STOPS	ADDEN	WAKE	RIE	TIIE	TEIE
UCR3	—	—	—	—	—	—	—	SWM
TXR_RXR	D7	D6	D5	D4	D3	D2	D1	D0
BRDH	D7	D6	D5	D4	D3	D2	D1	D0
BRDL	D7	D6	D5	D4	D3	D2	D1	D0
UFCR	—	—	UMOD2	UMOD1	UMOD0	BRDS	RxFTR1	RxFTR0
RxCNT	—	—	—	—	—	D2	D1	D0

**UART Register List**

### • USR Register

The USR register is the status register for the UART, which can be read by the program to determine the present status of the UART. All flags within the USR register are read only. Further explanation on each of the flags is given below:

Bit	7	6	5	4	3	2	1	0
Name	PERR	NF	FERR	OERR	RIDLE	RXIF	TIDLE	TXIF
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	1	0	1	1

Bit 7     **PERR:** Parity error flag  
           0: No parity error is detected  
           1: Parity error is detected

The PERR flag is the parity error flag. When this read only flag is “0”, it indicates a parity error has not been detected. When the flag is “1”, it indicates that the parity of the received word is incorrect. This error flag is applicable only if the parity is enabled and the parity type is selected. The flag can also be cleared by a software sequence which involves a read to the status register USR followed by an access to the TXR\_RXR data register.

Bit 6     **NF:** Noise flag  
           0: No noise is detected  
           1: Noise is detected

The NF flag is the noise flag. When this read only flag is “0”, it indicates no noise condition. When the flag is “1”, it indicates that the UART has detected noise on the receiver input. The NF flag is set during the same cycle as the RXIF flag but will not be set in the case of an overrun. The NF flag can be cleared to zero by a software sequence which will involve a read to the status register USR followed by an access to the TXR\_RXR data register.

- Bit 5 **FERR**: Framing error flag  
0: No framing error is detected  
1: Framing error is detected

The FERR flag is the framing error flag. When this read only flag is “0”, it indicates that there is no framing error. When the flag is “1”, it indicates that a framing error has been detected for the current character. The flag can also be cleared to zero by a software sequence which will involve a read to the status register USR followed by an access to the TXR\_RXR data register.

- Bit 4 **OERR**: Overrun error flag  
0: No overrun error is detected  
1: Overrun error is detected

The OERR flag is the overrun error flag which indicates when the receiver buffer has overflowed. When this read only flag is “0”, it indicates that there is no overrun error. When the flag is “1”, it indicates that an overrun error occurs which will inhibit further transfers to the TXR\_RXR receive data register. The flag is cleared to zero by a software sequence, which is a read to the status register USR followed by an access to the TXR\_RXR data register.

- Bit 3 **RIDLE**: Receiver status  
0: Data reception is in progress (Data being received)  
1: No data reception is in progress (Receiver is idle)

The RIDLE flag is the receiver status flag. When this read only flag is “0”, it indicates that the receiver is between the initial detection of the start bit and the completion of the stop bit. When the flag is “1”, it indicates that the receiver is idle. Between the completion of the stop bit and the detection of the next start bit, the RIDLE bit is “1” indicating that the UART receiver is idle and the RX/TX pin stays in logic high condition.

- Bit 2 **RXIF**: Receive TXR\_RXR data register status  
0: TXR\_RXR data register is empty  
1: TXR\_RXR data register has available data and reach Receiver FIFO trigger level

The RXIF flag is the receive data register status flag. When this read only flag is “0”, it indicates that the TXR\_RXR read data register is empty. When the flag is “1”, it indicates that the TXR\_RXR read data register contains new data and reaches the Receiver FIFO trigger level. When the contents of the shift register are transferred to the TXR\_RXR register, and reach Receiver FIFO trigger level, an interrupt is generated if RIE=1 in the UCR2 register. If one or more errors are detected in the received word, the appropriate receive-related flags NF, FERR, and/or PERR are set within the same clock cycle. The RXIF flag will eventually be cleared to zero when the USR register is read with RXIF set, followed by a read from the TXR\_RXR register, and if the TXR\_RXR register has no more new data available.

- Bit 1 **TIDLE**: Transmission idle  
0: Data transmission is in progress (Data being transmitted)  
1: No data transmission is in progress (Transmitter is idle)

The TIDLE flag is known as the transmission complete flag. When this read only flag is “0”, it indicates that a transmission is in progress. This flag will be set high when the TXIF flag is “1” and when there is no transmit data or break character being transmitted. When TIDLE is equal to “1”, the TX pin becomes idle with the pin state in logic high condition. The TIDLE flag is cleared to zero by reading the USR register with TIDLE set and then writing to the TXR\_RXR register. The flag is not generated when a data character or a break is queued and ready to be sent.

Bit 0      **TXIF**: Transmit TXR\_RXR data register status  
             0: Character is not transferred to the transmit shift register  
             1: Character has transferred to the transmit shift register (TXR\_RXR data register is empty)

The TXIF flag is the transmit data register empty flag. When this read only flag is “0”, it indicates that the character is not transferred to the transmitter shift register. When the flag is “1”, it indicates that the transmitter shift register has received a character from the TXR\_RXR data register. The TXIF flag is cleared to zero by reading the UART status register (USR) with TXIF set and then writing to the TXR\_RXR data register. Note that when the TXEN bit is set, the TXIF flag bit will also be set since the transmit data register is not yet full.

• **UCR1 Register**

The UCR1 register together with the UCR2 and UCR3 registers are the three UART control registers that are used to set the various options for the UART function, such as overall on/off control, parity control, data transfer bit length, single wire mode communication etc. Further explanation on each of the bits is given below:

Bit	7	6	5	4	3	2	1	0
Name	UARTEN	BNO	PREN	PRT1	PRT0	TXBRK	RX8	TX8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R	W
POR	0	0	0	0	0	0	x	0

“x”: Unknown

Bit 7      **UARTEN**: UART function enable control  
             0: Disable UART. TX and RX/TX pins are in a floating state  
             1: Enable UART. TX and RX/TX pins can function as UART pins

The UARTEN bit is the UART enable bit. When this bit is equal to “0”, the UART will be disabled and the RX/TX pin as well as the TX pin will be in a floating state. When the bit is equal to “1”, the UART will be enabled and the TX and RX/TX pins will function as defined by the SWM mode selection bit together with the TXEN and RXEN enable control bits.

When the UART is disabled, it will empty the buffer so any character remaining in the buffer will be discarded. In addition, the value of the baud rate counter will be reset. If the UART is disabled, all error and status flags will be reset. Also the TXEN, RXEN, TXBRK, RXIF, OERR, FERR, PERR and NF bits as well as the RxCNT register will be cleared to zero, while the TIDLE, TXIF and RIDLE bits will be set high. Other control bits in UCR1, UCR2, UCR3 UFCR, BRDH and BRDL registers will remain unaffected. If the UART is active and the UARTEN bit is cleared to zero, all pending transmissions and receptions will be terminated and the module will be reset as defined above. When the UART is re-enabled, it will restart in the same configuration.

Bit 6      **BNO**: Number of data transfer bits selection  
             0: 8-bit data transfer  
             1: 9-bit data transfer

This bit is used to select the data length format, which can have a choice of either 8-bit or 9-bit format. When this bit is equal to “1”, a 9-bit data length format will be selected. If the bit is equal to “0”, then an 8-bit data length format will be selected. If 9-bit data length format is selected, then bits RX8 and TX8 will be used to store the 9th bit of the received and transmitted data respectively.

Note that the 9th bit of data if BNO=1, or the 8th bit of data if BNO=0, which is used as the parity bit, does not transfer to RX8 or TXRX7 (i.e.TXR\_RXR.7) respectively when the parity function is enabled.

- Bit 5      **PREN**: Parity function enable control  
             0: Parity function is disabled  
             1: Parity function is enabled  
 This is the parity enable bit. When this bit is equal to “1”, the parity function will be enabled. If the bit is equal to “0”, then the parity function will be disabled.
- Bit 4~3    **PRT1~PRT0**: Parity type selection bits  
             00: Even parity for parity generator  
             01: Odd parity for parity generator  
             10: Mark parity for parity generator  
             11: Space parity for parity generator  
 These bits are the parity type selection bits. When these bits are equal to 00b, even parity type will be selected. If these bits are equal to 01b, then odd parity type will be selected. If these bits are equal to 10b, then a 1 (Mark) in the parity bit location will be selected. If these bits are equal to 11b, then a 0 (Space) in the parity bit location will be selected.
- Bit 2      **TXBRK**: Transmit break character  
             0: No break character is transmitted  
             1: Break characters transmit  
 The TXBRK bit is the Transmit Break Character bit. When this bit is “0”, there are no break characters and the TX pin operates normally. When the bit is “1”, there are transmit break characters and the transmitter will send logic zeros. When this bit is equal to “1”, after the buffered data has been transmitted, the transmitter output is held low for a minimum of a 13-bit length and until the TXBRK bit is reset.
- Bit 1      **RX8**: Receive data bit 8 for 9-bit data transfer format (read only)  
 This bit is only used if 9-bit data transfers are used, in which case this bit location will store the 9th bit of the received data known as RX8. The BNO bit is used to determine whether data transfers are in 8-bit or 9-bit format.
- Bit 0      **TX8**: Transmit data bit 8 for 9-bit data transfer format (write only)  
 This bit is only used if 9-bit data transfers are used, in which case this bit location will store the 9th bit of the transmitted data known as TX8. The BNO bit is used to determine whether data transfers are in 8-bit or 9-bit format.

• **UCR2 Register**

The UCR2 register is the second of the three UART control registers and serves several purposes. One of its main functions is to control the basic enable/disable operation of the UART Transmitter and Receiver as well as enabling the various UART interrupt sources. The register also serves to control the receiver STOP bit number selection, receiver wake-up enable and the address detect enable. Further explanation on each of the bits is given below:

Bit	7	6	5	4	3	2	1	0
Name	TXEN	RXEN	STOPS	ADDEN	WAKE	RIE	TIIE	TEIE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7      **TXEN**: UART Transmitter enabled control  
             0: UART transmitter is disabled  
             1: UART transmitter is enabled  
 The bit named TXEN is the Transmitter Enable Bit. When this bit is equal to “0”, the transmitter will be disabled with any pending data transmissions being aborted. In addition, the buffers will be reset. In this situation the TX pin will be in a floating state. If the TXEN bit is equal to “1” and the UARTEEN bit is also equal to “1”, the transmitter will be enabled and the TX pin will be controlled by the UART. Clearing the TXEN bit during a transmission will cause the data transmission to be aborted and will reset the transmitter. If this situation occurs, the TX pin will be in a floating state.

Bit 6	<p><b>RXEN:</b> UART Receiver enabled control          0: UART receiver is disabled          1: UART receiver is enabled</p> <p>The bit named RXEN is the Receiver Enable Bit. When this bit is equal to “0”, the receiver will be disabled with any pending data receptions being aborted. In addition, the receive buffers will be reset. In this situation the RX/TX pin will be in a floating state. If the RXEN bit is equal to “1” and the UARTEEN bit is also equal to “1”, the receiver will be enabled and the RX/TX pin will be controlled by the UART. Clearing the RXEN bit during a reception will cause the data reception to be aborted and will reset the receiver. If this situation occurs, the RX/TX pin will be in a floating state.</p>
Bit 5	<p><b>STOPS:</b> Number of stop bits selection for receiver          0: One stop bit format is used          1: Two stop bits format is used</p> <p>This bit determines if one or two stop bits are to be used for receiver. When this bit is equal to “1”, two stop bits are used. If this bit is equal to “0”, then only one stop bit is used. Two stop bits are used for transmitter.</p>
Bit 4	<p><b>ADDEN:</b> Address detect function enable control          0: Address detect function is disabled          1: Address detect function is enabled</p> <p>The bit named ADDEN is the address detect function enable control bit. When this bit is equal to “1”, the address detect function is enabled. When it occurs, if the 8th bit, which corresponds to TXR_RXR.7 if BNO=0 or the 9th bit, which corresponds to RX8 if BNO=1, has a value of “1”, then the received word will be identified as an address, rather than data. If the corresponding interrupt is enabled, an interrupt request will be generated each time the received word has the address bit set, which is the 8th or 9th bit depending on the value of BNO. If the address bit known as the 8th or 9th bit of the received word is “0” with the address detect function being enabled, an interrupt will not be generated and the received data will be discarded.</p>
Bit 3	<p><b>WAKE:</b> RX/TX pin wake-up UART function enable control          0: RX/TX pin wake-up UART function is disabled          1: RX/TX pin wake-up UART function is enabled</p> <p>This bit is used to control the wake-up UART function when a falling edge on the RX/TX pin occurs. Note that this bit is only available when the UART clock (<math>f_{H}</math>) is switched off. There will be no RX/TX pin wake-up UART function if the UART clock (<math>f_{H}</math>) exists. If the WAKE bit is set to 1 as the UART clock (<math>f_{H}</math>) is switched off, a UART wake-up request will be initiated when a falling edge on the RX/TX pin occurs. When this request happens and the corresponding interrupt is enabled, an RX/TX pin wake-up UART interrupt will be generated to inform the MCU to wake up the UART function by switching on the UART clock (<math>f_{H}</math>) via the application program. Otherwise, the UART function can not resume even if there is a falling edge on the RX/TX pin when the WAKE bit is cleared to 0.</p>
Bit 2	<p><b>RIE:</b> Receiver interrupt enable control          0: Receiver related interrupt is disabled          1: Receiver related interrupt is enabled</p> <p>This bit enables or disables the receiver interrupt. If this bit is equal to “1” and when the receiver overrun flag OERR or receive data available flag RXIF is set, the UART interrupt request flag will be set. If this bit is equal to “0”, the UART interrupt request flag will not be influenced by the condition of the OERR or RXIF flags.</p>
Bit 1	<p><b>TIE:</b> Transmitter Idle interrupt enable control          0: Transmitter idle interrupt is disabled          1: Transmitter idle interrupt is enabled</p> <p>This bit enables or disables the transmitter idle interrupt. If this bit is equal to “1” and when the transmitter idle flag TIDLE is set, due to a transmitter idle condition, the UART interrupt request flag will be set. If this bit is equal to “0”, the UART interrupt request flag will not be influenced by the condition of the TIDLE flag.</p>

Bit 0 **TEIE**: Transmitter Empty interrupt enable control  
 0: Transmitter empty interrupt is disabled  
 1: Transmitter empty interrupt is enabled  
 This bit enables or disables the transmitter empty interrupt. If this bit is equal to “1” and when the transmitter empty flag TXIF is set, due to a transmitter empty condition, the UART interrupt request flag will be set. If this bit is equal to “0”, the UART interrupt request flag will not be influenced by the condition of the TXIF flag.

• **UCR3 Register**

The UCR3 register is used to enable the UART Single Wire Mode communication. As the name suggests in the single wire mode the UART communication can be implemented in one single line, RX/TX, together with the control of the RXEN and TXEN bits in the UCR2 register.

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	SWM
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as “0”

Bit 0 **SWM**: Single Wire Mode enable control  
 0: Disable, the RX/TX pin is used as UART receiver function only  
 1: Enable, the RX/TX pin can be used as UART receiver or transmitter function controlled by the RXEN and TXEN bits  
 Note that when the Single Wire Mode is enabled, if both the RXEN and TXEN bits are high, the RX/TX pin will only be used as UART receiver input.

• **TXR\_RXR Register**

The TXR\_RXR register is the data register which is used to store the data to be transmitted on the TX pin or being received from the RX/TX pin.

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	x	x	x	x	x	x	x	x

“x”: Unknown

Bit 7~0 **D7~D0**: UART Transmit/Receive Data bit 7~bit 0

• **BRDH Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Baud rate divider high byte  
 The baud rate divider BRD (BRDH/BRDL) defines the UART clock divider ratio.  
 $Baud\ Rate = f_{ih} / (BRD + UMOD / 8)$   
 $BRD = 16 \sim 65535$  or  $8 \sim 65535$  depending on BRDS  
 Note: 1. BRD value should not be set to less than 16 when BRDS=0 or less than 8 when BRDS=1, otherwise errors may occur.  
 2. The BRDL must be written first and then BRDH, otherwise errors may occur.  
 3. The BRDH register should not be modified during data transmission process.

• **BRDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7~0     **D7~D0**: Baud rate values low byte  
 The baud rate divider BRD (BRDH/BRDL) defines the UART clock divider ratio.  
 $Baud\ Rate = f_{ih} / (BRD + UMOD/8)$   
 $BRD = 16 \sim 65535$  or  $8 \sim 65535$  depending on BRDS  
 Note: 1. BRD value should not be set to less than 16 when BRDS=0 or less than 8 when BRDS=1, otherwise errors may occur.  
 2. The BRDL must be written first and then BRDH, otherwise errors may occur.  
 3. The BRDL register should not be modified during data transmission process.

• **UFCR Register**

The UFCR register is the FIFO control register which is used for UART modulation control, BRD range selection and trigger level selection for RXIF and interrupt.

Bit	7	6	5	4	3	2	1	0
Name	—	—	UMOD2	UMOD1	UMOD0	BRDS	RxFTR1	RxFTR0
R/W	—	—	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	—	0	0	0	0	0	0

- Bit 7~6     Unimplemented, read as “0”
- Bit 5~3     **UMOD2~UMOD0**: UART Modulation Control bits  
 The modulation control bits are used to correct the baud rate of the received or transmitted UART signal. These bits determine if the extra UART clock cycle should be added in a UART bit time. The UMOD2~UMOD0 will be added to internal accumulator for every UART bit time. Until a carry to bit 3, the corresponding UART bit time increases a UART clock cycle.
- Bit 2       **BRDS**: BGD range selection  
 0: BRD range is from 16 to 65535  
 1: BRD range is from 8 to 65535  
 The BRDS is used to control the sampling point in a UART bit time. If the BRDS is cleared to zero, the sampling point will be  $BRD/2$ ,  $BRD/2 + 1 \times f_{ih}$ , and  $BRD/2 + 2 \times f_{ih}$  in a UART bit time. If the BRDS is set high, the sampling point will be  $BRD/2 - 1 \times f_{ih}$ ,  $BRD/2$ , and  $BRD/2 + 2 \times f_{ih}$  in a UART bit time.  
 Note that the BRDS bit should not be modified during data transmission process.
- Bit 1~0     **RxFTR1~RxFTR0**: Receiver FIFO trigger level (bytes)  
 00: 4 bytes in Receiver FIFO  
 01: 1 or more bytes in Receiver FIFO  
 10: 2 or more bytes in Receiver FIFO  
 11: 3 or more bytes in Receiver FIFO  
 For the receiver these bits define the number of received data bytes in the Receiver FIFO that will trigger the RXIF bit being set high, an interrupt will also be generated if the RIE bit is enabled. To prevent OERR from being set high, the receiver FIFO trigger level can be set to 2 bytes, avoiding an overrun state that cannot be processed by the program in time when more than 4 data bytes are received. After the reset the receiver FIFO is empty.

• **RxCNT Register**

The RxCNT register is the counter used to indicate the number of received data bytes in the Receiver FIFO which have not been read by the MCU. This register is read only.

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	D2	D1	D0
R/W	—	—	—	—	—	R	R	R
POR	—	—	—	—	—	0	0	0

Bit 7~3 Unimplemented, read as “0”

Bit 2~0 **D2~D0**: Receiver FIFO counter

The RxCNT register is the counter used to indicate the number of receiver data bytes in Receiver FIFO which is not read by MCU. When Receiver FIFO receives one byte data, the RxCNT will increase by one; when the MCU reads one byte data from Receiver FIFO, the RxCNT will decrease by one. If there are 4 bytes of data in the Receiver FIFO, the 5<sup>th</sup> data will be saved in the shift register. If there is 6<sup>th</sup> data, the 6<sup>th</sup> data will be saved in the shift register. But the RxCNT remains the value of 4. The RxCNT will be cleared when reset occurs or UARTEEN=1. This register is read only.

**Baud Rate Generator**

To setup the speed of the serial data communication, the UART function contains its own dedicated baud rate generator. The baud rate is controlled by its own internal free running 16-bit timer, the period of which is determined by two factors. The first of these is the value placed in the BRDH/BRDL register and the second is the UART modulation control bits, UMOD2~UMOD0. To prevent accumulated error of the receiver baud rate frequency, it is recommended to use two stop bits for resynchronization after each byte is received. If a baud rate BR is required with UART clock  $f_{H}$ .

$$f_{H}/BR = \text{Integer Part} + \text{Fractional Part}$$

The integer part is loaded into BRD (BRDH/BRDL). The fractional part is multiplied by 8 and rounded, then loaded into UMOD bit field as following:

$$BRD = \text{TRUNC}(f_{H}/BR)$$

$$UMOD = \text{ROUND}[\text{MOD}(f_{H}/BR) \times 8]$$

Therefore, the actual baud rate is as following:

$$\text{Baud rate} = f_{H}/[BRD + (UMOD/8)]$$

**Calculating the Baud Rate and Error Values**

For a clock frequency of 4MHz, determine the BRDH/BRDL register value, the actual baud rate and the error value for a desired baud rate of 230400.

From the above formula, the  $BRD = \text{TRUNC}(f_{H}/BR) = \text{TRUNC}(17.36111) = 17$

The  $UMOD = \text{ROUND}[\text{MOD}(f_{H}/BR) \times 8] = \text{ROUND}(0.36111 \times 8) = \text{ROUND}(2.88888) = 3$

The actual Baud Rate  $= f_{H}/[BRD + (UMOD/8)] = 230215.83$

Therefore the error is equal to  $(230215.83 - 230400)/230400 = -0.08\%$

**Modulation Control Example**

To get the best-fitting bit sequence for UART modulation control bits UMOD2~UMOD0, the following algorithm can be used: Firstly, the fractional part of the theoretical division factor is multiplied by 8. Then the product will be rounded and UMOD2~UMOD0 bits will be filled with the rounded value. The UMOD2~UMOD0 will be added to internal accumulator for every UART bit time. Until a carry to bit 3, the corresponding UART bit time increases a UART clock cycle. The following is an example using the fraction 0.36111 previously calculated:  $UMOD[2:0] = \text{ROUND}(0.36111 \times 8) = 011b$ .

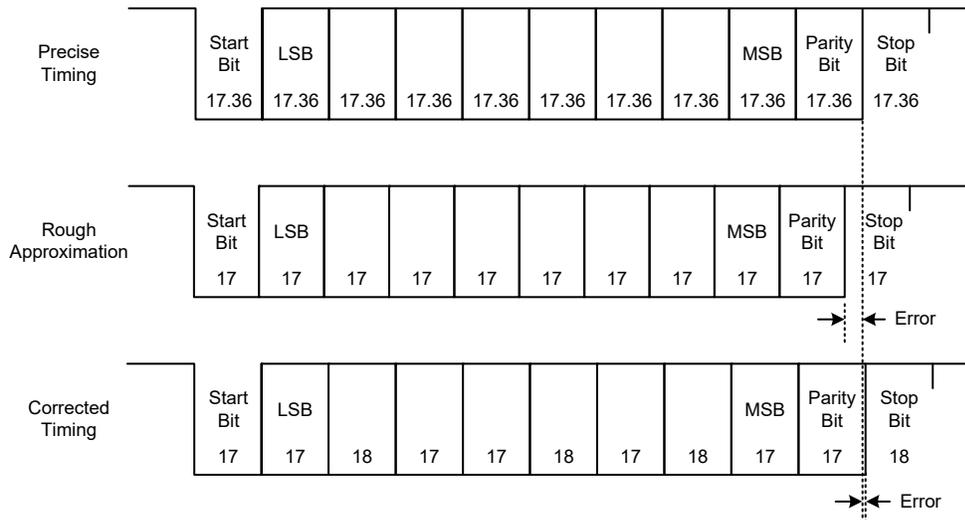
Fraction Addition	Carry to Bit 3	UART Bit Time Sequence	Extra UART Clock Cycle
0000b+0011b=0011b	No	Start bit	No
0011b+0011b=0110b	No	D0	No
0110b+0011b=1001b	Yes	D1	Yes
1001b+0011b=1100b	No	D2	No
1100b+0011b=1111b	No	D3	No
1111b+0011b=0010b	Yes	D4	Yes
0010b+0011b=0101b	No	D5	No
0101b+0011b=1000b	Yes	D6	Yes
1000b+0011b=1011b	No	D7	No
1011b+0011b=1110b	No	Parity bit	No
1110b+0011b=0001b	Yes	Stop bit	Yes

### Baud Rate Correction Example

The following figure presents an example using a baud rate of 230400 generated with UART clock  $f_H$ . The data format for the following figure is: eight data bits, parity enabled, no address bit, two stop bits.

The following figure shows three different frames:

- The upper frame is the correct one, with a bit-length of 17.36  $f_H$  cycles ( $4000000/230400=17.36$ ).
- The middle frame uses a rough estimate, with 17  $f_H$  cycles for the bit length.
- The lower frame shows a corrected frame using the best fit for the UART modulation control bits UMOD2~UMOD0.



### UART Setup and Control

For data transfer, the UART function utilizes a non-return-to-zero, more commonly known as NRZ, format. This is composed of one start bit, eight or nine data bits, and one or two stop bits. Parity is supported by the UART hardware, and can be setup to be even, odd, mark, space or no parity. For the most common data format, 8 data bits along with no parity and one stop bit, denoted as 8, N, 1, is used as the default setting, which is the setting at power-on. The number of data bits along with the parity are setup by programming the BNO, PRT1~PRT0 and PREN bits. The transmitter always uses two stop bits while the receiver uses one or two stop bits which is determined by the STOPS bit. The baud rate used to transmit and receive data is setup using the internal 16-bit baud rate generator,

while the data is transmitted and received LSB first. Although the UART transmitter and receiver are functionally independent, they both use the same data format and baud rate. In all cases stop bits will be used for data transmission.

**Enabling/Disabling the UART Interface**

The basic on/off function of the internal UART function is controlled using the UARTEN bit in the UCR1 register. If the UARTEN, TXEN and RXEN bits are set, then these two UART pins will act as normal TX output pin and RX/TX input pin respectively. If no data is being transmitted on the TX pin, then it will default to a logic high value.

Clearing the UARTEN bit will disable the TX and RX/TX pins and allow these two pins to be used as normal I/O or other pin-shared functional pins by configuring the corresponding pin-shared control bits. When the UART function is disabled the buffer will be reset to an empty condition, at the same time discarding any remaining residual data. Disabling the UART will also reset the error and status flags with bits TXEN, RXEN, TXBRK, RXIF, OERR, FERR, PERR and NF as well as register RxCNT being cleared while bits TIDLE, TXIF and RIDLE will be set. The remaining control bits in the UCR1, UCR2, UCR3, UFCR, BRDH and BRDL registers will remain unaffected. If the UARTEN bit in the UCR1 register is cleared while the UART is active, then all pending transmissions and receptions will be immediately suspended and the UART will be reset to a condition as defined above. If the UART is then subsequently re-enabled, it will restart again in the same configuration.

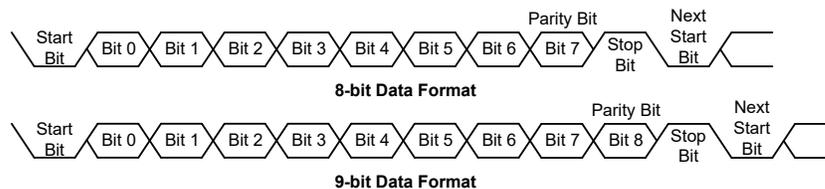
**Data, Parity and Stop Bit Selection**

The format of the data to be transferred is composed of various factors such as data bit length, parity on/off, parity type, address bits and the number of stop bits. These factors are determined by the setup of various bits within the UCR1 and UCR2 registers. The BNO bit controls the number of data bits which can be set to either 8 or 9, the PRT1~PRT0 bits control the choice of odd, even, mark or space parity, the PREN bit controls the parity on/off function and the STOPS bit decides whether one or two stop bits are to be used for the receiver, while the transmitter always uses two stop bits. The following table shows various formats for data transmission. The address bit, which is the MSB of the data byte, identifies the frame as an address character or data if the address detect function is enabled. The number of stop bits, which can be either one or two, is independent of the data length and is only configurable for the receiver. The transmitter uses two stop bits.

Start Bit	Data Bits	Address Bit	Parity Bit	Stop Bit
<b>Example of 8-bit Data Formats</b>				
1	8	0	0	1 or 2
1	7	0	1	1 or 2
1	7	1	0	1 or 2
<b>Example of 9-bit Data Formats</b>				
1	9	0	0	1 or 2
1	8	0	1	1 or 2
1	8	1	0	1 or 2

**Transmitter Receiver Data Format**

The following diagram shows the transmit and receive waveforms for both 8-bit and 9-bit data formats.



## UART Transmitter

Data word lengths of either 8 or 9 bits can be selected by programming the BNO bit in the UCR1 register. When BNO bit is set, the word length will be set to 9 bits. In this case the 9th bit, which is the MSB, needs to be stored in the TX8 bit in the UCR1 register. At the transmitter core lies the Transmitter Shift Register, more commonly known as the TSR, whose data is obtained from the transmit data register, which is known as the TXR\_RXR register. The data to be transmitted is loaded into this TXR\_RXR register by the application program. The TSR register is not written to with new data until the stop bit from the previous transmission has been sent out. As soon as this stop bit has been transmitted, the TSR can then be loaded with new data from the TXR\_RXR register, if it is available. It should be noted that the TSR register, unlike many other registers, is not directly mapped into the Data Memory area and as such is not available to the application program for direct read/write operations. An actual transmission of data will normally be enabled when the TXEN bit is set, but the data will not be transmitted until the TXR\_RXR register has been loaded with data and the baud rate generator has defined a shift clock source. However, the transmission can also be initiated by first loading data into the TXR\_RXR register, after which the TXEN bit can be set. When a transmission of data begins, the TSR is normally empty, in which case a transfer to the TXR\_RXR register will result in an immediate transfer to the TSR. If during a transmission the TXEN bit is cleared, the transmission will immediately cease and the transmitter will be reset. The TX output pin can then be configured as the I/O or other pin-shared function by configuring the corresponding pin-shared control bits.

### Transmitting Data

When the UART is transmitting data, the data is shifted on the TX pin from the shift register, with the least significant bit first. In the transmit mode, the TXR\_RXR register forms a buffer between the internal bus and the transmitter shift register. It should be noted that if 9-bit data format has been selected, then the MSB will be taken from the TX8 bit in the UCR1 register.

The steps to initiate a data transfer can be summarized as follows:

- Make the correct selection of the BNO, PRT1~PRT0 and PREN bits to define the required word length and parity type. Two stop bits are used for the transmitter.
- Setup the BRDH and BRDL registers and the UMOD2~UMOD0 bits to select the desired baud rate.
- Set the TXEN bit to ensure that the TX pin is used as a UART transmitter pin.
- Access the USR register and write the data that is to be transmitted into the TXR\_RXR register. Note that this step will clear the TXIF bit.

This sequence of events can now be repeated to send additional data.

It should be noted that when TXIF=0, data will be inhibited from being written to the TXR\_RXR register. Clearing the TXIF flag is always achieved using the following software sequence:

1. A USR register access
2. A TXR\_RXR register write execution

The read-only TXIF flag is set by the UART hardware and if set indicates that the TXR\_RXR register is empty and that other data can now be written into the TXR\_RXR register without overwriting the previous data. If the TEIE bit is set, then the TXIF flag will generate an interrupt.

During a data transmission, a write instruction to the TXR\_RXR register will place the data into the TXR\_RXR register, which will be copied to the shift register at the end of the present transmission. When there is no data transmission in progress, a write instruction to the TXR\_RXR register will place the data directly into the shift register, resulting in the commencement of data transmission, and the TXIF bit being immediately set. When a frame transmission is complete, which happens

after stop bits are sent or after the break frame, the TIDLE bit will be set. To clear the TIDLE bit the following software sequence is used:

1. A USR register access
2. A TXR\_RXR register write execution

Note that both the TXIF and TIDLE bits are cleared by the same software sequence.

### **Transmitting Break**

If the TXBRK bit is set high and the state keeps for a time of greater than  $(BRD+1) \times t_{th}$  while  $TIDLE=1$ , then break characters will be sent on the next transmission. Break character transmission consists of a start bit, followed by  $13 \times N$  '0' bits and stop bits, where  $N=1, 2$ , etc. If a break character is to be transmitted then the TXBRK bit must be first set by the application program, and then cleared to generate the stop bits. Transmitting a break character will not generate a transmit interrupt. Note that a break condition length is at least 13 bits long. If the TXBRK bit is continually kept at a logic high level, then the transmitter circuitry will transmit continuous break characters. After the application program has cleared the TXBRK bit, the transmitter will finish transmitting the last break character and subsequently send out two stop bits. The automatic logic highs at the end of the last break character will ensure that the start bit of the next frame is recognized.

### **UART Receiver**

The UART is capable of receiving word lengths of either 8 or 9 bits. If the BNO bit is set, the word length will be set to 9 bits with the MSB being stored in the RX8 bit of the UCR1 register. At the receiver core lies the Receive Serial Shift Register, commonly known as the RSR. The data which is received on the RX/TX pin is sent to the data recovery block. The data recovery block operating speed is 16 times that of the baud rate, while the main receive serial shifter operates at the baud rate. After the RX/TX pin is sampled for the stop bit, the received data in RSR is transferred to the receive data register, if the register is empty. The data which is received on the external RX/TX pin is sampled three times by a majority detect circuit to determine the logic level that has been placed onto the RX/TX pin. It should be noted that the RSR register, unlike many other registers, is not directly mapped into the Data Memory area and as such is not available to the application program for direct read/write operations.

### **Receiving Data**

When the UART receiver is receiving data, the data is serially shifted in on the external RX/TX pin, LSB first. In the read mode, the TXR\_RXR register forms a buffer between the internal bus and the receiver shift register. The TXR\_RXR register is a four-byte deep FIFO data buffer, where four bytes can be held in the FIFO while a fifth byte can continue to be received. Note that the application program must ensure that the data is read from TXR\_RXR before the fifth byte has been completely shifted in, otherwise this fifth byte will be discarded and an overrun error OERR will be subsequently indicated. For continuous multi-byte data transmission, it is strongly recommended that the receiver uses two stop bits to avoid a receiving error caused by the accumulated error of the receiver baud rate frequency.

The steps to initiate a data transfer can be summarized as follows:

- Make the correct selection of BNO, PRT1~PRT0, PREN and STOPS bits to define the word length, parity type and number of stop bits.
- Setup the BRDH, BRDL registers and the UMOD2~UMOD0 bits to select the desired baud rate.
- Set the RXEN bit to ensure that the RX/TX pin is used as a UART receiver pin.

At this point the receiver will be enabled which will begin to look for a start bit.

When a character is received the following sequence of events will occur:

- The RXIF bit in the USR register will be set when the TXR\_RXR register has data available, the number of the available data bytes can be checked by polling the RxCNT register content.
- When the contents of the shift register have been transferred to the TXR\_RXR register and reach Receiver FIFO trigger level, if the RIE bit is set, then an interrupt will be generated.
- If during reception, a frame error, noise error, parity error, or an overrun error has been detected, then the error flags can be set.

The RXIF bit can be cleared using the following software sequence:

1. A USR register access
2. A TXR\_RXR register read execution

### Receiving Break

Any break character received by the UART will be managed as a framing error. The receiver will count and expect a certain number of bit times as specified by the values programmed into the BNO bit plus one or two stop bits. If the break is much longer than 13 bit times, the reception will be considered as complete after the number of bit times specified by BNO plus one or two stop bits. The RXIF bit is set, FERR is set, zeros are loaded into the receive data register, interrupts are generated if appropriate and the RIDLE bit is set. A break is regarded as a character that contains only zeros with the FERR flag set. If a long break signal has been detected, the receiver will regard it as a data frame including a start bit, data bits and the invalid stop bit and the FERR flag will be set. The receiver must wait for a valid stop bit before looking for the next start bit. The receiver will not make the assumption that the break condition on the line is the next start bit. The break character will be loaded into the buffer and no further data will be received until one or two stop bits are received. It should be noted that the RIDLE read only flag will go high when the stop bits have not yet been received.

The reception of a break character on the UART registers will result in the following:

- The framing error flag, FERR, will be set.
- The receive data register, TXR\_RXR, will be cleared.
- The OERR, NF, PERR, RIDLE or RXIF flags will possibly be set.

### Idle Status

When the receiver is reading data, which means it will be in between the detection of a start bit and the reading of a stop bit, the receiver status flag in the USR register, otherwise known as the RIDLE flag, will have a zero value. In between the reception of a stop bit and the detection of the next start bit, the RIDLE flag will have a high value, which indicates the receiver is in an idle condition.

### Receiver Interrupt

The read only receive interrupt flag RXIF in the USR register is set by an edge generated by the receiver. An interrupt is generated if RIE=1, when a word is transferred from the Receive Shift Register, RSR, to the Receive Data Register, TXR\_RXR. An overrun error can also generate an interrupt if RIE=1.

When a subroutine will be called with an execution time longer than the time for UART to receive five data bytes, if the UART received data could not be read in time during the subroutine execution, clear the RXEN bit to zero in advance to suspend data reception. If the UART interrupt could not be served in time to process the overrun error during the subroutine execution, ensure that both EMI and RXEN bits are disabled during this period, and then enable EMI and RXEN again after the subroutine execution has been completed to continue the UART data reception.

## Managing Receiver Errors

Several types of reception errors can occur within the UART module, the following section describes the various types and how they are managed by the UART.

### Overrun Error – OERR

The TXR\_RXR register is composed of a four byte deep FIFO data buffer, where four bytes can be held in the FIFO register, while a fifth byte can continue to be received. Before this fifth byte has been entirely shifted in, the data should be read from the TXR\_RXR register. If this is not done, the overrun error flag OERR will be consequently indicated.

In the event of an overrun error occurring, the following will happen:

- The OERR flag in the USR register will be set.
- The TXR\_RXR contents will not be lost.
- The shift register will be overwritten.
- An interrupt will be generated if the RIE bit is set.

When the OERR flag is set to “1”, it is necessary to read five data bytes from the four-byte deep receiver FIFO and the shift register immediately to avoid unexpected errors, such as the UART is unable to receive data. If such an error occurs, clear the RXEN bit to “0” then set it to “1” again to continue data reception.

The OERR flag can be cleared by an access to the USR register followed by a read to the TXR\_RXR register.

### Noise Error – NF

Over-sampling is used for data recovery to identify valid incoming data and noise. If noise is detected within a frame the following will occur:

- The read only noise flag, NF, in the USR register will be set on the rising edge of the RXIF bit.
- Data will be transferred from the Shift register to the TXR\_RXR register.
- No interrupt will be generated. However, this bit rises at the same time as the RXIF bit which itself generates an interrupt.

Note that the NF flag is reset by a USR register read operation followed by a TXR\_RXR register read operation.

### Framing Error – FERR

The read only framing error flag, FERR, in the USR register, is set if a zero is detected instead of stop bits. If two stop bits are selected, both stop bits must be high; otherwise the FERR flag will be set. The FERR flag and the received data will be recorded in the USR and TXR\_RXR registers respectively, and the flag is cleared in any reset.

### Parity Error – PERR

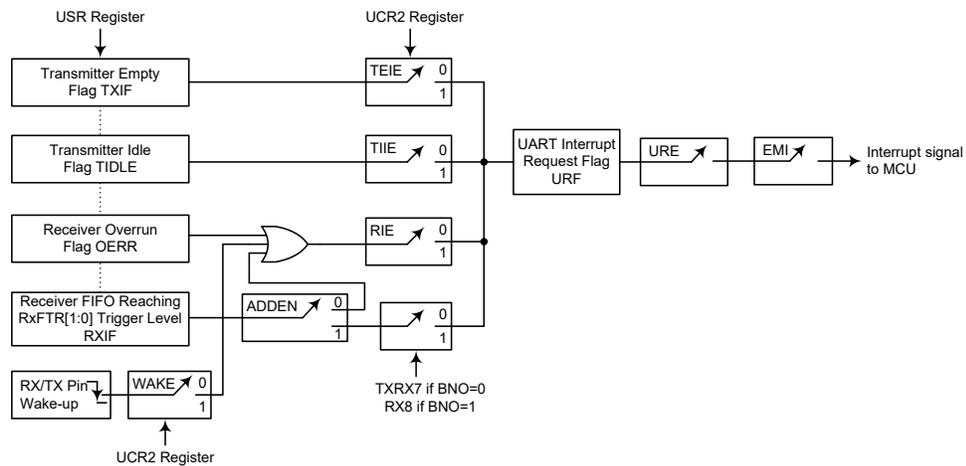
The read only parity error flag, PERR, in the USR register, is set if the parity of the received word is incorrect. This error flag is only applicable if the parity is enabled, PREN=1, and if the parity type, odd or even is selected. The read only PERR flag and the received data will be recorded in the USR and TXR\_RXR registers respectively. It is cleared on any reset, it should be noted that the flags, FERR and PERR, in the USR register should first be read by the application program before reading the data word.

### UART Interrupt Structure

Several individual UART conditions can generate a UART interrupt. When these conditions exist, a low pulse will be generated to get the attention of the microcontroller. These conditions are a transmitter data register empty, transmitter idle, receiver reaching FIFO trigger level, receiver overrun, address detect and an RX/TX pin wake-up. When any of these conditions are created, if the global interrupt enable bit and its corresponding interrupt control bit are enabled and the stack is not full, the program will jump to its corresponding interrupt vector where it can be serviced before returning to the main program. Four of these conditions have the corresponding USR register flags which will generate a UART interrupt if its associated interrupt enable control bit in the UCR2 register is set. The two transmitter interrupt conditions have their own corresponding enable control bits, while the two receiver interrupt conditions have a shared enable control bit. These enable bits can be used to mask out individual UART interrupt sources.

The address detect condition, which is also a UART interrupt source, does not have an associated flag, but will generate a UART interrupt when an address detect condition occurs if its function is enabled by setting the ADDEN bit in the UCR2 register. An RX/TX pin wake-up, which is also a UART interrupt source, does not have an associated flag, but will generate a UART interrupt if the UART clock ( $f_{IH}$ ) source is switched off and the WAKE and RIE bits in the UCR2 register are set when a falling edge on the RX/TX pin occurs.

Note that the USR register flags are read only and cannot be cleared or set by the application program, neither will they be cleared when the program jumps to the corresponding interrupt servicing routine, as is the case for some of the other interrupts. The flags will be cleared automatically when certain actions are taken by the UART, the details of which are given in the UART register section. The overall related interrupt can be disabled or enabled by the UART interrupt enable control bits in the interrupt control registers of the microcontroller to decide whether the interrupt requested by the UART module is masked out or allowed.



**UART Interrupt Structure**

### Address Detect Mode

Setting the Address Detect Mode bit, ADDEN, in the UCR2 register, enables this special mode. If this bit is enabled then an additional qualifier will be placed on the generation of a Receiver Data Available interrupt, which is requested by the RXIF flag. If the ADDEN bit is enabled, then when data is available, an interrupt will only be generated, if the highest received bit has a high value. Note that the URE and EMI interrupt enable bits must also be enabled for correct interrupt generation. This highest address bit is the 9th bit if BNO=1 or the 8th bit if BNO=0. If this bit is high, then the received word will be defined as an address rather than data. A Data Available interrupt will be generated every time the last bit of the received word is set. If the ADDEN bit is not enabled, then a Receiver Data Available interrupt will be generated each time the RXIF flag is set, irrespective of the data last bit status. The address detect mode and parity enable are mutually exclusive functions. Therefore, if the address detect mode is enabled, then to ensure correct operation, the parity function should be disabled by resetting the parity enable bit PREN to zero.

ADDEN	9th Bit if BNO=1, 8th Bit if BNO=0	UART Interrupt Generated
0	0	√
	1	√
1	0	×
	1	√

**ADDEN Bit Function**

### UART Power Down and Wake-up

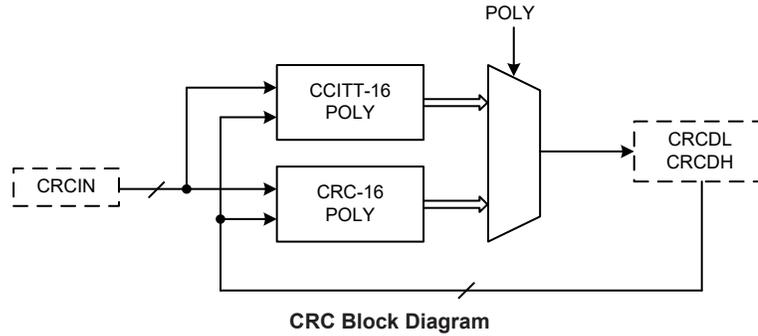
When the UART clock ( $f_{H}$ ) is off, the UART will cease to function, all clock sources to the module are shutdown. If the UART clock ( $f_{H}$ ) is off while a transmission is still in progress, then the transmission will be paused until the UART clock source derived from the microcontroller is activated. In a similar way, if the MCU enters the IDLE or SLEEP mode while receiving data, then the reception of data will likewise be paused. When the MCU enters the IDLE or SLEEP mode, note that the USR, UCR1, UCR2, UCR3, UFCR, RxCNT, TXR\_RXR, as well as the BRDH and BRDL registers will not be affected. It is recommended to make sure first that the UART data transmission or reception has been finished before the microcontroller enters the IDLE or SLEEP mode.

The UART function contains a receiver RX/TX pin wake-up function, which is enabled or disabled by the WAKE bit in the UnCR2 register. If this bit, along with the UART enable bit, UARTEN, the receiver enable bit, RXEN and the receiver interrupt bit, RIE, are all set when the UART clock ( $f_{H}$ ) is off, then a falling edge on the RX/TX pin will trigger an RX/TX pin wake-up UART interrupt. Note that as it takes certain system clock cycles after a wake-up, before normal microcontroller operation resumes, any data received during this time on the RX/TX pin will be ignored.

For a UART wake-up interrupt to occur, in addition to the bits for the wake-up being set, the global interrupt enable bit, EMI, the UART interrupt enable bit, URE, must be set. If the EMI and URE bits are not set then only a wake up event will occur and no interrupt will be generated. Note also that as it takes certain system clock cycles after a wake-up before normal microcontroller resumes, the UART interrupt will not be generated until after this time has elapsed.

## Cyclic Redundancy Check – CRC

The Cyclic Redundancy Check, CRC, calculation unit is an error detection technique test algorithm and uses to verify data transmission or storage data correctness. A CRC calculation takes a data stream or a block of data as input and generates a 16-bit output remainder. Ordinarily, a data stream is suffixed by a CRC code and used as a checksum when being sent or stored. Therefore, the received or restored data stream is calculated by the same generator polynomial as described in the following section.



### CRC Registers

The CRC generator contains an 8-bit CRC data input register, CRCIN, and a CRC checksum register pair, CRCDH and CRCDL. The CRCIN register is used to input new data and the CRCDH and CRCDL registers are used to hold the previous CRC calculation result. A CRC control register, CRCCR, is used to select which CRC generating polynomial is used.

Register Name	Bit							
	7	6	5	4	3	2	1	0
CRCIN	D7	D6	D5	D4	D3	D2	D1	D0
CRCDL	D7	D6	D5	D4	D3	D2	D1	D0
CRCDH	D15	D14	D13	D12	D11	D10	D9	D8
CRCCR	—	—	—	—	—	—	—	POLY

**CRC Register List**

#### • CRCIN Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0     **D7~D0**: CRC input data register

#### • CRCDL Register

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0     **D7~D0**: 16-bit CRC checksum low byte data register

• **CRCDH Register**

Bit	7	6	5	4	3	2	1	0
Name	D15	D14	D13	D12	D11	D10	D9	D8
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0      **D15~D8**: 16-bit CRC checksum high byte data register

• **CRCCR Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	POLY
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1      Unimplemented, read as “0”

Bit 0      **POLY**: 16-bit CRC generating polynomial selection  
 0: CRC-CCITT:  $X^{16}+X^{12}+X^5+1$   
 1: CRC-16:  $X^{16}+X^{15}+X^2+1$

**CRC Operation**

The CRC generator provides the 16-bit CRC result calculation based on the CRC16 and CCITT CRC16 polynomials. In this CRC generator, there are only these two polynomials available for the numeric values calculation. It can not support the 16-bit CRC calculations based on any other polynomials.

The following two expressions can be used for the CRC generating polynomial which is determined using the POLY bit in the CRC control register, CRCCR. The CRC calculation result is called as the CRC checksum, CRCSUM, and stored in the CRC checksum register pair, CRCDH and CRCDL.

- CRC-CCITT:  $X^{16}+X^{12}+X^5+1$ .
- CRC-16:  $X^{16}+X^{15}+X^2+1$ .

**CRC Computation**

Each write operation to the CRCIN register creates a combination of the previous CRC value stored in the CRCDH and CRCDL registers and the new data input. The CRC unit calculates the CRC data register value is based on byte by byte. It will take one MCU instruction cycle to calculate the CRC checksum.

**CRC Calculation Procedures**

1. Clear the checksum register pair, CRCDH and CRCDL.
2. Execute an “Exclusive OR” operation with the 8-bit input data byte and the 16-bit CRCSUM high byte. The result is called the temporary CRCSUM.
3. Shift the temporary CRCSUM value left by one bit and move a “0” into the LSB.
4. Check the shifted temporary CRCSUM value after procedure 3.

If the MSB is 0, then this shifted temporary CRCSUM will be considered as a new temporary CRCSUM.

Otherwise, execute an “Exclusive OR” operation with the shifted temporary CRCSUM in procedure 3 and a data “8005H”. Then the operation result will be regarded as the new temporary CRCSUM.

Note that the data to be perform an “Exclusive OR” operation is “8005H” for the CRC-16 polynomial while for the CRC-CCITT polynomial the data is “1021H”.

5. Repeat the procedure 3 ~ procedure 4 until all bits of the input data byte are completely calculated.
6. Repeat the procedure 2 ~ procedure 5 until all of the input data bytes are completely calculated. Then, the latest calculated result is the final CRC checksum, CRCSUM.

**CRC Calculation Examples**

- Write 1 byte input data into the CRCIN register and the corresponding CRC checksum are individually calculated as the following table shown.

CRC Data Input CRC Polynomial	00H	01H	02H	03H	04H	05H	06H	07H
CRC-CCITT ( $X^{16}+X^{12}+X^5+1$ )	0000H	1021H	2042H	3063H	4084H	50A5H	60C6H	70E7H
CRC-16 ( $X^{16}+X^{15}+X^2+1$ )	0000H	8005H	800FH	000AH	801BH	001EH	0014H	8011H

Note: The initial value of the CRC checksum register pair, CRCDH and CRCDL, is zero before each CRC input data is written into the CRCIN register.

- Write 4 bytes input data into the CRCIN register sequentially and the CRC checksum are sequentially listed in the following table.

CRC Data Input CRC Polynomial	CRCIN=78H→56H→34H→12H
CRC-CCITT ( $X^{16}+X^{12}+X^5+1$ )	(CRCDH, CRCDL)=FF9FH→BBC3H→A367H→D0FAH
CRC-16 ( $X^{16}+X^{15}+X^2+1$ )	(CRCDH, CRCDL)=0110h→91F1h→F2DEh→5C43h

Note: The initial value of the CRC checksum register pair, CRCDH and CRCDL, is zero before the sequential CRC data input operation.

**Program Memory CRC Checksum Calculation Example**

1. Clear the checksum register pair, CRCDH and CRCDL.
2. Select the CRC-CCITT or CRC-16 polynomial as the generating polynomial using the POLY bit in the CRCCR register.
3. Execute the table read instruction to read the program memory data value.
4. Write the table data low byte into the CRCIN register and execute the CRC calculation with the current CRCSUM value. Then a new CRCSUM result will be obtained and stored in the CRC checksum register pair, CRCDH and CRCDL.
5. Write the table data high byte into the CRCIN register and execute the CRC calculation with the current CRCSUM value. Then a new CRCSUM result will be obtained and stored in the CRC checksum register pair, CRCDH and CRCDL.
6. Repeat the procedure 3 ~ procedure 5 to read the next program memory data value and execute the CRC calculation until all program memory data are read followed by the sequential CRC calculation. Then the value in the CRC checksum register pair is the final CRC calculation result.

## Low Voltage Detector – LVD

The device has a Low Voltage Detector function, also known as LVD. This enabled the device to monitor the power supply voltage,  $V_{DD}$ , and provide a warning signal should it fall below a certain level. This function may be especially useful in battery applications where the supply voltage will gradually reduce as the battery ages, as it allows an early warning battery low signal to be generated. The Low Voltage Detector also has the capability of generating an interrupt signal.

### LVD Register

The Low Voltage Detector function is controlled using a single register with the name LVDC. Three bits in this register, VLVD2~VLVD0, are used to select one of eight fixed voltages below which a low voltage condition will be determined. A low voltage condition is indicated when the LVDO bit is set. If the LVDO bit is low, this indicates that the  $V_{DD}$  voltage is above the preset low voltage value. The LVDEN bit is used to control the overall on/off function of the low voltage detector. Setting the bit high will enable the low voltage detector. Clearing the bit to zero will switch off the internal low voltage detector circuits. As the low voltage detector will consume a certain amount of power, it may be desirable to switch off the circuit when not in use, an important consideration in power sensitive battery powered applications.

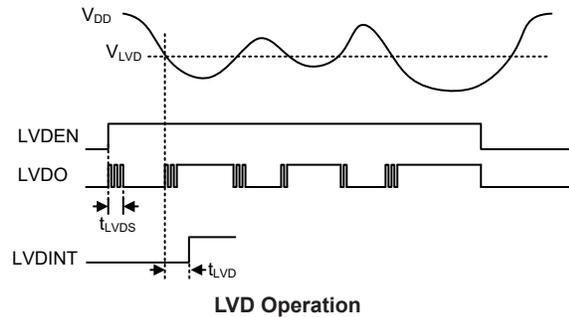
#### • LVDC Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	LVDO	LVDEN	—	VLVD2	VLVD1	VLVD0
R/W	—	—	R	R/W	—	R/W	R/W	R/W
POR	—	—	0	0	—	0	0	0

- Bit 7~6 Unimplemented, read as “0”
- Bit 5 **LVDO**: LVD output flag  
 0: No Low Voltage Detected  
 1: Low Voltage Detected
- Bit 4 **LVDEN**: Low Voltage Detector control  
 0: Disable  
 1: Enable
- Bit 3 Unimplemented, read as “0”
- Bit 2~0 **VLVD2~VLVD0**: Select LVD reference voltage  
 000: 1.8V  
 001: 2.0V  
 010: 2.4V  
 011: 2.7V  
 100: 3.0V  
 101: 3.3V  
 110: 3.6V  
 111: 4.0V

### LVD Operation

The Low Voltage Detector function operates by comparing the power supply voltage,  $V_{DD}$ , with a pre-specified voltage level stored in the LVDC register. This has a range of between 1.8V and 4.0V. When the power supply voltage,  $V_{DD}$ , falls below this pre-determined value, the LVDO bit will be set high indicating a low power supply voltage condition. When the device is in the SLEEP mode, the low voltage detector will be disabled even if the LVDEN bit is high. After enabling the Low Voltage Detector, a time delay  $t_{LVDS}$  should be allowed for the circuitry to stabilise before reading the LVDO bit. Note also that as the  $V_{DD}$  voltage may rise and fall rather slowly, at the voltage nears that of  $V_{LVD}$ , there may be multiple bit LVDO transitions.

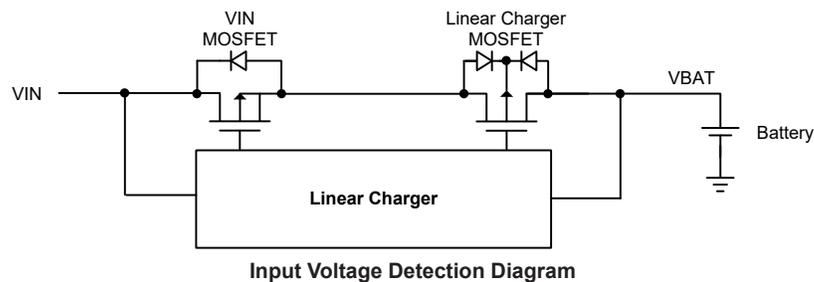


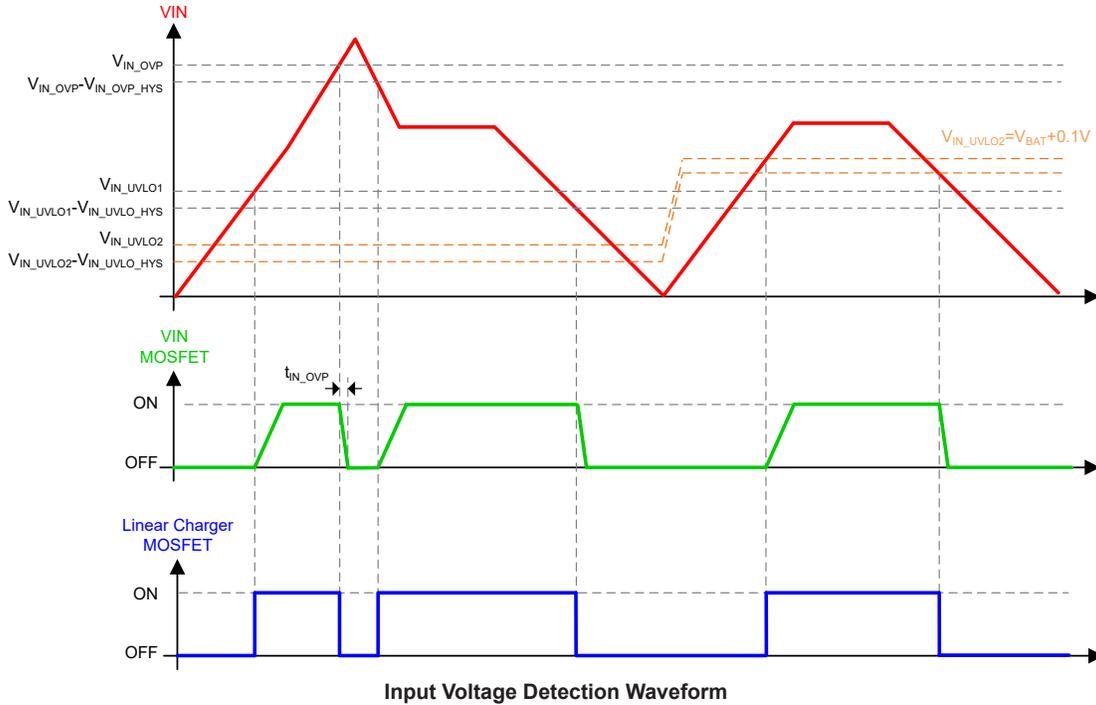
The Low Voltage Detector also has its own interrupt, providing an alternative means of low voltage detection, in addition to polling the LVDO bit. The interrupt will only be generated after a delay of  $t_{LVD}$  after the LVDO bit has been set high by a low voltage condition. When the device is in the SLEEP mode, the low voltage detector will be disabled even if the LVDEN bit is high. In this case, the LVF interrupt request flag will be set, causing an interrupt to be generated if  $V_{DD}$  falls below the preset LVD voltage. This will cause the device to wake-up from the IDLE Mode, however if the Low Voltage Detector wake up function is not required then the LVF flag should be first set high before the device enters the IDLE Mode.

## High Voltage Linear Charger

### Input Voltage Detect

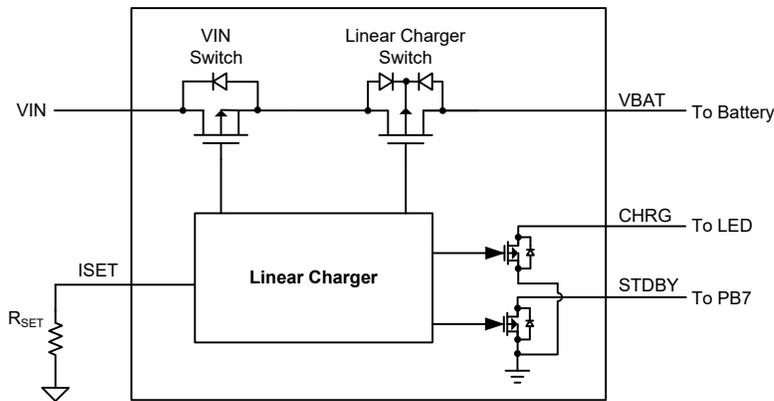
The device integrates an input voltage detect function. The maximum input rating is 20V to overcome unpredictable high voltages from the USB input. The input voltage goes through two switches, both of which will turn on when the  $V_{IN}$  is a normal voltage between 4.5V and 7.0V. When the input voltage exceeds 7.0V, the  $V_{IN}$  MOSFET will quickly turn off to protect the back-end circuit. When the input voltage is lower than 4V or  $V_{BAT}+0.1V$ , the linear charger MOSFET will turn off to prevent  $V_{BAT}$  current from flowing back to  $V_{IN}$  to reduce  $V_{BAT}$  leakage.





### Linear Charger

The device integrates a linear charger, the maximum charging current of which can be set to 1A through the ISET pin.

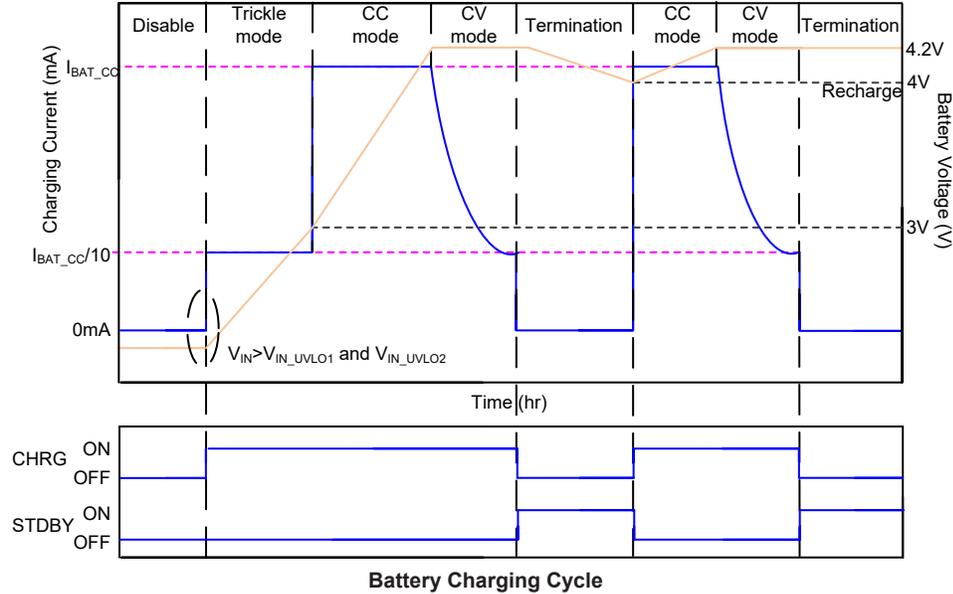


The external resistor, R<sub>SET</sub>, is used to set the charging current:

$$I_{BAT\_CC} \text{ (Charging Current)} = 2000/R_{SET}$$

The battery charging cycle curve is shown in the figure below. If the V<sub>BAT</sub> is lower than V<sub>BAT\_LOW</sub> - V<sub>BAT\_LOW\_HYS</sub>, the linear charger is in the trickle charge mode and the charging current is I<sub>BAT\_CC</sub>/10. Once the V<sub>BAT</sub> is higher than V<sub>BAT\_LOW</sub>, the constant current charge (CC) mode is applied and the charging current is I<sub>BAT\_CC</sub>. When V<sub>BAT</sub> has been charged to the battery charging target voltage of V<sub>BAT\_CV1/2</sub>, the device enters the constant voltage charge (CV) mode. Once the charging current drops to I<sub>BAT\_CC</sub>/10, the device is in a terminated state and stops charging. When V<sub>BAT</sub> is depleted and falls below the charging voltage of V<sub>BAT\_RECHG</sub>, the device will recharge the battery. When the temperature is higher than the protection temperature during charging, the charging current will automatically reduce, and the device enters the constant temperature charge (CT) mode.

The linear charger has two open-drain status indication outputs: the CHRG pin and STDBY signal. When the charger is in a charging status, the CHRG pin is pulled low and the STDBY outputs a high-impedance state. When the charger is fully charged, the STDBY signal is pulled low and the CHRG outputs a high-impedance state. In other status, both the CHRG and the STDBY output with a high-impedance state. STDBY can only be powered by VIN.



When the battery is not installed, the charger will charge the capacitance on the VBAT pin. When the external capacitance of the battery connection terminal BAT is  $10\mu\text{F}$ , the CHRG/STDBY will flash once every 1~4 seconds.

The linear charger has a temperature control function that automatically reduces the current to prevent temperature increase when the junction temperature exceeds  $T_{J(MAX)}$ . This means that the current in the constant current charge mode may be lower than the set  $I_{BAT\_CC}$ . This feature can protect the device from damage caused by larger charging power and operating environment.

### Reference Voltage

The linear charger integrates a reference voltage function. The output of the reference voltage is shared with the FN signal. When the D\_VREN is 1, the reference voltage function is enabled and the voltage is output by the FN signal. When the D\_VREN is 0, the reference voltage function is disabled and the FN signal is used as other function. The linear charger status will affect the reference voltage function, refer to the “Application Information” section.

### Multi-function FN Output Signal

The FN signal contains three functions, VIN status, linear charger status and reference voltage. It is necessary to configure the D\_SELFN, D\_VREN and D\_SELLC via the communication interface to enable the corresponding function.

Two-Line Control			FN Signal Function
D_SELLC	D_VREN	D_SELFN	
x	0	0	VIN status (INOK1)
0	0	1	Floating
1	0	1	Linear charger status
0→1 <sup>(1)</sup>	0	1	<t <sub>INOK2</sub> : VIN status (INOK2)
			>t <sub>INOK2</sub> +t <sub>LCS</sub> : Linear charger status
x	1	x <sup>(2)</sup>	Reference voltage

“x”: Don't care

Note: 1. D\_SELLC=1, D\_VREN=0 and D\_SELFN=1 are configured in the same communication, whereas the D\_SELLC was previously cleared to 0.

2. The FN signal function corresponding to the D\_SELFN setting is still valid, the appropriate status must be set according to the current conditions to avoid causing an abnormal reference voltage, refer to the “Application Information” section.

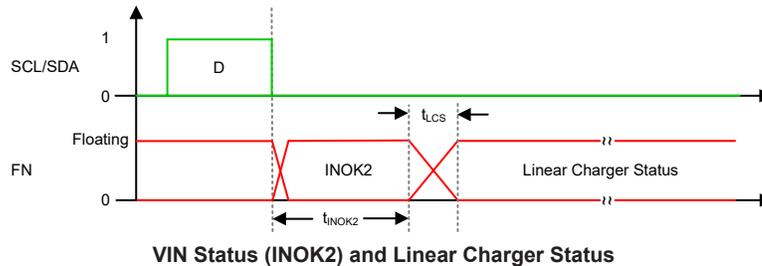
Linear Charger Status		
FN Signal Status	VIN Input Voltage Status	Description
Floating or pulled low	Invalid	The linear charger is disabled
Floating	Valid <sup>(Note)</sup>	The linear charger is disabled
		The linear charger is enabled and charging
Pulled low		The linear charger is enabled and has stopped

Note: Meet the following conditions:  $V_{IN\_UVLO1} < V_{IN}$ ,  $V_{IN\_UVLO2} < V_{IN}$  and  $V_{IN} < V_{IN\_OVP}$ .

VIN Input Voltage Status		
FN Signal Status		Description
INOK1	INOK2	
Floating	Floating	VIN input voltage is invalid
Floating	Pulled low	VIN input voltage is invalid
Pulled low	Floating	VIN input voltage is valid <sup>(Note)</sup>
Pulled low	Pulled low	VIN input voltage is invalid

Note: Meet the following conditions:  $V_{IN\_UVLO1} < V_{IN}$ ,  $V_{IN\_UVLO2} < V_{IN}$  and  $V_{IN} < V_{IN\_OVP}$ .

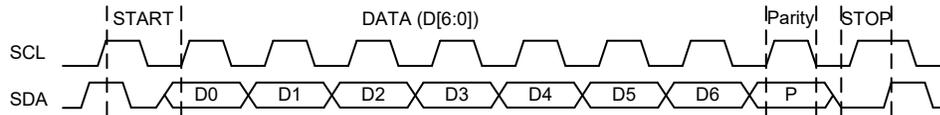
In the case of D\_SELLC=0, after configuring D\_SELLC=1, D\_VREN=0 and D\_SELFN=1 via the D value shown in the following figure, the FN signal outputs the VIN status (INOK2) and the linear charger status. The linear charger status must be read more than 8 times at intervals of 20μs or more, and then compare the number of different logic statuses, and the logic with more is the read result.



## Interface

The linear charger uses the SDA/SCL signal of the two-line communication interface for functional control and status reading with FN signal, which can enable/disable the linear charger and reference voltage function, or directly control the CHRГ and STDBY output status, or use the FN signal to read whether the input voltage is valid and whether the battery charged is complete.

The communication code is composed of one start bit, seven data bits, one even parity bit and one stop bit. The code must meet the definition to be effectively written into the linear charger, an incorrect operation will be ignored directly. The communication code requirements are as follows:



In order to ensure that the linear charger is operated at a correct voltage when powered on, the two-line communication interface is valid after the  $V_{BAT}$  is higher than  $V_{IF\_EN}$ , then the linear charger can be operated via the two-line communication interface. When the  $V_{BAT}$  is lower than  $V_{IF\_DIS}$ , the two-line communication interface will automatically return to the default value, and it cannot be used to operate the linear charger. The functions and state of the two-line communication interface are described as follows:

Data	Name	Function	Description	Default Value
D0	D_SETSTDBY	STDBY signal function setting	This setting is valid only when D1 is set to 1 0: STDBY signal is floating 1: STDBY signal is pulled low	0
D1	D_SELSTDBY	STDBY signal function selection	0: STDBY signal outputs the linear charging status STDBY signal is pulled low: Fully charged STDBY signal is floating: Not fully charged 1: STDBY signal outputs a status based on the D0 bit setting	0
D2	D_SETCHRG	CHRG pin function setting	This setting is valid only when D3 is set to 1 0: CHRG pin is floating 1: CHRG pin is pulled low	0
D3	D_SELCHRG	CHRG pin function selection	0: CHRG pin outputs the linear charging status CHRG pin is pulled low: Charging CHRG pin is floating: Not charging 1: CHRG pin outputs a status based on the D2 bit setting	0
D4	D_SELFN	FN signal function selection	0: FN signal outputs VIN status (INOK1) FN signal is pulled low: VIN input voltage is valid FN signal is floating: VIN input voltage is invalid 1: FN signal outputs VIN status (INOK2) and linear charger status < $t_{INOK2}$ : VIN status (INOK2) > $t_{INOK2}+t_{LCS}$ : Linear charger status VIN status The FN signal is pulled low for the INOK1 status and is floating for the INOK2 status: VIN input voltage is valid Others: VIN input voltage is invalid Linear charger status (it is only valid when there is a valid VIN input voltage) FN signal is pulled low: The linear charger is enabled and has stopped FN signal is floating: The linear charger is disabled, or the linear charger input power is abnormal, or the linear charger is enabled and charging	0
D5	D_VREN	Reference voltage function enable bit	0: Disable the reference voltage circuit 1: Enable the reference voltage circuit and output by the FN signal	0
D6	D_SELLC	Linear charger function enable bit	0: Disable the linear charger 1: Enable the linear charger, charging is controlled by hardware	1

## Power Consumption Considerations

The linear charger requires an ultra-low VBAT quiescent current when fully charged or not charging, it needs to be set up correctly to ensure that the battery is maintained at a fully charged state as much as possible. When the linear charger enters the normal charging mode, if the input voltage does not meet the input voltage range of the linear charger or triggers the charge termination state, the linear charging circuit and related circuits will be automatically shut down. At this time, the VBAT quiescent current is  $I_{BAT\_LKI}$ . When the linear charger function enable bit, D\_SELLC, is cleared to 0, the linear charger will be forced to shut down and the VBAT quiescent current will be maintained at  $I_{BAT\_LKI}$ , even though the input voltage meets the input voltage range of the linear charger.

In addition, during the shutdown of the linear charger, it can still be set via the communication interface. When the D\_VREN is set to 1, the FN signal will output a fixed reference voltage,  $V_{REF}$ , at this time, an additional power consumption will be generated on the device. In addition to the device operating state, the power consumption of the pull-low resistor of the SDA/SCL signal should also be considered into the VBAT quiescent current.

## Application Information

When the FN signal outputs the  $V_{REF}$  voltage, do not pull the FN signal low to avoid causing the  $V_{REF}$  reference voltage to be invalid. The following table can be referenced in each status to ensure that the FN signal maintains a normal  $V_{REF}$  output.

It is recommended to apply the control according to this table after the main firmware has completed the FN function reading and the use of the  $V_{REF}$  reference voltage.

Status		Two-Line Control	
VIN	Linear Charger	D_SELLC	D_SELFN
Not connected	Disable	0	1
Invalid	Disable	0	1
Valid	Disable	0	1
	Charging	1 <sup>(Note)</sup>	1
	Fully charged	0	1

Note: During the use of the  $V_{REF}$  reference voltage, when the linear charger status changes from charging to fully charged, it will cause the  $V_{REF}$  reference voltage to be invalid. To avoid this situation, it is therefore necessary to confirm the linear charger status via the FN signal before and after using the  $V_{REF}$  reference voltage. If the statuses are different, it means that the  $V_{REF}$  reference voltage was invalidated during its use, so re-execute the above operations or ignore the current  $V_{REF}$  output.

## Component Selection

### VIN Power Supply and Bypass Capacitors

The VIN power supply capacitor,  $C_{VIN2}$ , is suggested to have a value of 4.7 $\mu$ F. The power supply bypass capacitor,  $C_{VIN1}$ , can be used to filter out high-frequency noises on VIN when the circuit board is powered by the mains and the suggested capacitance value is 0.1 $\mu$ F.

### VBAT Output Capacitor

The VBAT output capacitor,  $C_{VBAT}$ , is suggested to have a value of 10 $\mu$ F.

### Linear Charger Current Regulation Resistor

The linear charger can select the output current according to the needs. It is recommended to use the grounding resistor  $R_{SET}$  with the recommended resistance value in the table below.

$I_{BAT\_CC}$ (A)	Resistor Package	$R_{SET}$ (k $\Omega$ )
1	0603	2
0.5		4
0.1		20

### Layout Guideline

To achieve better efficiency and reduce conduction noise, important PCB layout considerations are as follows:

1. Keep the main current path traces as short and wide as possible to reduce parasitic inductance and resistance.
2. Place the input/output capacitors as close as possible to the device pins.
3. Ensure that all feedback connections are short and straight. Components should be placed as close to the pins as possible.

### Thermal Consideration

The maximum power dissipation depends upon the thermal resistance of the device package, PCB layout, rate of surrounding airflow and difference between the junction and ambient temperature. The maximum power dissipation can be calculated by the following formula:

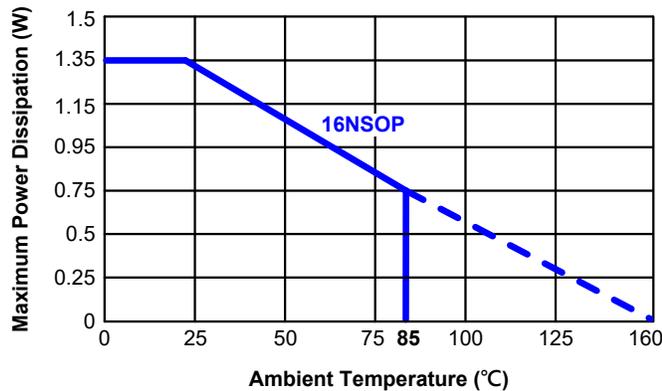
$$P_{D(MAX)} = (T_{J(MAX)} - T_a) / \theta_{JA} \quad (W)$$

Where  $T_{J(MAX)}$  is the maximum junction temperature,  $T_a$  is the ambient temperature and  $\theta_{JA}$  is the junction-to-ambient thermal resistance of device package.

For maximum operating rating conditions, the maximum junction temperature is 160°C. However, it is recommended that the maximum junction temperature does not exceed 125°C during normal operation to maintain high reliability. The de-rating curve of the maximum power dissipation is shown below:

$$P_{D(MAX)} = (160^\circ\text{C} - 25^\circ\text{C}) / (100^\circ\text{C}/\text{W}) = 1.35\text{W}$$

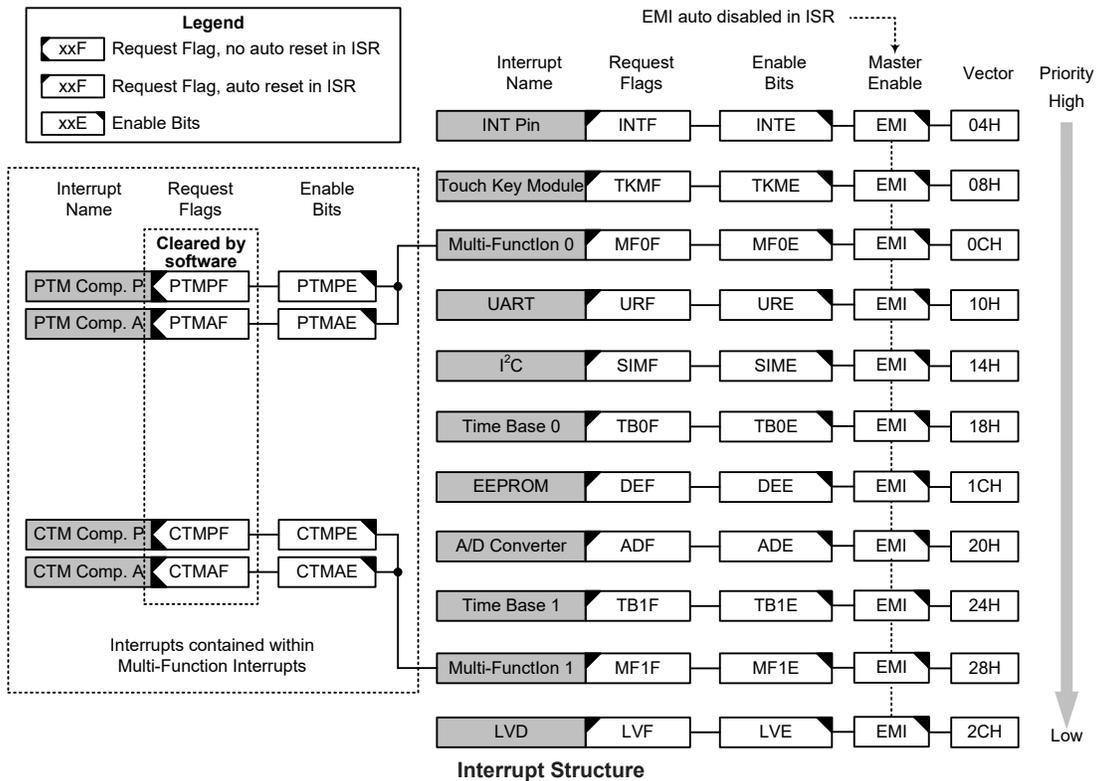
For a fixed  $T_{J(MAX)}$  of 160°C, the maximum power dissipation depends upon the operating ambient temperature and the package's thermal resistance,  $\theta_{JA}$ . The de-rating curve below shows the effect of rising ambient temperature on the maximum recommended power dissipation.



## Interrupts

Interrupts are an important part of any microcontroller system. When an external event or an internal function such as a Timer Module or an A/D converter requires microcontroller attention, their corresponding interrupt will enforce a temporary suspension of the main program allowing the microcontroller to direct attention to their respective needs. The device contains an external interrupt and several internal interrupt functions. The external interrupt is generated by the action of the external INT pin, while the internal interrupts are generated by various internal functions such as the TMs, Touch Key Module, Time Bases, I<sup>2</sup>C, LVD, EEPROM, UART and the A/D converter.

The various interrupt enable bits, together with their associated request flags, are shown in the accompanying diagrams with their order of priority. Some interrupt sources have their own individual vector while others share the same multi-function interrupt vector.



## Interrupt Registers

Overall interrupt control, which basically means the setting of request flags when certain microcontroller conditions occur and the setting of interrupt enable bits by the application program, is controlled by a series of registers, located in the Special Purpose Data Memory, as shown in the accompanying table. The number of registers depends upon the device chosen but fall into three categories. The first is the INTC0~INTC2 registers which setup the primary interrupts. The second is the MFIO~MF11 register which setups the Multi-function interrupt. Finally there is an INTEG register to setup the external interrupt trigger edge type.

Each register contains a number of enable bits to enable or disable individual interrupts as well as interrupt flags to indicate the presence of an interrupt request. The naming convention of these follows a specific pattern. First is listed an abbreviated interrupt type, then the (optional) number of that interrupt followed by either an “E” for enable/disable bit or “F” for request flag.

Function	Enable Bit	Request Flag	Notes
Global	EMI	—	—
INT Pin	INTE	INTF	—
Touch Key Module	TKME	TKMF	—
I <sup>2</sup> C Interface	SIME	SIMF	—
UART Interface	URE	URF	—
LVD	LVE	LVF	—
Time Base	TBnE	TBnF	n=0~1
EEPROM	DEE	DEF	—
A/D Converter	ADE	ADF	—
Multi-function	MFnE	MFnF	n=0~1
CTM	CTMPE	CTMPF	—
	CTMAE	CTMAF	
PTM	PTMPE	PTMPF	—
	PTMAE	PTMAF	

**Interrupt Register Bit Naming Conventions**

Register Name	Bit							
	7	6	5	4	3	2	1	0
INTEG	—	—	—	—	—	—	INTS1	INTS0
INTC0	—	MF0F	TKMF	INTF	MF0E	TKME	INTE	EMI
INTC1	DEF	TB0F	SIMF	URF	DEE	TB0E	SIME	URE
INTC2	LVF	MF1F	TB1F	ADF	LVE	MF1E	TB1E	ADE
MF10	—	—	PTMAF	PTMPF	—	—	PTMAE	PTMPE
MF11	—	—	CTMAF	CTMPF	—	—	CTMAE	CTMPE

**Interrupt Register List**

• **NTEG Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	INTS1	INTS0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~4 Unimplemented, read as “0”

Bit 1~0 **INTS1~INTS0**: Interrupt edge control for INT pin  
 00: Disable  
 01: Rising edge  
 10: Falling edge  
 11: Rising and falling edges

• **INTC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	MF0F	TKMF	INTF	MF0E	TKME	INTE	EMI
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as “0”

Bit 6 **MF0F**: Multi-function interrupt 0 request flag  
 0: No request  
 1: Interrupt request

- Bit 5      **TKMF**: Touch key module interrupt request flag  
             0: No request  
             1: Interrupt request
- Bit 4      **INTF**: INT interrupt request flag  
             0: No request  
             1: Interrupt request
- Bit 3      **MF0E**: Multi-function interrupt 0 control  
             0: Disable  
             1: Enable
- Bit 2      **TKME**: Touch key module interrupt control  
             0: Disable  
             1: Enable
- Bit 1      **INTE**: INT interrupt control  
             0: Disable  
             1: Enable
- Bit 0      **EMI**: Global interrupt control  
             0: Disable  
             1: Enable

• **INTC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	DEF	TB0F	SIMF	URF	DEE	TB0E	SIME	URE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7      **DEF**: Data EEPROM Interrupt request flag  
             0: No request  
             1: Interrupt request
- Bit 6      **TB0F**: Time Base 0 interrupt request flag  
             0: No request  
             1: Interrupt request
- Bit 5      **SIMF**: I<sup>2</sup>C interrupt request flag  
             0: No request  
             1: Interrupt request
- Bit 4      **URF**: UART interrupt request flag  
             0: No request  
             1: Interrupt request
- Bit 3      **DEE**: Data EEPROM Interrupt control  
             0: Disable  
             1: Enable
- Bit 2      **TB0E**: Time Base 0 interrupt control  
             0: Disable  
             1: Enable
- Bit 1      **SIME**: I<sup>2</sup>C interrupt control  
             0: Disable  
             1: Enable
- Bit 0      **URE**: UART interrupt control  
             0: Disable  
             1: Enable

• **INTC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	LVF	MF1F	TB1F	ADF	LVE	MF1E	TB1E	ADE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

- Bit 7      **LVF**: LVD interrupt request flag  
0: No request  
1: Interrupt request
- Bit 6      **MF1F**: Multi-function 1 interrupt request flag  
0: No request  
1: Interrupt request
- Bit 5      **TB1F**: Time Base 1 interrupt request flag  
0: No request  
1: Interrupt request
- Bit 4      **ADF**: A/D converter interrupt request flag  
0: No request  
1: Interrupt request
- Bit 3      **LVE**: LVD interrupt control  
0: Disable  
1: Enable
- Bit 2      **MF1E**: Multi-function 1 interrupt control  
0: Disable  
1: Enable
- Bit 1      **TB1E**: Time Base 1 interrupt control  
0: Disable  
1: Enable
- Bit 0      **ADE**: A/D converter interrupt control  
0: Disable  
1: Enable

• **MFIO Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	PTMAF	PTMPF	—	—	PTMAE	PTMPE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

- Bit 7~6      Unimplemented, read as “0”
- Bit 5      **PTMAF**: PTM Comparator A match interrupt request flag  
0: No request  
1: Interrupt request  
Note that this bit must be cleared to zero by the application program when the interrupt is serviced.
- Bit 4      **PTMPF**: PTM Comparator P match interrupt request flag  
0: No request  
1: Interrupt request  
Note that this bit must be cleared to zero by the application program when the interrupt is serviced.
- Bit 3~2      Unimplemented, read as “0”
- Bit 1      **PTMAE**: PTM Comparator A match interrupt control  
0: Disable  
1: Enable
- Bit 0      **PTMPE**: PTM Comparator P match interrupt control  
0: Disable  
1: Enable

• **MF1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	CTMAF	CTMPF	—	—	CTMAE	CTMPE
R/W	—	—	R/W	R/W	—	—	R/W	R/W
POR	—	—	0	0	—	—	0	0

Bit 7~6 Unimplemented, read as “0”

Bit 5 **CTMAF**: CTM Comparator A match interrupt request flag  
 0: No request  
 1: Interrupt request

Note that this bit must be cleared to zero by the application program when the interrupt is serviced.

Bit 4 **CTMPF**: CTM Comparator P match interrupt request flag  
 0: No request  
 1: Interrupt request

Note that this bit must be cleared to zero by the application program when the interrupt is serviced.

Bit 3~2 Unimplemented, read as “0”

Bit 1 **CTMAE**: CTM Comparator A match interrupt control  
 0: Disable  
 1: Enable

Bit 0 **CTMPE**: CTM Comparator P match interrupt control  
 0: Disable  
 1: Enable

**Interrupt Operation**

When the conditions for an interrupt event occur, such as a Touch Key Counter overflow, a TM Comparator P or Comparator A match or A/D conversion completion, etc., the relevant interrupt request flag will be set. Whether the request flag actually generates a program jump to the relevant interrupt vector is determined by the condition of the interrupt enable bit. If the enable bit is set high then the program will jump to its relevant vector; if the enable bit is zero then although the interrupt request flag is set an actual interrupt will not be generated and the program will not jump to the relevant interrupt vector. The global interrupt enable bit, if cleared to zero, will disable all interrupts.

When an interrupt is generated, the Program Counter, which stores the address of the next instruction to be executed, will be transferred onto the stack. The Program Counter will then be loaded with a new address which will be the value of the corresponding interrupt vector. The microcontroller will then fetch its next instruction from this interrupt vector. The instruction at this vector will usually be a JMP which will jump to another section of program which is known as the interrupt service routine. Here is located the code to control the appropriate interrupt. The interrupt service routine must be terminated with a RETI, which retrieves the original Program Counter address from the stack and allows the microcontroller to continue with normal execution at the point where the interrupt occurred.

Once an interrupt subroutine is serviced, all other interrupts will be blocked, as the global interrupt enable bit, EMI bit will be cleared automatically. This will prevent any further interrupt nesting from occurring. However, if other interrupt requests occur during this interval, although the interrupt will not be immediately serviced, the request flag will still be recorded.

If an interrupt requires immediate servicing while the program is already in another interrupt service routine, the EMI bit should be set after entering the routine to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the Stack Pointer is decremented. If immediate service is desired, the stack must be prevented from

becoming full. In case of simultaneous requests, the Interrupt Structure diagram shows the priority that is applied. All of the interrupt request flags when set will wake-up the device if it is in SLEEP or IDLE Mode, however to prevent a wake-up from occurring the corresponding flag should be set before the device is in SLEEP or IDLE Mode.

### **External Interrupt**

The external interrupt is controlled by signal transitions on the INT pin. An external interrupt request will take place when the external interrupt request flag, INTF, is set, which will occur when a transition, whose type is chosen by the edge select bits, appears on the external interrupt pin. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective external interrupt enable bit, INTE, must first be set. Additionally the correct interrupt edge type must be selected using the INTEG register to enable the external interrupt function and to choose the trigger edge type. As the external interrupt pin is pin-shared with I/O pins, it can only be configured as an external interrupt pin if the external interrupt enable bit in the corresponding interrupt register has been set. The pin must also be setup as an input by setting the corresponding bit in the port control register. When the interrupt is enabled, the stack is not full and the correct transition type appears on the external interrupt pin, a subroutine call to the external interrupt vector, will take place. When the interrupt is serviced, the external interrupt request flags, INTF, will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts. Note that any pull-high resistor selections on the external interrupt pins will remain valid even if the pin is used as an external interrupt input.

The INTEG register is used to select the type of active edge that will trigger the external interrupt. A choice of either rising or falling or both edge types can be chosen to trigger an external interrupt. Note that the INTEG register can also be used to disable the external interrupt function.

### **Touch Key Module Interrupt**

For a Touch Key interrupt to occur, the global interrupt enable bit, EMI, and the Touch Key interrupt enable bit, TKME, must be first set. An actual Touch Key interrupt will take place when the Touch Key interrupt request flag, TMKF, is set, a situation that will occur when the time slot counter overflows. When the interrupt is enabled, the stack is not full and the Touch Key time slot counter overflow occurs, a subroutine call to the relevant interrupt vector, will take place. When the interrupt is serviced, the Touch Key interrupt request flag will be automatically reset and the EMI bit will also be automatically cleared to disable other interrupts.

### **I<sup>2</sup>C Interrupt**

An I<sup>2</sup>C Interrupt request will take place when the I<sup>2</sup>C Interrupt request flag, SIMF, is set, which occurs when a byte of data has been received or transmitted by the I<sup>2</sup>C interface, an I<sup>2</sup>C address match or I<sup>2</sup>C time-out occurrence. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and the I<sup>2</sup>C Interrupt enable bit, SIME, must first be set. When the interrupt is enabled, the stack is not full and any of the above described situations occurs, a subroutine call to the I<sup>2</sup>C interrupt vector, will take place. When the I<sup>2</sup>C Interface Interrupt is serviced, the interrupt request flag, SIMF, will be automatically reset and the EMI bit will be cleared to disable other interrupts.

### **UART Transfer Interrupt**

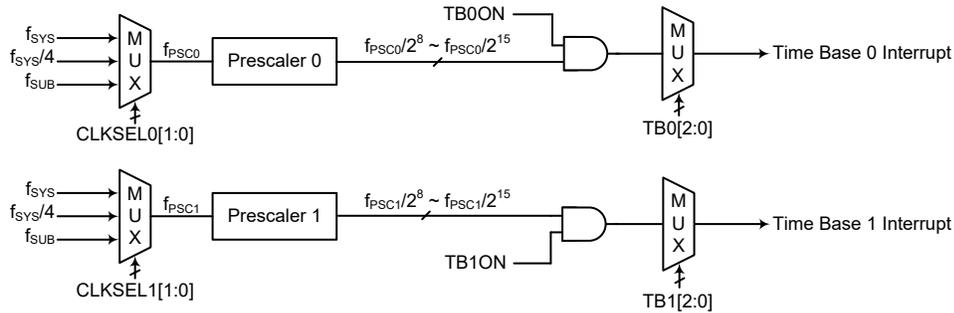
Several individual UART conditions can generate a UART interrupt. When one of these conditions occurs, an interrupt signal will be generated to get the attention of the microcontroller. These conditions are a transmitter data register empty, transmitter idle, receiver reaching FIFO trigger

level, receiver overrun, address detect and an RX/TX pin wake-up. To allow the program to branch to the respective interrupt vector addresses, the global interrupt enable bit, EMI, and the UART interrupt enable bit, URE, must first be set. When the interrupt is enabled, the stack is not full and any of these conditions are created, a subroutine call to the UART interrupt vector will take place. When the UART Interrupt is serviced, the UART interrupt request flag, URF, will be automatically cleared and the EMI bit will be automatically cleared to disable other interrupts. However, the USR register flags will only be cleared when certain actions are taken by the UART, the details of which are given in the UART section.

**Time Base Interrupts**

The function of the Time Base interrupts is to provide regular time signal in the form of an internal interrupt. They are controlled by the overflow signals from their respective timer functions. When these happen their respective interrupt request flags, TB0F or TB1F will be set. To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI and Time Base enable bits, TB0E or TB1E, must first be set. When the interrupt is enabled, the stack is not full and the Time Base overflows, a subroutine call to their respective vector locations will take place. When the interrupt is serviced, the respective interrupt request flag, TB0F or TB1F, will be automatically reset and the EMI bit will be cleared to disable other interrupts.

The purpose of the Time Base interrupt is to provide an interrupt signal at fixed time periods. Its clock source,  $f_{PSC0}$  or  $f_{PSC1}$ , originates from the internal clock source  $f_{SYS}$ ,  $f_{SYS}/4$  or  $f_{SUB}$  and then passes through a divider, the division ratio of which is selected by programming the appropriate bits in the TB0C and TB1C registers to obtain longer interrupt periods whose value ranges. The clock source which in turn controls the Time Base interrupt period is selected using the CLKSEL0[1:0] and CLKSEL1[1:0] bits in the PSC0R and PSC1R register.



**Time Base Interrupts**

**• PSCnR Register (n=0~1)**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	CLKSELn1	CLKSELn0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as “0”

Bit 1~0 **CLKSELn1~CLKSELn0**: Prescaler clock source  $f_{PSCn}$  selection  
 00:  $f_{SYS}$   
 01:  $f_{SYS}/4$   
 1x:  $f_{SUB}$

• **TB0C Register**

Bit	7	6	5	4	3	2	1	0
Name	TB0ON	—	—	—	—	TB02	TB01	TB00
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

- Bit 7      **TB0ON**: Time Base 0 control  
             0: Disable  
             1: Enable
- Bit 6~3    Unimplemented, read as “0”
- Bit 2~0    **TB02~TB00**: Select Time Base 0 time-out period  
             000:  $2^8/f_{PSC0}$   
             001:  $2^9/f_{PSC0}$   
             010:  $2^{10}/f_{PSC0}$   
             011:  $2^{11}/f_{PSC0}$   
             100:  $2^{12}/f_{PSC0}$   
             101:  $2^{13}/f_{PSC0}$   
             110:  $2^{14}/f_{PSC0}$   
             111:  $2^{15}/f_{PSC0}$

• **TB1C Register**

Bit	7	6	5	4	3	2	1	0
Name	TB1ON	—	—	—	—	TB12	TB11	TB10
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

- Bit 7      **TB1ON**: Time Base 1 control  
             0: Disable  
             1: Enable
- Bit 6~3    Unimplemented, read as “0”
- Bit 2~0    **TB12~TB10**: Select Time Base 1 time-out period  
             000:  $2^8/f_{PSC1}$   
             001:  $2^9/f_{PSC1}$   
             010:  $2^{10}/f_{PSC1}$   
             011:  $2^{11}/f_{PSC1}$   
             100:  $2^{12}/f_{PSC1}$   
             101:  $2^{13}/f_{PSC1}$   
             110:  $2^{14}/f_{PSC1}$   
             111:  $2^{15}/f_{PSC1}$

**EEPROM Interrupt**

An EEPROM Interrupt request will take place when the EEPROM Interrupt request flag, DEF, is set, which occurs when an EEPROM erase or write cycle ends. To allow the program to branch to its interrupt vector address, the global interrupt enable bit, EMI, and the EEPROM Interrupt enable bit, DEE, must first be set. When the interrupt is enabled, the stack is not full and an EEPROM erase or write cycle ends, a subroutine call to the EEPROM Interrupt vector will take place. When the EEPROM Interrupt is serviced, the EEPROM Interrupt flag, DEF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

**A/D Converter Interrupt**

The A/D Converter Interrupt is controlled by the termination of an A/D conversion process. An A/D Converter Interrupt request will take place when the A/D Converter Interrupt request flag, ADF, is set, which occurs when the A/D conversion process finishes. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and A/D Interrupt enable bit,

ADE, must first be set. When the interrupt is enabled, the stack is not full and the A/D conversion process has ended, a subroutine call to the A/D Converter Interrupt vector will take place. When the interrupt is serviced, the A/D Converter Interrupt flag, ADF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

### **Multi-function Interrupts**

Within the device there are two Multi-function interrupts. Unlike the other independent interrupts, these interrupts have no independent source, but rather are formed from other existing interrupt sources, namely the TM interrupts.

A Multi-function interrupt request will take place when the Multi-function interrupt request flag MFnF are set. The Multi-function interrupt flag will be set when any of its included functions generate an interrupt request flag. To allow the program to branch to its respective interrupt vector address, when the Multi-function interrupt is enabled and the stack is not full, and one of the interrupts contained within the Multi-function interrupt occurs, a subroutine call to the Multi-function interrupt vector will take place. When the interrupt is serviced, the related Multi-Function request flag will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts.

However, it must be noted that, although the Multi-function Interrupt request flag will be automatically reset when the interrupt is serviced, the request flags from the original source of the Multi-function interrupt will not be automatically reset and must be manually reset by the application program.

### **TM Interrupts**

The Compact and Periodic Type TMs have two interrupts, one comes from the comparator A match situation and the other comes from the comparator P match situation. All of the TM interrupts are contained within the Multi-function Interrupts. For each of the Compact and Periodic Type TMs there are two interrupt request flags, xTMPF and xTMAF, and two enable control bits, xTMPE and xTMAE. A TM interrupt request will take place when any of the TM request flags are set, a situation which occurs when a TM comparator P or A match situation happens.

To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, respective TM Interrupt enable bit and the relevant Multi-function Interrupt enable bit, MFnE, must first be set. When the interrupt is enabled, the stack is not full and a TM comparator match situation occurs, a subroutine call to the relevant TM Interrupt vector locations will take place. When the TM interrupt is serviced, the EMI bit will be automatically cleared to disable other interrupts, however only the related MFnF flag will be automatically cleared. As the TM interrupt request flags will not be automatically cleared, they have to be cleared by the application program.

### **LVD Interrupt**

An LVD interrupt request will take place when the LVD interrupt request flag, LVF, is set, which occurs when the Low Voltage Detector function detects a low power supply voltage. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, Low Voltage interrupt enable bit, LVE, must first be set. When the interrupt is enabled, the stack is not full and a low voltage condition occurs, a subroutine call to the LVD interrupt vector will take place. When the Low Voltage Interrupt is serviced, the LVD Interrupt flag, LVF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

## Interrupt Wake-up Function

Each of the interrupt functions has the capability of waking up the microcontroller when in the SLEEP or IDLE Mode. A wake-up is generated when an interrupt request flag changes from low to high and is independent of whether the interrupt is enabled or not. Therefore, even though this device is in the SLEEP or IDLE Mode and its system oscillator stopped, situations such as external edge transitions on the external interrupt pin or a low power supply voltage may cause their respective interrupt flag to be set high and consequently generate an interrupt. Care must therefore be taken if spurious wake-up situations are to be avoided. If an interrupt wake-up function is to be disabled then the corresponding interrupt request flag should be set high before the device enters the SLEEP or IDLE Mode. The interrupt enable bits have no effect on the interrupt wake-up function.

## Programming Considerations

By disabling the relevant interrupt enable bits, a requested interrupt can be prevented from being serviced, however, once an interrupt request flag is set, it will remain in this condition in the interrupt register until the corresponding interrupt is serviced or until the request flag is cleared by the application program.

Where a certain interrupt is contained within a Multi-function interrupt, then when the interrupt service routine is executed, as only the Multi-function interrupt request flags, MF<sub>n</sub>F, will be automatically cleared, the individual request flag for the function needs to be cleared by the application program.

It is recommended that programs do not use the “CALL” instruction within the interrupt service subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately. If only one stack is left and the interrupt is not well controlled, the original control sequence will be damaged once a CALL subroutine is executed in the interrupt subroutine.

Every interrupt has the capability of waking up the microcontroller when it is in the SLEEP or IDLE Mode, the wake-up being generated when the interrupt request flag changes from low to high. If it is required to prevent a certain interrupt from waking up the microcontroller then its respective request flag should be first set high before enter SLEEP or IDLE Mode.

As only the Program Counter is pushed onto the stack, then when the interrupt is serviced, if the contents of the accumulator, status register or other registers are altered by the interrupt service program, their contents should be saved to the memory at the beginning of the interrupt service routine.

To return from an interrupt subroutine, either an RET or RETI instruction may be executed. The RETI instruction in addition to executing a return to the main program also automatically sets the EMI bit high to allow further interrupts. The RET instruction however only executes a return to the main program leaving the EMI bit in its present zero state and therefore disabling the execution of further interrupts.

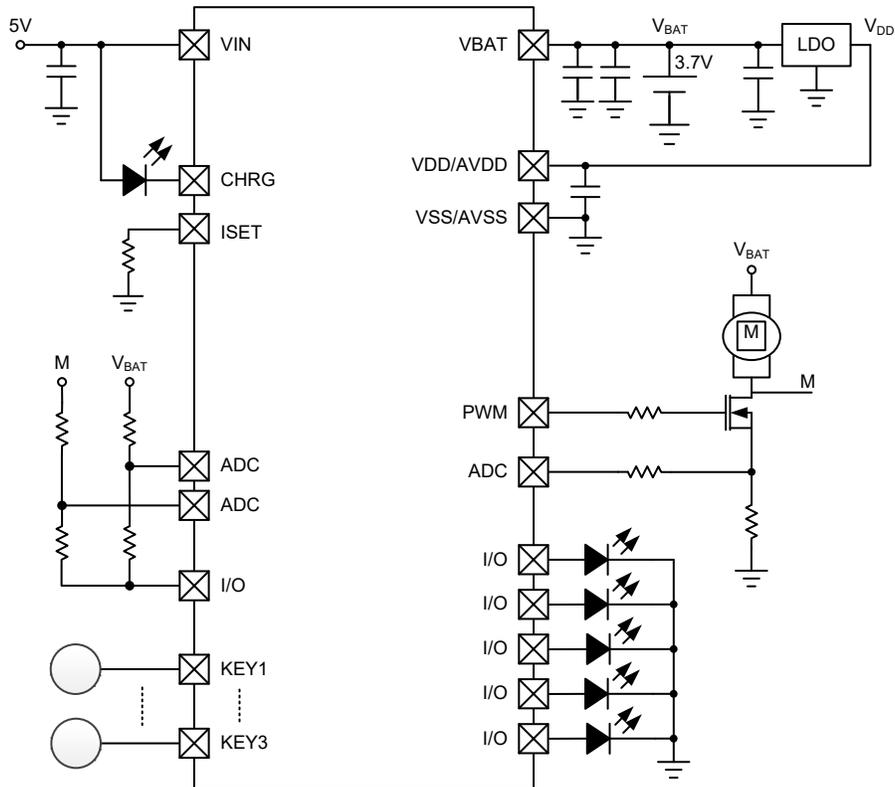
## Configuration Options

Configuration options refer to certain options within the MCU that are programmed into the device during the programming process. During the development process, these options are selected using the HT-IDE software development tools. All options must be defined for proper system function, the details of which are shown in the table.

No.	Options
<b>Oscillator Option</b>	
1	HIRC frequency selection – $f_{HIRC}$ : 8MHz, 12MHz or 16MHz

Note: When the HIRC has been configured at a frequency shown in this table, the HIRC1 and HIRC0 bits should also be setup to select the same frequency to achieve the HIRC frequency accuracy specified in the A.C. Characteristics.

## Application Circuits



## Instruction Set

### Introduction

Central to the successful operation of any microcontroller is its instruction set, which is a set of program instruction codes that directs the microcontroller to perform certain operations. In the case of Holtek microcontroller, a comprehensive and flexible set of over 60 instructions is provided to enable programmers to implement their application with the minimum of programming overheads.

For easier understanding of the various instruction codes, they have been subdivided into several functional groupings.

### Instruction Timing

Most instructions are implemented within one instruction cycle. The exceptions to this are branch, call, or table read instructions where two instruction cycles are required. One instruction cycle is equal to 4 system clock cycles, therefore in the case of an 8MHz system oscillator, most instructions would be implemented within 0.5 $\mu$ s and branch or call instructions would be implemented within 1 $\mu$ s. Although instructions which require one more cycle to implement are generally limited to the JMP, CALL, RET, RETI and table read instructions, it is important to realize that any other instructions which involve manipulation of the Program Counter Low register or PCL will also take one more cycle to implement. As instructions which change the contents of the PCL will imply a direct jump to that new address, one more cycle will be required. Examples of such instructions would be “CLR PCL” or “MOV PCL, A”. For the case of skip instructions, it must be noted that if the result of the comparison involves a skip operation then this will also take one more cycle, if no skip is involved then only one cycle is required.

### Moving and Transferring Data

The transfer of data within the microcontroller program is one of the most frequently used operations. Making use of several kinds of MOV instructions, data can be transferred from registers to the Accumulator and vice-versa as well as being able to move specific immediate data directly into the Accumulator. One of the most important data transfer applications is to receive data from the input ports and transfer data to the output ports.

### Arithmetic Operations

The ability to perform certain arithmetic operations and data manipulation is a necessary feature of most microcontroller applications. Within the Holtek microcontroller instruction set are a range of add and subtract instruction mnemonics to enable the necessary arithmetic to be carried out. Care must be taken to ensure correct handling of carry and borrow data when results exceed 255 for addition and less than 0 for subtraction. The increment and decrement instructions such as INC, INCA, DEC and DECA provide a simple means of increasing or decreasing by a value of one of the values in the destination specified.

## Logical and Rotate Operation

The standard logical operations such as AND, OR, XOR and CPL all have their own instruction within the Holtek microcontroller instruction set. As with the case of most instructions involving data manipulation, data must pass through the Accumulator which may involve additional programming steps. In all logical data operations, the zero flag may be set if the result of the operation is zero. Another form of logical data manipulation comes from the rotate instructions such as RR, RL, RRC and RLC which provide a simple means of rotating one bit right or left. Different rotate instructions exist depending on program requirements. Rotate instructions are useful for serial port programming applications where data can be rotated from an internal register into the Carry bit from where it can be examined and the necessary serial bit set high or low. Another application which rotate data operations are used is to implement multiplication and division calculations.

## Branches and Control Transfer

Program branching takes the form of either jumps to specified locations using the JMP instruction or to a subroutine using the CALL instruction. They differ in the sense that in the case of a subroutine call, the program must return to the instruction immediately when the subroutine has been carried out. This is done by placing a return instruction “RET” in the subroutine which will cause the program to jump back to the address right after the CALL instruction. In the case of a JMP instruction, the program simply jumps to the desired location. There is no requirement to jump back to the original jumping off point as in the case of the CALL instruction. One special and extremely useful set of branch instructions are the conditional branches. Here a decision is first made regarding the condition of a certain data memory or individual bits. Depending upon the conditions, the program will continue with the next instruction or skip over it and jump to the following instruction. These instructions are the key to decision making and branching within the program perhaps determined by the condition of certain input switches or by the condition of internal data bits.

## Bit Operations

The ability to provide single bit operations on Data Memory is an extremely flexible feature of all Holtek microcontrollers. This feature is especially useful for output port bit programming where individual bits or port pins can be directly set high or low using either the “SET [m].i” or “CLR [m].i” instructions respectively. The feature removes the need for programmers to first read the 8-bit output port, manipulate the input data to ensure that other bits are not changed and then output the port with the correct new data. This read-modify-write process is taken care of automatically when these bit operation instructions are used.

## Table Read Operations

Data storage is normally implemented by using registers. However, when working with large amounts of fixed data, the volume involved often makes it inconvenient to store the fixed data in the Data Memory. To overcome this problem, Holtek microcontrollers allow an area of Program Memory to be setup as a table where data can be directly stored. A set of easy to use instructions provides the means by which this fixed data can be referenced and retrieved from the Program Memory.

## Other Operations

In addition to the above functional instructions, a range of other instructions also exist such as the “HALT” instruction for Power-down operations and instructions to control the operation of the Watchdog Timer for reliable program operations under extreme electric or electromagnetic environments. For their relevant operations, refer to the functional related sections.

## Instruction Set Summary

The instructions related to the data memory access in the following table can be used when the desired data memory is located in Data Memory sector 0.

### Table Conventions

x: Bits immediate data  
 m: Data Memory address  
 A: Accumulator  
 i: 0~7 number of bits  
 addr: Program memory address

Mnemonic	Description	Cycles	Flag Affected
<b>Arithmetic</b>			
ADD A,[m]	Add Data Memory to ACC	1	Z, C, AC, OV, SC
ADDM A,[m]	Add ACC to Data Memory	1 <sup>Note</sup>	Z, C, AC, OV, SC
ADD A,x	Add immediate data to ACC	1	Z, C, AC, OV, SC
ADC A,[m]	Add Data Memory to ACC with Carry	1	Z, C, AC, OV, SC
ADCM A,[m]	Add ACC to Data memory with Carry	1 <sup>Note</sup>	Z, C, AC, OV, SC
SUB A,x	Subtract immediate data from the ACC	1	Z, C, AC, OV, SC, CZ
SUB A,[m]	Subtract Data Memory from ACC	1	Z, C, AC, OV, SC, CZ
SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	1 <sup>Note</sup>	Z, C, AC, OV, SC, CZ
SBC A,x	Subtract immediate data from ACC with Carry	1	Z, C, AC, OV, SC, CZ
SBC A,[m]	Subtract Data Memory from ACC with Carry	1	Z, C, AC, OV, SC, CZ
SBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	1 <sup>Note</sup>	Z, C, AC, OV, SC, CZ
DAA [m]	Decimal adjust ACC for Addition with result in Data Memory	1 <sup>Note</sup>	C
<b>Logic Operation</b>			
AND A,[m]	Logical AND Data Memory to ACC	1	Z
OR A,[m]	Logical OR Data Memory to ACC	1	Z
XOR A,[m]	Logical XOR Data Memory to ACC	1	Z
ANDM A,[m]	Logical AND ACC to Data Memory	1 <sup>Note</sup>	Z
ORM A,[m]	Logical OR ACC to Data Memory	1 <sup>Note</sup>	Z
XORM A,[m]	Logical XOR ACC to Data Memory	1 <sup>Note</sup>	Z
AND A,x	Logical AND immediate Data to ACC	1	Z
OR A,x	Logical OR immediate Data to ACC	1	Z
XOR A,x	Logical XOR immediate Data to ACC	1	Z
CPL [m]	Complement Data Memory	1 <sup>Note</sup>	Z
CPLA [m]	Complement Data Memory with result in ACC	1	Z
<b>Increment &amp; Decrement</b>			
INCA [m]	Increment Data Memory with result in ACC	1	Z
INC [m]	Increment Data Memory	1 <sup>Note</sup>	Z
DECA [m]	Decrement Data Memory with result in ACC	1	Z
DEC [m]	Decrement Data Memory	1 <sup>Note</sup>	Z
<b>Rotate</b>			
RRA [m]	Rotate Data Memory right with result in ACC	1	None
RR [m]	Rotate Data Memory right	1 <sup>Note</sup>	None
RRCA [m]	Rotate Data Memory right through Carry with result in ACC	1	C
RRC [m]	Rotate Data Memory right through Carry	1 <sup>Note</sup>	C
RLA [m]	Rotate Data Memory left with result in ACC	1	None
RL [m]	Rotate Data Memory left	1 <sup>Note</sup>	None
RLCA [m]	Rotate Data Memory left through Carry with result in ACC	1	C
RLC [m]	Rotate Data Memory left through Carry	1 <sup>Note</sup>	C

Mnemonic	Description	Cycles	Flag Affected
<b>Data Move</b>			
MOV A,[m]	Move Data Memory to ACC	1	None
MOV [m],A	Move ACC to Data Memory	1 <sup>Note</sup>	None
MOV A,x	Move immediate data to ACC	1	None
<b>Bit Operation</b>			
CLR [m].i	Clear bit of Data Memory	1 <sup>Note</sup>	None
SET [m].i	Set bit of Data Memory	1 <sup>Note</sup>	None
<b>Branch Operation</b>			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if Data Memory is zero	1 <sup>Note</sup>	None
SZA [m]	Skip if Data Memory is zero with data movement to ACC	1 <sup>Note</sup>	None
SZ [m].i	Skip if bit i of Data Memory is zero	1 <sup>Note</sup>	None
SNZ [m]	Skip if Data Memory is not zero	1 <sup>Note</sup>	None
SNZ [m].i	Skip if bit i of Data Memory is not zero	1 <sup>Note</sup>	None
SIZ [m]	Skip if increment Data Memory is zero	1 <sup>Note</sup>	None
SDZ [m]	Skip if decrement Data Memory is zero	1 <sup>Note</sup>	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC	1 <sup>Note</sup>	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC	1 <sup>Note</sup>	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
<b>Table Read Operation</b>			
TABRD [m]	Read table (specific page) to TBLH and Data Memory	2 <sup>Note</sup>	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory	2 <sup>Note</sup>	None
ITABRD [m]	Increment table pointer TBLP first and Read table (specific page) to TBLH and Data Memory	2 <sup>Note</sup>	None
ITABRDL [m]	Increment table pointer TBLP first and Read table (last page) to TBLH and Data Memory	2 <sup>Note</sup>	None
<b>Miscellaneous</b>			
NOP	No operation	1	None
CLR [m]	Clear Data Memory	1 <sup>Note</sup>	None
SET [m]	Set Data Memory	1 <sup>Note</sup>	None
CLR WDT	Clear Watchdog Timer	1	TO, PDF
SWAP [m]	Swap nibbles of Data Memory	1 <sup>Note</sup>	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC	1	None
HALT	Enter power down mode	1	TO, PDF

Note: 1. For skip instructions, if the result of the comparison involves a skip then two cycles are required, if no skip takes place only one cycle is required.

2. Any instruction which changes the contents of the PCL will also require 2 cycles for execution.

### Extended Instruction Set

The extended instructions are used to support the full range address access for the data memory. When the accessed data memory is located in any data memory sector except sector 0, the extended instruction can be used to directly access the data memory instead of using the indirect addressing access. This can not only reduce the use of Flash memory space but also improve the CPU execution efficiency.

Mnemonic	Description	Cycles	Flag Affected
<b>Arithmetic</b>			
LADD A,[m]	Add Data Memory to ACC	2	Z, C, AC, OV, SC
LADDM A,[m]	Add ACC to Data Memory	2 <sup>Note</sup>	Z, C, AC, OV, SC
LADC A,[m]	Add Data Memory to ACC with Carry	2	Z, C, AC, OV, SC
LADCM A,[m]	Add ACC to Data memory with Carry	2 <sup>Note</sup>	Z, C, AC, OV, SC
LSUB A,[m]	Subtract Data Memory from ACC	2	Z, C, AC, OV, SC, CZ
LSUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	2 <sup>Note</sup>	Z, C, AC, OV, SC, CZ
LSBC A,[m]	Subtract Data Memory from ACC with Carry	2	Z, C, AC, OV, SC, CZ
LSBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	2 <sup>Note</sup>	Z, C, AC, OV, SC, CZ
LDAA [m]	Decimal adjust ACC for Addition with result in Data Memory	2 <sup>Note</sup>	C
<b>Logic Operation</b>			
LAND A,[m]	Logical AND Data Memory to ACC	2	Z
LOR A,[m]	Logical OR Data Memory to ACC	2	Z
LXOR A,[m]	Logical XOR Data Memory to ACC	2	Z
LANDM A,[m]	Logical AND ACC to Data Memory	2 <sup>Note</sup>	Z
LORM A,[m]	Logical OR ACC to Data Memory	2 <sup>Note</sup>	Z
LXORM A,[m]	Logical XOR ACC to Data Memory	2 <sup>Note</sup>	Z
LCPL [m]	Complement Data Memory	2 <sup>Note</sup>	Z
LCPLA [m]	Complement Data Memory with result in ACC	2	Z
<b>Increment &amp; Decrement</b>			
LINCA [m]	Increment Data Memory with result in ACC	2	Z
LINC [m]	Increment Data Memory	2 <sup>Note</sup>	Z
LDECA [m]	Decrement Data Memory with result in ACC	2	Z
LDEC [m]	Decrement Data Memory	2 <sup>Note</sup>	Z
<b>Rotate</b>			
LRRA [m]	Rotate Data Memory right with result in ACC	2	None
LRR [m]	Rotate Data Memory right	2 <sup>Note</sup>	None
LRRCA [m]	Rotate Data Memory right through Carry with result in ACC	2	C
LRRC [m]	Rotate Data Memory right through Carry	2 <sup>Note</sup>	C
LRLA [m]	Rotate Data Memory left with result in ACC	2	None
LRL [m]	Rotate Data Memory left	2 <sup>Note</sup>	None
LRLCA [m]	Rotate Data Memory left through Carry with result in ACC	2	C
LRLC [m]	Rotate Data Memory left through Carry	2 <sup>Note</sup>	C
<b>Data Move</b>			
LMOV A,[m]	Move Data Memory to ACC	2	None
LMOV [m],A	Move ACC to Data Memory	2 <sup>Note</sup>	None
<b>Bit Operation</b>			
LCLR [m].i	Clear bit of Data Memory	2 <sup>Note</sup>	None
LSET [m].i	Set bit of Data Memory	2 <sup>Note</sup>	None

Mnemonic	Description	Cycles	Flag Affected
<b>Branch</b>			
LSZ [m]	Skip if Data Memory is zero	2 <sup>Note</sup>	None
LSZA [m]	Skip if Data Memory is zero with data movement to ACC	2 <sup>Note</sup>	None
LSNZ [m]	Skip if Data Memory is not zero	2 <sup>Note</sup>	None
LSZ [m].i	Skip if bit i of Data Memory is zero	2 <sup>Note</sup>	None
LSNZ [m].i	Skip if bit i of Data Memory is not zero	2 <sup>Note</sup>	None
LSIZ [m]	Skip if increment Data Memory is zero	2 <sup>Note</sup>	None
LSDZ [m]	Skip if decrement Data Memory is zero	2 <sup>Note</sup>	None
LSIZA [m]	Skip if increment Data Memory is zero with result in ACC	2 <sup>Note</sup>	None
LSDZA [m]	Skip if decrement Data Memory is zero with result in ACC	2 <sup>Note</sup>	None
<b>Table Read</b>			
LTABRD [m]	Read table (specific page) to TBLH and Data Memory	3 <sup>Note</sup>	None
LTABRDL [m]	Read table (last page) to TBLH and Data Memory	3 <sup>Note</sup>	None
LITABRD [m]	Increment table pointer TBLP first and Read table (specific page) to TBLH and Data Memory	3 <sup>Note</sup>	None
LITABRDL [m]	Increment table pointer TBLP first and Read table (last page) to TBLH and Data Memory	3 <sup>Note</sup>	None
<b>Miscellaneous</b>			
LCLR [m]	Clear Data Memory	2 <sup>Note</sup>	None
LSET [m]	Set Data Memory	2 <sup>Note</sup>	None
LSWAP [m]	Swap nibbles of Data Memory	2 <sup>Note</sup>	None
LSWAPA [m]	Swap nibbles of Data Memory with result in ACC	2	None

Note: 1. For these extended skip instructions, if the result of the comparison involves a skip then three cycles are required, if no skip takes place two cycles is required.

2. Any extended instruction which changes the contents of the PCL register will also require three cycles for execution.

## Instruction Definition

<b>ADC A,[m]</b>	Add Data Memory to ACC with Carry
Description	The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC + [m] + C$
Affected flag(s)	OV, Z, AC, C, SC
<b>ADCM A,[m]</b>	Add ACC to Data Memory with Carry
Description	The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.
Operation	$[m] \leftarrow ACC + [m] + C$
Affected flag(s)	OV, Z, AC, C, SC
<b>ADD A,[m]</b>	Add Data Memory to ACC
Description	The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC + [m]$
Affected flag(s)	OV, Z, AC, C, SC
<b>ADD A,x</b>	Add immediate data to ACC
Description	The contents of the Accumulator and the specified immediate data are added. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC + x$
Affected flag(s)	OV, Z, AC, C, SC
<b>ADDM A,[m]</b>	Add ACC to Data Memory
Description	The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.
Operation	$[m] \leftarrow ACC + [m]$
Affected flag(s)	OV, Z, AC, C, SC
<b>AND A,[m]</b>	Logical AND Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC \text{ "AND" } [m]$
Affected flag(s)	Z
<b>AND A,x</b>	Logical AND immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bit wise logical AND operation. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC \text{ "AND" } x$
Affected flag(s)	Z

<b>ANDM A,[m]</b>	Logical AND ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.
Operation	$[m] \leftarrow \text{ACC} \text{ "AND" } [m]$
Affected flag(s)	Z
<b>CALL addr</b>	Subroutine call
Description	Unconditionally calls a subroutine at the specified address. The Program Counter then increments by 1 to obtain the address of the next instruction which is then pushed onto the stack. The specified address is then loaded and the program continues execution from this new address. As this instruction requires an additional operation, it is a two cycle instruction.
Operation	Stack $\leftarrow$ Program Counter + 1 Program Counter $\leftarrow$ addr
Affected flag(s)	None
<b>CLR [m]</b>	Clear Data Memory
Description	Each bit of the specified Data Memory is cleared to 0.
Operation	$[m] \leftarrow 00\text{H}$
Affected flag(s)	None
<b>CLR [m].i</b>	Clear bit of Data Memory
Description	Bit i of the specified Data Memory is cleared to 0.
Operation	$[m].i \leftarrow 0$
Affected flag(s)	None
<b>CLR WDT</b>	Clear Watchdog Timer
Description	The TO, PDF flags and the WDT are all cleared.
Operation	WDT cleared TO $\leftarrow$ 0 PDF $\leftarrow$ 0
Affected flag(s)	TO, PDF
<b>CPL [m]</b>	Complement Data Memory
Description	Each bit of the specified Data Memory is logically complemented (1's complement). Bits which previously contained a 1 are changed to 0 and vice versa.
Operation	$[m] \leftarrow [m]$
Affected flag(s)	Z
<b>CPLA [m]</b>	Complement Data Memory with result in ACC
Description	Each bit of the specified Data Memory is logically complemented (1's complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC $\leftarrow$ [m]
Affected flag(s)	Z

<b>DAA [m]</b>	Decimal-Adjust ACC for addition with result in Data Memory
Description	Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.
Operation	[m] ← ACC + 00H or [m] ← ACC + 06H or [m] ← ACC + 60H or [m] ← ACC + 66H
Affected flag(s)	C
<b>DEC [m]</b>	Decrement Data Memory
Description	Data in the specified Data Memory is decremented by 1.
Operation	[m] ← [m] - 1
Affected flag(s)	Z
<b>DECA [m]</b>	Decrement Data Memory with result in ACC
Description	Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	ACC ← [m] - 1
Affected flag(s)	Z
<b>HALT</b>	Enter power down mode
Description	This instruction stops the program execution and turns off the system clock. The contents of the Data Memory and registers are retained. The WDT and prescaler are cleared. The power down flag PDF is set and the WDT time-out flag TO is cleared.
Operation	TO ← 0 PDF ← 1
Affected flag(s)	TO, PDF
<b>INC [m]</b>	Increment Data Memory
Description	Data in the specified Data Memory is incremented by 1.
Operation	[m] ← [m] + 1
Affected flag(s)	Z
<b>INCA [m]</b>	Increment Data Memory with result in ACC
Description	Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	ACC ← [m] + 1
Affected flag(s)	Z

<b>JMP addr</b>	Jump unconditionally
Description	The contents of the Program Counter are replaced with the specified address. Program execution then continues from this new address. As this requires the insertion of a dummy instruction while the new address is loaded, it is a two cycle instruction.
Operation	Program Counter $\leftarrow$ addr
Affected flag(s)	None
<b>MOV A,[m]</b>	Move Data Memory to ACC
Description	The contents of the specified Data Memory are copied to the Accumulator.
Operation	ACC $\leftarrow$ [m]
Affected flag(s)	None
<b>MOV A,x</b>	Move immediate data to ACC
Description	The immediate data specified is loaded into the Accumulator.
Operation	ACC $\leftarrow$ x
Affected flag(s)	None
<b>MOV [m],A</b>	Move ACC to Data Memory
Description	The contents of the Accumulator are copied to the specified Data Memory.
Operation	[m] $\leftarrow$ ACC
Affected flag(s)	None
<b>NOP</b>	No operation
Description	No operation is performed. Execution continues with the next instruction.
Operation	No operation
Affected flag(s)	None
<b>OR A,[m]</b>	Logical OR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.
Operation	ACC $\leftarrow$ ACC “OR” [m]
Affected flag(s)	Z
<b>OR A,x</b>	Logical OR immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bitwise logical OR operation. The result is stored in the Accumulator.
Operation	ACC $\leftarrow$ ACC “OR” x
Affected flag(s)	Z
<b>ORM A,[m]</b>	Logical OR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.
Operation	[m] $\leftarrow$ ACC “OR” [m]
Affected flag(s)	Z

<b>RET</b>	Return from subroutine
Description	The Program Counter is restored from the stack. Program execution continues at the restored address.
Operation	Program Counter ← Stack
Affected flag(s)	None
<b>RET A,x</b>	Return from subroutine and load immediate data to ACC
Description	The Program Counter is restored from the stack and the Accumulator loaded with the specified immediate data. Program execution continues at the restored address.
Operation	Program Counter ← Stack ACC ← x
Affected flag(s)	None
<b>RETI</b>	Return from interrupt
Description	The Program Counter is restored from the stack and the interrupts are re-enabled by setting the EMI bit. EMI is the master interrupt global enable bit. If an interrupt was pending when the RETI instruction is executed, the pending Interrupt routine will be processed before returning to the main program.
Operation	Program Counter ← Stack EMI ← 1
Affected flag(s)	None
<b>RL [m]</b>	Rotate Data Memory left
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.
Operation	[m].(i+1) ← [m].i; (i=0~6) [m].0 ← [m].7
Affected flag(s)	None
<b>RLA [m]</b>	Rotate Data Memory left with result in ACC
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.(i+1) ← [m].i; (i=0~6) ACC.0 ← [m].7
Affected flag(s)	None
<b>RLC [m]</b>	Rotate Data Memory left through Carry
Description	The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.
Operation	[m].(i+1) ← [m].i; (i=0~6) [m].0 ← C C ← [m].7
Affected flag(s)	C

<b>RLCA [m]</b>	Rotate Data Memory left through Carry with result in ACC
Description	Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.(i+1) ← [m].i; (i=0~6) ACC.0 ← C C ← [m].7
Affected flag(s)	C
<b>RR [m]</b>	Rotate Data Memory right
Description	The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.
Operation	[m].i ← [m].(i+1); (i=0~6) [m].7 ← [m].0
Affected flag(s)	None
<b>RRA [m]</b>	Rotate Data Memory right with result in ACC
Description	Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.i ← [m].(i+1); (i=0~6) ACC.7 ← [m].0
Affected flag(s)	None
<b>RRC [m]</b>	Rotate Data Memory right through Carry
Description	The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.
Operation	[m].i ← [m].(i+1); (i=0~6) [m].7 ← C C ← [m].0
Affected flag(s)	C
<b>RRCA [m]</b>	Rotate Data Memory right through Carry with result in ACC
Description	Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.i ← [m].(i+1); (i=0~6) ACC.7 ← C C ← [m].0
Affected flag(s)	C
<b>SBC A,[m]</b>	Subtract Data Memory from ACC with Carry
Description	The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	ACC ← ACC - [m] - C
Affected flag(s)	OV, Z, AC, C, SC, CZ

<b>SBC A, x</b>	Subtract immediate data from ACC with Carry
Description	The immediate data and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$ACC \leftarrow ACC - [m] - C$
Affected flag(s)	OV, Z, AC, C, SC, CZ
<b>SBCM A,[m]</b>	Subtract Data Memory from ACC with Carry and result in Data Memory
Description	The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$[m] \leftarrow ACC - [m] - C$
Affected flag(s)	OV, Z, AC, C, SC, CZ
<b>SDZ [m]</b>	Skip if decrement Data Memory is 0
Description	The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$[m] \leftarrow [m] - 1$ Skip if $[m]=0$
Affected flag(s)	None
<b>SDZA [m]</b>	Skip if decrement Data Memory is zero with result in ACC
Description	The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m] - 1$ Skip if $ACC=0$
Affected flag(s)	None
<b>SET [m]</b>	Set Data Memory
Description	Each bit of the specified Data Memory is set to 1.
Operation	$[m] \leftarrow FFH$
Affected flag(s)	None
<b>SET [m].i</b>	Set bit of Data Memory
Description	Bit i of the specified Data Memory is set to 1.
Operation	$[m].i \leftarrow 1$
Affected flag(s)	None

<b>SIZ [m]</b>	Skip if increment Data Memory is 0
Description	The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$[m] \leftarrow [m] + 1$ Skip if $[m]=0$
Affected flag(s)	None
<b>SIZA [m]</b>	Skip if increment Data Memory is zero with result in ACC
Description	The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m] + 1$ Skip if $ACC=0$
Affected flag(s)	None
<b>SNZ [m].i</b>	Skip if bit i of Data Memory is not 0
Description	If bit i of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.
Operation	Skip if $[m].i \neq 0$
Affected flag(s)	None
<b>SNZ [m]</b>	Skip if Data Memory is not 0
Description	The contents of the specified Data Memory are read out and then written back to the specified Data Memory again. If the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.
Operation	Skip if $[m] \neq 0$
Affected flag(s)	None
<b>SUB A,[m]</b>	Subtract Data Memory from ACC
Description	The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$ACC \leftarrow ACC - [m]$
Affected flag(s)	OV, Z, AC, C, SC, CZ
<b>SUBM A,[m]</b>	Subtract Data Memory from ACC with result in Data Memory
Description	The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$[m] \leftarrow ACC - [m]$
Affected flag(s)	OV, Z, AC, C, SC, CZ

<b>SUB A,x</b>	Subtract immediate data from ACC
Description	The immediate data specified by the code is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$ACC \leftarrow ACC - x$
Affected flag(s)	OV, Z, AC, C, SC, CZ
<b>SWAP [m]</b>	Swap nibbles of Data Memory
Description	The low-order and high-order nibbles of the specified Data Memory are interchanged.
Operation	$[m].3\sim[m].0 \leftrightarrow [m].7\sim[m].4$
Affected flag(s)	None
<b>SWAPA [m]</b>	Swap nibbles of Data Memory with result in ACC
Description	The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC.3\sim ACC.0 \leftarrow [m].7\sim[m].4$ $ACC.7\sim ACC.4 \leftarrow [m].3\sim[m].0$
Affected flag(s)	None
<b>SZ [m]</b>	Skip if Data Memory is 0
Description	The contents of the specified Data Memory are read out and then written back to the specified Data Memory again. If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	Skip if $[m]=0$
Affected flag(s)	None
<b>SZA [m]</b>	Skip if Data Memory is 0 with data movement to ACC
Description	The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m]$ Skip if $[m]=0$
Affected flag(s)	None
<b>SZ [m].i</b>	Skip if bit i of Data Memory is 0
Description	If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.
Operation	Skip if $[m].i=0$
Affected flag(s)	None

<b>TABRD [m]</b>	Read table (specific page) to TBLH and Data Memory
Description	The low byte of the program code (specific page) addressed by the table pointer (TBLP and TBHP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
<b>TABRDL [m]</b>	Read table (last page) to TBLH and Data Memory
Description	The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
<b>ITABRD [m]</b>	Increment table pointer low byte first and read table (specific page) to TBLH and Data Memory
Description	Increment table pointer low byte, TBLP, first and then the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
<b>ITABRDL [m]</b>	Increment table pointer low byte first and read table (last page) to TBLH and Data Memory
Description	Increment table pointer low byte, TBLP, first and then the low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
<b>XOR A,[m]</b>	Logical XOR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC “XOR” [m]
Affected flag(s)	Z
<b>XORM A,[m]</b>	Logical XOR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.
Operation	[m] ← ACC “XOR” [m]
Affected flag(s)	Z
<b>XOR A,x</b>	Logical XOR immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bitwise logical XOR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC “XOR” x
Affected flag(s)	Z

### Extended Instruction Definition

The extended instructions are used to directly access the data stored in any data memory sections.

**LADC A,[m]**      Add Data Memory to ACC with Carry

Description      The contents of the specified Data Memory, Accumulator and the carry flag are added.  
The result is stored in the Accumulator.

Operation         $ACC \leftarrow ACC + [m] + C$

Affected flag(s)    OV, Z, AC, C, SC

**LADCM A,[m]**    Add ACC to Data Memory with Carry

Description      The contents of the specified Data Memory, Accumulator and the carry flag are added.  
The result is stored in the specified Data Memory.

Operation         $[m] \leftarrow ACC + [m] + C$

Affected flag(s)    OV, Z, AC, C, SC

**LADD A,[m]**      Add Data Memory to ACC

Description      The contents of the specified Data Memory and the Accumulator are added.  
The result is stored in the Accumulator.

Operation         $ACC \leftarrow ACC + [m]$

Affected flag(s)    OV, Z, AC, C, SC

**LADDM A,[m]**    Add ACC to Data Memory

Description      The contents of the specified Data Memory and the Accumulator are added.  
The result is stored in the specified Data Memory.

Operation         $[m] \leftarrow ACC + [m]$

Affected flag(s)    OV, Z, AC, C, SC

**LAND A,[m]**      Logical AND Data Memory to ACC

Description      Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.

Operation         $ACC \leftarrow ACC \text{ "AND" } [m]$

Affected flag(s)    Z

**LANDM A,[m]**    Logical AND ACC to Data Memory

Description      Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.

Operation         $[m] \leftarrow ACC \text{ "AND" } [m]$

Affected flag(s)    Z

<b>LCLR [m]</b>	Clear Data Memory
Description	Each bit of the specified Data Memory is cleared to 0.
Operation	$[m] \leftarrow 00H$
Affected flag(s)	None
<b>LCLR [m].i</b>	Clear bit of Data Memory
Description	Bit <i>i</i> of the specified Data Memory is cleared to 0.
Operation	$[m].i \leftarrow 0$
Affected flag(s)	None
<b>LCPL [m]</b>	Complement Data Memory
Description	Each bit of the specified Data Memory is logically complemented (1's complement). Bits which previously contained a 1 are changed to 0 and vice versa.
Operation	$[m] \leftarrow [m]$
Affected flag(s)	Z
<b>LCPLA [m]</b>	Complement Data Memory with result in ACC
Description	Each bit of the specified Data Memory is logically complemented (1's complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	$ACC \leftarrow [m]$
Affected flag(s)	Z
<b>LDAA [m]</b>	Decimal-Adjust ACC for addition with result in Data Memory
Description	Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.
Operation	$[m] \leftarrow ACC + 00H$ or $[m] \leftarrow ACC + 06H$ or $[m] \leftarrow ACC + 60H$ or $[m] \leftarrow ACC + 66H$
Affected flag(s)	C
<b>LDEC [m]</b>	Decrement Data Memory
Description	Data in the specified Data Memory is decremented by 1.
Operation	$[m] \leftarrow [m] - 1$
Affected flag(s)	Z

<b>LDECA [m]</b>	Decrement Data Memory with result in ACC
Description	Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC \leftarrow [m] - 1$
Affected flag(s)	Z
<b>LINC [m]</b>	Increment Data Memory
Description	Data in the specified Data Memory is incremented by 1.
Operation	$[m] \leftarrow [m] + 1$
Affected flag(s)	Z
<b>LINCA [m]</b>	Increment Data Memory with result in ACC
Description	Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC \leftarrow [m] + 1$
Affected flag(s)	Z
<b>LMOV A,[m]</b>	Move Data Memory to ACC
Description	The contents of the specified Data Memory are copied to the Accumulator.
Operation	$ACC \leftarrow [m]$
Affected flag(s)	None
<b>LMOV [m],A</b>	Move ACC to Data Memory
Description	The contents of the Accumulator are copied to the specified Data Memory.
Operation	$[m] \leftarrow ACC$
Affected flag(s)	None
<b>LOR A,[m]</b>	Logical OR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.
Operation	$ACC \leftarrow ACC \text{ "OR" } [m]$
Affected flag(s)	Z
<b>LORM A,[m]</b>	Logical OR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.
Operation	$[m] \leftarrow ACC \text{ "OR" } [m]$
Affected flag(s)	Z

<b>LRL [m]</b>	Rotate Data Memory left
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.
Operation	$[m].(i+1) \leftarrow [m].i; (i=0\sim6)$ $[m].0 \leftarrow [m].7$
Affected flag(s)	None
<b>LRLA [m]</b>	Rotate Data Memory left with result in ACC
Description	The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	$ACC.(i+1) \leftarrow [m].i; (i=0\sim6)$ $ACC.0 \leftarrow [m].7$
Affected flag(s)	None
<b>LRLC [m]</b>	Rotate Data Memory left through Carry
Description	The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.
Operation	$[m].(i+1) \leftarrow [m].i; (i=0\sim6)$ $[m].0 \leftarrow C$ $C \leftarrow [m].7$
Affected flag(s)	C
<b>LRLCA [m]</b>	Rotate Data Memory left through Carry with result in ACC
Description	Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	$ACC.(i+1) \leftarrow [m].i; (i=0\sim6)$ $ACC.0 \leftarrow C$ $C \leftarrow [m].7$
Affected flag(s)	C
<b>LRR [m]</b>	Rotate Data Memory right
Description	The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.
Operation	$[m].i \leftarrow [m].(i+1); (i=0\sim6)$ $[m].7 \leftarrow [m].0$
Affected flag(s)	None

<b>LRRA [m]</b>	Rotate Data Memory right with result in ACC
Description	Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.i ← [m].(i+1); (i=0~6) ACC.7 ← [m].0
Affected flag(s)	None
<b>LRRC [m]</b>	Rotate Data Memory right through Carry
Description	The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.
Operation	[m].i ← [m].(i+1); (i=0~6) [m].7 ← C C ← [m].0
Affected flag(s)	C
<b>LRRCA [m]</b>	Rotate Data Memory right through Carry with result in ACC
Description	Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.
Operation	ACC.i ← [m].(i+1); (i=0~6) ACC.7 ← C C ← [m].0
Affected flag(s)	C
<b>LSBC A,[m]</b>	Subtract Data Memory from ACC with Carry
Description	The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	ACC ← ACC – [m] – C
Affected flag(s)	OV, Z, AC, C, SC, CZ
<b>LSBCM A,[m]</b>	Subtract Data Memory from ACC with Carry and result in Data Memory
Description	The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	[m] ← ACC – [m] – C
Affected flag(s)	OV, Z, AC, C, SC, CZ

<b>LSDZ [m]</b>	Skip if decrement Data Memory is 0
Description	The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$[m] \leftarrow [m] - 1$ Skip if $[m]=0$
Affected flag(s)	None
<b>LSDZA [m]</b>	Skip if decrement Data Memory is zero with result in ACC
Description	The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0, the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m] - 1$ Skip if $ACC=0$
Affected flag(s)	None
<b>LSET [m]</b>	Set Data Memory
Description	Each bit of the specified Data Memory is set to 1.
Operation	$[m] \leftarrow FFH$
Affected flag(s)	None
<b>LSET [m].i</b>	Set bit of Data Memory
Description	Bit i of the specified Data Memory is set to 1.
Operation	$[m].i \leftarrow 1$
Affected flag(s)	None
<b>LSIZ [m]</b>	Skip if increment Data Memory is 0
Description	The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$[m] \leftarrow [m] + 1$ Skip if $[m]=0$
Affected flag(s)	None

<b>LSIZA [m]</b>	Skip if increment Data Memory is zero with result in ACC
Description	The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m] + 1$ Skip if ACC=0
Affected flag(s)	None
<b>LSNZ [m].i</b>	Skip if bit i of Data Memory is not 0
Description	If bit i of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is 0 the program proceeds with the following instruction.
Operation	Skip if $[m].i \neq 0$
Affected flag(s)	None
<b>LSNZ [m]</b>	Skip if Data Memory is not 0
Description	The contents of the specified Data Memory are read out and then written to the specified Data Memory again. If the content of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is 0 the program proceeds with the following instruction.
Operation	Skip if $[m] \neq 0$
Affected flag(s)	None
<b>LSUB A,[m]</b>	Subtract Data Memory from ACC
Description	The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$ACC \leftarrow ACC - [m]$
Affected flag(s)	OV, Z, AC, C, SC, CZ
<b>LSUBM A,[m]</b>	Subtract Data Memory from ACC with result in Data Memory
Description	The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.
Operation	$[m] \leftarrow ACC - [m]$
Affected flag(s)	OV, Z, AC, C, SC, CZ

<b>LSWAP [m]</b>	Swap nibbles of Data Memory
Description	The low-order and high-order nibbles of the specified Data Memory are interchanged.
Operation	$[m].3\sim[m].0 \leftrightarrow [m].7\sim[m].4$
Affected flag(s)	None
<b>LSWAPA [m]</b>	Swap nibbles of Data Memory with result in ACC
Description	The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.
Operation	$ACC.3\sim ACC.0 \leftarrow [m].7\sim[m].4$ $ACC.7\sim ACC.4 \leftarrow [m].3\sim[m].0$
Affected flag(s)	None
<b>LSZ [m]</b>	Skip if Data Memory is 0
Description	The contents of the specified Data Memory are read out and then written to the specified Data Memory again. If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	Skip if $[m]=0$
Affected flag(s)	None
<b>LSZA [m]</b>	Skip if Data Memory is 0 with data movement to ACC
Description	The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0 the program proceeds with the following instruction.
Operation	$ACC \leftarrow [m]$ Skip if $[m]=0$
Affected flag(s)	None
<b>LSZ [m].i</b>	Skip if bit i of Data Memory is 0
Description	If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a three cycle instruction. If the result is not 0, the program proceeds with the following instruction.
Operation	Skip if $[m].i=0$
Affected flag(s)	None
<b>LTABRD [m]</b>	Read table (specific page) to TBLH and Data Memory
Description	The low byte of the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	$[m] \leftarrow$ program code (low byte) $TBLH \leftarrow$ program code (high byte)
Affected flag(s)	None

<b>LTABRDL [m]</b>	Read table (last page) to TBLH and Data Memory
Description	The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
<b>LITABRD [m]</b>	Increment table pointer low byte first and read table (specific page) to TBLH and Data Memory
Description	Increment table pointer low byte, TBLP, first and then the program code (specific page) addressed by the table pointer (TBHP and TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
<b>LITABRDL [m]</b>	Increment table pointer low byte first and read table (last page) to TBLH and Data Memory
Description	Increment table pointer low byte, TBLP, first and then the low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.
Operation	[m] ← program code (low byte) TBLH ← program code (high byte)
Affected flag(s)	None
<b>LXOR A,[m]</b>	Logical XOR Data Memory to ACC
Description	Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC “XOR” [m]
Affected flag(s)	Z
<b>LXORM A,[m]</b>	Logical XOR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.
Operation	[m] ← ACC “XOR” [m]
Affected flag(s)	Z

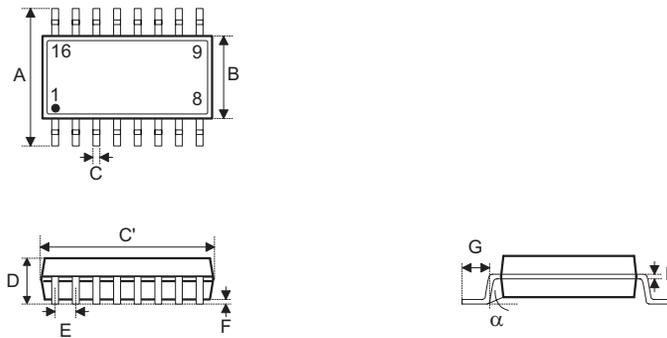
## Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the [Holtek website](#) for the latest version of the [Package/Carton Information](#).

Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- The Operation Instruction of Packing Materials
- Carton information

**16-pin NSOP (150mil) Outline Dimensions**



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.236 BSC		
B	0.154 BSC		
C	0.012	—	0.020
C'	0.390 BSC		
D	—	—	0.069
E	0.050 BSC		
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
$\alpha$	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	6.00 BSC		
B	3.90 BSC		
C	0.31	—	0.51
C'	9.90 BSC		
D	—	—	1.75
E	1.27 BSC		
F	0.10	—	0.25
G	0.40	—	1.27
H	0.10	—	0.25
$\alpha$	0°	—	8°

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